

PIC24HJ32GP202/204 and PIC24HJ16GP304 Data Sheet

High-Performance, 16-bit Microcontrollers

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ISBN: 978-1-61341-366-1

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PIC24HJ32GP202/204 and PIC24HJ16GP304

High-Performance, 16-bit Microcontrollers

Operating Range:

- Up to 40 MIPS operation (@ 3.0-3.6V):
 - Industrial temperature range (-40°C to +85°C)
 - Extended temperature range (-40°C to +125°C)
- Up to 20 MIPS operation (@ 3.0-3.6V):
 - High temperature range (-40°C to +150°C)

High-Performance CPU:

- Modified Harvard architecture
- C compiler optimized instruction set
- 16 bit wide data path
- 24 bit wide instructions
- Linear program memory addressing up to 4M instruction words
- · Linear data memory addressing up to 64 Kbytes
- 71 base instructions, mostly one word/one cycle
- Sixteen 16-bit general purpose registers
- Flexible and powerful addressing modes
- Software stack
- 16 x 16 multiply operations
- 32/16 and 16/16 divide operations
- Up to ±16-bit shifts for up to 40-bit data

Interrupt Controller:

- 5-cycle latency
- Up to 21 available interrupt sources
- Up to three external interrupts
- Seven programmable priority levels
- · Four processor exceptions

On-Chip Flash and SRAM:

- Flash program memory (up to 32 Kbytes)
- Data SRAM (2 Kbytes)
- Boot and general security for program Flash

Digital I/O:

- Peripheral Pin Select (PPS) functionality
- Up to 35 programmable digital I/O pins
- Wake-up/Interrupt-on-Change for up to 31 pins
- Output pins can drive from 3.0V to 3.6V
- Up to 5.5V output with open drain configuration on 5V tolerant pins with external pull-up
- 4 mA sink on all I/O pins

System Management:

- Flexible clock options:
 - External, crystal, resonator, internal RC
 - Fully integrated Phase-Locked Loop (PLL)
 - Extremely low jitter PLL
- Power-up Timer
- Oscillator Start-up Timer/Stabilizer
- · Watchdog Timer with its own RC oscillator
- Fail-Safe Clock Monitor (FSCM)
- · Reset by multiple sources

Power Management:

- On-chip 2.5V voltage regulator
- · Switch between clock sources in real time
- Idle, Sleep and Doze modes with fast wake-up

Timers/Capture/Compare:

- Timer/Counters, up to three 16-bit timers:
 - Can pair up to make one 32-bit timer
 - One timer runs as Real-Time Clock with external 32.768 kHz oscillator
 - Programmable prescaler
- Input Capture (up to four channels):
 - Capture on up, down or both edges
 - 16-bit capture input functions
 - 4-deep FIFO on each capture
- Output Compare (up to two channels):
 - Single or Dual 16-bit Compare mode
 - 16-bit Glitchless PWM Mode

Communication Modules:

- 4-wire SPI
 - Framing supports I/O interface to simple codecs
 - Supports 8-bit and 16-bit data
 - Supports all serial clock formats and sampling modes
- I²C[™]
 - Full Multi-Master Slave mode support
 - 7-bit and 10-bit addressing
 - Bus collision detection and arbitration
 - Integrated signal conditioning
 - Slave address masking
- UART
 - Interrupt on address bit detect
 - Interrupt on UART error
 - Wake-up on START bit from Sleep mode
 - 4-character TX and RX FIFO buffers
 - LIN bus support
 - IrDA® encoding and decoding in hardware
 - High-Speed Baud mode
 - Hardware flow control with CTS and RTS

Analog-to-Digital Converters (ADCs):

- 10-bit, 1.1 Msps or 12-bit, 500 ksps conversion:
 - Two and four simultaneous samples (10-bit ADC)
 - Up to 13 input channels with auto-scanning
 - Conversion start can be manual or synchronized with one of four trigger sources
 - Conversion possible in Sleep mode
 - ±2 LSb max integral nonlinearity
 - ±1 LSb max differential nonlinearity

CMOS Flash Technology:

- Low-power, high-speed Flash technology
- Fully static design
- 3.3V (±10%) operating voltage
- Industrial and extended temperature
- Low-power consumption

Packaging:

- 28-pin SPDIP/SOIC/SSOP/QFN-S
- 44-pin QFN/TQFP

Note: See Table 1 for the exact peripheral features per device.

PIC24HJ32GP202/204 and PIC24HJ16GP304 Product Families

The device names, pin counts, memory sizes and peripheral availability of each family are listed in Table 1, followed by their pinout diagrams.

		ory			Re	mappa	ble Pe	ripher	als				-	
Device	Pins	Program Flash Memory (Kbytes)	MAA	Remappable Pins	16-bit Timer	Input Capture	Output Compare Standard PWM	UART	External Interrupts ⁽²⁾	SPI	10/12-bit ADC	I²C™	(Maximum) suid O/I	Packages
PIC24HJ32GP202	28	32	2	16	3 ⁽¹⁾	4	2	1	3	1	1 ADC, 10 ch	1	21	SPDIP SOIC SSOP QFN-S
PIC24HJ32GP204	44	32	2	26	3 ⁽¹⁾	4	2	1	3	1	1 ADC, 13 ch	1	35	QFN TQFP
PIC24HJ16GP304	44	16	2	26	3 ⁽¹⁾	4	2	1	3	1	1 ADC, 13 ch	1	35	QFN TQFP

TABLE 1: PIC24HJ32GP202/204 AND PIC24HJ16GP304 CONTROLLER FAMILIES

Note 1: Only two out of three timers are remappable.

2: Only two out of three interrupts are remappable.

Pin Diagrams



Pin Diagrams (Continued) 44-Pin QFN⁽²⁾ = Pins are up to 5V tolerant PGEC1/AN3/C2IN+/RP1⁽¹⁾/CN5/RB1 PGED1/AN2/C2IN-/RP0⁽¹⁾/CN4/RB0 AN10/RP14⁽¹⁾/CN12/RB14 TCK/RA7 TMS/RA10 AN9/RP15⁽¹⁾/CN11/RB15 AN0/VREF+/CN2/RA0 AN1/VREF-/CN3/RA1 MCLR AVDD AVSS AN4/RP2⁽¹⁾/CN6/RB2 23 11 AN11/RP13⁽¹⁾/CN13/RB13 AN5/RP3(1)/CN7/RB3 24 AN12/RP12⁽¹⁾/CN14/RB12 10 AN6/RP16⁽¹⁾/CN8/RC0 25 PGEC2/RP11⁽¹⁾/CN15/RB11 9 AN7/RP17(1)/CN9/RC1 26 PGED2/RP10(1)/CN16/RB10 8 AN8/RP18(1)/CN10/RC2 27 VCAP(3) 7 PIC24HJ32GP204 VDD 28 6 Vss PIC24HJ16GP304 Vss 29 5 RP25⁽¹⁾/CN19/RC9 OSC1/CLKI/CN30/RA2 30 RP24⁽¹⁾/CN20/RC8 4 RP23(1)/CN17/RC7 OSC2/CLKO/CN29/RA3 31 3 TDO/RA8 32 RP22(1)/CN18/RC6 2 SOSCI/RP4⁽¹⁾/CN1/RB4 33 % % % % SDA1/RP9(1)/CN21/RB9 38 39 40 45 43 44 1 RP19⁽¹⁾/CN28/RC3 RP20⁽¹⁾/CN25/RC4 RP21⁽¹⁾/CN26/RC5 VSS PGED3/ASDA1/RP5⁽¹⁾/CN27/RB5 PGEC3/ASCL1/RP6⁽¹⁾/CN24/RB6 VDD SOSCO/T1CK/CN0/RA4 TDI/RA9 INT0/RP7⁽¹⁾/CN23/RB7 SCL1/RP8⁽¹⁾/CN22/RB8 Note 1: The RPn pins can be used by any remappable peripheral. See Table 1 for the list of available peripherals. 2: The metal plane at the bottom of the device is not connected to any pins and is recommended to be connected to VSs externally. 3: Refer to Section 2.3 "CPU Logic Filter Capacitor Connection (VCAP)" for proper connection to this pin.

Pin Diagrams (Continued)



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An errata sheet, describing minor operational differences from the data sheet and recommended workarounds, may exist for current devices. As device/documentation issues become known to us, we will publish an errata sheet. The errata will specify the revision of silicon and revision of document to which it applies.

To determine if an errata sheet exists for a particular device, please check with one of the following:

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NOTES:

1.0 DEVICE OVERVIEW

- Note 1: This data sheet summarizes the features of the PIC24HJ32GP202/204 and PIC24HJ16GP304 devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the *"dsPIC33F/PIC24H Family Reference Manual"*. Please see the Microchip web site (www.microchip.com) for the latest dsPIC33F/PIC24H Family Reference Manual sections.
 - 2: Some registers and associated bits described in this section may not be available on all devices. Refer to Section 4.0 "Memory Organization" in this data sheet for device-specific register and bit information.

This document contains device-specific information for the following devices:

- PIC24HJ32GP202
- PIC24HJ32GP204
- PIC24HJ16GP304

Figure 1-1 shows a general block diagram of the core and peripheral modules in the PIC24HJ32GP202/204 and PIC24HJ16GP304 family of devices. Table 1-1 lists the functions of the various pins shown in the pinout diagrams.



Pin Name	Pin Type	Buffer Type	PPS	Description									
AN0-AN12		Analog	No	Analog input channels.									
CLKI CLKO	I O	ST/CMOS	No No	External clock source input. Always associated with OSC1 pin function Oscillator crystal output. Connects to crystal or resonator in Crystal Oscillator mode. Optionally functions as CLKO in RC and EC modes. Always associated with OSC2 pin function.									
OSC1	I	ST/CMOS	No	Oscillator crystal input. ST buffer when configured in RC mode; CMOS									
OSC2	I/O	—	No	otherwise. Oscillator crystal output. Connects to crystal or resonator in Crystal Oscillator mode. Optionally functions as CLKO in RC and EC modes.									
SOSCI SOSCO	I O	ST/CMOS	No No	32.768 kHz low-power oscillator crystal input; CMOS otherwise. 32.768 kHz low-power oscillator crystal output.									
CN0-CN30	I	ST	No	Change notification inputs. Can be software programmed for internal weak pull-ups on all inputs.									
IC1-IC2 IC7-IC8	I	ST	Yes Yes	Capture inputs 1/2. Capture inputs 7/8.									
OCFA OC1-OC2	I O	ST —	Yes Yes	Compare Fault A input (for Compare Channels 1 and 2). Compare outputs 1 through 2.									
INT0 INT1 INT2		ST ST ST	No Yes Yes	External interrupt 0. External interrupt 1. External interrupt 2.									
RA0-RA4 RA7-RA10	I/O	ST	No No	PORTA is a bidirectional I/O port.									
RB0-RB15	I/O	ST	No	PORTB is a bidirectional I/O port.									
RC0-RC9	I/O	ST	No	PORTC is a bidirectional I/O port.									
T1CK	Ι	ST	No	Timer1 external clock input.									
T2CK T3CK		ST ST	Yes Yes	Timer2 external clock input. Timer3 external clock input.									
U1CTS	1	ST	Yes	UART1 clear to send.									
U1RTS	Ō	_	Yes	UART1 ready to send.									
U1RX	I	ST	Yes	UART1 receive.									
U1TX	0	_	Yes	UART1 transmit.									
SCK1	I/O	ST	Yes	Synchronous serial clock input/output for SPI1.									
SDI1		ST	Yes	SPI1 data in.									
<u>SDO</u> 1 SS1	0 I/O	ST	Yes Yes	SPI1 data out. SPI1 slave synchronization or frame pulse I/O.									
SCL1	I/O	ST	No	Synchronous serial clock input/output for I2C1.									
SDA1	1/O	ST	No	Synchronous serial data input/output for I2C1.									
ASCL1	I/O	ST	No	Alternate synchronous serial clock input/output for I2C1.									
ASDA1	I/O	ST	No	Alternate synchronous serial data input/output for I2C1.									
TMS	I	ST	No	JTAG Test mode select pin.									
тск	I	ST	No	JTAG test clock input pin.									
TDI TDO		ST	No No	JTAG test data input pin.									
PGED	I/O	ST	No										
PGEC1		ST	No	Clock input pin for programming/debugging communication channel 1.									
PGED2	I/O	ST	No	Data I/O pin for programming/debugging communication channel 2.									
PGEC2	1	ST	No	Clock input pin for programming/debugging communication channel 2.									
PGED3	I/O	ST	No	Data I/O pin for programming/debugging communication channel 3.									
PGEC3	1 1	ST	No	Clock input pin for programming/debugging communication channel 3.									

PPS = Peripheral Pin Select

	•												
Pin Nam	е	Pin Type	Buffer Type	PPS	Description								
VCAP		Р	_	No	CPU logic filter capacitor connection.								
Vss		Р	_	No	Ground reference for logic and I/O pins.								
Vref+		Ι	Analog	No	Analog voltage reference (high) input.								
Vref-		Ι	Analog	No	Analog voltage reference (low) input.								
Avdd		Ρ	Р	No	Positive supply for analog modules. This pin must be connected at all times.								
MCLR		I/P	ST	No	Master Clear (Reset) input. This pin is an active-low Reset to the device.								
Avss		Р	Р	No	Ground reference for analog modules.								
Vdd		Р	_	No	lo Positive supply for peripheral logic and I/O pins.								
Legend: (CMO	S = CM	OS compatil	ole inpu	t or output Analog = Analog input O = Output								

I = Input

TABLE 1-1: PINOUT I/O DESCRIPTIONS (CONTINUED)

ST = Schmitt Trigger input with CMOS levels PPS = Peripheral Pin Select O = OutputP = Power

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1.1 Referenced Sources

This device data sheet is based on the following individual chapters of the *"dsPIC33F/PIC24H Family Reference Manual"*. These documents should be considered as the general reference for the operation of a particular module or device feature.

Note: To access the documents listed below, browse to the documentation section of the PIC24HJ32GP204 product page on the Microchip web site (www.microchip.com) or select a family reference manual section from the following list.

> In addition to parameters, features, and other documentation, the resulting page provides links to the related family reference manual sections.

- Section 1. "Introduction" (DS70197)
- Section 2. "CPU" (DS70204)
- Section 3. "Data Memory" (DS70202)
- Section 4. "Program Memory" (DS70203)
- Section 5. "Flash Programming" (DS70191)
- Section 6. "Interrupts" (DS70184)
- Section 7. "Oscillator" (DS70186)
- Section 8. "Reset" (DS70192)
- Section 9. "Watchdog Timer and Power-Saving Modes" (DS70196)
- Section 10. "I/O Ports" (DS70193)
- Section 11. "Timers" (DS70205)
- Section 12. "Input Capture" (DS70198)
- Section 13. "Output Compare" (DS70209)
- Section 16. "Analog-to-Digital Converter (ADC)" (DS70183)
- Section 17. "UART" (DS70188)
- Section 18. "Serial Peripheral Interface (SPI)" (DS70206)
- Section 19. "Inter-Integrated Circuit™ (I2C™)" (DS70195)
- Section 23. "CodeGuard™ Security" (DS70199)
- Section 24. "Programming and Diagnostics" (DS70207)
- Section 25. "Device Configuration" (DS70194)
- Section 26. "Development Tool Support" (DS70200)

NOTES:

2.0 GUIDELINES FOR GETTING STARTED WITH 16-BIT MICROCONTROLLERS

- Note 1: This data sheet summarizes the features of the PIC24HJ32GP202/204 and PIC24HJ16GP304 family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the "dsPIC33F/PIC24H Family Reference Manual", which is available from the Microchip website (www.microchip.com).
 - 2: Some registers and associated bits described in this section may not be available on all devices. Refer to Section 4.0 "Memory Organization" in this data sheet for device-specific register and bit information.

2.1 Basic Connection Requirements

Getting started with the PIC24HJ32GP202/204 and PIC24HJ16GP304 family of 16-bit microcontrollers requires attention to a minimal set of device pin connections before proceeding with development. The following is a list of pin names, which must always be connected:

- All VDD and Vss pins (see Section 2.2 "Decoupling Capacitors")
- All AVDD and AVSS pins (even if the ADC module is not used)

(see Section 2.2 "Decoupling Capacitors")

- VCAP (see Section 2.3 "CPU Logic Filter Capacitor Connection (VCAP)")
- MCLR pin (see Section 2.4 "Master Clear (MCLR) Pin")
- PGECx/PGEDx pins used for In-Circuit Serial Programming[™] (ICSP[™]) and debugging purposes (see Section 2.5 "ICSP Pins")
- OSC1 and OSC2 pins when external oscillator source is used

(see Section 2.6 "External Oscillator Pins")

Additionally, the following pins may be required:

• VREF+/VREF- pins are used when external voltage reference for the ADC module is implemented

Note:	The	AVdd	and	AVss	pins	mu	st be
	conne	ected	indep	endent	of	the	ADC
	voltag	ge refe					

2.2 Decoupling Capacitors

The use of decoupling capacitors on every pair of power supply pins, such as VDD, VSS, AVDD and AVSs is required.

Consider the following criteria when using decoupling capacitors:

- Value and type of capacitor: Recommendation of 0.1 μ F (100 nF), 10-20V. This capacitor should be a low-ESR and have a resonance frequency in the range of 20 MHz and higher. It is recommended that ceramic capacitors be used.
- Placement on the printed circuit board: The decoupling capacitors should be placed as close to the pins as possible. It is recommended to place the capacitors on the same side of the board as the microcontroller. If space is constricted, the capacitor can be placed on another layer on the PCB using a via; however, ensure that the trace length from the pin to the capacitor is within one-quarter inch (6 mm) in length.
- Handling high frequency noise: If the board is experiencing high frequency noise, upward of tens of MHz, add a second ceramic-type capacitor in parallel to the above described decoupling capacitor. The value of the second capacitor can be in the range of $0.01 \ \mu$ F to $0.001 \ \mu$ F. Place this second capacitor next to the primary decoupling capacitor. In high-speed circuit designs, consider implementing a decade pair of capacitances as close to the power and ground pins as possible. For example, $0.1 \ \mu$ F in parallel with $0.001 \ \mu$ F.
- Maximizing performance: On the board layout from the power supply circuit, run the power and return traces to the decoupling capacitors first, and then to the microcontroller pins. This ensures that the decoupling capacitors are first in the power chain. Equally important is to keep the trace length between the capacitor and the power pins to a minimum thereby reducing PCB track inductance.

FIGURE 2-1: RECOMMENDED MINIMUM CONNECTION



2.2.1 TANK CAPACITORS

On boards with power traces running longer than six inches in length, it is suggested to use a tank capacitor for integrated circuits including microcontrollers to supply a local power source. The value of the tank capacitor should be determined based on the trace resistance that connects the power supply source to the microcontroller, and the maximum current drawn by the microcontroller in the application. In other words, select the tank capacitor so that it meets the acceptable voltage sag at the device. Typical values range from 4.7 μ F to 47 μ F.

2.3 CPU Logic Filter Capacitor Connection (VCAP)

A low-ESR (< 5 Ohms) capacitor is required on the VCAP pin, which is used to stabilize the voltage regulator output voltage. The VCAP pin must not be connected to VDD, and must have a capacitor between 4.7 μ F and 10 μ F, 16V connected to ground. The type can be ceramic or tantalum. Refer to **Section 22.0** "**Electrical Characteristics**" for additional information.

The placement of this capacitor should be close to the VCAP. It is recommended that the trace length not exceed one-quarter inch (6 mm). Refer to **Section 19.2 "On-Chip Voltage Regulator"** for details.

2.4 Master Clear (MCLR) Pin

The MCLR pin provides for two specific device functions:

- Device Reset
- Device programming and debugging

During device programming and debugging, the resistance and capacitance that can be added to the pin must be considered. Device programmers and debuggers drive the $\overline{\text{MCLR}}$ pin. Consequently, specific voltage levels (VIH and VIL) and fast signal transitions must not be adversely affected. Therefore, specific values of R and C will need to be adjusted based on the application and PCB requirements.

For example, as shown in Figure 2-2, it is recommended that capacitor C is isolated from the MCLR pin during programming and debugging operations.

Place the components shown in Figure 2-2 within one-quarter inch (6 mm) from the MCLR pin.





^{2:} $R1 \le 470W$ will limit any current flowing into $\overline{\text{MCLR}}$ from the external capacitor C, in the event of $\overline{\text{MCLR}}$ pin breakdown, due to Electrostatic Discharge (ESD) or <u>Electrical</u> Overstress (EOS). Ensure that the MCLR pin VIH and VIL specifications are met.

2.5 ICSP Pins

The PGECx and PGEDx pins are used for In-Circuit Serial ProgrammingTM (ICSP)TM and debugging purposes. It is recommended to keep the trace length between the ICSP connector and the ICSP pins on the microcontroller as short as possible. If the ICSP connector is expected to experience an ESD event, a series resistor is recommended, with the value in the range of a few tens of Ohms, not to exceed 100 Ohms.

Pull-up resistors, series diodes and capacitors on the PGECx and PGEDx pins are not recommended as they will interfere with the programmer/debugger communications to the device. If such discrete components are an application requirement, they should be removed from the circuit during programming and debugging. Alternatively, refer to the AC/DC characteristics and timing requirements information in the respective device Flash programming specification for information on capacitive loading limits and pin input voltage high (VIH) and input low (VIL) requirements.

Ensure that the "Communication Channel Select" (i.e., PGECx/PGEDx pins) programmed into the device matches the physical connections for the ICSP to MPLAB[®] ICD 2, MPLAB ICD 3, or MPLAB REAL ICE[™] in-circuit emulator

For more information on MPLAB ICD 2, MPLAB ICD 3, or MPLAB REAL ICE in-circuit emulator connection requirements, refer to the following documents that are available on the Microchip website.

- "MPLAB[®] ICD 2 In-Circuit Debugger User's Guide" DS51331
- *"Using MPLAB[®] ICD 2"* (poster) DS51265
- "MPLAB[®] ICD 2 Design Advisory" DS51566
- "Using MPLAB[®] ICD 3" (poster) DS51765
- "MPLAB[®] ICD 3 Design Advisory" DS51764
- "MPLAB[®] REAL ICE™ In-Circuit Emulator User's Guide" DS51616
- "Using MPLAB[®] REAL ICE™ In-Circuit Emulator" (poster) DS51749

2.6 External Oscillator Pins

Many microcontrollers have options for at least two oscillators: a high-frequency primary oscillator and a low-frequency secondary oscillator (refer to Section 8.0 "Oscillator Configuration" for details).

The oscillator circuit should be placed on the same side of the board as the microcontroller. Also, place the oscillator circuit close to the respective oscillator pins, not exceeding one-half inch (12 mm) distance between them. The load capacitors should be placed next to the oscillator itself, on the same side of the board. Use a grounded copper pour around the oscillator circuit to isolate them from surrounding circuits. The grounded copper pour should be routed directly to the MCU ground. Do not run any signal traces or power traces inside the ground pour. Also, if using a two-sided board, avoid any traces on the other side of the board where the crystal is placed. A suggested layout is shown in Figure 2-3.

FIGURE 2-3: SUGGESTED PLACEMENT OF THE OSCILLATOR CIRCUIT



2.7 Oscillator Value Conditions on Device Start-up

If the PLL of the target device is enabled and configured for the device start-up oscillator, the maximum oscillator source frequency must be limited to \leq 8 MHz for start-up with PLL enabled. This means that if the external oscillator frequency is outside this range, the application must start-up in FRC mode first. The default PLL settings after a POR with an oscillator frequency outside this range will violate the device operating speed.

Once the device powers up, the application firmware can initialize the PLL SFRs, CLKDIV and PLLDBF to a suitable value, and then perform a clock switch to the Oscillator + PLL clock source. Note that clock switching must be enabled in the device Configuration word.

2.8 Configuration of Analog and Digital Pins During ICSP Operations

If MPLAB ICD 2, MPLAB ICD 3, or MPLAB REAL ICE in-circuit emulator is selected as a debugger, it automatically initializes all of the A/D input pins (ANx) as "digital" pins, by setting all bits in the AD1PCFGL registers.

The bits in the registers that correspond to the A/D pins that are initialized by MPLAB ICD 2, MPLAB ICD 3 or MPLAB REAL ICE in-circuit emulator, must not be cleared by the user application firmware; otherwise, communication errors will result between the debugger and the device.

If your application needs to use certain A/D pins as analog input pins during the debug session, the user application must clear the corresponding bits in the AD1PCFGL register during initialization of the ADC module.

When the MPLAB ICD 2, MPLAB ICD 3 or MPLAB REAL ICE in-circuit emulator is used as a programmer, the user application firmware must correctly configure the AD1PCFGL register. Automatic initialization of this register is only done during debugger operation. Failure to correctly configure the register(s) will result in all A/D pins being recognized as analog input pins, resulting in the port value being read as a logic '0', which may affect user application functionality.

2.9 Unused I/Os

Unused I/O pins should be configured as outputs and driven to a logic low state.

Alternatively, connect a 1k to 10k resistor between Vss and the unused pins.

3.0 CPU

- Note 1: This data sheet summarizes the features of the PIC24HJ32GP202/204 and PIC24HJ16GP304 family of devices. However, it is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to "Section 2. CPU" (DS70204) of the "dsPIC33F/PIC24H Family Reference Manual", which is available from the Microchip website (www.microchip.com).
 - 2: Some registers and associated bits described in this section may not be available on all devices. Refer to Section 4.0 "Memory Organization" in this data sheet for device-specific register and bit information.

The PIC24HJ32GP202/204 and PIC24HJ16GP304 CPU modules have a 16-bit (data) modified Harvard architecture with an enhanced instruction set and addressing modes. The CPU has a 24-bit instruction word with a variable length opcode field. The Program Counter (PC) is 23 bits wide and addresses up to 4M x 24 bits of user program memory space. The actual amount of program memory implemented varies by device. A single-cycle instruction prefetch mechanism is used to help maintain throughput and provides predictable execution. All instructions execute in a single cycle, with the exception of instructions that change the program flow, the double word move (MOV.D) instruction and the table instructions. Overhead-free, single-cycle program loop constructs are supported using the REPEAT instruction, which is interruptible at any time.

The PIC24HJ32GP202/204 and PIC24HJ16GP304 devices have sixteen, 16-bit working registers in the programmer's model. Each of the working registers can serve as a data, address or address offset register. The 16th working register (W15) operates as a software Stack Pointer (SP) for interrupts and calls.

The instruction set includes many addressing modes and is designed for optimum C compiler efficiency. For most instructions, the devices are capable of executing a data (or program data) memory read, a working register (data) read, a data memory write and a program (instruction) memory read per instruction cycle. As a result, three parameter instructions can be supported, allowing A + B = C operations to be executed in a single cycle.

A block diagram of the CPU is shown in Figure 3-1. The programmer's model for the PIC24HJ32GP202/204 and PIC24HJ16GP304 is shown in Figure 3-2.

3.1 Data Addressing Overview

The data space can be linearly addressed as 32K words or 64 Kbytes using an Address Generation Unit (AGU). The upper 32 Kbytes of the data space memory map can optionally be mapped into program space at any 16K program word boundary defined by the 8-bit Program Space Visibility Page register (PSVPAG). The program to data space mapping feature lets any instruction access program space as if it were data space.

The data space also includes 2 Kbytes of DMA RAM, which is primarily used for DMA data transfers, but this may be used as general purpose RAM.

3.2 Special MCU Features

The PIC24HJ32GP202/204 and PIC24HJ16GP304 devices feature a 17-bit by 17-bit, single-cycle multiplier. The multiplier can perform signed, unsigned and mixed-sign multiplication. Using a 17-bit by 17-bit multiplier for 16-bit by 16-bit multiplication makes mixed-sign multiplication possible.

The PIC24HJ32GP202/204 and PIC24HJ16GP304 devices support 16/16 and 32/16 integer divide operations. All divide instructions are iterative operations. They must be executed within a REPEAT loop, resulting in a total execution time of 19 instruction cycles. The divide operation can be interrupted during any of those 19 cycles without loss of data.

A multi-bit data shifter is used to perform up to a 16-bit, left or right shift in a single cycle.



FIGURE 3-1: PIC24HJ32GP202/204 AND PIC24HJ16GP304 CPU CORE BLOCK DIAGRAM

W0/WREG W1 W2 Do Shadow W3 W4 W5 W6 W7 W6 W7 W6 W7 W7 W8 W9 W10 W11 W12 W13 W14/Frame Pointer W15/Stack Pointer SPLIM Stack Pointer Limit Register 7 0 7 Data Table Page Address 7 Program Space Visibility Page Address 15 0 15 CORCON 15 0 CORCON Core Configuration Register		D15	D0
W1 Image: Distance W3 W3 W4 W4 W3 W4 W4 W4 W3 W4 W4 W4 </td <td></td> <td>W0/WREG</td> <td></td>		W0/WREG	
W2 Image: Constraint of the second secon		W1	
W4 W5 W6 W7 W8 W7 W9 W10 W11 W12 W13 W14/Frame Pointer W15/Stack Pointer Stack Pointer Limit Register PC2 PC0 TBLPAG Data Table Page Address 7 TBLPAG PSVPAG Program Space Visibility Page Address 15 0 CORCON Core Configuration Register		W2	
W4 W3 W8 W7 W8 W7 W9 W10 W11 W12 W13 W14/Frame Pointer W15/Stack Pointer Stack Pointer Limit Register SPLIM Stack Pointer Limit Register SPLIM Stack Pointer Limit Register Stack Pointer Limit Register		W3	L
W6 W7 Working Registers W8 W9 Working Registers W10 W11 W12 W11 W12 W13 W14/Frame Pointer W15/Stack Pointer Stack Pointer Limit Register 7 0 Data Table Page Address Program Counter 7 0 Data Table Page Address REPEAT Loop Counter 15 CORCON Core Configuration Register		W4	
W7 W W8 W W9 W10 W11 W12 W13 W14/Frame Pointer W15/Stack Pointer Stack Pointer Limit Register 7 0 Data Table Page Address PC0 7 0 PSVPAG Program Space Visibility Page Address 15 0 15 0 CORCON Core Configuration Register		W5	
W8 W9 W10 W10 W11 W12 W13 W14/Frame Pointer W15/Stack Pointer Stack Pointer Limit Register 7 0 7 0 PC2 PC0 0 Program Counter 7 0 Data Table Page Address Program Counter 15 0 15 0 CORCON Core Configuration Register		W6	
W3 W3 W10 W10 W11 W12 W13 W14/Frame Pointer W15/Stack Pointer W15/Stack Pointer W15/Stack Pointer M15/Stack Pointer V15/Stack Pointer M16/Stack Pointer V15/Stack Pointer M17/Stack Pointer		W7	Working Pogistors
W10 W11 W12 W13 W14/Frame Pointer W15/Stack Pointer SPLIM Stack Pointer Limit Register		W8	
W11 W12 W13 W14/Frame Pointer W15/Stack Pointer SPLIM Stack Pointer Limit Register PC2 PC2 PC0 Program Counter TBLPAG Data Table Page Address TBLPAG Program Space Visibility Page Address 15 0 CORCON Core Configuration Register		W9	
W12 W13 W14/Frame Pointer W15/Stack Pointer SPLIM Stack Pointer Limit Register PC2 PC0 0 Program Counter 7 0 Data Table Page Address 7 15 0 15 15 0 CORCON		W10	
W13 W14/Frame Pointer W15/Stack Pointer SPLIM Stack Pointer Limit Register PC2 PC3 PC4 PC2 PC3 PC4 PC5 Program Counter TBLPAG Data Table Page Address TBLPAG PSVPAG Program Space Visibility Page Address 15 0 CORCON Core Configuration Register		W11	
W14/Frame Pointer W15/Stack Pointer SPLIM Stack Pointer Limit Register PC22 PC0 0 Program Counter 7 0 Data Table Page Address 7 0 PSVPAG Program Space Visibility Page Address 15 0 RCOUNT REPEAT Loop Counter 15 0 CORCON Core Configuration Register		W12	
W15/Stack Pointer SPLIM Stack Pointer Limit Register PC2 PC0 0 7 0 Data Table Page Address 7 0 PSVPAG Pogram Space Visibility Page Address 15 0 CORCON Core Configuration Register		W13	
SPLIM Stack Pointer Limit Register PC22 PC0 0 Program Counter 7 0 TBLPAG Data Table Page Address 7 0 PSVPAG Program Space Visibility Page Address 15 0 RCOUNT REPEAT Loop Counter 15 0 CORCON Core Configuration Register		W14/Frame Pointer	
PC2 PC0 Program Counter PC0 Program Counter PC0 Program Counter PC0 Program Counter PSVPAG Program Space Visibility Page Address 15 COUNT REPEAT Loop Counter 15 CORCON Core Configuration Register		W15/Stack Pointer	
PC2 PC0 Program Counter PC0 Program Counter PC0 Program Counter PC0 Program Counter PSVPAG Program Space Visibility Page Address 15 COUNT REPEAT Loop Counter 15 CORCON Core Configuration Register			
0 Program Counter 7 0 TBLPAG Data Table Page Address 7 0 PSVPAG Program Space Visibility Page Address 15 0 RCOUNT REPEAT Loop Counter 15 0 CORCON Core Configuration Register		SPLIM	Stack Pointer Limit Register
RCOUNT REPEAT Loop Counter 15 0 CORCON Core Configuration Register	TBLPAG Data Tat		35
CORCON Core Configuration Register			
DC IPL2 IPL1 IPL0 RA N OV Z C STATUS Register			
SRH			I OV Z C STATUS Register

3.3 CPU Control Registers

REGISTER 3-1: SR: CPU STATUS REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	U-0	R/W-0								
_		_	_	_	_	_	DC								
bit 15							bit 8								
R/W-0 ⁽¹⁾	R/W-0 ⁽²⁾	R/W-0 ⁽²⁾	R-0	R/W-0	R/W-0	R/W-0	R/W-0								
	IPL<2:0> ⁽²⁾		RA	N	OV	Z	С								
bit 7							bit 0								
Legend:	1 1 1					(0)									
C = Clear on	•	R = Readable		-	mented bit, read	as '0'									
S = Set only		W = Writable		-n = Value at POR											
'1' = Bit is se	t	'0' = Bit is clea	ared	x = Bit is unk	nown										
bit 15-9	Unimplemen	ted: Read as 'i	n'												
bit 8	-	Unimplemented: Read as '0' DC: MCU ALU Half Carry/Borrow bit													
		L = A carry-out from the 4th low-order bit (for byte sized data) or 8th low-order bit (for word sized data)													
	of the res	of the result occurred													
		= No carry-out from the 4th low-order bit (for byte sized data) or 8th low-order bit (for word sized data) of the result occurred													
data) of the result occurred bit 7-5 IPL<2:0>: CPU Interrupt Priority Level Status bits ⁽²⁾															
		nterrupt Priority			ots disabled										
		nterrupt Priority													
		nterrupt Priority													
		nterrupt Priority													
		nterrupt Priority													
		nterrupt Priority nterrupt Priority)											
		nterrupt Priority													
bit 4	RA: REPEAT	Loop Active bit													
		oop in progress oop not in prog													
bit 3	N: MCU ALU	J ALU Negative bit													
		sult was negative sult was non-negative (zero or positive)													
bit 2		U Overflow bit	(·]												
			thmetic (2's co	omplement). It i	indicates an ove	rflow of the ma	gnitude which								
	causes the si	gn bit to change	e state.				•								
		low occurred for signed arithmetic (in this arithmetic operation)													
L:1 4		0 = No overflow occurred Z: MCU ALU Zero bit													
bit 1		= An operation which affects the Z bit has set it at some time in the past													
					s cleared it (i.e.,		sult)								
bit 0		Carry/Borrow			ζ,		,								
				oit (MSb) of the	result occurred										
	•	out from the Mo	•	· /											
Note 1: Th	he IPL<2:0> bits	are concatenat	ad with the ID	1 ~3~ hit (COP	P(ON > 3 >) to for	m the CDI Lint	orrunt Priority								
	evel. The value in														
	PL<3> = 1.			-											

2: The IPL<2:0> Status bits are read-only when the NSTDIS bit (INTCON1<15>) = 1.

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0				
—	—	—	—	—	—	—	—				
bit 15							bit 8				
U-0	U-0	U-0	U-0	R/C-0	R/W-0	U-0	U-0				
—	—	—	_	IPL3 ⁽¹⁾	PSV	—					
bit 7				•		· · · ·	bit 0				
Legend:		C = Clear only	/ bit								
R = Readable	bit	W = Writable	bit	-n = Value at	POR	'1' = Bit is set					
0' = Bit is clea	red	'x = Bit is unkr	nown	U = Unimpler	l as '0'						
bit 15-4	Unimplemen	ted: Read as '0)'								
bit 3	IPL3: CPU In	terrupt Priority	Level Status b	oit 3 ⁽¹⁾							
	1 = CPU inter	rupt priority lev	el is greater th	nan 7							
	0 = CPU inter	rupt priority lev	el is 7 or less								
bit 2 PSV: Program Space Visibility in Data Space Enable bit											
	1 = Program	space visible in	data space								
	0 = Program s	space not visibl	e in data spac	ce							

REGISTER 3-2: CORCON: CORE CONTROL REGISTER

Unimplemented: Read as '0'

Note 1: The IPL3 bit is concatenated with the IPL<2:0> bits (SR<7:5>) to form the CPU interrupt priority level.

bit 1-0

3.4 Arithmetic Logic Unit (ALU)

The Arithmetic Logic Unit (ALU) is 16 bits wide and is capable of addition, subtraction, bit shifts and logic operations. Unless otherwise mentioned, arithmetic operations are 2's complement in nature. The ALU may affect the values of the Carry (C), Zero (Z), Negative (N), Overflow (OV) and Digit Carry (DC) Status bits in the SR register depending on the operation. The C and DC Status bits operate as Borrow and Digit Borrow bits respectively, for subtraction operations.

The ALU can perform 8-bit or 16-bit operations depending on the mode of the instruction that is used. Data for the ALU operation can come from the W register array, or data memory depending on the addressing mode of the instruction. Likewise, output data from the ALU can be written to the W register array or a data memory location.

Refer to the *"16-bit MCU and DSC Programmer's Reference Manual"* (DS70157) for more information on the SR bits affected by each instruction.

The CPU incorporates hardware support for both multiplication and division. This includes a dedicated hardware multiplier and a support hardware for 16-bit divisor division.

3.4.1 MULTIPLIER

Using the high-speed 17-bit x 17-bit multiplier, the ALU supports unsigned, signed or mixed-sign operation in several multiplication modes:

- 16-bit x 16-bit signed
- 16-bit x 16-bit unsigned
- 16-bit signed x 5-bit (literal) unsigned
- 16-bit unsigned x 16-bit unsigned
- 16-bit unsigned x 5-bit (literal) unsigned
- 16-bit unsigned x 16-bit signed
- 8-bit unsigned x 8-bit unsigned

3.4.2 DIVIDER

The divide block supports 32-bit/16-bit and 16-bit/16-bit signed and unsigned integer divide operations with the following data sizes.

- 32-bit signed/16-bit signed divide
- 32-bit unsigned/16-bit unsigned divide
- 16-bit signed/16-bit signed divide
- 16-bit unsigned/16-bit unsigned divide

The quotient for all divide instructions ends up in W0 and the remainder in W1. A 16-bit signed and unsigned DIV instructions can specify any W register for both the 16-bit divisor (Wn) and any W register (aligned) pair (W(m + 1):Wm) for the 32-bit dividend. The divide algorithm takes one cycle per bit of divisor, so both 32-bit/16-bit and 16-bit/16-bit instructions take the same number of cycles to execute.

3.4.3 MULTI-BIT DATA SHIFTER

The multi-bit data shifter is capable of performing up to 16-bit arithmetic or logic right shifts, or up to 16-bit left shifts in a single cycle. The source can be either a working register or a memory location.

The shifter requires a signed binary value to determine both the magnitude (number of bits) and direction of the shift operation. A positive value shifts the operand right. and a negative value shifts the operand left. A value of '0' does not modify the operand.

4.0 MEMORY ORGANIZATION

Note: This data sheet summarizes the features of the PIC24HJ32GP202/204 and PIC24HJ16GP304 family of devices. However, it is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the "dsPIC33F/PIC24H Family Reference Manual", "Section 4. Program Memory" (DS70202), which is available from the Microchip website (www.microchip.com).

The PIC24HJ32GP202/204 and PIC24HJ16GP304 architecture features separate program and data memory spaces and buses. This architecture also allows the direct access of program memory from the data space during code execution.

4.1 Program Address Space

The devices program address memory space is 4M instructions. The space is addressable by a 24-bit value derived either from the 23-bit Program Counter (PC) during program execution, or from table operation or data space remapping as described in Section 4.4 "Interfacing Program and Data Memory Spaces".

User application access to the program memory space is restricted to the lower half of the address range (0x000000 to 0x7FFFFF). The exception is the use of TBLRD/TBLWT operations, which use TBLPAG<7> to permit access to the Configuration bits and Device ID sections of the configuration memory space.

The memory maps for the PIC24HJ32GP202/204 and PIC24HJ16GP304 devices are shown in Figure 4-1.



FIGURE 4-1: PROGRAM MEMORY FOR PIC24HJ32GP202/204 AND PIC24HJ16GP304 DEVICES

4.1.1 PROGRAM MEMORY ORGANIZATION

The program memory space is organized in word-addressable blocks. Although it is treated as 24 bits wide, it is more appropriate to think of each address of the program memory as a lower and upper word, with the upper byte of the upper word being unimplemented. The lower word always has an even address, while the upper word has an odd address (See Figure 4-2).

Program memory addresses are always word-aligned on the lower word, and addresses are incremented or decremented by two during code execution. This arrangement provides compatibility with data memory space addressing and makes data in the program memory space accessible.

4.1.2 INTERRUPT AND TRAP VECTORS

All devices reserve the addresses between 0x00000 and 0x000200 for hard-coded program execution vectors. A hardware Reset vector is provided to redirect code execution from the default value of the PC on device Reset to the actual start of code. A GOTO instruction is programmed by the user application at 0x000000, with the actual address for the start of code at 0x000002.

The devices also have two interrupt vector tables, located from 0x000004 to 0x0000FF and 0x000100 to 0x0001FF. These vector tables allow each of the many device interrupt sources to be handled by separate Interrupt Service Routines (ISRs). Section 7.1 "Interrupt Vector Table" provides a more detailed discussion of the interrupt vector tables.



FIGURE 4-2: PROGRAM MEMORY ORGANIZATION

4.2 Data Address Space

The CPU has a separate 16 bit wide data memory space. The data space is accessed using separate Address Generation Units (AGUs) for read and write operations. The data memory maps is shown in Figure 4-3.

All Effective Addresses (EAs) in the data memory space are 16 bits wide and point to the bytes within the data space. This arrangement gives a data space address range of 64 Kbytes or 32K words. The lower half of the data memory space (that is, when EA<15>=0) is used for implemented memory addresses, while the upper half (EA<15>=1) is reserved for the Program Space Visibility area (see Section 4.4.3 "Reading Data from Program Memory Using Program Space Visibility").

PIC24HJ32GP202/204 and PIC24HJ16GP304 devices implement up to 2 Kbytes of data memory. Should an EA point to a location outside of this area, an all-zero word or byte will be returned.

4.2.1 DATA SPACE WIDTH

The data memory space is organized in byte addressable, 16 bit wide blocks. Data is aligned in data memory and registers as 16-bit words, but all data space EAs resolve to bytes. The Least Significant Bytes (LSBs) of each word have even addresses, while the Most Significant Bytes (MSBs) have odd addresses.

4.2.2 DATA MEMORY ORGANIZATION AND ALIGNMENT

To maintain backward compatibility with PIC[®] devices and improve data space memory usage efficiency, the PIC24HJ32GP202/204 and PIC24HJ16GP304 instruction set supports both word and byte operations. As a consequence of byte accessibility, all effective address calculations are internally scaled to step through word-aligned memory. For example, the core recognizes that Post-Modified Register Indirect Addressing mode [Ws++] will result in a value of Ws + 1 for byte operations and Ws + 2 for word operations.

Data byte reads will read the complete word that contains the byte, using the LSB of any EA to determine which byte to select. The selected byte is placed onto the LSB of the data path. That is, data memory and registers are organized as two parallel byte-wide entities with shared (word) address decode, but separate write lines. Data byte writes only write to the corresponding side of the array or register that matches the byte address. All word accesses must be aligned to an even address. Misaligned word data fetches are not supported, so care must be taken when mixing byte and word operations, or when translating from 8-bit MCU code. If a misaligned read or write is attempted, an address error trap is generated. If the error occurred on a read, the instruction underway is completed. If the instruction occurred on a write, the instruction is executed but the write does not occur. In either case, a trap is then executed, allowing the system and/or user application to examine the machine state prior to execution of the address Fault.

All byte loads into any W register are loaded into the Least Significant Byte. The Most Significant Byte is not modified.

A sign-extend instruction (SE) is provided to allow users to translate 8-bit signed data to 16-bit signed values. Alternatively, for 16-bit unsigned data, user applications can clear the MSB of any W register by executing a zero-extend (ZE) instruction on the appropriate address.

4.2.3 SFR SPACE

The first 2 Kbytes of the Near Data Space, from 0x0000 to 0x07FF, is primarily occupied by Special Function Registers (SFRs). These are used by the PIC24HJ32GP202/204 and PIC24HJ16GP304 core and peripheral modules to control the operation of the device.

SFRs are distributed among the modules that they control, and are generally grouped together by module. Much of the SFR space contains unused addresses; these are read as '0'. A complete listing of implemented SFRs, including their addresses, is shown in Table 4-1 through Table 4-22.

Note:	The actual set of peripheral features and interrupts varies by the device. Refer to											
	the corresponding device tables and											
	pinout diagrams for device-specific											
	information.											

4.2.4 NEAR DATA SPACE

The 8 Kbyte area between 0x0000 and 0x1FFF is referred to as the Near Data Space. Locations in this space are directly addressable via 13-bit absolute address field within all memory direct instructions. Additionally, the whole data space is addressable using MOV instructions, which support Memory Direct Addressing mode with a 16-bit address field, or by using Indirect Addressing mode using a working register as an address pointer.

FIGURE 4-3: DATA MEMORY MAP FOR PIC24HJ32GP202/204 AND PIC24HJ16GP304 DEVICES WITH 2 KB RAM



SFR Name	SFR Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
WREG0	0000								Working Re	gister 0					-			0000
WREG1	0002								Working Re	egister 1								0000
WREG2	0004								Working Re	egister 2								0000
WREG3	0006								Working Re	egister 3								0000
WREG4	0008								Working Re	egister 4								0000
WREG5	000A								Working Re	egister 5								0000
WREG6	000C		Working Register 6														0000	
WREG7	000E		Working Register 7												0000			
WREG8	0010													0000				
WREG9	0012		Working Register 9												0000			
WREG10	0014		Working Register 10														0000	
WREG11	0016	Working Register 11														0000		
WREG12	0018		Working Register 12														0000	
WREG13	001A								Working Re	gister 13								0000
WREG14	001C								Working Re	gister 14								0000
WREG15	001E								Working Re	gister 15								0800
SPLIM	0020							Sta	ck Pointer Li	mit Register								xxxx
PCL	002E							Program	Counter Lo	w Word Reg	jister							0000
PCH	0030	_	_	_	—	_	_	_	—			Progra	m Counter	High Byte F	Register			0000
TBLPAG	0032	_	_	_	—	_	_	_	_			Table F	Page Addre	ss Pointer F	Register			0000
PSVPAG	0034	—	_	—	_	_	_		—		Progra	am Memory	Visibility P	age Addres	s Pointer Re	egister		0000
RCOUNT	0036							Repe	at Loop Cou	unter Registe	er							xxxx
SR	0042	-	_	_	_	_	_	—	DC	IPL2	IPL1	IPL0	RA	N	OV	Z	С	0000
CORCON	0044		_	—				—	—	—	_	_	—	IPL3	PSV	—	—	0000
DISICNT	0052	_	— — Disable Interrupts Counter Register 200										xxxx					

TABLE 4-2: CHANGE NOTIFICATION REGISTER MAP FOR PIC24HJ32GP202

SFR Name	SFR Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
CNEN1	0060	CN15IE	CN14IE	CN13IE	CN12IE	CN11IE			-	CN7IE	CN6IE	CN5IE	CN4IE	CN3IE	CN2IE	CN1IE	CN0IE	0000
CNEN2	0062	_	CN30IE	CN29IE	_	CN27IE		_	CN24IE	CN23IE	CN22IE	CN21IE		_	_	_	CN16IE	0000
CNPU1	0068	CN15PUE	CN14PUE	CN13PUE	CN12PUE	CN11PUE	_	_	_	CN7PUE	CN6PUE	CN5PUE	CN4PUE	CN3PUE	CN2PUE	CN1PUE	CN0PUE	0000
CNPU2	006A	_	CN30PUE	CN29PUE		CN27PUE	_		CN24PUE	CN23PUE	CN22PUE	CN21PUE	_	_			CN16PUE	0000

Legend: x = unknown value on Reset, - = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-3: CHANGE NOTIFICATION REGISTER MAP FOR PIC24HJ32GP204 AND PIC24HJ16GP304

SFR Nam	01		Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
CNEM	J1 006	60	CN15IE	CN14IE	CN13IE	CN12IE	CN11IE	CN10IE	CN9IE	CN8IE	CN7IE	CN6IE	CN5IE	CN4IE	CN3IE	CN2IE	CN1IE	CN0IE	0000
CNEM	12 006	62	—	CN30IE	CN29IE	CN28IE	CN27IE	CN26IE	CN25IE	CN24IE	CN23IE	CN22IE	CN21IE	CN20IE	CN19IE	CN18IE	CN17IE	CN16IE	0000
CNPL	J1 006	68	CN15PUE	CN14PUE	CN13PUE	CN12PUE	CN11PUE	CN10PUE	CN9PUE	CN8PUE	CN7PUE	CN6PUE	CN5PUE	CN4PUE	CN3PUE	CN2PUE	CN1PUE	CN0PUE	0000
CNPL	J2 006	6A	—	CN30PUE	CN29PUE	CN28PUE	CN27PUE	CN26PUE	CN25PUE	CN24PUE	CN23PUE	CN22PUE	CN21PUE	CN20PUE	CN19PUE	CN18PUE	CN17PUE	CN16PUE	0000

TABLE 4-4: INTERRUPT CONTROLLER REGISTER MAP

			-		-					-			-	-	_	-	-	-
SFR Name	SFR Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
INTCON1	0080	NSTDIS	_	—	—	_	—	—	_	—	DIV0ERR	_	MATHERR	ADDRERR	STKERR	OSCFAIL	—	0000
INTCON2	0082	ALTIVT	DISI	_	_	_	_	_	_	_	—	_	_	_	INT2EP	INT1EP	INT0EP	0000
IFS0	0084		_	AD1IF	U1TXIF	U1RXIF	SPI1IF	SPI1EIF	T3IF	T2IF	OC2IF	IC2IF	_	T1IF	OC1IF	IC1IF	INT0IF	0000
IFS1	0086		_	INT2IF	_	_	_	_	_	IC8IF	IC7IF	_	INT1IF	CNIF	_	MI2C1IF	SI2C1IF	0000
IFS4	008C		_	_	_	_	_	_	_	_	—	_	_	_	_	U1EIF	_	0000
IEC0	0094		_	AD1IE	U1TXIE	U1RXIE	SPI1IE	SPI1EIE	T3IE	T2IE	OC2IE	IC2IE	_	T1IE	OC1IE	IC1IE	INT0IE	0000
IEC1	0096		_	INT2IE	_	_	_	_	_	IC8IE	IC7IE	_	INT1IE	CNIE	_	MI2C1IE	SI2C1IE	0000
IEC4	009C	_	_	_	_	_	_	—	_	_	_	_	_	_	_	U1EIE	_	0000
IPC0	00A4	—		T1IP<2:0>			(OC1IP<2:0	>	—		IC1IP<2:0>		—	11	NT0IP<2:0>	•	4444
IPC1	00A6	—		T2IP<2:0>		_	(OC2IP<2:0	>	—		IC2IP<2:0>		—	_	_	_	4440
IPC2	00A8	—	ι	J1RXIP<2:0)>	-	Ś	SPI1IP<2:0)>	—		SPI1EIP<2:0)>	—		T3IP<2:0>		4444
IPC3	00AA	—	_	—	_	-	_	_	_	—		AD1IP<2:0>	>	—	U	1TXIP<2:0:	>	0044
IPC4	00AC	—		CNIP<2:0>	>	-	_	_	_	—		WI2C1IP<2:0)>	—	SI	2C1IP<2:0	>	4044
IPC5	00AE	—		IC8IP<2:0>	>	-		IC7IP<2:0:	>	—	_	_	_	—	11	VT1IP<2:0>	•	4404
IPC7	00B2	—	_	—	_	-	_	_	_	—		INT2IP<2:0	>	—	_	_	_	0040
IPC16	00C4		_	_	_	_			_	_		U1EIP<2:0>	>	_	_	_	_	0040
INTTREG	00E0		_	_	_		ILR<	3:0>		_			VE	CNUM<6:0>				0000

TABLE 4	-5:	TIMER I	REGIST	ER MAI	Ρ													
SFR Name	SFR Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
TMR1	0100								Timer1	Register								0000
PR1	0102								Period R	legister 1								FFFF
T1CON	0104	TON	_	TSIDL	—	—	—	—	—	—	TGATE	TCKP	S<1:0>	—	TSYNC	TCS	—	0000
TMR2	0106		Timer2 Register														0000	
TMR3HLD	0108		Timer2 Register Timer3 Holding Register (for 32-bit timer operations only)															xxxx
TMR3	010A								Timer3	Register								0000
PR2	010C								Period R	legister 2								FFFF
PR3	010E								Period R	legister 3								FFFF
T2CON	0110	TON	—	TSIDL	_	_	_	_	_	_	TGATE	TCKPS	S<1:0>	T32	—	TCS		0000
T3CON	0112	TON	_	TSIDL	_	_	_	_	_	_	TGATE	TCKPS	S<1:0>	_	—	TCS	_	0000
Legend:	x = unkno	own value o	n Reset –	- = unimple	mented rea	ad as '0' R	eset values	s are shown	in hexade	cimal								

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal

TABLE 4-6: INPUT CAPTURE REGISTER MAP

	•••																	
SFR Name	SFR Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
IC1BUF	0140								Input 1 Cap	ture Registe	r							xxxx
IC1CON	0142	—	—	ICSIDL	—	_			—	ICTMR	ICI<	1:0>	ICOV	ICBNE		ICM<2:0>		0000
IC2BUF	0144		Input 2 Capture Register													xxxx		
IC2CON	0146	—	—	ICSIDL	—	—	_		_	ICTMR	ICI<	1:0>	ICOV	ICBNE		ICM<2:0>		0000
IC7BUF	0158								Input 7 Cap	ture Registe	r							xxxx
IC7CON	015A	_	_	ICSIDL	_	_	_	_	_	ICTMR	ICI<	1:0>	ICOV	ICBNE		ICM<2:0>		0000
IC8BUF	015C								Input 8Capt	ure Register	-							xxxx
IC8CON	015E	_	_	ICSIDL	_	_	_	_	—	ICTMR	ICI<	1:0>	ICOV	ICBNE		ICM<2:0>		0000
1 1			D .			L (al D												

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-7: OUTPUT COMPARE REGISTER MAP

SFR Name	SFR Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
OC1RS	0180							Output	Compare 1	Secondary I	Register							xxxx
OC1R	0182		Output Compare 1 Register															xxxx
OC1CON	0184	OCSIDL OCFLT OCTSEL OCM<2:0>														0000		
OC2RS	0186							Output	Compare 2	Secondary I	Register							xxxx
OC2R	0188							0	utput Comp	are 2 Regist	er							xxxx
OC2CON	018A	—		OCSIDL	—	_			—	—		_	OCFLT	OCTSEL		OCM<2:0>		0000
Lawrendi			D			1 (a) D												

TABLE 4-8: I2C1 REGISTER MAP

SFR Name	SFR Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets		
I2C1RCV	0200	_	-		_			—	_				Receive	Register				0000		
I2C1TRN	0202	_	_	_	_	_	_	_	-				Transmit	Register				OOFF		
I2C1BRG	0204	_	_	_	_	_	_	_		Baud Rate Generator Register										
I2C1CON	0206	I2CEN	_	I2CSIDL	SCLREL	IPMIEN	A10M	DISSLW	SMEN	GCEN	STREN	ACKDT	ACKEN	RCEN	PEN	RSEN	SEN	1000		
I2C1STAT	0208	ACKSTAT	TRSTAT	_	_	_	BCL	GCSTAT	ADD10	IWCOL	I2COV	D_A	Р	S	R_W	RBF	TBF	0000		
I2C1ADD	020A	_	_	_	_	_	_					Address	Register					0000		
I2C1MSK	020C	_	_	_	_	_						Address Ma	isk Register					0000		

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-9: UART1 REGISTER MAP

SFR Name	SFR Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
U1MODE	0220	UARTEN	—	USIDL	IREN	RTSMD	_	UEN1	UEN0	WAKE	LPBACK	ABAUD	URXINV	BRGH	PDSE	L<1:0>	STSEL	0000
U1STA	0222	UTXISEL1	UTXINV	UTXISEL0	_	UTXBRK	UTXEN	UTXBF	F TRMT URXISEL<1:0> ADDEN RIDLE PERR FERR OERR URXDA								0110	
U1TXREG	0224	_	_	_	_	_						UART	Transmit Re	gister				xxxx
U1RXREG	0226	_	_	_	_	_						UART	Receive Reo	gister				0000
U1BRG	0228							Bau	d Rate Ger	nerator Presc	aler							0000

Legend: x = unknown value on Reset, - = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-10: SPI1 REGISTER MAP

SFR Name	SFR Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
SPI1STAT	0240	SPIEN	-	SPISIDL	—	—	—	_		—	SPIROV	_		—	_	SPITBF	SPIRBF	0000
SPI1CON1	0242	-	_	_	DISSCK	DISSDO	MODE16	SMP	CKE	SSEN	CKP	MSTEN		SPRE<2:0>		PPRE	<1:0>	0000
SPI1CON2	0244	FRMEN	SPIFSD	FRMPOL	_	_	_	_	_	_	_	_	_	_	_	FRMDLY	_	0000
SPI1BUF	0248							SPI1 Trans	mit and Red	ceive Buffer	Register							0000

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TABLE 4-11: PERIPHERAL PIN SELECT INPUT REGISTER MAP

File Name	Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
RPINR0	0680	_	_	_		I	NT1R<4:0>				_		—	—	_	_	_	1F00
RPINR1	0682	_	_	_	_		_	_							INT2R<4:0>			001F
RPINR3	0686	_	_	_		г	3CKR<4:0>	>		-	_	-		٦	2CKR<4:0	>		1F1F
RPINR7	068E	_	_	_			IC2R<4:0>								IC1R<4:0>			1F1F
RPINR10	0694	_	_	_			IC8R<4:0>								IC7R<4:0>			1F1F
RPINR11	0696	_	_	_	_		_	_						C	OCFAR<4:0:	>		001F
RPINR18	06A4	_	_	_		U	1CTSR<4:0	>						ι	J1RXR<4:0:	>		1F1F
RPINR20	06A8	_	_	_		S	SCK1R<4:0:	>		-	_	-		:	SDI1R<4:0>	•		1F1F
RPINR21	06AA	_	_	_	_	_	_	_	_		_				SS1R<4:0>			001F

Legend: x = unknown value on Reset, - = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-12: PERIPHERAL PIN SELECT OUTPUT REGISTER MAP FOR PIC24HJ32GP202

File Name	Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
RPOR0	06C0		—	—			RP1R<4:0>			—	_				RP0R<4:0>			0000
RPOR1	06C2		_	_			RP3R<4:0>			_					RP2R<4:0>			0000
RPOR2	06C4		_	_			RP5R<4:0>			_	-	-			RP4R<4:0>			0000
RPOR3	06C6	_	_	_			RP7R<4:0>			_	_	_			RP6R<4:0>			0000
RPOR4	06C8		_	_			RP9R<4:0>			_	-	-			RP8R<4:0>			0000
RPOR5	06CA	_	_	_		F	RP11R<4:0;	>		_	_	_		F	RP10R<4:0:	>		0000
RPOR6	06CC	_	_	_		F	RP13R<4:0:	>		—	_			F	RP12R<4:0:	>		0000
RPOR7	06CE		_	_		F	RP15R<4:0:	>		—	_			F	RP14R<4:0:	>		0000
File Name	Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Reset
-----------	------	--------	--------	--------	--------	--------	------------	-------	-------	-------	-------	-------	-------	-------	------------	-------	-------	--------------
RPOR0	06C0	_					RP1R<4:0>			—	_	—			RP0R<4:0>			0000
RPOR1	06C2		_	_			RP3R<4:0>				_	_			RP2R<4:0>			0000
RPOR2	06C4	_	_	_			RP5R<4:0>			_	_	_			RP4R<4:0>			0000
RPOR3	06C6	_	_	_			RP7R<4:0>					_			RP6R<4:0>			0000
RPOR4	06C8	_	_	_			RP9R<4:0>			_		_			RP8R<4:0>			0000
RPOR5	06CA		_	_		F	RP11R<4:0>	>		_		_			RP10R<4:0:	>		0000
RPOR6	06CC	_	_	_		F	RP13R<4:0:	>		_	_	_			RP12R<4:0:	>		0000
RPOR7	06CE	_	_	_		F	RP15R<4:0:	>				_			RP14R<4:0:	>		0000
RPOR8	06D0	_	_	_		F	RP17R<4:0:	>				_			RP16R<4:0:	>		0000
RPOR9	06D2	_	_	_		F	RP19R<4:0:	>				_			RP18R<4:0:	>		0000
RPOR10	06D4	_	_	_		F	RP21R<4:0;	>		_	_	_			RP20R<4:0:	>		0000
RPOR11	06D6		_	_		F	RP23R<4:0;	>		_	_				RP22R<4:0:	>		000
RPOR12	06D8	_	-	_		F	RP25R<4:0	>		_	_	_			RP24R<4:0	>		000

TABLE 4-13: PERIPHERAL PIN SELECT OUTPUT REGISTER MAP FOR PIC24HJ32GP204 AND PIC24HJ16GP304

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

File Name	Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
ADC1BUF0	0300								ADC Data	Buffer 0		•						xxxx
ADC1BUF1	0302								ADC Data	Buffer 1								xxxx
ADC1BUF2	0304								ADC Data	Buffer 2								xxxx
ADC1BUF3	0306								ADC Data	Buffer 3								xxxx
ADC1BUF4	0308								ADC Data	Buffer 4								xxxx
ADC1BUF5	030A								ADC Data	Buffer 5								xxxx
ADC1BUF6	030C								ADC Data	Buffer 6								xxxx
ADC1BUF7	030E								ADC Data	Buffer 7								xxxx
ADC1BUF8	0310								ADC Data	Buffer 8								xxxx
ADC1BUF9	0312														xxxx			
ADC1BUFA	0314								ADC Data	Buffer 10								xxxx
ADC1BUFB	0316								ADC Data	Buffer 11								xxxx
ADC1BUFC	0318								ADC Data	Buffer 12								xxxx
ADC1BUFD	031A								ADC Data	Buffer 13								xxxx
ADC1BUFE	031C								ADC Data	Buffer 14								xxxx
ADC1BUFF	031E								ADC Data	Buffer 15								xxxx
AD1CON1	0320	ADON	—	ADSIDL	_	—	AD12B	FOR	M<1:0>	5	SSRC<2:0>		_	SIMSAM	ASAM	SAMP	DONE	0000
AD1CON2	0322	,	VCFG<2:0	>			CSCNA	CHP	S<1:0>	BUFS	—		SMPI	<3:0>		BUFM	ALTS	0000
AD1CON3	0324	ADRC	_	_		S	AMC<4:0>						ADCS	6<7:0>				0000
AD1CHS123	0326	_		—			CH123N	VB<1:0>	CH123SB	_		-		—	CH123N	NA<1:0>	CH123SA	0000
AD1CHS0	0328	CH0NB	HONB - - CH0SB<4:0> CH0NA - - CH0SA<4:0> 000												0000			
AD1PCFGL	032C	_	_	—	PCFG12		PCFG10		PCFG8	PCFG7	PCFG6	PCFG5	PCFG4	PCFG3	PCFG2	PCFG1	PCFG0	0000
AD1CSSL	0330	—	-	—	CSS12	CSS11	CSS10	CSS9	CSS8	CSS7	CSS6	CSS5	CSS4	CSS3	CSS2	CSS1	CSS0	0000

TABLE 4-14: ADC1 REGISTER MAP FOR PIC24HJ32GP204 AND PIC24HJ16GP304

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-15 :	ADC1 REGISTER MAP FOR PIC24HJ32GP202
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	•. /																	
File Name	Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
ADC1BUF0	0300								ADC Data	a Buffer 0								xxxx
ADC1BUF1	0302								ADC Data	a Buffer 1								xxxx
ADC1BUF2	0304								ADC Data	a Buffer 2								xxxx
ADC1BUF3	0306								ADC Data	a Buffer 3								xxxx
ADC1BUF4	0308								ADC Data	a Buffer 4								xxxx
ADC1BUF5	030A								ADC Data	a Buffer 5								xxxx
ADC1BUF6	030C								ADC Data	a Buffer 6								xxxx
ADC1BUF7	030E								ADC Data	a Buffer 7								xxxx
ADC1BUF8	0310								ADC Data	a Buffer 8								xxxx
ADC1BUF9	0312		ADC Data Buffer 9 xxx												xxxx			
ADC1BUFA	0314								ADC Data	a Buffer 10								xxxx
ADC1BUFB	0316								ADC Data	a Buffer 11								xxxx
ADC1BUFC	0318								ADC Data	a Buffer 12								xxxx
ADC1BUFD	031A								ADC Data	a Buffer 13								xxxx
ADC1BUFE	031C								ADC Data	a Buffer 14								xxxx
ADC1BUFF	031E								ADC Data	a Buffer 15								xxxx
AD1CON1	0320	ADON		ADSIDL	-		AD12B	FOR	M<1:0>	5	SSRC<2:0:	>	_	SIMSAM	ASAM	SAMP	DONE	0000
AD1CON2	0322	``	VCFG<2:0:	>	—	—	CSCNA	CHP	S<1:0>	BUFS	—		SMPI	<3:0>		BUFM	ALTS	0000
AD1CON3	0324	ADRC	_	—			SAMC<4:0	>					ADC	S<7:0>				0000
AD1CHS123	0326	—	—	—	—	—	CH123N	VB<1:0>	CH123SB	—	—	—	—	—	CH123	NA<1:0>	CH123SA	0000
AD1CHS0	0328	CH0NB	—	—		(CH0SB<4:0		-	CHONA	—	—		(CH0SA<4:)>	r	0000
AD1PCFGL	032C	—	—	—	PCFG12	PCFG11	PCFG10	PCFG9	—	—	—	PCFG5	PCFG4	PCFG3	PCFG2	PCFG1	PCFG0	0000
AD1CSSL	0330	_	-	—	CSS12	CSS11	CSS10	CSS9	—	—	_	CSS5	CSS4	CSS3	CSS2	CSS1	CSS0	0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-16: PORTA REGISTER MAP FOR PIC24HJ32GP202

File Name	Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
TRISA	02C0	—		—		-		-	—		-		TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	001F
PORTA	02C2	_	_	_	_	_	_	_	_	_	_	_	RA4	RA3	RA2	RA1	RA0	xxxx
LATA	02C4	_	_	_	_	_	_	_	_	_	_	_	LATA4	LATA3	LATA2	LATA1	LATA0	xxxx
ODCA	02C6	—	-	—	_	_	_	-	—	_	_	_	ODCA4	ODCA3	ODCA2	ODCA1	ODCA0	0000

Legend: x = unknown value on Reset, - = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-17: PORTA REGISTER MAP FOR PIC24HJ32GP204 AND PIC24HJ16GP304

File Name	Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
TRISA	02C0	—		—	_		TRISA10	TRISA9	TRISA8	TRISA7		-	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	001F
PORTA	02C2		_	_	_	_	RA10	RA9	RA8	RA7	_	_	RA4	RA3	RA2	RA1	RA0	xxxx
LATA	02C4		_	_	_	_	LATA10	LATA9	LATA8	LATA7	_	_	LATA4	LATA3	LATA2	LATA1	LATA0	xxxx
ODCA	02C6	_	_	—	_	-	ODCA10	ODCA9	ODCA8	ODCA7	-	-	ODCA4	ODCA3	ODCA2	ODCA1	ODCA0	0000

PIC24HJ32GP202/204 AND PIC24HJ16GP304

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-18: PORTB REGISTER MAP

File Name	Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
TRISB	02C8	TRISB15	TRISB14	TRISB13	TRISB12	TRISB11	TRISB10	TRISB9	TRISB8	TRISB7	TRISB6	TRISB5	TRISB4	TRISB3	TRISB2	TRISB1	TRISB0	FFFF
PORTB	02CA	RB15	RB14	RB13	RB12	RB11	RB10	RB9	RB8	RB7	RB6	RB5	RB4	RB3	RB2	RB1	RB0	XXXX
LATB	02CC	LATB15	LATB14	LATB13	LATB12	LATB11	LATB10	LATB9	LATB8	LATB7	LATB6	LATB5	LATB4	LATB3	LATB2	LATB1	LATB0	XXXX
ODCB	02CE	ODCB15	ODCB14	ODCB13	ODCB12	ODCB11	ODCB10	ODCB9	ODCB8	ODCB7	ODCB6	ODCB5	ODCB4	ODCB3	ODCB2	ODCB1	ODCB0	0000

Legend: x = unknown value on Reset, - = unimplemented, read as '0'. Reset values are shown in hexadecimal for PinHigh devices.

TABLE 4-19: PORTC REGISTER MAP FOR PIC24HJ32GP204 AND PIC24HJ16GP304

File Name	Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
TRISC	02D0		_				_	TRISC9	TRISC8	TRISC7	TRISC6	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0	03FF
PORTC	02D2	_		_	_		_	RC9	RC8	RC7	RC6	RC5	RC4	RC4	RC2	RC1	RC0	xxxx
LATC	02D4		_				_	LATC9	LATC8	LATC7	LATC6	LATC5	LATC4	LATC4	LATC2	LATC1	LATC0	xxxx
ODCC	02D6	_	-	_	_		_	ODCC9	ODCC8	ODCC7	ODCC6	ODCC5	ODCC4	ODCC4	ODCC2	ODCC1	ODCC0	0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

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TABLE 4-20: SYSTEM CONTROL REGISTER MAP

File Name	Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
RCON	0740	TRAPR	IOPUWR	—	—	-	_	CM	VREGS	EXTR	SWR	SWDTEN	WDTO	SLEEP	IDLE	BOR	POR	_{XXXX} (1)
OSCCON	0742	_	(COSC<2:0>	>	- NOSC<2:0> CLKLOCK IOLOCK LOCK - CF - LPOSCEN OSWEN					₀₃₀₀ (2)							
CLKDIV	0744	ROI	I	DOZE<2:0>	>	DOZEN	FI	RCDIV<2:0)>	PLLPOS	ST<1:0>	_		F	PLLPRE<4:	0>		3040
PLLFBD	0746	_	_	_	_	PLLDIV<8:0>						0030						
OSCTUN	0748	_	_	_	_	TUN<5:0>							0000					

Legend: x = unknown value on Reset, - = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: RCON register Reset values dependent on type of Reset.

2: OSCCON register Reset values dependent on the FOSC Configuration bits and by type of Reset.

TABLE 4-21: NVM REGISTER MAP

File Name	Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
NVMCON	0760	WR	WREN	WRERR	_		_		—	-	ERASE	_	_		NVMO	P<3:0>		₀₀₀₀ (1)
NVMKEY	0766				_		_		-				NVMKE	Y<7:0>				0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: Reset value shown is for POR only. Value on other Reset states is dependent on the state of memory write or erase operations at the time of Reset.

TABLE 4-22: PMD REGISTER MAP

File Name	Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
PMD1	0770		_	T3MD	T2MD	T1MD	_		_	I2C1MD	_	U1MD	_	SPI1MD	_	_	AD1MD	0000
PMD2	0772	IC8MD	IC7MD	_	_	_	-	IC2MD	IC1MD	_	_	—	_	_	_	OC2MD	OC1MD	0000

Legend: x = unknown value on Reset, - = unimplemented, read as '0'. Reset values are shown in hexadecimal.

4.2.5 SOFTWARE STACK

In addition to its use as a working register, the W15 register is also used as a software Stack Pointer. The Stack Pointer always points to the first available free word and grows from lower to higher addresses. It pre-decrements for stack pops and post-increments for stack pushes, as shown in Figure 4-4. For a PC push during any CALL instruction, the MSB of the PC is zero-extended before the push, ensuring that the MSB is always clear.

Note:	A PC push during exception processing
	concatenates the SRL register to the MSB
	of the PC prior to the push.

The Stack Pointer Limit register (SPLIM) associated with the Stack Pointer sets an upper address boundary for the stack. SPLIM is uninitialized at Reset. Similarly, the Stack Pointer, SPLIM<0> is forced to '0' because all stack operations must be word aligned.

When an EA is generated using W15 as a source or destination pointer, the resulting address is compared with the value in SPLIM. If the contents of the Stack Pointer (W15) and the SPLIM register are equal and a push operation is performed, a stack error trap will not occur. The stack error trap will occur on a subsequent push operation. For example, to cause a stack error trap when the stack grows beyond address 0x1000 in RAM, initialize the SPLIM with the value 0x0FFE.

Similarly, a Stack Pointer underflow (stack error) trap is generated when the Stack Pointer address is found to be lesser than 0x0800. This prevents the stack from interfering with the Special Function Register (SFR) space.

A write to the SPLIM register should not be immediately followed by an indirect read operation using W15.



FIGURE 4-4: CALL STACK FRAME

4.2.6 DATA RAM PROTECTION FEATURE

The PIC24H product family supports Data RAM protection features that enable segments of RAM to be protected when used in conjunction with Boot and Secure Code Segment Security. BSRAM (Secure RAM segment for BS) is accessible only from the Boot Segment Flash code when enabled. SSRAM (Secure RAM segment for RAM) is accessible only from the Secure Segment Flash code when enabled. See Table 4-1 for an overview of the BSRAM and SSRAM SFRs.

4.3 Instruction Addressing Modes

The addressing modes shown in Table 4-23 form the basis of the addressing modes optimized to support the specific features of individual instructions. The addressing modes provided in the MAC class of instructions differ from those in the other instruction types.

4.3.1 FILE REGISTER INSTRUCTIONS

Most file register instructions use a 13-bit address field (f) to directly address data present in the first 8192 bytes of data memory (Near Data Space). Most file register instructions employ a working register, W0, which is denoted as WREG in these instructions. The destination is typically either the same file register or WREG (with the exception of the MUL instruction), which writes the result to a register or register pair. The MOV instruction allows additional flexibility and can access the entire data space.

4.3.2 MCU INSTRUCTIONS

The three-operand MCU instructions are of the form:

Operand 3 = Operand 1 <function> Operand 2 where:

Operand 1 is always a working register (that is, the addressing mode can only be register direct), which is referred to as Wb.

Operand 2 can be a W register, fetched from data memory, or a 5-bit literal. The result location can be either a W register or a data memory location. The following addressing modes are supported by MCU instructions:

- Register Direct
- Register Indirect
- Register Indirect Post-Modified
- Register Indirect Pre-Modified
- 5-bit or 10-bit Literal
- Note: Not all instructions support all the addressing modes given above. Individual instructions can support different subsets of these addressing modes.

Addressing Mode Description	
File Register Direct	The address of the file register is specified explicitly.
Register Direct	The contents of a register are accessed directly.
Register Indirect	The contents of Wn forms the Effective Address (EA.)
Register Indirect Post-Modified	The contents of Wn forms the EA. Wn is post-modified (incremented or decremented) by a constant value.
Register Indirect Pre-Modified	Wn is pre-modified (incremented or decremented) by a signed constant value to form the EA.
Register Indirect with Register Offset (Register Indexed)	The sum of Wn and Wb forms the EA.
Register Indirect with Literal Offset	The sum of Wn and a literal forms the EA.

4.3.3 MOVE (MOV) INSTRUCTION

Move instructions provide a greater degree of addressing flexibility than the other instructions. In addition to the Addressing modes supported by most MCU instructions, MOV instructions also support Register Indirect with Register Offset Addressing mode. This is also referred to as Register Indexed mode.

Note:	For the MOV instructions, the addressing mode specified in the instruction can differ					
	for the source and the destination EA.					
	However, the 4-bit Wb (Register Offset)					
	field is shared by both source and					
	destination (but typically only used by					
	one).					

In summary, move instructions support the following addressing modes:

- Register Direct
- Register Indirect
- Register Indirect Post-modified
- Register Indirect Pre-modified
- Register Indirect with Register Offset (Indexed)
- Register Indirect with Literal Offset
- 8-bit Literal
- 16-bit Literal

Note:	Not	all	instructions	support	all	the
	addr	essir	ng modes give	n above. I	ndivi	dual
	instructions may support different subsets					
	of th	ese a	addressing mo	odes.		

4.3.4 OTHER INSTRUCTIONS

Besides the addressing modes outlined previously, some instructions use literal constants of various sizes. For example, BRA (branch) instructions use 16-bit signed literals to specify the branch destination directly, whereas the DISI instruction uses a 14-bit unsigned literal field. In some instructions, such as ADD Acc, the source of an operand or result is implied by the opcode itself. Certain operations, such as NOP, do not have any operands.

4.4 Interfacing Program and Data Memory Spaces

The device architecture uses a 24-bit-wide program space and a 16 bit wide data space. The architecture is also a modified Harvard scheme, which means that the data can also be present in the program space. To use this data successfully, it must be accessed in a way that preserves the alignment of information in both spaces.

Aside from normal execution, the architecture provides two methods by which program space can be accessed during operation:

- Using table instructions to access individual bytes or words anywhere in the program space
- Remapping a portion of the program space into the data space (Program Space Visibility)

Table instructions allow an application to read or write to small areas of the program memory. This capability makes the method ideal for accessing data tables that need to be updated periodically. It also allows access to all bytes of the program word. The remapping method allows an application to access a large block of data on a read-only basis, which is ideal for look ups from a large table of static data. The application can only access the least significant word of the program word.

4.4.1 ADDRESSING PROGRAM SPACE

Since the address ranges for the data and program spaces are 16 and 24 bits, respectively, a method is needed to create a 23-bit or 24-bit program address from 16-bit data registers. The solution depends on the interface method to be used.

For table operations, the 8-bit Table Page register (TBLPAG) is used to define a 32K word region within the program space. This is concatenated with a 16-bit EA to arrive at a full 24-bit program space address. In this format, the Most Significant bit of TBLPAG is used to determine if the operation occurs in the user memory (TBLPAG<7> = 0) or the configuration memory (TBLPAG<7> = 1).

For remapping operations, the 8-bit Program Space Visibility register (PSVPAG) is used to define a 16K word page in the program space. When the Most Significant bit of the EA is '1', PSVPAG is concatenated with the lower 15 bits of the EA to form a 23-bit program space address. Unlike table operations, this limits remapping operations strictly to the user memory area.

Table 4-24 and Figure 4-5 show how the program EA is created for table operations and remapping accesses from the data EA. Here, P<23:0> refers to a program space word, and D<15:0> refers to a data space word.

	Access	Program Space Address					
Access Type	Space	<23>	<22:16>	<15>	<14:1>	<0>	
Instruction Access	User	0		PC<22:1>		0	
(Code Execution)		0xx xxxx xxxx xxxx xxxx xxx0					
TBLRD/TBLWT	User	TBLPAG<7:0>		Data EA<15:0>			
(Byte/Word Read/Write)		0xxx xxxx xxxx xxxx xxxx					
	Configuration			Data EA<15:0>			
				xxxx xxxx xxxx			
Program Space Visibility	User	0 PSVPAG<7:0> Data EA<1		Data EA<14:	0> ⁽¹⁾		
(Block Remap/Read)		0	XXXX XXXX	2	XXX XXXX XXXX	xxxx	

TABLE 4-24: PROGRAM SPACE ADDRESS CONSTRUCTION

Note 1: Data EA<15> is always '1' in this case, but is not used in calculating the program space address. Bit 15 of the address is PSVPAG<0>.





4.4.2 DATA ACCESS FROM PROGRAM MEMORY USING TABLE INSTRUCTIONS

The TBLRDL and TBLWTL instructions offer a direct method to read or write the lower word of any address within the program space without going through data space. The TBLRDH and TBLWTH instructions are the only methods to read or write the upper 8 bits of a program space word as data.

The PC is incremented by 2 for each successive 24-bit program word. This allows program memory addresses to directly map to data space addresses. Program memory can thus be regarded as two 16 bit wide word address spaces, residing side by side, each with the same address range. TBLRDL and TBLWTL access the space that contains the least significant data word. TBLRDH and TBLWTH access the space that contains the upper data byte.

Two table instructions are provided to move byte or word sized (16-bit) data to and from program space. Both function as either byte or word operations.

• TBLRDL (Table Read Low): In Word mode, this instruction maps the lower word of the program space location (P<15:0>) to a data address (D<15:0>).

In Byte mode, either the upper or lower byte of the lower program word is mapped to the lower byte of a data address. The upper byte is selected when Byte Select is '1'; the lower byte is selected when it is '0'.

• TBLRDH (Table Read High): In Word mode, this instruction maps the entire upper word of a program address (P<23:16>) to a data address. Note that D<15:8>, the 'phantom byte', will always be '0'.

In Byte mode, this instruction maps the upper or lower byte of the program word to D<7:0> of the data address, as in the TBLRDL instruction. Note that the data will always be '0' when the upper 'Phantom' byte is selected (Byte Select = 1).

In a similar fashion, two table instructions, TBLWTH and TBLWTL, are used to write individual bytes or words to a program space address. The details of their operation are explained in Section 5.0 "Flash Program Memory".

For all table operations, the area of program memory space to be accessed is determined by the Table Page register (TBLPAG). TBLPAG covers the entire program memory space of the device, including user and configuration spaces. When TBLPAG<7> = 0, the table page is located in the user memory space. When TBLPAG<7> = 1, the page is located in configuration space.



FIGURE 4-6: ACCESSING PROGRAM MEMORY WITH TABLE INSTRUCTIONS

4.4.3 READING DATA FROM PROGRAM MEMORY USING PROGRAM SPACE VISIBILITY

The upper 32 Kbytes of data space may optionally be mapped into any 16K word page of the program space. This option provides transparent access to the stored constant data from the data space without the need to use special instructions (such as TBLRDL/H).

Program space access through the data space occurs if the Most Significant bit of the data space EA is '1' and program space visibility is enabled by setting the PSV bit in the Core Control register (CORCON<2>). The location of the program memory space to be mapped into the data space is determined by the Program Space Visibility Page register (PSVPAG). This 8-bit register defines any one of 256 possible pages of 16K words in program space. In effect, PSVPAG functions as the upper 8 bits of the program memory address, with the 15 bits of the EA functioning as the lower bits. By incrementing the PC by 2 for each program memory word, the lower 15 bits of data space addresses directly map to the lower 15 bits in the corresponding program space addresses.

Data reads to this area add a cycle to the instruction being executed, since two program memory fetches are required.

Although each data space address 0x8000 and higher maps directly into a corresponding program memory address (see Figure 4-7), only the lower 16 bits of the

24-bit program word are used to contain the data. The upper 8 bits of any program space location used as data should be programmed with '1111 1111' or '0000 0000' to force a NOP. This prevents possible issues should the area of code ever be accidentally executed.

Note: PSV access is temporarily disabled during table reads/writes.

For operations that use PSV and are executed outside a REPEAT loop, the MOV and MOV.D instructions require one instruction cycle in addition to the specified execution time. All other instructions require two instruction cycles in addition to the specified execution time.

For operations that use PSV, and are executed inside a REPEAT loop, these instances require two instruction cycles in addition to the specified execution time of the instruction:

- · Execution in the first iteration
- · Execution in the last iteration
- Execution prior to exiting the loop due to an interrupt
- Execution upon re-entering the loop after an interrupt is serviced

Any other iteration of the REPEAT loop will allow the instruction using PSV to access data to execute in a single cycle.





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NOTES:

5.0 FLASH PROGRAM MEMORY

- Note 1: This data sheet summarizes the features of the PIC24HJ32GP202/204 and PIC24HJ16GP304 family of devices. However, it is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to "Section 4. Program Memory" (DS70202) of the "dsPIC33F/PIC24H Family Reference Manual", which is available from the Microchip website (www.microchip.com).
 - Some registers and associated bits described in this section may not be available on all devices. Refer to Section 4.0 "Memory Organization" in this data sheet for device-specific register and bit information.

The PIC24HJ32GP202/204 and PIC24HJ16GP304 devices contain internal Flash program memory to store and execute application code. The memory is readable, writable and erasable during normal operation over the entire VDD range.

Flash memory can be programmed in two ways:

- In-Circuit Serial Programming[™] (ICSP[™]) programming capability
- Run-Time Self-Programming (RTSP)

ICSP allows a device to be serially programmed while in the end application circuit. This is done with two lines for programming clock and programming data (one of the alternate programming pin pairs: PGECx/PGEDx), and three other lines for power (VDD), ground (VSS) and Master Clear (MCLR). This allows customers to manufacture boards with unprogrammed devices and then program the microcontroller just before shipping the product. This also allows the most recent firmware or a custom firmware to be programmed.

RTSP is accomplished using TBLRD (table read) and TBLWT (table write) instructions. With RTSP, the user application can write program memory data either in 'blocks' or 'rows' of 64 instructions (192 bytes) at a time or a single program memory word, and erase program memory in blocks or 'pages' of 512 instructions (1536 bytes) at a time.

5.1 Table Instructions and Flash Programming

Regardless of the method used, all programming of Flash memory is done with the table read and table write instructions. These allow direct read and write access to the program memory space from the data memory while the device is in normal operating mode. The 24-bit target address in the program memory is formed using bits <7:0> of the TBLPAG register and the Effective Address (EA) from a W register specified in the table instruction, as shown in Figure 5-1.

The TBLRDL and the TBLWTL instructions are used to read or write to the bits<15:0> of program memory. TBLRDL and TBLWTL can access program memory in both Word and Byte modes.

The TBLRDH and TBLWTH instructions are used to read or write to bits<23:16> of program memory. TBLRDH and TBLWTH can also access program memory in Word or Byte mode.

FIGURE 5-1: ADDRESSING FOR TABLE REGISTERS



5.2 RTSP Operation

The Flash program memory array is organized into rows of 64 instructions or 192 bytes. RTSP allows the user application to erase a page of memory, which consists of eight rows (512 instructions) at a time, and to program one row or one word at a time. The 8-row erase pages and single row write rows are edge-aligned from the beginning of program memory, on boundaries of 1536 bytes and 192 bytes, respectively.

The program memory implements holding buffers that can contain 64 instructions of programming data. Prior to the actual programming operation, the write data must be loaded into the buffers sequentially. The instruction words loaded must always be from a group of 64 boundary.

The basic sequence for RTSP programming is to set up a Table Pointer, then do a series of TBLWT instructions to load the buffers. Programming is performed by setting the control bits in the NVMCON register. A total of 64 TBLWTL and TBLWTH instructions are required to load the instructions.

All table write operations are single-word writes (two instruction cycles) because only the buffers are written. A programming cycle is required for programming each row.

5.3 Programming Operations

A complete programming sequence is necessary for programming or erasing the internal Flash in RTSP mode. The processor stalls (waits) until the programming operation is finished.

The programming time depends on the FRC accuracy (see Table 22-18) and the value of the FRC Oscillator Tuning register (see Register 8-4). Use the following formula to calculate the minimum and maximum values for the Row Write Time, Page Erase Time, and Word Write Cycle Time parameters (see Table 22-12).

EQUATION 5-1:	PROGRAMMING TIME

Τ	
7.37 $MHz \times (FRC Accuracy)\% \times (FRC Tuning)\%$	

For example, if the device is operating at $+125^{\circ}$ C, the FRC accuracy will be $\pm 5\%$. If the TUN<5:0> bits (see Register 8-4) are set to `b111111, the minimum row write time is equal to Equation 5-2.

EQUATION 5-2:	MINIMUM ROW WRITE
	TIME

T _ 11064 Cycles	- 1 425
$I_{RW} = \frac{1}{7.37} MH_z \times (1 + 0.05) \times (1 - 0.00375)$	= 1.435 ms

The maximum row write time is equal to Equation 5-3.

EQUATION 5-3: MAXIMUM ROW WRITE TIME

$$T_{RW} = \frac{11064 \ Cycles}{7.37 \ MHz \times (1 - 0.05) \times (1 - 0.00375)} = 1.586 ms$$

Setting the WR bit (NVMCON<15>) starts the operaion, and the WR bit is automatically cleared when the operation is finished.

5.4 Control Registers

The two SFRs that are used to read and write the program Flash memory are:

- NVMCON: Flash Memory Control Register
- NVMKEY: Nonvolatile Memory Key Register

The NVMCON register (Register 5-1) controls which blocks need to be erased, which memory type is to be programmed and the start of the programming cycle.

NVMKEY (Register 5-2) is a write-only register that is used for write protection. To start a programming or erase sequence, the user application must consecutively write 0x55 and 0xAA to the NVMKEY register. Refer to **Section 5.3** "**Programming Operations**" for further details.

REGISTER 5-1: NVMCON: FLASH MEMORY CONTROL REGISTER

bit 15							bit 8
WR	WREN	WRERR	—	—	—	—	—
R/SO-0 ⁽¹⁾	R/W-0 ⁽¹⁾	R/W-0 ⁽¹⁾	U-0	U-0	U-0	U-0	U-0

U-0	R/W-0	U-0	U-0	R/W-0	R/W-0	R/W-0(1)	R/W-0(')
—	ERASE	—	—		NVMOP	<3:0> ⁽²⁾	
bit 7							bit 0

Legend:	SO = Settable Only bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read	d as '0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15	WR: Write Control bit
	 1 = Initiates a Flash memory program or erase operation. The operation is self-timed and the bit is cleared by hardware once operation is complete 0 = Program or erase operation is complete and inactive
bit 14	WREN: Write Enable bit
	 1 = Enable Flash program/erase operations 0 = Inhibit Flash program/erase operations
bit 13	WRERR: Write Sequence Error Flag bit
	 1 = An improper program or erase sequence attempt or termination has occurred (bit is set automatically on any set attempt of the WR bit) 0 = The program or erase operation completed normally
bit 12-7	Unimplemented: Read as '0'
bit 6	ERASE: Erase/Program Enable bit
	 1 = Perform the erase operation specified by NVMOP<3:0> on the next WR command 0 = Perform the program operation specified by NVMOP<3:0> on the next WR command
bit 5-4	Unimplemented: Read as '0'
bit 3-0	NVMOP<3:0>: NVM Operation Select bits ⁽²⁾
	If ERASE = 1: 1111 = Memory bulk erase operation 1101 = Erase General Segment 1100 = Erase Secure Segment 0011 = No operation 0010 = Memory page erase operation 0001 = No operation 0000 = Erase a single Configuration register byte
	If ERASE = 0: 1111 = No operation 1101 = No operation 1100 = No operation 0011 = Memory word program operation 0010 = No operation 0001 = Memory row program operation 0000 = Program a single Configuration register byte
Note 1:	These bits can only be reset on a Power-on Reset (POR).

2: All other combinations of NVMOP<3:0> are unimplemented.

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	_	—	—	—	—
bit 15							bit 8
W-0	W-0	W-0	W-0	W-0	W-0	W-0	W-0
			NVMK	EY<7:0>			
bit 7							bit 0
Legend: SO = Settable Only bit			e Only bit				
R = Readable bit W = Writable bit			U = Unimple	mented bit, read	d as '0'		
-n = Value at P	OR	'1' = Bit is set		'0' = Bit is cle	eared	x = Bit is unkr	nown

REGISTER 5-2: NVMKEY: NONVOLATILE MEMORY KEY REGISTER

bit 15-8 Unimplemented: Read as '0'

bit 7-0 NVMKEY<7:0>: Key Register (write-only) bits

5.4.1 PROGRAMMING ALGORITHM FOR FLASH PROGRAM MEMORY

Programmers can program one row of program Flash memory at a time. To do this, it is necessary to erase the 8-row erase page that contains the desired row. The general process is:

- 1. Read eight rows of program memory (512 instructions) and store in data RAM.
- 2. Update the program data in RAM with the desired new data.
- 3. Erase the block (see Example 5-1):
 - a) Set the NVMOP bits (NVMCON<3:0>) to ⁽⁰⁰¹⁰⁾ to configure for block erase. Set ERASE (NVMCON<6>) and WREN (NVMCON<14>) bits.
 - b) Write the starting address of the page to be erased into the TBLPAG and W registers.
 - c) Write 0x55 to NVMKEY.
 - d) Write 0xAA to NVMKEY.
 - e) Set the WR bit (NVMCON<15>). The erase cycle begins and the CPU stalls for the duration of the erase cycle. When the erase is done, the WR bit is cleared automatically.

- 4. Write the first 64 instructions from data RAM into the program memory buffers (see Example 5-2).
- 5. Write the program block to Flash memory:
 - a) Set the NVMOP bits to '0001' to configure for row programming. Clear the ERASE bit and set the WREN bit.
 - b) Write 0x55 to NVMKEY.
 - c) Write 0xAA to NVMKEY.
 - d) Set the WR bit. The programming cycle begins and the CPU stalls for the duration of the write cycle. When the write to Flash memory is done, the WR bit is cleared automatically.
- Repeat steps 4 and 5, using the next available 64 instructions from the block in data RAM by incrementing the value in TBLPAG, until all 512 instructions are written back to Flash memory.

To protect against accidental operations, the write initiate sequence for NVMKEY must be used to allow any erase or program operation to proceed. After the programming command has been executed, the user application must wait for the programming time until programming is complete. The two instructions following the start of the programming sequence should be NOPs, as shown in Example 5-3.

EXAMPLE 5-1: ERASING A PROGRAM MEMORY PAGE

; Set up NVMCON for block erase operation	; Set up NVMCON for block erase operation							
MOV #0x4042, W0	;							
MOV W0, NVMCON	; Initialize NVMCON							
; Init pointer to row to be ERASED								
MOV #tblpage(PROG_ADDR), W0	;							
MOV W0, TBLPAG	; Initialize PM Page Boundary SFR							
MOV #tbloffset(PROG_ADDR), W0	; Initialize in-page EA[15:0] pointer							
TBLWTL W0, [W0]	; Set base address of erase block							
DISI #5	; Block all interrupts with priority less than 7							
	; for next 5 instructions							
MOV #0x55, W0								
MOV W0, NVMKEY	; Write the 55 key							
MOV #0xAA, W1	;							
MOV W1, NVMKEY	; Write the AA key							
BSET NVMCON, #WR	; Start the erase sequence							
NOP	; Insert two NOPs after the erase							
NOP	; command is asserted							

EXAMPLE 5-2: LOADING THE WRITE BUFFERS

	-		
;	Set up NVMCO	N for row programmin	g operations
	MOV	#0x4001, W0	;
	MOV	W0, NVMCON	; Initialize NVMCON
		-	ogram memory location to be written
;	program memo:	ry selected, and wri	tes enabled
	MOV	#0x0000, W0	i
	MOV	W0, TBLPAG	; Initialize PM Page Boundary SFR
	MOV	#0x6000, W0	
;	Perform the	TBLWT instructions t	o write the latches
;	0th_program_	word	
	MOV	#LOW_WORD_0, W2	;
	MOV	<pre>#HIGH_BYTE_0, W3</pre>	;
		W2, [W0]	; Write PM low word into program latch
		W3, [W0++]	; Write PM high byte into program latch
;	lst_program_		
	MOV	· · · · · · · · · · · · · · · · · · ·	;
	MOV	#HIGH_BYTE_1, W3	;
		W2, [W0]	; Write PM low word into program latch
		W3, [W0++]	; Write PM high byte into program latch
;			
	MOV	#LOW_WORD_2, W2	;
	MOV		;
		W2, [W0]	; Write PM low word into program latch
	TBLWTH	W3, [W0++]	; Write PM high byte into program latch
	•		
	•		
1	•		
;	63rd_program		
	MOV	#LOW_WORD_31, W2	;
	MOV	#HIGH_BYTE_31, W3	
		W2, [W0]	; Write PM low word into program latch
	TBLWTH	W3, [W0++]	; Write PM high byte into program latch

EXAMPLE 5-3: INITIATING A PROGRAMMING SEQUENCE

DISI	#5	; Block all interrupts with priority less than 7 ; for next 5 instructions
MOV	#0x55, W0	
MOV	W0, NVMKEY	; Write the 55 key
MOV	#0xAA, W1	;
MOV	W1, NVMKEY	; Write the AA key
BSET	NVMCON, #WR	; Start the erase sequence
NOP		; Insert two NOPs after the
NOP		; erase command is asserted

6.0 RESETS

- Note 1: This data sheet summarizes the features of the PIC24HJ32GP202/204 and PIC24HJ16GP304 family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to "Section 8. Reset" (DS70192) of the "dsPIC33F/PIC24H Family Reference Manual", which is available from the Microchip website (www.microchip.com).
 - 2: Some registers and associated bits described in this section may not be available on all devices. Refer to Section 4.0 "Memory Organization" in this data sheet for device-specific register and bit information.

The Reset module combines all reset sources and controls the device Master Reset Signal, SYSRST. The following is a list of device Reset sources:

- POR: Power-on Reset
- BOR: Brown-out Reset
- MCLR: Master Clear Pin Reset
- SWR: RESET Instruction
- WDTO: Watchdog Timer Reset
- CM: Configuration Mismatch Reset
- TRAPR: Trap Conflict Reset
- IOPUWR: Illegal Condition Device Reset
 - Illegal Opcode Reset
 - Uninitialized W Register Reset
 - Security Reset

FIGURE 6-1: RESET SYSTEM BLOCK DIAGRAM

A simplified block diagram of the Reset module is shown in Figure 6-1.

Any active source of reset will make the SYSRST signal active. On system Reset, some of the registers associated with the CPU and peripherals are forced to a known Reset state and some are unaffected.

Note: Refer to the specific peripheral section or Section 3.0 "CPU" of this manual for register Reset states.

All types of device Reset sets a corresponding status bit in the RCON register to indicate the type of Reset (see Register 6-1).

A POR clears all the bits, except for the POR bit (RCON<0>), that are set. The user application can set or clear any bit at any time during code execution. The RCON bits only serve as status bits. Setting a particular Reset status bit in software does not cause a device Reset to occur.

The RCON register also has other bits associated with the Watchdog Timer and device power-saving states. The function of these bits is discussed in other sections of this manual.

Note: The status bits in the RCON register should be cleared after they are read so that the next RCON register value after a device Reset is meaningful.



R/W-0	R/W-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0		
TRAPR	IOPUWR	_			—	CM	VREGS		
bit 15							bit 8		
R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-1	R/W-1		
EXTR	SWR	SWDTEN ⁽²⁾	WDTO	SLEEP	IDLE	BOR	POR		
bit 7							bit (
Legend:									
R = Readable	e bit	W = Writable	oit	U = Unimpler	mented bit, read	d as '0'			
-n = Value at	POR	'1' = Bit is set		'0' = Bit is cle	ared	x = Bit is unk	nown		
bit 15	TPADD. Tran	Reset Flag bit							
	•	onflict Reset ha	soccurred						
		onflict Reset ha		d					
bit 14	IOPUWR: Ille	gal Opcode or	Uninitialized ^v	W Access Res	et Flag bit				
				gal address m	ode or uninitial	lized W registe	er used as a		
		Address Pointer caused a Reset 0 = An illegal opcode or uninitialized W Reset has not occurred							
	-	-		teset has not o	ccurrea				
bit 13-10	Unimplemented: Read as '0'								
bit 9		CM: Configuration Mismatch Flag bit							
	 1 = A configuration mismatch Reset has occurred 0 = A configuration mismatch Reset has not occurred 								
bit 8	VREGS: Voltage Regulator Standby During Sleep bit								
	1 = Voltage regulator is active during Sleep								
	0 = Voltage r	egulator goes i	nto Standby r	node during Sl	еер				
bit 7		nal Reset (MCL	,						
	1 = A Master Clear (pin) Reset has occurred								
		Clear (pin) Res							
bit 6		re Reset (Instru							
		instruction has instruction has							
bit 5		oftware Enable/							
	1 = WDT is e								
	0 = WDT is di								
bit 4	WDTO: Watc	hdog Timer Tim	ne-out Flag bi	t					
	1 = WDT time-out has occurred								
		e-out has not or							
bit 3	SLEEP: Wake-up from Sleep Flag bit								
	1 = Device has been in Sleep mode 0 = Device has not been in Sleep mode								
bit 2		up from Idle Fla	•						
			9 Dit						
	1 = Device was in Idle mode 0 = Device was not in Idle mode								

REGISTER 6-1: RCON: RESET CONTROL REGISTER⁽¹⁾

Note 1: All of the Reset status bits can be set or cleared in software. Setting one of these bits in software does not cause a device Reset.

2: If the FWDTEN Configuration bit is '1' (unprogrammed), the WDT is always enabled, regardless of the SWDTEN bit setting.

REGISTER 6-1: RCON: RESET CONTROL REGISTER⁽¹⁾ (CONTINUED)

- bit 1 BOR: Brown-out Reset Flag bit 1 = A Brown-out Reset has occurred A Brown out Reset has not accurred
 - 0 = A Brown-out Reset has not occurred
- bit 0 **POR:** Power-on Reset Flag bit
 - 1 = A Power-on Reset has occurred
 - 0 = A Power-on Reset has not occurred
- **Note 1:** All of the Reset status bits can be set or cleared in software. Setting one of these bits in software does not cause a device Reset.
 - 2: If the FWDTEN Configuration bit is '1' (unprogrammed), the WDT is always enabled, regardless of the SWDTEN bit setting.

6.1 System Reset

The PIC24HJ32GP202/204 and PIC24HJ16GP304 family of devices have two types of Reset:

- Cold Reset
- Warm Reset

A cold Reset is the result of a Power-on Reset (POR) or a Brown-out Reset (BOR). On a cold Reset, the FNOSC configuration bits in the FOSC device configuration register selects the device clock source. A warm Reset is the result of all other reset sources, including the RESET instruction. On warm Reset, the device will continue to operate from the current clock source as indicated by the Current Oscillator Selection bits (COSC<2:0>) in the Oscillator Control register (OSCCON<14:12>).

The device is kept in a Reset state until the system power supplies have stabilized at appropriate levels and the oscillator clock is ready. The sequence in which this occurs is shown in Figure 6-2.

Oscillator Mode	Oscillator Start-up Delay	Oscillator Start-up Timer	PLL Lock Time	Total Delay
FRC, FRCDIV16, FRCDIVN	Toscd	_	_	Toscd
FRCPLL	Toscd	—	TLOCK	TOSCD + TLOCK
XT	Toscd	Тоѕт	—	TOSCD + TOST
HS	Toscd	Tost	—	TOSCD + TOST
EC	—	—	—	—
XTPLL	Toscd	Тоѕт	TLOCK	TOSCD + TOST + TLOCK
HSPLL	Toscd	Tost	TLOCK	TOSCD + TOST + TLOCK
ECPLL	—	—	TLOCK	TLOCK
SOSC	Toscd	Тоѕт	_	TOSCD + TOST
LPRC	Toscd	_	_	Toscd

TABLE 6-1:OSCILLATOR DELAY

Note 1: TOSCD = Oscillator Start-up Delay (1.1 μs max for FRC, 70 μs max for LPRC). Crystal Oscillator start-up times vary with crystal characteristics, load capacitance, etc.

2: TOST = Oscillator Start-up Timer Delay (1024 oscillator clock period). For example, TOST = 102.4 μs for a 10 MHz crystal and TOST = 32 ms for a 32 kHz crystal.

3: TLOCK = PLL lock time (1.5 ms nominal), if PLL is enabled.



Symbol	Parameter	Value
VPOR	POR threshold	1.8V nominal
TPOR	POR extension time	30 μs maximum
VBOR	BOR threshold	2.5V nominal
TBOR	BOR extension time	100 μs maximum
TPWRT	Programmable power-up time delay	0-128 ms nominal
TFSCM	Fail-Safe Clock Monitor Delay	900 μs maximum

TABLE 6-2: OSCILLATOR PARAMETERS

Note: When the device exits the Reset condition (begins normal operation), the device operating parameters (voltage, frequency, temperature, etc.) must be within their operating ranges, otherwise the device may not function correctly. The user application must ensure that the delay between the time power is first applied, and the time SYSRST becomes inactive, is long enough to get operating parameters all within specification.

6.2 Power-on Reset (POR)

A Power-on Reset (POR) circuit ensures the device is reset from power-on. The POR circuit is active until VDD crosses the VPOR threshold and the delay TPOR has elapsed. The delay TPOR ensures the internal device bias circuits become stable.

The device supply voltage characteristics must meet the specified starting voltage and rise rate requirements to generate the POR. Refer to Section 22.0 "Electrical Characteristics" for details.

The POR status bit in the Reset Control register (RCON<0>) is set to indicate the Power-on Reset.

6.2.1 Brown-out Reset (BOR) and Power-up Timer (PWRT)

The on-chip regulator has a Brown-out Reset (BOR) circuit that resets the device when the VDD is too low (VDD < VBOR) for proper device operation. The BOR circuit keeps the device in Reset until VDD crosses VBOR threshold and the delay TBOR has elapsed. The delay TBOR ensures the voltage regulator output becomes stable.

The BOR status bit in the Reset Control register (RCON<1>) is set to indicate the Brown-out Reset.

The device will not run at full speed after a BOR as the VDD should rise to acceptable levels for full-speed operation. The PWRT provides power-up time delay (TPWRT) to ensure that the system power supplies have stabilized at the appropriate levels for full-speed operation before the SYSRST is released.

The power-up timer delay (TPWRT) is programmed by the Power-on Reset Timer Value Select (FPWRT<2:0>) bits in the POR Configuration (FPOR<2:0>) register, which provides eight settings (from 0 ms to 128 ms). Refer to Section 19.0 "Special Features" for further details.

Figure 6-3 shows the typical brown-out scenarios. The reset delay (TBOR + TPWRT) is initiated each time VDD rises above the VBOR trip point



6.3 External Reset (EXTR)

The external Reset is generated by driving the MCLR pin low. The MCLR pin is a Schmitt trigger input with an additional glitch filter. Reset pulses that are longer than the minimum pulse-width will generate a Reset. Refer to **Section 22.0 "Electrical Characteristics"** for minimum pulse-width specifications. The External Reset (MCLR) Pin (EXTR) bit in the Reset Control (RCON) register is set to indicate the MCLR Reset.

6.3.1 EXTERNAL SUPERVISORY CIRCUIT

Many systems have external supervisory circuits that generate reset signals to Reset multiple devices in the system. This external Reset signal can be directly connected to the MCLR pin to Reset the device when the rest of system is Reset.

6.3.2 INTERNAL SUPERVISORY CIRCUIT

When using the internal power supervisory circuit to Reset the device, the external reset pin (MCLR) should be tied directly or resistively to VDD. In this case, the MCLR pin will not be used to generate a Reset. The external reset pin (MCLR) does not have an internal pull-up and must not be left unconnected.

6.4 Software RESET Instruction (SWR)

Whenever the RESET instruction is executed, the device will assert SYSRST, placing the device in a special Reset state. This Reset state will not re-initialize the clock. The clock source in effect prior to the RESET instruction will remain. SYSRST is released at the next instruction cycle, and the reset vector fetch will commence.

The Software Reset (Instruction) Flag (SWR) bit in the Reset Control register (RCON<6>) is set to indicate the software Reset.

6.5 Watchdog Time-out Reset (WDTO)

Whenever a Watchdog <u>time-out</u> occurs, the device will asynchronously assert SYSRST. The clock source will remain unchanged. A WDT time-out during Sleep or Idle mode will wake-up the processor, but will not reset the processor.

The Watchdog Timer Time-out Flag bit (WDTO) in the Reset Control register (RCON<4>) is set to indicate the Watchdog Reset. Refer to **Section 19.4 "Watchdog Timer (WDT)**" for more information on Watchdog Reset.

6.6 Trap Conflict Reset

If a lower-priority hard trap occurs while a higher-priority trap is being processed, a hard trap conflict Reset occurs. The hard traps include exceptions of priority level 13 through level 15, inclusive. The address error (level 13) and oscillator error (level 14) traps fall into this category.

The Trap Reset Flag bit (TRAPR) in the Reset Control register (RCON<15>) is set to indicate the Trap Conflict Reset. Refer to **Section 7.0 "Interrupt Controller"** for more information on trap conflict Resets.

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6.7 Configuration Mismatch Reset

To maintain the integrity of the peripheral pin select control registers, they are constantly monitored with shadow registers in hardware. If an unexpected change in any of the registers occur (such as cell disturbances caused by ESD or other external events), a configuration mismatch Reset occurs.

The Configuration Mismatch Flag bit (CM) in the Reset Control register (RCON<9>) is set to indicate the configuration mismatch Reset. Refer to **Section 10.0 "I/O Ports"** for more information on the configuration mismatch Reset.

Note: The configuration mismatch feature and associated reset flag is not available on all devices.

6.8 Illegal Condition Device Reset

An illegal condition device Reset occurs due to the following sources:

- Illegal Opcode Reset
- Uninitialized W Register Reset
- Security Reset

TABLE 6-3:

The Illegal Opcode or Uninitialized W Access Reset Flag bit (IOPUWR) in the Reset Control register (RCON<14>) is set to indicate the illegal condition device Reset.

6.8.1 ILLEGAL OPCODE RESET

A device Reset is generated if the device attempts to execute an illegal opcode value that is fetched from program memory.

The illegal opcode Reset function can prevent the device from executing program memory sections that are used to store constant data. To take advantage of the illegal opcode Reset, use only the lower 16 bits of

RESET FLAG BIT OPERATION

each program memory section to store the data values. The upper 8 bits should be programmed with 0x3F, which is an illegal opcode value.

6.8.2 UNINITIALIZED W REGISTER RESET

Any attempts to use the uninitialized W register as an address pointer will Reset the device. The W register array (with the exception of W15) is cleared during all resets and is considered uninitialized until written to.

6.8.3 SECURITY RESET

If a Program Flow Change (PFC) or Vector Flow Change (VFC) targets a restricted location in a protected segment (Boot and Secure Segment), that operation will cause a security Reset.

The PFC occurs when the Program Counter is reloaded as a result of a Call, Jump, Computed Jump, Return, Return from Subroutine, or other form of branch instruction.

The VFC occurs when the Program Counter is reloaded with an Interrupt or Trap vector.

Refer to Section 19.6 "Code Protection and CodeGuard[™] Security" for more information on Security Reset.

6.9 Using the RCON Status Bits

The user application can read the Reset Control (RCON) register after any device Reset to determine the cause of the reset.

Note: The status bits in the RCON register should be cleared after they are read so that the next RCON register value after a device Reset will be meaningful.

Table 6-3 provides a summary of the reset flag bit operation.

Flag Bit	Set by:	Cleared by:
TRAPR (RCON<15>)	Trap conflict event	POR, BOR
IOPWR (RCON<14>)	Illegal opcode or uninitialized W register access or Security Reset	POR, BOR
CM (RCON<9>)	Configuration Mismatch	POR, BOR
EXTR (RCON<7>)	MCLR Reset	POR
SWR (RCON<6>)	RESET instruction	POR, BOR
WDTO (RCON<4>)	WDT time-out	PWRSAV instruction, CLRWDT instruction, POR, BOR
SLEEP (RCON<3>)	PWRSAV #SLEEP instruction	POR, BOR
IDLE (RCON<2>)	PWRSAV #IDLE instruction	POR, BOR
BOR (RCON<1>)	POR, BOR	—
POR (RCON<0>)	POR	—

Note: All Reset flag bits can be set or cleared by user software.

7.0 INTERRUPT CONTROLLER

- Note 1: This data sheet summarizes the features of the PIC24HJ32GP202/204 and PIC24HJ16GP304 family of devices. However, it is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Section 6. Interrupts"** (DS70184) of the *"dsPIC33F/PIC24H Family Reference Manual"*, which is available from the Microchip website (www.microchip.com).
 - 2: Some registers and associated bits described in this section may not be available on all devices. Refer to Section 4.0 "Memory Organization" in this data sheet for device-specific register and bit information.

The PIC24HJ32GP202/204 and PIC24HJ16GP304 interrupt controllers reduce the numerous peripheral interrupt request signals to a single interrupt request signal to the PIC24HJ32GP202/204 and PIC24HJ16GP304 CPU.

It has the following features:

- Up to eight processor exceptions and software traps
- Seven user-selectable priority levels
- Interrupt Vector Table (IVT) with up to 118 vectors
- A unique vector for each interrupt or exception source
- Fixed priority within a specified user priority level
- Alternate Interrupt Vector Table (AIVT) for debug support
- · Fixed interrupt entry and return latencies

7.1 Interrupt Vector Table

Figure 7-1 shows the Interrupt Vector Table. The IVT resides in program memory, starting at location 0x000004. The IVT contains 126 vectors consisting of eight nonmaskable trap vectors and up to 118 sources of interrupt. In general, each interrupt source has its own vector. Each interrupt vector contains a 24 bit wide address. The value programmed into each interrupt vector location is the starting address of the associated Interrupt Service Routine (ISR).

Interrupt vectors are prioritized in terms of their natural priority; this priority is linked to their position in the vector table. Lower addresses generally have a higher natural priority. For example, the interrupt associated with vector 0 will take priority over interrupts at any other vector address.

PIC24HJ32GP202/204 and PIC24HJ16GP304 devices implement up to 21 unique interrupts and 4 nonmaskable traps. These are summarized in Table 7-1 and Table 7-2.

7.1.1 ALTERNATE INTERRUPT VECTOR TABLE

The Alternate Interrupt Vector Table (AIVT) is located after the IVT, as shown in Figure 7-1. Access to the AIVT is provided by the ALTIVT control bit (INTCON2<15>). If the ALTIVT bit is set, all interrupt and exception processes use the alternate vectors instead of the default vectors. The alternate vectors are organized in the same manner as the default vectors.

The AIVT supports debugging by providing a means to switch between an application and a support environment without requiring the interrupt vectors to be reprogrammed. This feature also enables switching between applications for evaluation of different software algorithms at run time. If the AIVT is not needed, the AIVT should be programmed with the same addresses used in the IVT.

7.2 Reset Sequence

A device Reset is not a true exception because the interrupt controller is not involved in the Reset process. The device clear its registers in response to a Reset, which forces the PC to zero. The microcontroller then begins the program execution at location 0x000000. The user application can use a GOTO instruction at the Reset address which redirects program execution to the appropriate start-up routine.

Note: Any unimplemented or unused vector locations in the IVT and AIVT should be programmed with the address of a default interrupt handler routine that contains a RESET instruction.

1			
	Reset – GOTO Instruction	0x000000	
	Reset – GOTO Address	0x000002	
	Reserved	0x000004	
	Oscillator Fail Trap Vector		
	Address Error Trap Vector		
	Stack Error Trap Vector		
	Math Error Trap Vector		
	Reserved		
	Reserved		
	Reserved		_
	Interrupt Vector 0	0x000014	
	Interrupt Vector 1		
	~		
	~		
	~		
	Interrupt Vector 52	0x00007C	Interrupt Vector Table (IVT) ⁽¹⁾
	Interrupt Vector 53	0x00007E	
rity	Interrupt Vector 54	0x000080	
rio	~		
<u>с</u>	~		
rde	~		
Ō	Interrupt Vector 116	0x0000FC	
Ira	Interrupt Vector 117	0x0000FE	
atı	Reserved	0x000100	
Z	Reserved	0x000102	
Decreasing Natural Order Priority	Reserved		
993	Oscillator Fail Trap Vector		
SCL	Address Error Trap Vector		
ă	Stack Error Trap Vector		
	Math Error Trap Vector		
	Reserved		
	Reserved		
	Reserved		
	Interrupt Vector 0	0x000114	
	Interrupt Vector 1		
	~		
	~		
	~		Alternate Interrupt Vector Table (AIVT) ⁽¹⁾
	Interrupt Vector 52	0x00017C	
	Interrupt Vector 53	0x00017E	
	Interrupt Vector 54	0x000180	
	~		
	~		
	~		
	Interrupt Vector 116		_
	Interrupt Vector 117	0x0001FE	
	Start of Code	0x000200	
V			

TABLE 7-1: INTERRUPT VECTORS						
Vector Number	Interrupt Request (IRQ) Number	IVT Address	AIVT Address	Interrupt Source		
8	0	0x000014	0x000114	INT0 – External Interrupt 0		
9	1	0x000016	0x000116	IC1 – Input Capture 1		
10	2	0x000018	0x000118	OC1 – Output Compare 1		
11	3	0x00001A	0x00011A	T1 – Timer1		
12	4	0x00001C	0x00011C	Reserved		
13	5	0x00001E	0x00011E	IC2 – Input Capture 2		
14	6	0x000020	0x000120	OC2 – Output Compare 2		
15	7	0x000022	0x000122	T2 – Timer2		
16	8	0x000024	0x000124	T3 – Timer3		
17	9	0x000026	0x000126	SPI1E – SPI1 Error		
18	10	0x000028	0x000128	SPI1 – SPI1 Transfer Done		
19	11	0x00002A	0x00012A	U1RX – UART1 Receiver		
20	12	0x00002C	0x00012C	U1TX – UART1 Transmitter		
21	13	0x00002E	0x00012E	ADC1 – ADC1		
22	14	0x000030	0x000130	Reserved		
23	15	0x000032	0x000132	Reserved		
24	16	0x000034	0x000134	SI2C1 – I2C1 Slave Events		
25	17	0x000036	0x000136	MI2C1 – I2C1 Master Events		
26	18	0x000038	0x000138	Reserved		
27	19	0x00003A	0x00013A	Change Notification Interrupt		
28	20	0x00003C	0x00013C	INT1 – External Interrupt 1		
29	21	0x00003E	0x00013E	Reserved		
30	22	0x000040	0x000140	IC7 – Input Capture 7		
31	23	0x000042	0x000142	IC8 – Input Capture 8		
32-36	24-28	0x000044-0x00004C	0x000144-0x00014C	Reserved		
37	29	0x00004E	0x00014E	INT2 – External Interrupt 2		
38-72	30-64	0x000050-0x000094	0x000150-0x000194	Reserved		
73	65	0x000096	0x000196	U1E – UART1 Error		
74-125	66-117	0x000098-0x0000FE	0x000198-0x0001FE	Reserved		

TABLE 7-1: INTERRUPT VECTORS

TABLE 7-2: TRAP VECTORS

Vector Number	IVT Address	AIVT Address	Trap Source
0	0x000004	0x000104	Reserved
1	0x000006	0x000106	Oscillator Failure
2	0x000008	0x000108	Address Error
3	0x00000A	0x00010A	Stack Error
4	0x00000C	0x00010C	Math Error
5	0x00000E	0x00010E	Reserved
6	0x000010	0x000110	Reserved
7	0x000012	0x000112	Reserved

7.3 Interrupt Control and Status Registers

PIC24HJ32GP202/204 and PIC24HJ16GP304 devices implement a total of 17 registers for the interrupt controller:

- Interrupt Control Register 1 (INTCON1)
- Interrupt Control Register 2 (INTCON2)
- Interrupt Flag Status Registers (IFSx)
- Interrupt Enable Control Registers (IECx)
- Interrupt Priority Control Registers (IPCx)
- Interrupt Control and Status Register (INTTREG)

7.3.1 INTCON1 AND INTCON2

Global interrupt control functions are controlled from INTCON1 and INTCON2. INTCON1 contains the Interrupt Nesting Disable bit (NSTDIS) as well as the control and status flags for the processor trap sources. The INTCON2 register controls the external interrupt request signal behavior and the use of the Alternate Interrupt Vector Table.

7.3.2 IFSx

The IFS registers maintain all the interrupt request flags. Each source of interrupt has a status bit, which is set by the respective peripherals or external signal and this is cleared via software.

7.3.3 IECx

The IEC registers maintain all the interrupt enable bits. These control bits are used individually to enable interrupts from the peripherals or external signals.

7.3.4 IPCx

The IPC registers are used to set the interrupt priority level for each source of interrupt. Each user interrupt source can be assigned to one of the eight priority levels.

7.3.5 INTTREG

The INTTREG register contains the associated interrupt vector number and the new CPU interrupt priority level, which are latched into vector number (VECNUM<6:0>) and Interrupt level (ILR<3:0>) bit fields in the INTTREG register. The new interrupt priority level is the priority of the pending interrupt.

The interrupt sources are assigned to the IFSx, IECx and IPCx registers in the same sequence that they are listed in Table 7-1. For example, the INT0 (External Interrupt 0) is shown as having vector number 8 and a natural order priority of 0. Thus, the INT0IF bit is found in IFS0<0>, the INT0IE bit in IEC0<0>, and the INT0IP bits in the first position of IPC0 (IPC0<2:0>).

7.3.6 STATUS REGISTERS

Although these are not specifically part of the interrupt control hardware, two of the CPU Control registers contain bits that control interrupt functionality:

- The CPU STATUS register, SR, contains the IPL<2:0> bits (SR<7:5>). These bits indicate the current CPU interrupt priority level. The user can change the current CPU priority level by writing to the IPL bits.
- The CORCON register contains the IPL3 bit which, together with IPL<2:0>, also indicates the current CPU priority level. IPL3 is a read-only bit, so that trap events cannot be masked by the user software.

All Interrupt registers are described in Register 7-1 through Register 7-19.

U-0	U-0 U-0	U-0	U-0	U-0	R/W-0
_				_	DC
					bit 8
/W-0 ⁽³⁾ R/	N-0 ⁽³⁾ R-0	R/W-0	R/W-0	R/W-0	R/W-0
PL1 ⁽²⁾ IP	L0 ⁽²⁾ RA	N	OV	Z	С
L.			•	•	bit C
	— W-0 ⁽³⁾ R/	— — — —			<u></u>

SR: CPU STATUS REGISTER⁽¹⁾ **REGISTER 7-1:**

Legend:		
C = Clear only bit	R = Readable bit	U = Unimplemented bit, read as '0'
S = Set only bit	W = Writable bit	-n = Value at POR
'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

IPL<2:0>: CPU Interrupt Priority Level Status bits⁽²⁾ bit 7-5

111 = CPU Interrupt Priority Level is 7 (15), user interrupts disabled

110 = CPU Interrupt Priority Level is 6 (14)

101 = CPU Interrupt Priority Level is 5 (13)

- 100 = CPU Interrupt Priority Level is 4 (12) 011 = CPU Interrupt Priority Level is 3 (11)
- 010 = CPU Interrupt Priority Level is 2 (10)
- 001 = CPU Interrupt Priority Level is 1 (9)
- 000 = CPU Interrupt Priority Level is 0 (8)
- **Note 1:** For complete register details, see Register 3-1.
 - 2: The IPL<2:0> bits are concatenated with the IPL<3> bit (CORCON<3>) to form the CPU Interrupt Priority Level. The value in parentheses indicates the IPL if IPL<3> = 1. User interrupts are disabled when IPL<3> = 1.
 - 3: The IPL<2:0> Status bits are read-only when the NSTDIS bit (INTCON1<15>) = 1.

REGISTER 7-2: CORCON: CORE CONTROL REGISTER⁽¹⁾

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0	
—	—	—	—	—	_	—	—	
bit 15							bit 8	
U-0	U-0	U-0	U-0	R/C-0	R/W-0	U-0	U-0	
—	—	—	—	IPL3 ⁽²⁾	PSV	—	—	
bit 7							bit 0	
Legend: C = Clear only bit			y bit					
R = Readable bit W = Writable bit		bit	-n = Value at POR '1' = Bit is set					
0' = Bit is cleared 'x = Bit is unknown			nown	U = Unimplemented bit, read as '0'				

bit 3 IPL3: CPU Interrupt Priority Level Status bit 3⁽²⁾ 1 = CPU interrupt priority level is greater than 7 0 = CPU interrupt priority level is 7 or less

Note 1: For complete register details, see Register 3-2.

2: The IPL3 bit is concatenated with the IPL<2:0> bits (SR<7:5>) to form the CPU Interrupt Priority Level.

R/W-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0		
NSTDIS	_	—	—	—	_	—	_		
bit 15							bit		
U-0	R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0		
	DIV0ERR	<u> </u>	MATHERR	ADDRERR	STKERR	OSCFAIL			
bit 7					•••••		bit		
Legend:									
R = Readable	e bit	W = Writable	e bit	U = Unimplem	nented bit, read	d as '0'			
-n = Value at	POR	'1' = Bit is set		'0' = Bit is cleared		x = Bit is unknown			
bit 15	NSTDIS: Inte 1 = Interrupt r 0 = Interrupt r	nesting is disa nesting is ena	bled bled						
bit 14-7	Unimplemen	ted: Read as	ʻ0 '						
bit 6	DIV0ERR: Arithmetic Error Status bit								
			used by a divide caused by a d						
bit 5	Unimplemen	ted: Read as	'0'						
bit 4	MATHERR: Arithmetic Error Status bit 1 = Math error trap has occurred 0 = Math error trap has not occurred								
bit 3	ADDRERR: Address Error Trap Status bit 1 = Address error trap has occurred 0 = Address error trap has not occurred								
bit 2	STKERR: Stack Error Trap Status bit 1 = Stack error trap has occurred 0 = Stack error trap has not occurred								
bit 1	OSCFAIL: Oscillator Failure Trap Status bit 1 = Oscillator failure trap has occurred 0 = Oscillator failure trap has not occurred								
	0 = Oscillator	iallule trap ha	as not occurred						

REGISTER 7-3: INTCON1: INTERRUPT CONTROL REGISTER 1

R/W-0	R-0	U-0	U-0	U-0	U-0	U-0	U-0			
ALTIVT	DISI		—			—	—			
bit 15							bit 8			
U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0			
—	—	—	—	—	INT2EP	INT1EP	INT0EP			
bit 7							bit (
Legend:										
R = Readabl	e bit	W = Writable	bit	U = Unimple	mented bit, rea	d as '0'				
-n = Value at	POR	'1' = Bit is set		(0' = Bit is cleared x = Bit is			unknown			
bit 15	ALTIVT: Enable Alternate Interrupt Vector Table bit									
	1 = Use alternate vector table									
	0 = Use standard (default) vector table									
bit 14	DISI: DISI Instruction Status bit									
	1 = DISI instruction is active 0 = DISI instruction is not active									
hit 10 0										
bit 13-3	Unimplemented: Read as '0'									
bit 2	INT2EP: External Interrupt 2 Edge Detect Polarity Select bit									
	1 = Interrupt on negative edge 0 = Interrupt on positive edge									
bit 1	INT1EP: External Interrupt 1 Edge Detect Polarity Select bit									
	1 = Interrupt on negative edge									
	0 = Interrupt on positive edge									
bit 0	INTOEP: Ext	ernal Interrupt C	Edge Deteo	t Polarity Selec	t bit					
		on negative edg		-						
	0 = Interrupt on positive edge									

REGISTER 7-4: INTCON2: INTERRUPT CONTROL REGISTER 2

REGISTER 7	-5: IFS0:	INTERRUPT	FLAG STAT	US REGISTI	ER 0					
U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0			
_	—	AD1IF	U1TXIF	U1RXIF	SPI1IF	SPI1EIF	T3IF			
bit 15							bit 8			
D/M/ 0	D/M/ 0	D/M/ O		D/M/O	D/W/ 0	D/M/ O	D/M/ O			
R/W-0 T2IF	R/W-0 OC2IF	R/W-0 IC2IF	U-0	R/W-0 T1IF	R/W-0 OC1IF	R/W-0 IC1IF	R/W-0 INT0IF			
bit 7	UCZIF	ICZIF			OCTIF	ICTIF	bit			
Legend:			1.5							
R = Readable		W = Writable		-	nented bit, rea					
-n = Value at F	POR	'1' = Bit is set	: 	'0' = Bit is cle	ared	x = Bit is unkn	own			
bit 15-4	Unimplemen	ted: Read as	0'							
bit 13	AD1IF: ADC	1 Conversion C	Complete Inter	rupt Flag Statu	s bit					
	AD1IF: ADC1 Conversion Complete Interrupt Flag Status bit 1 = Interrupt request has occurred 0 = Interrupt request has not occurred									
bit 12	-	RT1 Transmitte		n Status hit						
				y olalus bit						
	 1 = Interrupt request has occurred 0 = Interrupt request has not occurred 									
bit 11	U1RXIF: UAF	RT1 Receiver I	nterrupt Flag S	Status bit						
		request has oc request has no								
bit 10	-	-		oit						
	SPI1IF: SPI1 Event Interrupt Flag Status bit 1 = Interrupt request has occurred									
	0 = Interrupt request has not occurred									
bit 9	SPI1EIF: SPI1 Fault Interrupt Flag Status bit									
	1 = Interrupt request has occurred									
bit 8	0 = Interrupt request has not occurred									
Dit O	T3IF: Timer3 Interrupt Flag Status bit 1 = Interrupt request has occurred									
	0 = Interrupt request has not occurred									
bit 7	T2IF: Timer2	Interrupt Flag	Status bit							
	 1 = Interrupt request has occurred 0 = Interrupt request has not occurred 									
L:1. 0	•	•			. 1. 14					
bit 6	•	ut Compare Ch		upt Flag Status	5 DIT					
	 1 = Interrupt request has occurred 0 = Interrupt request has not occurred 									
bit 5	-	-		-lag Status bit						
	IC2IF: Input Capture Channel 2 Interrupt Flag Status bit 1 = Interrupt request has occurred									
	0 = Interrupt	request has no	t occurred							
bit 4	-	ited: Read as								
bit 3		Interrupt Flag								
		request has oc request has nc								
bit 2	-	ut Compare Ch		upt Flag Status	s bit					
	-	request has oc								
		request has no								

REGISTER 7-5: IFS0: INTERRUPT FLAG STATUS REGISTER 0

REGISTER 7-5: IFS0: INTERRUPT FLAG STATUS REGISTER 0 (CONTINUED)

- bit 1 IC1IF: Input Capture Channel 1 Interrupt Flag Status bit
 - 1 = Interrupt request has occurred
 - 0 = Interrupt request has not occurred
- bit 0 INTOIF: External Interrupt 0 Flag Status bit
 - 1 = Interrupt request has occurred
 - 0 = Interrupt request has not occurred
| REGISTER | <i>I</i> -0. IF31.1 | INTERRUPT | | | _1\ 1 | | |
|--------------|---------------------|------------------------------------|----------------|------------------|-----------------|-----------------|---------|
| U-0 | U-0 | R/W-0 | U-0 | U-0 | U-0 | U-0 | U-0 |
| — | — | INT2IF | | | _ | — | - |
| bit 15 | | | | | | | bit 8 |
| | | | | | | | |
| R/W-0 | R/W-0 | U-0 | R/W-0 | R/W-0 | U-0 | R/W-0 | R/W-0 |
| IC8IF | IC7IF | — | INT1IF | CNIF | — | MI2C1IF | SI2C1IF |
| bit 7 | | | | | | | bit (|
| Legend: | | | | | | | |
| R = Readab | le bit | W = Writable | oit | U = Unimpler | mented bit, rea | d as '0' | |
| -n = Value a | t POR | '1' = Bit is set | | '0' = Bit is cle | | x = Bit is unkr | nown |
| | | | | | | | |
| bit 15-4 | Unimplemen | ted: Read as ' |)' | | | | |
| bit 13 | INT2IF: Exter | rnal Interrupt 2 | Flag Status bi | t | | | |
| | • | request has occ | | | | | |
| | - | request has not | | | | | |
| bit 12-8 | - | ted: Read as ' | | | | | |
| bit 7 | - | Capture Channe | - | -lag Status bit | | | |
| | | request has occ
request has not | | | | | |
| bit 6 | - | Capture Channe | | Flag Status bit | | | |
| | - | request has occ | - | 5 | | | |
| | | request has not | | | | | |
| bit 5 | Unimplemen | nted: Read as 'o |)' | | | | |
| bit 4 | INT1IF: Exter | rnal Interrupt 1 | Flag Status bi | t | | | |
| | | request has occ | | | | | |
| 1 1 0 | • | request has not | | | | | |
| bit 3 | | Change Notifica | • | Flag Status bit | | | |
| | - | request has occ
request has not | | | | | |
| bit 2 | | ited: Read as '(| | | | | |
| bit 1 | - | 1 Master Event | | ag Status bit | | | |
| | | request has occ | • | - 3 | | | |
| | 0 = Interrupt | request has not | occurred | | | | |
| bit 0 | SI2C1IF: I2C | 1 Slave Events | Interrupt Flag | g Status bit | | | |
| | • | request has occ | | | | | |
| | 0 = Interrupt | request has not | occurred | | | | |

REGISTER 7-6: IFS1: INTERRUPT FLAG STATUS REGISTER 1

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8
U-0	U-0	U-0	U-0	U-0	U-0	R/W-0	U-0
—		—	—	—	—	U1EIF	—
bit 7							bit 0
Legend:							
R = Readable	bit	W = Writable	bit	U = Unimpler	mented bit, read	as '0'	
-n = Value at P	OR	'1' = Bit is set		'0' = Bit is cle	ared	x = Bit is unkr	nown
bit 15-2	Unimplemen	ted: Read as '	כי				
bit 1	U1EIF: UART	1 Error Interru	ot Flag Status	bit			
	1 = Interrupt r	equest has occ	curred				

REGISTER 7-7: IFS4: INTERRUPT FLAG STATUS REGISTER 4

bit 0 Unimplemented: Read as '0'

0 = Interrupt request has not occurred

REGISTER 7	'-8: IEC0:	INTERRUPT	ENABLE CO		GISTER 0		
U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	_	AD1IE	U1TXIE	U1RXIE	SPI1IE	SPI1EIE	T3IE
bit 15							bit
R/W-0	R/W-0	R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
T2IE	OC2IE	IC2IE	_	T1IE	OC1IE	IC1IE	INTOIE
bit 7							bit
Legend:							
R = Readable	bit	W = Writable	bit	U = Unimpler	nented bit, read	d as '0'	
-n = Value at F	POR	'1' = Bit is se	t	'0' = Bit is cle		x = Bit is unkn	own
bit 15-4	Unimplemen	ted: Read as	0'				
bit 13			•	rupt Enable bit			
		request enable					
bit 12	-	request not en RT1 Transmitte		blo bit			
DIL 12		request enable	•				
		request not en					
bit 11	U1RXIE: UAF	RT1 Receiver I	nterrupt Enab	e bit			
	•	request enable					
1.1.4.0	-	request not en					
bit 10		Event Interrup request enable					
	•	request enable					
bit 9	SPI1EIE: SPI	I1 Error Interru	pt Enable bit				
		request enable					
	-	request not en					
bit 8		Interrupt Enab					
		request enable request not en					
bit 7	-	Interrupt Enab					
	1 = Interrupt i	request enable	d				
	-	request not en					
bit 6	•	ut Compare Cl		upt Enable bit			
		request enable request not en					
bit 5	-	Capture Chanr		Enable bit			
	-	request enable	-				
	0 = Interrupt i	request not en	abled				
bit 4	Unimplemen	ted: Read as	0'				
bit 3		Interrupt Enab					
	•	request enable request not en					
bit 2	-	ut Compare Cl		upt Enable bit			
	-	request enable					
	0 = Interrupt i	•					

REGISTER 7-8: IEC0: INTERRUPT ENABLE CONTROL REGISTER 0

REGISTER 7-8: IEC0: INTERRUPT ENABLE CONTROL REGISTER 0 (CONTINUED)

- bit 1 IC1IE: Input Capture Channel 1 Interrupt Enable bit
 - 1 = Interrupt request enabled

bit 0

- 0 = Interrupt request not enabled
- INTOIE: External Interrupt 0 Enable bit
 - 1 = Interrupt request enabled
 - 0 = Interrupt request not enabled

REGISTER	7-9: IEC1:	INTERRUPT	ENABLE C	ONTROL RE	GISTER 1		
U-0	U-0	R/W-0	U-0	U-0	U-0	U-0	U-0
—	—	INT2IE	_		—	—	_
bit 15							bit 8
R/W-0	R/W-0	U-0	R/W-0	R/W-0	U-0	R/W-0	R/W-0
IC8IE	IC7IE	—	INT1IE	CNIE		MI2C1IE	SI2C1IE
bit 7							bit 0
Legend:			L :4			-l (0)	
R = Readabl		W = Writable	Dit	•	mented bit, rea		
-n = Value at	POR	'1' = Bit is set		'0' = Bit is cle	eared	x = Bit is unkr	iown
bit 15-14	Unimplemen	ted: Read as '	٦ '				
bit 13	-	mal Interrupt 2					
		request enabled					
		request not ena					
bit 12-8	Unimplemen	ted: Read as '	כי				
bit 7	IC8IE: Input C	Capture Channe	el 8 Interrupt	Enable bit			
	1 = Interrupt r	request enable	b				
	0 = Interrupt r	request not ena	bled				
bit 6		Capture Channe		Enable bit			
	•	request enabled					
h in c	-	request not ena					
bit 5	-	ted: Read as '					
bit 4		rnal Interrupt 1 request enabled					
		request enabled					
bit 3	-	Change Notifica		Enable bit			
	-	request enable	-				
	0 = Interrupt r	request not ena	bled				
bit 2	Unimplemen	ted: Read as '	כי				
bit 1	MI2C1IE: I2C	1 Master Even	ts Interrupt Ei	nable bit			
		request enable					
	•	request not ena					
bit 0		1 Slave Events	-	able bit			
		request enabled	מ				
	0 - Interrupt r	request not ena	hlad				

REGISTER 7-9: IEC1: INTERRUPT ENABLE CONTROL REGISTER 1

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8
U-0	U-0	U-0	U-0	U-0	U-0	R/W-0	U-0
_	—	—	_	—	_	U1EIE	
bit 7							bit 0
Legend:							
R = Readable	bit	W = Writable	bit	U = Unimpler	mented bit, read	l as '0'	
-n = Value at P	OR	'1' = Bit is set		'0' = Bit is cle	ared	x = Bit is unkr	nown
bit 15-2	Unimplemen	ted: Read as 'd	כ'				
bit 1	U1EIE: UART	1 Error Interru	ot Enable bit				
	-	equest enabled equest not ena					
	sapti	99222211010110					

REGISTER 7-10: IEC4: INTERRUPT ENABLE CONTROL REGISTER 4

Unimplemented: Read as '0'

bit 0

U-0	R/W-1	R/W-0	R/W-0	U-0	R/W-1	R/W-0	R/W-0
		T1IP<2:0>				OC1IP<2:0>	
bit 15	÷						bit 8
		D/M/ O	D/M/O			D/M/ O	DAMA
U-0	R/W-1	R/W-0 IC1IP<2:0>	R/W-0	U-0	R/W-1	R/W-0 INT0IP<2:0>	R/W-0
 bit 7		1011F<2.0>		—		INTUF<2.0>	bit (
							Dit V
Legend:							
R = Readab	le bit	W = Writable I	oit	U = Unimple	mented bit, rea	ad as '0'	
-n = Value a	t POR	'1' = Bit is set		'0' = Bit is cle	eared	x = Bit is unkn	own
bit 15	Unimpleme	ented: Read as 'o)'				
bit 13	-	Timer1 Interrupt					
DIL 14-12		rupt is priority 7 (ł	•	ty interrunt)			
	•		lightest phon	ty interrupt)			
	•						
	•						
		rupt is priority 1 rupt source is disa	abled				
bit 11		ented: Read as '(
	-			1 Interrupt Drie	ity bito		
bit 10-8		>: Output Compa rupt is priority 7 (ł		•	ity Dits		
	•		ingridot priori	ty interrupt)			
	•						
	•						
		rupt is priority 1 rupt source is disa	abled				
bit 7		ented: Read as '(
bit 6-4	-	: Input Capture C		orrupt Priority h	vite		
DIL 0-4		rupt is priority 7 (h			115		
	•	apris priority / (i	lightest phon	ty menupt)			
	•						
	•						
		rupt is priority 1 rupt source is disa	ablad				
bit 3		ented: Read as '(
	-			, hita			
bit 2-0		>: External Interr rupt is priority 7 (ł					
	•	upt is priority 7 (i	lighest phon	ty interrupt)			
	•						
	•						
		rupt is priority 1 rupt source is disa					

REGISTER 7-11: IPC0: INTERRUPT PRIORITY CONTROL REGISTER 0

U-0	R/W-1	R/W-0	R/W-0	U-0	R/W-1	R/W-0	R/W-0
—		T2IP<2:0>				OC2IP<2:0>	
bit 15							bit
		DAVA	DAMO				
U-0	R/W-1	R/W-0	R/W-0	U-0	U-0	U-0	U-0
 bit 7		IC2IP<2:0>				_	bit
							Dit
Legend:							
R = Readab	le bit	W = Writable I	oit	U = Unimpler	mented bit, rea	ıd as '0'	
-n = Value a	t POR	'1' = Bit is set		'0' = Bit is cle	ared	x = Bit is unkn	own
bit 15	Unimpleme	ented: Read as 'o)'				
bit 14-12	T2IP<2:0>:	Timer2 Interrupt	Priority bits				
	111 = Interi	rupt is priority 7 (I	nighest priori	ity interrupt)			
	•						
	•						
	001 – Inter	rupt is priority 1					
		rupt source is disa	abled				
bit 11		ented: Read as 'o					
bit 10-8	-	>: Output Compa		2 Interrupt Prior	itv bits		
		rupt is priority 7 (I		-			
	•		5	,,, ,			
	•						
	•						
		rupt is priority 1 rupt source is disa	abled				
bit 7		ented: Read as '(
bit 6-4	-	: Input Capture C		errupt Priority b	ite		
		rupt is priority 7 (I			113		
	•		ingricot priori	ity interrupt)			
	•						
	•						
	001 = Interi	rupt is priority 1					
	000 1-1		مامام				
bit 3-0		rupt source is disa ented: Read as 'o					

REGISTER 7-12: IPC1: INTERRUPT PRIORITY CONTROL REGISTER 1

REGISTER	<i>i</i> -13. II 02	2: INTERRUPT I					
U-0	R/W-1	R/W-0	R/W-0	U-0	R/W-1	R/W-0	R/W-0
_		U1RXIP<2:0>				SPI1IP<2:0>	
bit 15							bit
U-0	R/W-1	R/W-0	R/W-0	U-0	R/W-1	R/W-0	R/W-0
		SPI1EIP<2:0>		—		T3IP<2:0>	
bit 7							bit
Legend:							
R = Readabl	e bit	W = Writable b	oit	U = Unimplei	mented bit, rea	ad as '0'	
-n = Value at	POR	'1' = Bit is set		'0' = Bit is cle	eared	x = Bit is unkne	own
bit 15	Unimplem	ented: Read as '0)'				
bit 14-12	U1RXIP<2:	:0>: UART1 Rece	iver Interrup	t Priority bits			
	111 = Inter	rupt is priority 7 (h	nighest priori	ty interrupt)			
	•						
	•						
	001 = Inter	rupt is priority 1					
		rupt source is disa	abled				
bit 11	Unimplem	ented: Read as '0)'				
bit 10-8	SPI1IP<2:0	>: SPI1 Event Int	errupt Priori	y bits			
	111 = Inter	rupt is priority 7 (ł	nighest priori	ty interrupt)			
	•						
	•						
	• 001 = Inter	rupt is priority 1					
		rupt source is disa	abled				
bit 7	Unimplem	ented: Read as '0)'				
bit 6-4		:0>: SPI1 Error In		ity bits			
		rupt is priority 7 (h					
	•						
	•						
	• 001 – Inter	rupt is priority 1					
		rupt source is disa	abled				
bit 3	Unimplem	ented: Read as '0)'				
bit 2-0	-	Timer3 Interrupt					
	111 = Inter		-	ty interrunt)			
		rupt is priority r (r	ingricot priori	ty interrupt)			
	•	rupt is priority 7 (i	lightest phon	ty interrupt)			
	•		ingriest priori	ty interrupty			
	• • 001 - Inter	rupt is priority 1	iignest phon	ty menupty			

REGISTER 7-13: IPC2: INTERRUPT PRIORITY CONTROL REGISTER 2

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—		—	—	—	—		—
oit 15							bit 8
U-0	R/W-1	R/W-0	R/W-0	U-0	R/W-1	R/W-0	R/W-0
—		AD1IP<2:0>		—		U1TXIP<2:0>	
pit 7							bit 0
_egend:							
R = Readab	le bit	W = Writable	bit	U = Unimple	mented bit, rea	id as '0'	
n = Value a	= Value at POR '1' = Bit is set				eared	x = Bit is unkr	nown
bit 15-7	Unimpleme	ented: Read as '	n'				
oit 6-4	-	>: ADC1 Convers		o Intorrunt Pric	vrity bite		
//t 0- 4		rupt is priority 7 (-	-	inty bits		
	•	apt is priority 7 (nighest phone	ly interrupt)			
	•						
	•						
		rupt is priority 1 rupt source is dis	abled				
oit 3		ented: Read as '					
oit 2-0	•	0>: UART1 Trans		int Priority hits			
		rupt is priority 7 (
	•		inglieet priem	.,			
	•						
	•	unt in priority d					
		rupt is priority 1 rupt source is dis	abled				
		up: 000100 13 013	usicu				

REGISTER 7-14: IPC3: INTERRUPT PRIORITY CONTROL REGISTER 3

U-0	R/W-1	R/W-0	R/W-0	U-0	U-0	U-0	U-0
—		CNIP<2:0>		_	—		_
bit 15							bit
		DAMA	D 444 0			DAMO	DANO
U-0	R/W-1	R/W-0 MI2C1IP<2:0>	R/W-0	U-0	R/W-1	R/W-0 SI2C1IP<2:0>	R/W-0
 bit 7		MIZCHF<2.0>				5120 TIF <2.0>	bit
Legend:							
R = Readab	le bit	W = Writable	bit	U = Unimpler	mented bit, rea	d as '0'	
-n = Value a	t POR	'1' = Bit is set		'0' = Bit is cle	ared	x = Bit is unkr	nown
bit 15	-	ented: Read as '		_			
bit 14-12		: Change Notifica					
	111 = Inter	rupt is priority 7 (I	highest priori	ty interrupt)			
	•						
	•						
		rupt is priority 1 rupt source is dis	abled				
bit 11-7		ented: Read as '					
bit 6-4	MI2C1IP<2	:0>: I2C1 Master	Events Inter	rupt Priority bits	3		
		rupt is priority 7 (I					
	•		•				
	•						
	•	rupt is priority 1					
		rupt is priority 1 rupt source is dis	abled				
bit 3		ented: Read as '					
bit 2-0	-	:0>: I2C1 Slave E		nt Priority bits			
Dit 2-0		rupt is priority 7 (I					
	•		iigiiost priotii	y monupi)			
	•						
	•						
		rupt is priority 1 rupt source is dis					

REGISTER 7-15: IPC4: INTERRUPT PRIORITY CONTROL REGISTER 4

U-0	R/W-1	R/W-0	R/W-0	U-0	R/W-1	R/W-0	R/W-0
		IC8IP<2:0>				IC7IP<2:0>	
bit 15	·						bit
U-0	U-0	U-0	U-0	U-0	R/W-1	R/W-0	R/W-0
_			_	_		INT1IP<2:0>	
bit 7							bit
Legend:							
R = Readab	le bit	W = Writable b	oit	U = Unimpler	nented bit, rea	ad as '0'	
-n = Value a	t POR	'1' = Bit is set		'0' = Bit is cle	ared	x = Bit is unkn	own
bit 15	-	nted: Read as '0					
bit 14-12		Input Capture C			ts		
	111 = Interr	upt is priority 7 (h	lighest priorit	y interrupt)			
	•						
	•						
	•						
	• 001 = Interr	upt is priority 1					
		upt is priority 1 upt source is disa	abled				
bit 11	000 = Interr						
	000 = Interr Unimpleme	upt source is disa	3	errupt Priority bi	its		
bit 11 bit 10-8	000 = Interr Unimpleme IC7IP<2:0>:	upt source is disa nted: Read as '0	, hannel 7 Inte		its		
	000 = Interr Unimpleme IC7IP<2:0>:	upt source is disa nted: Read as '0 : Input Capture C	, hannel 7 Inte		its		
	000 = Interr Unimpleme IC7IP<2:0>:	upt source is disa nted: Read as '0 : Input Capture C	, hannel 7 Inte		its		
	000 = Intern Unimpleme IC7IP<2:0>: 111 = Intern • •	upt source is disa nted: Read as '0 : Input Capture C upt is priority 7 (h	, hannel 7 Inte		its		
	000 = Intern Unimpleme IC7IP<2:0>: 111 = Intern • • • 001 = Intern	upt source is disa nted: Read as '0 : Input Capture C	, hannel 7 Inte iighest priorit		its		
bit 10-8	000 = Intern Unimpleme IC7IP<2:0>: 111 = Intern	upt source is disa nted: Read as '0 Input Capture C upt is priority 7 (h upt is priority 1	, hannel 7 Inte ighest priorit abled		its		
	000 = Intern Unimpleme IC7IP<2:0>: 111 = Intern • • • 001 = Intern 000 = Intern Unimpleme	upt source is disa inted: Read as '0 input Capture C upt is priority 7 (h upt is priority 1 upt source is disa inted: Read as '0	, hannel 7 Inte iighest priorit abled	y interrupt)	its		
bit 10-8 bit 7-3	000 = Intern Unimpleme IC7IP<2:0>: 111 = Intern • • 001 = Intern 000 = Intern Unimpleme INT1IP<2:0>	upt source is disa inted: Read as '0 input Capture C upt is priority 7 (h upt is priority 1 upt source is disa inted: Read as '0 >: External Intern	, hannel 7 Inte ighest priority abled , upt 1 Priority	y interrupt) bits	its		
bit 10-8 bit 7-3	000 = Intern Unimpleme IC7IP<2:0>: 111 = Intern • • 001 = Intern 000 = Intern Unimpleme INT1IP<2:0>	upt source is disa inted: Read as '0 input Capture C upt is priority 7 (h upt is priority 1 upt source is disa inted: Read as '0	, hannel 7 Inte ighest priority abled , upt 1 Priority	y interrupt) bits	its		
bit 10-8 bit 7-3	000 = Intern Unimpleme IC7IP<2:0>: 111 = Intern • • 001 = Intern 000 = Intern Unimpleme INT1IP<2:0>	upt source is disa inted: Read as '0 input Capture C upt is priority 7 (h upt is priority 1 upt source is disa inted: Read as '0 >: External Intern	, hannel 7 Inte ighest priority abled , upt 1 Priority	y interrupt) bits	its		
bit 10-8 bit 7-3	000 = Intern Unimpleme IC7IP<2:0>: 111 = Intern 001 = Intern 000 = Intern Unimpleme INT1IP<2:0>: 111 = Intern	upt source is disa inted: Read as '0 input Capture C upt is priority 7 (h upt is priority 1 upt source is disa inted: Read as '0 >: External Intern	, hannel 7 Inte ighest priority abled , upt 1 Priority	y interrupt) bits	its		

REGISTER 7-16: IPC5: INTERRUPT PRIORITY CONTROL REGISTER 5

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	_		_	_	—	_
bit 15							bit 8
U-0	R/W-1	R/W-0	R/W-0	U-0	U-0	U-0	U-0
—		INT2IP<2:0>		—	—	—	—
bit 7							bit 0
Legend:							
R = Readable	bit	W = Writable I	oit	U = Unimpler	mented bit, read	as '0'	
-n = Value at F	POR	'1' = Bit is set		'0' = Bit is cle	ared	x = Bit is unkr	nown
bit 15-7 bit 6-4	INT2IP<2:0>: 111 = Interrup • • • 001 = Interrup	ted: Read as '(External Interr ot is priority 7 (h ot is priority 1 ot source is disa	upt 2 Priority nighest priorit				

REGISTER 7-17: IPC7: INTERRUPT PRIORITY CONTROL REGISTER 7

bit 3-0 Unimplemented: Read as '0'

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	_	_		—	_	—	—
bit 15							bit 8
U-0	R/W-1	R/W-0	R/W-0	U-0	U-0	U-0	U-0
—		U1EIP<2:0>		—	—	—	
bit 7							bit 0
Legend:							
R = Readab	le bit	W = Writable I	oit	U = Unimpler	mented bit, read	as '0'	
-n = Value a	t POR	'1' = Bit is set		'0' = Bit is cle	ared	x = Bit is unkr	nown
bit 15-7	Unimplemen	ted: Read as ')'				
bit 6-4	U1EIP<2:0>:	UART1 Error In	nterrupt Prior	ity bits			
	111 = Interrup	ot is priority 7 (ł	nighest priorit	ty interrupt)			
	•						
	•						
	• 001 = Interrup	ot is priority 1					
		ot source is disa	abled				
bit 3-0	Unimplemen	ted: Read as 'd)'				

REGISTER 7-18: IPC16: INTERRUPT PRIORITY CONTROL REGISTER 16

REGISTER 7-19: INTTREG: INTERRUPT CONTROL AND STATUS REGISTER

U-0	U-0	U-0	U-0	R-0	R-0	R-0	R-0
—			—		IL	R<3:0>	
bit 15							bit 8
U-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0
—				VECNUM<6:0	>		
bit 7							bit C
Legend:							
R = Readab	le bit	W = Writable I	oit	U = Unimplen	nented bit, re	ad as '0'	
-n = Value a	t POR	'1' = Bit is set		'0' = Bit is clea	ared	x = Bit is unkno	own
bit 15-12	Unimplemen	ted: Read as '0)'				
bit 11-8		w CPU Interrup	•	el bits			
	1111 = CPU	Interrupt Priorit	y Level is 15				
	•						
	•						
	0001 = CPU	Interrupt Priorit	y Level is 1				
	0000 = CPU	Interrupt Priorit	y Level is 0				
bit 7	Unimplemen	ted: Read as 'd)'				
bit 6-0	VECNUM<6:	D>: Vector Num	ber of Pendir	ng Interrupt bits			
	0111111 = lr	terrupt Vector	pending is nu	mber 135			
	•						
	•						
	0000001 = lr	terrupt Vector	pending is nu	mber 9			
	300000± – II						

7.4 Interrupt Setup Procedures

7.4.1 INITIALIZATION

To configure an interrupt source at initialization:

- 1. Set the NSTDIS bit (INTCON1<15>) if nested interrupts are not desired.
- Select the user-assigned priority level for the interrupt source by writing the control bits in the appropriate IPCx register. The priority level will depend on the specific application and type of interrupt source. If multiple priority levels are not desired, the IPCx register control bits for all enabled interrupt sources can be programmed to the same non-zero value.

Note: At a device Reset, the IPCx registers are initialized such that all user interrupt sources are assigned to priority level 4.

- 3. Clear the interrupt flag status bit associated with the peripheral in the associated IFSx register.
- 4. Set the interrupt enable control bit associated with the source in the appropriate IECx register to enable the interrupt source.

7.4.2 INTERRUPT SERVICE ROUTINE

The method used to declare an Interrupt Service Routine (ISR) and initialize the IVT with the correct vector address depends on the programming language (C or Assembler) and the language development toolsuite used to develop the application.

In general, the user application must clear the interrupt flag in the appropriate IFSx register for the source of interrupt that the ISR handles. Otherwise, the program will re-enter the ISR immediately after exiting the routine. If the ISR is coded in assembly language, it must be terminated using a RETFIE instruction to unstack the saved PC value, SRL value and old CPU priority level.

7.4.3 TRAP SERVICE ROUTINE

A Trap Service Routine (TSR) is coded like an ISR, except that the appropriate trap status flag in the INTCON1 register must be cleared to avoid re-entry into the TSR.

7.4.4 INTERRUPT DISABLE

All user interrupts can be disabled using this procedure:

- 1. Push the current SR value onto the software stack using the PUSH instruction.
- 2. Force the CPU to priority level 7 by inclusive ORing the value OEh with SRL.

To enable user interrupts, the POP instruction can be used to restore the previous SR value.

Note:	Only user interrupts with a priority level of
	7 or lower can be disabled. Trap sources
	(level 8-level 15) cannot be disabled.

The DISI instruction provides a convenient way to disable interrupts of priority levels 1-6 for a fixed period of time. Level 7 interrupt sources are not disabled by the DISI instruction.

8.0 **OSCILLATOR CONFIGURATION**

- Note 1: This data sheet summarizes the features of the PIC24HJ32GP202/204 and PIC24HJ16GP304 family of devices. However, it is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to "Section 7. Oscillator" (DS70186) of the "dsPIC33F/PIC24H Family Reference Manual", which is available from the Microchip website (www.microchip.com).
 - 2: Some registers and associated bits described in this section may not be available on all devices. Refer to Section 4.0 "Memory Organization" in this data sheet for device-specific register and bit information.

The oscillator system provides:

- External and internal oscillator options as clock sources
- · An on-chip PLL to scale the internal operating frequency to the required system clock frequency
- · An internal FRC oscillator that can also be used with the PLL, thereby allowing full speed operation without any external clock generation hardware
- Clock switching between various clock sources
- Programmable clock postscaler for system power • savings
- A Fail-Safe Clock Monitor (FSCM) that detects clock failure and takes fail-safe measures
- An Oscillator Control register (OSCCON)
- · Nonvolatile Configuration bits for main oscillator selection

A simplified diagram of the oscillator system is shown in Figure 8-1.



3: The term FP refers to the clock source for all the peripherals, while FCY refers to the clock source for the CPU. Throughout this document FCY and FP are used interchangeably, except in the case of Doze mode. FP and FCY will be different when Doze mode is used in any ratio other than 1:1, which is the default.

8.1 CPU Clocking System

The PIC24HJ32GP202/204 and PIC24HJ16GP304 devices provide the following seven system clock options.

- Fast RC (FRC) Oscillator
- FRC Oscillator with PLL
- Primary (XT, HS or EC) Oscillator
- Primary Oscillator with PLL
- Secondary (LP) Oscillator
- Low-Power RC (LPRC) Oscillator
- FRC Oscillator with postscaler

8.1.1 SYSTEM CLOCK SOURCES

8.1.1.1 Fast RC

The Fast RC (FRC) internal oscillator runs at a nominal frequency of 7.37 MHz. User software can tune the FRC frequency. User software can optionally specify a factor (ranging from 1:2 to 1:256) by which the FRC clock frequency is divided. This factor is selected using the FRCDIV<2:0> bits (CLKDIV<10:8>).

8.1.1.2 Primary

The primary oscillator can use one of the following as its clock source:

- Crystal (XT): Crystals and ceramic resonators in the range of 3.5 MHz to 10 MHz. The crystal is connected to the OSC1 and OSC2 pins.
- HS (High-Speed Crystal): Crystals in the range of 10 MHz to 40 MHz. The crystal is connected to the OSC1 and OSC2 pins.
- EC (External Clock): The external clock signal is directly applied to the OSC1 pin.

8.1.1.3 Secondary

The secondary (LP) oscillator is designed for low power and uses a 32.768 kHz crystal or ceramic resonator. The LP oscillator uses SOSCI and SOSCO pins.

8.1.1.4 Low-Power RC

The Low-Power RC (LPRC) internal oscIllator runs at a nominal frequency of 32.768 kHz. It is also used as a reference clock by the Watchdog Timer (WDT) and Fail-Safe Clock Monitor (FSCM).

8.1.1.5 FRC

The clock signals generated by the FRC and primary oscillators can be optionally applied to an on-chip Phase-Locked Loop (PLL) to provide a wide range of output frequencies for device operation. PLL configuration is described in **Section 8.1.3 "PLL Configuration**".

The FRC frequency depends on the FRC accuracy (see Table 22-18) and the value of the FRC Oscillator Tuning register (see Register 8-4).

8.1.2 SYSTEM CLOCK SELECTION

The oscillator source used at a device Power-on Reset event is selected using Configuration bit settings. The oscillator Configuration bit settings are located in the Configuration registers in the program memory. (Refer to Section 19.1 "Configuration Bits" for further details.) The Initial Oscillator Selection Configuration bits, FNOSC<2:0> (FOSCSEL<2:0>), and the Primary Configuration Oscillator Mode Select bits. POSCMD<1:0> (FOSC<1:0>), select the oscillator source that is used at a Power-on Reset. The FRC primary oscillator is the default (unprogrammed) selection.

The Configuration bits allow users to choose among 12 different clock modes, shown in Table 8-1.

The output of the oscillator (or the output of the PLL if a PLL mode has been selected) FOSC is divided by 2 to generate the device instruction clock (FCY) and the peripheral clock time base (FP). FCY defines the operating speed of the device, and speeds up to 40 MHz are supported by the PIC24HJ32GP202/204 and PIC24HJ16GP304 architecture.

Instruction execution speed or device operating frequency, FCY, is given by:

EQUATION 8-1: DEVICE OPERATING FREQUENCY

$$FCY = \frac{FOSC}{2}$$

8.1.3 PLL CONFIGURATION

The primary oscillator and internal FRC oscillator can optionally use on-chip PLL to obtain higher speeds of operation. The PLL provides significant flexibility in selecting the device operating speed. A block diagram of the PLL is shown in Figure 8-2.

The output of the primary oscillator or FRC, denoted as 'FIN' is divided down by a prescale factor (N1) of 2, 3, ... or 33 before it is being provided to the PLL's Voltage Controlled Oscillator (VCO). The input to the VCO must be selected in the range of 0.8 MHz to 8 MHz. The prescale factor 'N1' is selected using the PLLPRE<4:0> bits (CLKDIV<4:0>).

The PLL Feedback Divisor, selected using the PLLDIV<8:0> bits (PLLFBD<8:0>), provides a factor 'M', by which the input to the VCO is multiplied. This factor must be selected such that the resulting VCO output frequency is in the range of 100 MHz to 200 MHz.

The VCO output is further divided by a postscale factor 'N2.' This factor is selected using the PLLPOST<1:0> bits (CLKDIV<7:6>). 'N2' can be 2, 4 or 8, and must be selected such that the PLL output frequency (Fosc) is in the range of 12.5 MHz to 80 MHz, which generates device operating speeds of 6.25-40 MIPS. For a primary oscillator or FRC oscillator, output 'FIN', the PLL output 'FOSC' is given by:

EQUATION 8-2: Fosc CALCULATION

$$FOSC = FIN \cdot \left(\frac{M}{N1 \cdot N2}\right)$$

For example, when a 10 MHz crystal is being used, with "XT with PLL" being the selected oscillator mode.

• If PLLPRE<4:0> = 0, then N1 = 2. This yields a VCO input of 10/2 = 5 MHz, which is within the acceptable range of 0.8-8 MHz.

- If PLLDIV<8:0> = 0x1E, then M = 32. This yields a VCO output of 5 x 32 = 160 MHz, which is within the 100 MHz to 200 MHz range, which is needed.
- If PLLPOST<1:0> = 0, then N2 = 2. This provides a Fosc of 160/2 = 80 MHz. The resultant device operating speed is 80/2 = 40 MIPS.

EQUATION 8-3: XT WITH PLL MODE EXAMPLE

$$FCY = \frac{FOSC}{2} = \frac{1}{2} \cdot \left(\frac{10000000 \cdot 32}{2 \cdot 2}\right) = 40$$
 MIPS

FIGURE 8-2: PIC24HJ32GP202/204 AND PIC24HJ16GP304 PLL BLOCK DIAGRAM



TABLE 8-1: CONFIGURATION BIT VALUES FOR CLOCK SELECTION

Oscillator Mode	Oscillator Source	POSCMD<1:0>	FNOSC<2:0>	See Note
Fast RC Oscillator with Divide-by-N (FRCDIVN)	Internal	xx	111	1, 2
Fast RC Oscillator with Divide-by-16 (FRCDIV16)	Internal	xx	110	1
Low-Power RC Oscillator (LPRC)	Internal	xx	101	1
Secondary (Timer1) Oscillator (SOSC)	Secondary	xx	100	1
Primary Oscillator (HS) with PLL (HSPLL)	Primary	10	011	—
Primary Oscillator (XT) with PLL (XTPLL)	Primary	01	011	-
Primary Oscillator (EC) with PLL (ECPLL)	Primary	00	011	1
Primary Oscillator (HS)	Primary	10	010	_
Primary Oscillator (XT)	Primary	01	010	_
Primary Oscillator (EC)	Primary	00	010	1
Fast RC Oscillator with PLL (FRCPLL)	Internal	xx	001	1
Fast RC Oscillator (FRC)	Internal	xx	000	1

Note 1: OSC2 pin function is determined by the OSCIOFNC Configuration bit.

2: This is the default oscillator mode for an unprogrammed (erased) device.

REGISTER	8-1: OSCC	ON: OSCILL/	ATOR CON	TROL REGIS	TER ^(1,3)				
U-0	R-0	R-0	R-0	U-0	R/W-y	R/W-y	R/W-y		
_		COSC<2:0>		—		NOSC<2:0> ⁽²⁾			
bit 15				· · · · · · · · · · · · · · · · · · ·					
R/W-0	R/W-0	R-0	U-0	R/C-0	U-0	R/W-0	R/W-0		
CLKLOCK	IOLOCK	LOCK	_	CF	_	LPOSCEN	OSWEN		
bit 7							bit		
Legend:		y = Value set	from Configu	ration bits on P	OR	C = Clea	r only bit		
R = Readab	le bit	W = Writable	bit	U = Unimplen	nented bit, rea	d as '0'			
-n = Value a	t POR	'1' = Bit is set		'0' = Bit is clea		x = Bit is unkn	own		
bit 15	Unimplomon	ted: Read as '	· ·						
bit 13	-			bits (read-only)					
	101 = Low-Po 100 = Second 011 = Primar 010 = Primar 001 = Fast R	C oscillator (FR ower RC oscilla dary oscillator (y oscillator (XT, y oscillator (XT, C oscillator (FR C oscillator (FR	tor (LPRC) SOSC) HS, EC) with HS, EC) C) with PLL						
bit 11	Unimplemen	ted: Read as 'd)'						
bit 10-8	NOSC<2:0>:	New Oscillator	Selection bit	_S (2)					
	110 = Fast R 101 = Low-Pe 100 = Second 011 = Primar 010 = Primar 001 = Fast R	C oscillator (FR C oscillator (FR ower RC oscilla dary oscillator (y oscillator (XT, y oscillator (XT, C oscillator (FR C oscillator (FR	C) with Divic tor (LPRC) SOSC) HS, EC) with HS, EC) C) with PLL	le-by-16					
bit 7	CLKLOCK: (Clock Lock Enal	ble bit						
				disabled (FOS		0b01)			
		•		lock source is le lock source can		by clock switchin	g		
bit 6	IOLOCK: Per 1 = Peripheri	ipheral Pin Sel al Pin Select is	ect Lock bit locked, write	e to peripheral p	in select regis	ter is not allowed	-		
bit 5	LOCK: PLL L	ock Status bit (read-only)						
				start-up timer is t-up timer is in p		L is disabled			
bit 4		ted: Read as '			0				
	Vrites to this regis dsPIC33F/PIC24				ection 7. "Osc	cillator" (DS701	86) in the		
Т	Direct clock switch This applies to clo	ck switches in e	either directio	n. In these insta	ances, the app				

REGISTER 8-1: OSCCON: OSCILLATOR CONTROL REGISTER^(1,3)

mode as a transition clock source between the two PLL modes.

REGISTER 8-1: OSCCON: OSCILLATOR CONTROL REGISTER^(1,3) (CONTINUED)

bit 3	CF: Clock Fail Detect bit (read/clear by application)
	1 = FSCM has detected clock failure
	0 = FSCM has not detected clock failure
bit 2	Unimplemented: Read as '0'
bit 1	LPOSCEN: Secondary (LP) Oscillator Enable bit
	1 = Enable secondary oscillator
	0 = Disable secondary oscillator
bit 0	OSWEN: Oscillator Switch Enable bit
	1 = Request oscillator switch to selection specified by NOSC<2:0> bits
	0 = Oscillator switch is complete
Note 1:	Writes to this register require an unlock sequence. Refer to Section 7. "Osc

- Note 1: Writes to this register require an unlock sequence. Refer to Section 7. "Oscillator" (DS70186) in the "dsPIC33F/PIC24H Family Reference Manual" for details.
 - 2: Direct clock switches between any primary oscillator mode with PLL and FRCPLL mode are not permitted. This applies to clock switches in either direction. In these instances, the application must switch to FRC mode as a transition clock source between the two PLL modes.
 - **3:** This register is reset only on a Power-on Reset (POR).

REGISTER	8-2: CLKI	DIV: CLOCK D	IVISOR RE	GISTER ⁽²⁾			
R/W-0	R/W-0	R/W-1	R/W-1	R/W-0	R/W-0	R/W-0	R/W-0
ROI		DOZE<2:0>		DOZEN ⁽¹⁾		FRCDIV<2:0>	
bit 15							bit 8
R/W-0	R/W-1	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PLLPC)ST<1:0>				PLLPRE<4:0)>	
bit 7							bit C
Legend:		y = Value set	from Configu	ration bits on PO	DR		
R = Readable	e bit	W = Writable	bit	U = Unimplem	nented bit, rea	ad as '0'	
-n = Value at	POR	'1' = Bit is set		'0' = Bit is clea		x = Bit is unkı	nown
bit 15		er on Interrupt bi					
		ots will clear the I			r clock/periph	eral clock ratio is	s set to 1:1
bit 14-12	•	ots have no effec					
DIL 14-12	111 = FCY/1			Select bits			
	110 = FCY/6	-					
	101 = FCY/3						
	100 = FCY/1	16					
	011 = FCY/8						
	010 = FCY/4						
	001 = FCY/2						
bit 11	000 = FCY/1	ı DZE Mode Enabl	a hit(1)				
DICTI	1 = DOZE<	:2:0> field specifi	es the ratio b		pheral clocks	and the process	or clocks
		sor clock/periphe					
bit 10-8		0>: Internal Fast	RC Oscillato	or Postscaler bits	6		
		divide by 256					
		divide by 64					
		divide by 32 divide by 16					
	011 = FRC						
	010 = FRC	-					
	001 = FRC						
	000 = FRC	divide by 1 (defa	ult)				
bit 7-6	PLLPOST<	1:0>: PLL VCO	Output Divide	er Select bits (als	so denoted as	s 'N2', PLL posts	caler)
	11 = Output	/8					
	10 = Reserv						
	01 = Output						
	00 = Output						
bit 5		ented: Read as '					
bit 4-0	PLLPRE<4: 11111 = Inp	: 0>: PLL Phase I out/33	Detector Inpu	it Divider bits (al	so denoted a	s 'N1', PLL pres	caler)
	•						
	•						
	•						
	00001 = Inp	out/3					

REGISTER 8-2: CLKDIV: CLOCK DIVISOR REGISTER⁽²⁾

- Note 1: This bit is cleared when the ROI bit is set and an interrupt occurs.
 - **2:** This register is reset only on a Power-on Reset (POR).

REGISTER	0-J. FLLIL		DBACK DIV				
U-0	U-0	U-0	U-0	U-0	U-0	U-0	R/W-0
_	—	_	_	_	—	_	PLLDIV<8>
bit 15							bit 8
R/W-0	R/W-0	R/W-1	R/W-1	R/W-0	R/W-0	R/W-0	R/W-0
			PLLDI	V<7:0>			
bit 7							bit C
Legend:							
R = Readabl	le bit	W = Writable	bit	U = Unimpler	mented bit, read	as '0'	
-n = Value at	t POR	'1' = Bit is set		'0' = Bit is cle	ared	x = Bit is unk	known
bit 15-9	Unimplemen	ted: Read as '	0'				
bit 8-0	PLLDIV<8:0>	-: PLL Feedbac	ck Divisor bits	(also denoted	as 'M', PLL mul	tiplier)	
	111111111 =	= 513					
	•						
	•						
	•						
	000110000 =	= 50 (default)					
	•						
	•						
	•						
	000000010 = 000000001 =						

REGISTER 8-3: PLLFBD: PLL FEEDBACK DIVISOR REGISTER⁽¹⁾

Note 1: This register is reset only on a Power-on Reset (POR).

00000000 = 2

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
_	_	_		_		_	_
bit 15							bit 8
U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—			TUN	<5:0> ⁽¹⁾		
bit 7							bit (
Legend:							
R = Readable	bit	W = Writable I	oit	U = Unimpler	mented bit, read	l as '0'	
-n = Value at P	OR	'1' = Bit is set		'0' = Bit is cle	ared	x = Bit is unkr	nown
bit 15-6	Unimplemen	ted: Read as 'o)'				
bit 5-0	TUN<5:0>: F	RC Oscillator T	uning bits ⁽¹⁾				
	111111 = Ce	nter frequency	- 0.375% (7.3	345 MHz)			
	•						
	•						
	100001 = Ce	nter frequency	- 11.625% (6	.52 MHz)			
		nter frequency					
		nter frequency					
	011110 = Ce	nter frequency	+ 11.25% (8.2	20 MHz)			
	•						
	•						
	000001 = Ce	nter frequency	+ 0.375% (7.	40 MHz)			
		nter frequency					
		1 2	``	,			

REGISTER 8-4: OSCTUN: FRC OSCILLATOR TUNING REGISTER⁽²⁾

- **Note 1:** OSCTUN functionality has been provided to help customers compensate for temperature effects on the FRC frequency over a wide range of temperatures. The tuning step size is an approximation and is neither characterized nor tested.
 - 2: This register is reset only on a Power-on Reset (POR).

8.2 Clock Switching Operation

Applications are free to switch among any of the four clock sources (Primary, LP, FRC and LPRC) under software control at any time. To limit the possible side effects of this flexibility, devices have a safeguard lock built into the switch process.

Note: Primary Oscillator mode has three different submodes (XT, HS and EC), which are determined by the POSCMD<1:0> Configuration bits. While an application can switch to and from Primary Oscillator mode in software, it cannot switch among the different primary submodes without reprogramming the device.

8.2.1 ENABLING CLOCK SWITCHING

To enable clock switching, the FCKSM1 Configuration bit in the Configuration register must be programmed to '0'. (Refer to **Section 19.1 "Configuration Bits"** for further details.) If the FCKSM1 Configuration bit is unprogrammed ('1'), the clock switching function and Fail-Safe Clock Monitor function are disabled. This is the default setting.

The NOSC control bits (OSCCON<10:8>) do not control the clock selection when clock switching is disabled. However, the COSC bits (OSCCON<14:12>) reflect the clock source selected by the FNOSC Configuration bits.

The OSWEN control bit (OSCCON<0>) has no effect when clock switching is disabled. It is held at '0' at all times.

8.2.2 OSCILLATOR SWITCHING SEQUENCE

Performing a clock switch requires the following basic sequence:

- 1. Read the COSC bits (OSCCON<14:12>) to determine the current oscillator source, if desired.
- 2. Perform the unlock sequence to allow a write to the OSCCON register high byte.
- 3. Write the appropriate value to the NOSC control bits (OSCCON<10:8>) for the new oscillator source.
- 4. Perform the unlock sequence to allow a write to the OSCCON register low byte.
- 5. Set the OSWEN bit to initiate the oscillator switch.

Once the basic sequence is completed, the system clock hardware responds automatically as follows:

 The clock switching hardware compares the COSC status bits with the new value of the NOSC control bits. If both of them are the same, the clock switch is a redundant operation. In this case, the OSWEN bit is cleared automatically and the clock switch is aborted.

- If a valid clock switch has been initiated, the status bits, LOCK (OSCCON<5>) and CF (OSCCON<3>) are cleared.
- 3. The new oscillator is turned on by the hardware if it is not currently running. If a crystal oscillator has to be turned on, the hardware waits until the Oscillator Start-up Timer (OST) expires. If the new source is using the PLL, the hardware waits until a PLL lock is detected (LOCK = 1).
- 4. The hardware waits for 10 clock cycles from the new clock source and then performs the clock switch.
- The hardware clears the OSWEN bit to indicate a successful clock transition. In addition, the NOSC bit values are transferred to the COSC status bits.
- 6. The old clock source is turned off at this time, with the exception of LPRC (if WDT or FSCM are enabled) or LP (if LPOSCEN remains set).
 - Note 1: The processor continues to execute code throughout the clock switching sequence. Timing-sensitive code should not be executed during this time.
 - 2: Direct clock switches between any primary oscillator mode with PLL and FRC-PLL mode are not permitted. This applies to clock switches in either direction. In these instances, the application must switch to FRC mode as a transition clock source between the two PLL modes.
 - 3: Refer to Section 7. "Oscillator" (DS70186) in the "dsPIC33F/PIC24H Family Reference Manual" for details.

8.3 Fail-Safe Clock Monitor (FSCM)

The Fail-Safe Clock Monitor (FSCM) allows the device to continue to operate even in the event of an oscillator failure. The FSCM function is enabled by programming. If the FSCM function is enabled, the LPRC internal oscillator runs at all times (except during Sleep mode) and is not subject to control by the Watchdog Timer.

In the event of an oscillator failure, the FSCM generates a clock failure trap event and switches the system clock over to the FRC oscillator. Then the application program can either attempt to restart the oscillator or execute a controlled shutdown. The trap can be treated as a warm Reset by simply loading the Reset address into the oscillator fail trap vector.

If the PLL multiplier is used to scale the system clock, the internal FRC is also multiplied by the same factor on clock failure. Essentially, the device switches to FRC with PLL on a clock failure.

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NOTES:

9.0 POWER-SAVING FEATURES

- Note 1: This data sheet summarizes the features of the PIC24HJ32GP202/204 and PIC24HJ16GP304 family of devices. However, it is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to "Section 9. Watchdog Timer and Power Savings Modes" (DS70196) of the "dsPIC33F/PIC24H Family Reference Manual", which is available from the Microchip website (www.microchip.com).
 - 2: Some registers and associated bits described in this section may not be available on all devices. Refer to Section 4.0 "Memory Organization" in this data sheet for device-specific register and bit information.

The PIC24HJ32GP202/204 and PIC24HJ16GP304 devices provide the ability to manage power consumption by selectively managing clocking to the CPU and the peripherals. In general, a lower clock frequency and a reduction in the number of circuits being clocked constitutes lower consumed power. PIC24HJ32GP202/204 and PIC24HJ16GP304 devices can manage power consumption in four different ways:

- Clock frequency
- Instruction-based Sleep and Idle modes
- Software-controlled Doze mode
- Selective peripheral control in software

Combinations of the above methods can be used to selectively customize an application's power consumption while still maintaining critical application features, such as timing-sensitive communications.

9.1 Clock Frequency and Clock Switching

PIC24HJ32GP202/204 and PIC24HJ16GP304 devices allow a wide range of clock frequencies to be selected under application control. If the system clock configuration is not locked, users can choose low-power or high-precision oscillators by simply changing the NOSC bits (OSCCON<10:8>). The process of changing a system clock during operation, as well as limitations to the process, are discussed in more detail in Section 8.0 "Oscillator Configuration".

9.2 Instruction-Based Power-Saving Modes

PIC24HJ32GP202/204 and PIC24HJ16GP304 devices have two special power-saving modes that are entered through the execution of a special PWRSAV instruction. Sleep mode stops clock operation and halts all code execution. Idle mode halts the CPU and code execution, but allows peripheral modules to continue operation. Example 9-1 shows the Assembler syntax of the PWRSAV instruction.

Note: SLEEP_MODE and IDLE_MODE are constants defined in the assembler include file for the selected device.

Sleep and Idle modes can be exited as a result of an enabled interrupt, WDT time-out or a device Reset. When the device exits these modes, it is said to wake-up.

9.2.1 SLEEP MODE

In the Sleep mode:

- The system clock source is shut down. If an on-chip oscillator is used, it is turned off.
- The device current consumption is reduced to a minimum, provided that no I/O pin is sourcing current
- The Fail-Safe Clock Monitor does not operate, since the system clock source is disabled
- The LPRC clock continues to run if the WDT is enabled
- The WDT, if enabled, is automatically cleared prior to entering Sleep mode
- Some device features or peripherals may continue to operate. This includes items such as the input change notification on the I/O ports, or peripherals that use an external clock input.
- Any peripheral that requires the system clock source for its operation is disabled

The device will wake-up from Sleep mode on any of these events:

- Any interrupt source that is individually enabled
- Any form of device Reset
- A WDT time-out

On wake-up from Sleep mode, the processor restarts with the same clock source that was active when Sleep mode was entered.

EXAMPLE 9-1: PWRSAV INSTRUCTION SYNTAX

PWRSAV#SLEEP_MODE; Put the device into Sleep modePWRSAV#IDLE_MODE; Put the device into Idle mode

9.2.2 IDLE MODE

The following occur in Idle mode:

- The CPU stops executing instructions
- The WDT is automatically cleared
- The system clock source remains active. By default, all peripheral modules continue to operate normally from the system clock source, but can also be selectively disabled (see Section 9.4 "Peripheral Module Disable").
- If the WDT or FSCM is enabled, the LPRC also remains active

The device will wake from Idle mode on any of these events:

- Any interrupt that is individually enabled
- Any device Reset
- A WDT time-out

On wake-up from Idle mode, the clock is reapplied to the CPU and instruction execution will begin (2-4 cycles later), starting with the instruction following the PWRSAV instruction, or the first instruction in the ISR.

9.2.3 INTERRUPTS COINCIDENT WITH POWER SAVE INSTRUCTIONS

Any interrupt that coincides with the execution of a PWRSAV instruction is held off until entry into Sleep or Idle mode is completed. The device then wakes up from Sleep or Idle mode.

9.3 Doze Mode

The preferred strategies for reducing power consumption are changing clock speed and invoking one of the power-saving modes. In some circumstances, however, these are not practical. For example, it may be necessary for an application to maintain uninterrupted synchronous communication, even while it is doing nothing else. Reducing system clock speed can introduce communication errors, while using a power-saving mode can stop communications completely.

Doze mode is a simple and effective alternative method to reduce power consumption while the device is still executing code. In this mode, the system clock continues to operate from the same source and at the same speed. Peripheral modules continue to be clocked at the same speed, while the CPU clock speed is reduced. Synchronization between the two clock domains is maintained, allowing the peripherals to access the SFRs while the CPU executes code at a slower rate. Doze mode is enabled by setting the DOZEN bit (CLKDIV<11>). The ratio between peripheral and core clock speed is determined by the DOZE<2:0> bits (CLKDIV<14:12>). There are eight possible configurations, from 1:1 to 1:128, with 1:1 being the default setting.

Programs can use Doze mode to selectively reduce power consumption in event-driven applications. This allows clock-sensitive functions, such as synchronous communications, to continue without interruption while the CPU idles, waiting for something to invoke an interrupt routine. An automatic return to full-speed CPU operation on interrupts can be enabled by setting the ROI bit (CLKDIV<15>). By default, interrupt events have no effect on Doze mode operation.

For example, suppose the device is operating at 20 MIPS and the CAN module has been configured for 500 kbps based on this device operating speed. If the device is placed in Doze mode with a clock frequency ratio of 1:4, the CAN module continues to communicate at the required bit rate of 500 kbps, but the CPU now starts executing instructions at a frequency of 5 MIPS.

9.4 Peripheral Module Disable

The Peripheral Module Disable (PMD) registers provide a method to disable a peripheral module by stopping all clock sources supplied to that module. When a peripheral is disabled using the appropriate PMD control bit, the peripheral is in a minimum power consumption state. The control and status registers associated with the peripheral are also disabled. So writes to those registers will have no effect and read values will be invalid.

A peripheral module is enabled only if both the associated bit in the PMD register are cleared and the peripheral is supported by the specific PIC24H variant. If the peripheral is present in the device, it is enabled in the PMD register by default.

Note: If a PMD bit is set, the corresponding module is disabled after a delay of one instruction cycle. Similarly, if a PMD bit is cleared, the corresponding module is enabled after a delay of one instruction cycle (assuming the module control registers are already configured to enable module operation).

U-0	U-0	R/W-0	R/W-0	R/W-0	U-0	U-0	U-0
_	—	T3MD	T2MD	T1MD	_	—	—
oit 15		·				•	bit
R/W-0	U-0	R/W-0	U-0	R/W-0	U-0	U-0	R/W-0
I2C1MD		U1MD	—	SPI1MD		_	AD1MD ⁽¹⁾
bit 7							bit
Legend:							
R = Readabl	le bit	W = Writable	bit	U = Unimplem	ented bit, rea	d as '0'	
-n = Value at	POR	'1' = Bit is set		'0' = Bit is clea	red	x = Bit is un	known
bit 15-14	-	ented: Read as '					
bit 13		er3 Module Disat					
		module is disable module is enable					
bit 12		er2 Module Disat					
DIL 12		module is disable					
		module is enable					
bit 11	T1MD: Time	er1 Module Disat	ole bit				
	1 = Timer1 I	module is disable	ed				
		module is enable					
bit 10-8	Unimpleme	ented: Read as '	כ'				
bit 7	-	C1 Module Disat	ole bit				
		odule is disabled odule is enabled					
bit 6		ented: Read as '	<u>`</u>				
bit 5	-	RT1 Module Disa					
DIL D		module is disabl					
	-	module is enable					
bit 4	Unimpleme	ented: Read as '	o'				
bit 3	SPI1MD: SI	PI1 Module Disal	ole bit				
		odule is disabled odule is enabled					
bit 2-1		ented: Read as '	o'				
bit 0	-	DC1 Module Disa					
		nodule is disable					
			u				

Note 1: PCFGx bits have no effect if the ADC module is disabled by setting this bit. In this case, all port pins multiplexed with ANx will be in Digital mode.

R/W-0	R/W-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0
IC8MD	IC7MD		—	—	_	IC2MD	IC1MD
bit 15							bit 8
U-0	U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0
_		_	_	_	_	OC2MD	OC1MD
bit 7							bit (
Legend:							
R = Readab	le bit	W = Writable	bit	U = Unimpler	nented bit, rea	ad as '0'	
-n = Value a	It POR	'1' = Bit is set		'0' = Bit is cle		x = Bit is unkr	nown
bit 15	IC8MD: Input	Capture 8 Mo	dule Disable b	it			
		oture 8 module oture 8 module					
bit 14		Capture 2 Mo		.i+			
	•	ture 7 module		nt (
		oture 7 module					
bit 13-10	Unimplemen	ted: Read as '	0'				
bit 9	IC2MD: Input	Capture 2 Mo	dule Disable b	it			
		oture 2 module oture 2 module					
bit 8	IC1MD: Input	Capture 1 Mo	dule Disable b	it			
		oture 1 module oture 1 module					
bit 7-2	Unimplemen	ted: Read as '	0'				
bit 1	OC2MD: Out	put Compare 2	Module Disab	ole bit			
		ompare 2 modu					
h # 0	•	ompare 2 modu					
bit 0		put Compare 1 ompare 1 modu					

10.0 I/O PORTS

- Note 1: This data sheet summarizes the features of the PIC24HJ32GP202/204 and PIC24HJ16GP304 family of devices. However, it is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to "Section 10. I/O Ports" (DS70193) of the "dsPIC33F/PIC24H Family Reference Manual", which is available from the Microchip website (www.microchip.com).
 - 2: Some registers and associated bits described in this section may not be available on all devices. Refer to Section 4.0 "Memory Organization" in this data sheet for device-specific register and bit information.

All of the device pins (except VDD, VSS, MCLR and OSC1/CLKI) are shared among the peripherals and the parallel I/O ports. All I/O input ports feature Schmitt Trigger inputs for improved noise immunity.

10.1 Parallel I/O (PIO) Ports

A parallel I/O port that shares a pin with a peripheral is generally subservient to the peripheral. The peripheral's output buffer data and control signals are provided to a pair of multiplexers. The multiplexers select whether the peripheral or the associated port has ownership of the output data and control signals of the I/O pin. The logic also prevents "loop through", in which a port's digital output can drive the input of a peripheral that shares the same pin. Figure 10-1 shows how ports are shared with other peripherals and the associated I/O pin to which they are connected.

When a peripheral is enabled and the peripheral is actively driving an associated pin, the use of the pin as a general purpose output pin is disabled. The I/O pin can be read, but the output driver for the parallel port bit is disabled. If a peripheral is enabled, but the peripheral is not actively driving a pin, that pin can be driven by a port.

All port pins have three registers directly associated with their operation as digital I/O. The data direction register (TRISx) determines whether the pin is an input or an output. If the data direction bit is '1', then the pin is an input. All port pins are defined as inputs after a Reset. Reads from the latch (LATx) read the latch. Writes to the latch, write the latch. Reads from the port (PORTx) read the port pins, while writes to the port pins write the latch.

Any bit and its associated data and control registers that are not valid for a particular device will be disabled. This means that the corresponding LATx and TRISx registers and the port pin will read as zeros.

When a pin is shared with another peripheral or function that is defined as an input only, it is nevertheless regarded as a dedicated port because there is no other competing source of outputs.





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10.2 Open-Drain Configuration

In addition to the PORT, LAT and TRIS registers for data control, some port pins can also be individually configured for either digital or open-drain output. This is controlled by the Open-Drain Control register, ODCx, associated with each port. Setting any of the bits configures the corresponding pin to act as an open-drain output.

The open-drain feature allows the generation of outputs higher than VDD (e.g., 5V) on any desired 5V tolerant pins by using external pull-up resistors. The maximum open-drain voltage allowed is the same as the maximum VIH specification.

See the "**Pin Diagrams**" section for the available pins and their functionality.

10.3 Configuring Analog Port Pins

The AD1PCFG and TRIS registers control the operation of the Analog-to-Digital (A/D) port pins. The port pins that are desired as analog inputs must have their corresponding TRIS bit set (input). If the TRIS bit is cleared (output), the digital output level (VOH or VOL) will be converted.

The AD1PCFGL register has a default value of 0x0000; therefore, all pins that share ANx functions are analog (not digital) by default.

When the PORT register is read, all pins configured as analog input channels will read as cleared (a low level).

Pins configured as digital inputs will not convert an analog input. Analog levels on any pin that is defined as a digital input (including the ANx pins) can cause the input buffer to consume current that exceeds the device specifications.

10.4 I/O Port Write/Read Timing

One instruction cycle is required between a port direction change or port write operation and a read operation of the same port. Typically this instruction would be a NOP. Examples are shown in Example 10-1 and Example 10-2. This also applies to PORT bit operations, such as BSET PORTB, # RB0, which are single cycle read-modify-write. All PORT bit operations, such as MOV PORTB, W0 or BSET PORTB, # RBx, read the pin and *not* the latch.

10.5 Input Change Notification

The input change notification function of the I/O ports allows the PIC24HJ32GP202/204 and PIC24HJ16GP304 devices to generate interrupt requests to the processor in response to a change-of-state on selected input pins. This feature can detect input change-of-states even in Sleep mode, when the clocks are disabled. Depending on the device pin count, up to 31 external signals (CNx pin) can be selected (enabled) for generating an interrupt request on a change-of-state.

Four control registers are associated with the CN module. The CNEN1 and CNEN2 registers contain the interrupt enable control bits for each of the CN input pins. Setting any of these bits enables a CN interrupt for the corresponding pins.

Each CN pin also has a weak pull-up connected to it. The pull-ups act as a current source connected to the pin, and eliminate the need for external resistors when push button or keypad devices are connected. The pull-ups are enabled separately using the CNPU1 and CNPU2 registers, which contain the control bits for each of the CN pins. Setting any of the control bits enables the weak pull-ups for the corresponding pins.

Note: Pull-ups on change notification pins should always be disabled when the port pin is configured as a digital output.

EXAMPLE 10-1: PORT WRITE/READ EXAMPLE

MOV	0xFF00, W0	; Configure PORTB<15:8> as inputs
MOV NOP	W0, TRISBB	; and PORTB<7:0> as outputs
NOP		; Delay 1 cycle
btss	PORTB, #13	; Next Instruction

EXAMPLE 10-2: PORT BIT OPERATIONS

Incorrect:					
BSET	PORTB,	#RB1	;Set	PORTB <rb1></rb1>	high
BSET	PORTB,	#RB6	;Set	PORTB <rb6></rb6>	high
Correct:					
BSET	PORTB,	#RB1	;Set	PORTB <rb1></rb1>	high
NOP					
BSET	PORTB,	#RB6	;Set	PORTB <rb6></rb6>	high
NOP					
Preferred:					
BSET	LATB, I	LATB1	;Set	PORTB <rb1></rb1>	high
BSET	LATB, 1	LATB6	;Set	PORTB <rb6></rb6>	high

10.6 Peripheral Pin Select

A major challenge in general purpose devices is providing the largest possible set of peripheral features while minimizing the conflict of features on I/O pins. The challenge is even greater on low-pin count devices. In an application where more than one peripheral must be assigned to a single pin, inconvenient workarounds in application code or a complete redesign may be the only option.

Peripheral pin select configuration enables peripheral set selection and placement on a wide range of I/O pins. By increasing the pinout options available on a particular device, programmers can better tailor the microcontroller to their entire application, rather than trimming the application to fit the device.

The peripheral pin select configuration feature operates over a fixed subset of digital I/O pins. Programmers can independently map the input and/or output of most digital peripherals to any one of these I/O pins. Peripheral pin select is performed in software, and generally does not require the device to be reprogrammed. Hardware safeguards are included that prevent accidental or spurious changes to the peripheral mapping, once it has been established.

10.6.1 AVAILABLE PINS

The peripheral pin select feature is used with a range of up to 26 pins. The number of available pins depends on the particular device and its pin count. Pins that support the peripheral pin select feature include the designation "RPn" in their full pin designation, where "RP" designates a remappable peripheral and "n" is the remappable pin number.

10.6.2 CONTROLLING PERIPHERAL PIN SELECT

Peripheral pin select features are controlled through two sets of special function registers to map peripherals and to map outputs.

Since they are separately controlled, a particular peripheral's input and output (if the peripheral has both) can be placed on any selectable function pin without constraint.

The association of a peripheral to a peripheral selectable pin is handled in two different ways, depending on whether an input or output is being mapped.

10.6.2.1 Input Mapping

The inputs of the peripheral pin select options are mapped on the basis of the peripheral. A control register associated with a peripheral dictates the pin it will be mapped to. The RPINRx registers are used to configure peripheral input mapping (see Register 10-1 through Register 10-9). Each register contains sets of 5-bit fields, with each set associated with one of the remappable peripherals. Programming a given peripheral's bit field with an appropriate 5-bit value maps the RPn pin with that value to that peripheral. For any given device, the valid range of values for any bit field corresponds to the maximum number of peripheral pin selections supported by the device.

Figure 10-2 Illustrates remappable pin selection for U1RX input.

Note:	For input mapping only, the Peripheral Pin				
	Select (PPS) functionality does not have				
	priority over the TRISx settings. There-				
	fore, when configuring the RPn pin for				
	input, the corresponding bit in the TRISx				
	register must also be configured for input				
	(i.e., set to '1').				

FIGURE 10-2: REMAPPABLE MUX INPUT FOR U1RX



TABLE 10-1:	REMAPPABLE PERIPHERAL INPUTS ⁽¹⁾

Input Name	Function Name	Register	Configuration Bits	
External Interrupt 1	INT1	RPINR0	INT1R<4:0>	
External Interrupt 2	INT2	RPINR1	INT2R<4:0>	
Timer 2 External Clock	T2CK	RPINR3	T2CKR<4:0>	
Timer 3 External Clock	T3CK	RPINR3	T3CKR<4:0>	
Input Capture 1	IC1	RPINR7	IC1R<4:0>	
Input Capture 2	IC2	RPINR7	IC2R<4:0>	
Input Capture 7	IC7	RPINR10	IC7R<4:0>	
Input Capture 8	IC8	RPINR10	IC8R<4:0>	
Output Compare Fault A	OCFA	RPINR11	OCFAR<4:0>	
UART 1 Receive	U1RX	RPINR18	U1RXR<4:0>	
UART 1 Clear To Send	U1CTS	RPINR18	U1CTSR<4:0>	
SPI 1 Data Input	SDI1	RPINR20	SDI1R<4:0>	
SPI 1 Clock Input	SCK1IN	RPINR20	SCK1R<4:0>	
SPI 1 Slave Select Input	SS1IN	RPINR21	SS1R<4:0>	

Note 1: Unless otherwise noted, all inputs use the Schmitt input buffers.

10.6.2.2 Output Mapping

In contrast to inputs, the outputs of the peripheral pin select options are mapped on the basis of the pin. In this case, a control register associated with a particular pin dictates the peripheral output to be mapped. The RPORx registers are used to control output mapping. Like the RPINRx registers, each register contains sets of 5-bit fields, with each set associated with one RPn pin (see Register 10-10 through Register 10-22). The value of the bit field corresponds to one of the peripherals, and that peripheral's output is mapped to the pin (see Table 10-2 and Figure 10-3).

The list of peripherals for output mapping also includes a null value of '00000' because of the mapping technique. This permits any given pin to remain unconnected from the output of any of the pin selectable peripherals.

FIGURE 10-3: MULTIPLEXING OF REMAPPABLE OUTPUT FOR RPn



TABLE 10-2: OUTPUT SELECTION FOR REMAPPABLE PIN (RPr
--

Function	RPnR<4:0>	Output Name		
NULL	00000	RPn tied to default port pin		
U1TX	00011	RPn tied to UART1 Transmit		
U1RTS	00100	RPn tied to UART1 Ready To Send		
SDO1	00111	RPn tied to SPI1 Data Output		
SCK1OUT	01000	RPn tied to SPI1 Clock Output		
SS1OUT	01001	RPn tied to SPI1 Slave Select Output		
OC1	10010	RPn tied to Output Compare 1		
OC2	10011	RPn tied to Output Compare 2		

10.6.3 CONTROLLING CONFIGURATION CHANGES

Because peripheral remapping can be changed during run time, some restrictions on peripheral remapping are needed to prevent accidental configuration changes. PIC24H devices include three features to prevent alterations to the peripheral map:

- Control register lock sequence
- · Continuous state monitoring
- Configuration bit pin select lock

10.6.3.1 Control Register Lock

Under normal operation, writes to the RPINRx and RPORx registers are not allowed. Attempted writes appear to execute normally, but the contents of the registers remain unchanged. To change these registers, they must be unlocked in hardware. The register lock is controlled by the IOLOCK bit (OSCCON<6>). Setting the IOLOCK bit prevents writes to the control registers; clearing this bit allows writes.

To set or clear the IOLOCK bit, a specific command sequence must be executed:

- 1. Write 0x46 to OSCCON<7:0>.
- 2. Write 0x57 to OSCCON<7:0>.
- 3. Clear (or set) IOLOCK as a single operation.

Note:	MPLAB [®] C30 provides built-in C language functions for unlocking the OSCCON register:						
	builtin_write_OSCCONL(value) builtin_write_OSCCONH(value)						
	See MPLAB Help for more information.						

Unlike the similar sequence with the oscillator's LOCK bit, IOLOCK remains in one state until changed. This allows all the peripheral pin selects to be configured with a single unlock sequence followed by an update to all control registers, then locked with a second lock sequence.

10.6.3.2 Continuous State Monitoring

In addition to being protected from direct writes, the contents of the RPINRx and RPORx registers are constantly monitored in hardware by shadow registers. If an unexpected change in any of the registers occurs (such as cell disturbances caused by ESD or other external events), a configuration mismatch Reset will be triggered.

10.6.3.3 Configuration Bit Pin Select Lock

As an additional level of safety, the device can be configured to prevent more than one write session to the RPINRx and RPORx registers. The IOL1WAY configuration bit (FOSC<5>) blocks the IOLOCK bit from being cleared after it has been set once.

In the default (unprogrammed) state, IOL1WAY is set restricting the users to one write session. Programming IOL1WAY allows user applications unlimited access (with the proper use of the unlock sequence) to the peripheral pin select registers.

10.7 Peripheral Pin Select Registers

The PIC24HJ32GP202/204 and PIC24HJ16GP304 devices implement 17 registers for remappable peripheral configuration:

- Input Remappable Peripheral Registers (9)
- Output Remappable Peripheral Registers (8)
 - Note: Input and Output Register values can only be changed if the IOLOCK bit (OSC-CON<6>) = 0. See Section 10.6.3.1 "Control Register Lock" for a specific command sequence.

11.0	11.0	11.0		D/4/ 4		D/4/ 4		
U-0	U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	
	—	—			INT1R<4:0>			
bit 15							bit 8	
U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0	
_	—	—	_	—	—	—	—	
bit 7							bit 0	
Legend:								
R = Readab	le bit	W = Writable	bit	U = Unimpler	nented bit, read	d as '0'		
-n = Value a	It POR	'1' = Bit is set	t '0' = Bit is clear		ared	red x = Bit is unknown		
bit 15-13	Unimplemen	ted: Read as '	0'					
bit 12-8	INT1R<4:0>:	Assign Externa	al Interrupt 1	(INTR1) to the o	correspondina	RPn pin		
		-		(
	11111 = Input tied to Vss 11001 = Input tied to RP25							
	•							
	•							
	•							
	00001 = I npu	It tied to RP1						
	00000 = Inpu							

REGISTER 10-1: RPINR0: PERIPHERAL PIN SELECT INPUT REGISTER 0

bit 7-0	Unimplemented: Read as '0'

REGISTER 10-2: RPINR1: PERIPHERAL PIN SELECT INPUT REGISTER 1

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0	
		—	_		_		_	
bit 15							bit 8	
U-0	U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	
					INT2R<4:0>			
bit 7		-					bit 0	
Legend:								
R = Readable	e bit	W = Writable	bit	U = Unimplemented bit, read as '0'				
-n = Value at POR '1' =		'1' = Bit is set		'0' = Bit is cle	'0' = Bit is cleared		x = Bit is unknown	
bit 15-5	Unimplemen	ted: Read as '	כ'					
bit 4-0	INT2R<4:0>:	Assign Externa	al Interrupt 2 (INTR2) to the	corresponding F	RPn pin		
	11111 = Input tied to Vss 11001 = Input tied to RP25							
	•							
	•							
	•							
	00001 = Inpu 00000 = Inpu							
REGISTER	10-3: RPINR	3: PERIPHE	RAL PIN SI			8 3		
----------------------------------	---	---	---------------	------------------	-----------------	-----------------	-------	
U-0	U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	
	—				T3CKR<4:0)>		
bit 15							bit 8	
U-0	U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	
	—	—			T2CKR<4:0)>		
bit 7							bit 0	
Legend:								
R = Readabl	le bit	W = Writable I	oit	U = Unimplei	mented bit, rea	ad as '0'		
-n = Value at	t POR	'1' = Bit is set		'0' = Bit is cle	eared	x = Bit is unkr	nown	
bit 15-13 bit 12-8 bit 7-5	T3CKR<4:0> 11111 = Inpu 11001 = Inpu • • • 00001 = Inpu 00000 = Inpu	t tied to Vss t tied to RP25 t tied to RP1	3 External Cl	ock (T3CK) to t	he correspond	ding RPn pin		
bit 4-0	T2CKR<4:0> 11111 = Inpu	: Assign Timer2 t tied to Vss t tied to RP25 t tied to RP1		ock (T2CK) to t	he correspond	ding RPn pin		

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		11.0								
U-0	U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1			
	—				IC2R<4:0>		1.14			
bit 15							bit			
U-0	U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1			
_	—				IC1R<4:0>					
bit 7							bit			
Legend:										
R = Readab	le bit	W = Writable	bit	bit U = Unimplemented bit, read as '0'						
-n = Value a	t POR	'1' = Bit is se	t	'0' = Bit is cle	eared	x = Bit is unkr	nown			
	11001 = Input • •	11111 = Input tied to Vss 11001 = Input tied to RP25 • • • • • • • • • • • • •								
bit 7-5	Unimplement	ed: Read as	' 0'							
bit 4-0	IC1R<4:0>: As 11111 = Input 11001 = Input • • • • • • • • • • • • •	tied to Vss tied to RP25 tied to RP1		to the correspo	onding RPn pir	1				

REGISTER 10-4: RPINR7: PERIPHERAL PIN SELECT INPUT REGISTER 7

U-0	U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	
_	_				IC8R<4:0>			
oit 15							bit 8	
U-0	U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	
		_			IC7R<4:0>			
oit 7							bit (
Legend:								
R = Readab	adable bit W = Writable bit U = Unimplemented bit, read as '0'							
-n = Value a	t POR	'1' = Bit is set		'0' = Bit is cle	ared	x = Bit is unkr	nown	
	11001 = Inpu • • 00001 = Inpu 00000 = Inpu							
bit 7-5	Unimplemen	ted: Read as 'o)'					
bit 4-0	11111 = In pu	it tied to RP25 It tied to RP1	oture 7 (IC7)	to the correspo	onding RPn pir	ı		

REGISTER 10-5: RPIR10: PERIPHERAL PIN SELECT INPUT REGISTER 10

REGISTER 10-6: RPINR11: PERIPHERAL PIN SELECT INPUT REGISTER 11

1-0 L — -	J-0 l	U-0	U-0	U-0	U-0	U-0
		_				
					_	
		i				bit 8
J-0 L	J-0 R/	/W-1	R/W-1	R/W-1	R/W-1	R/W-1
		OCFAR<4:0>				
						bit 0
VV = V	Vritable bit	ι	J = Unimplem	ented bit, read	as '0'	
-n = Value at POR '1' = Bit is set		'('0' = Bit is cleared x = Bit is unknow			own
	 W = V	W = Writable bit	W = Writable bit	W = Writable bit U = Unimplem	 — — OCFAR<4:0> W = Writable bit U = Unimplemented bit, read 	— — OCFAR<4:0> W = Writable bit U = Unimplemented bit, read as '0'

bit 15-5 Unimplemented: Read as '0'

bit 4-0

OCFAR<4:0>: Assign Output Capture A (OCFA) to the corresponding RPn pin

11111 = Input tied to Vss 11001 = Input tied to RP25

- ٠
- •
- ٠

00001 = Input tied to RP1 00000 = Input tied to RP0

U-0	U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1		
_	_	_			U1CTSR<4:	0>			
bit 15							bit 8		
U-0	U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1		
—	—	—			U1RXR<4:0	>			
bit 7							bit (
Legend:									
R = Readab		W = Writable	Vritable bit U = Unimplemented bit, read as '0'						
-n = Value at POR '1' = Bit is set '0' = Bit is cleared x =							nown		
	11001 = Input tied to RP25 • • • • • • • • • • • • • • • • • • •								
bit 7-5	Unimpleme	nted: Read as '	0'						
bit 4-0	11111 = Inp 11001 = Inp • • • 00001 = Inp	>: Assign UART ut tied to Vss ut tied to RP25 ut tied to RP1 ut tied to RP0	1 Receive (U	11RX) to the co	orresponding F	RPn pin			

REGISTER 10-7: RPINR18: PERIPHERAL PIN SELECT INPUT REGISTER 18

U-0	U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1			
_	_	_			SCK1R<4:0	>				
oit 15							bit 8			
U-0	U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1			
		—			SDI1R<4:0>	>				
oit 7							bit 0			
Legend:										
R = Readab	le bit	W = Writable	bit	U = Unimpler	mented bit, rea	d as '0'				
-n = Value at POR '1' = Bit is set '0' = Bit is cl					ared	x = Bit is unkr	nown			
	11001 = Inpu • • 00001 = Inpu	<pre>11111 = Input tied to Vss 11001 = Input tied to RP25</pre>								
bit 7-5	Unimplement	ted: Read as	ʻ0'							
bit 4-0	SDI1R<4:0>: 11111 = Inpu 11001 = Inpu	t tied to Vss		011) to the corre	esponding RPı	ו pin				

REGISTER 10-8: RPINR20: PERIPHERAL PIN SELECT INPUT REGISTER 20

REGISTER 10-9: RPINR21: PERIPHERAL PIN SELECT INPUT REGISTER 21

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0		
—	—	—	—	—	—	—	—		
bit 15						·	bit 8		
U-0	U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1		
—	—	SS1R<4:0>							
bit 7							bit 0		
Legend:									
R = Readabl	le bit	W = Writable	bit	U = Unimplen	nented bit, read	d as '0'			
-n = Value at	t POR	'1' = Bit is set		'0' = Bit is cle	ared	x = Bit is unkr	Bit is unknown		
bit 15-5	Unimplemer	ted: Read as '	0'						
bit 4-0	SS1R<4:0>:	Assign SPI1 SI	ave Select In	put (SS1IN) to t	the correspond	ing RPn pin			
	11111 = Inpu	ut tied to Vss							
	11001 – I nni	ut tied to RP25							
	$\pm \pm 0.01 - 1000$								
	•								
	• •								
	• •								

00001 = Input tied to RP1

00000 = Input tied to RP0

REGISTER 10-10: RPOR0: PERIPHERAL PIN SELECT OUTPUT REGISTER 0

U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—			RP1R<4:0>		
bit 15							bit 8

U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	_	—			RP0R<4:0>		
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit,	read as '0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-13 Unimplemented: Read as '0'

bit 12-8 **RP1R<4:0>:** Peripheral Output Function is Assigned to RP1 Output Pin (see Table 10-2 for peripheral function numbers)

bit 7-5 Unimplemented: Read as '0'

bit 4-0 **RP0R<4:0>:** Peripheral Output Function is Assigned to RP0 Output Pin (see Table 10-2 for peripheral function numbers)

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REGISTER 10-11: RPOR1: PERIPHERAL PIN SELECT OUTPUT REGISTER 1

		-n = Value at POR '1' = Bit is set			0' = Bit is cleared $x = Bit is unk$			
R = Readable bit W = Writable bit			oit	U = Unimpler	mented bit, rea	ad as '0'		
Legend:								
bit 7	•						bit 0	
—	—	—	RP2R<4:0>					
U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	
bit 15							bit 8	
-		_			RP3R<4:0>	>		
U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	

bit 12-8 **RP3R<4:0>:** Peripheral Output Function is Assigned to RP3 Output Pin (see Table 10-2 for peripheral function numbers)

bit 7-5 Unimplemented: Read as '0'

bit 4-0 **RP2R<4:0>:** Peripheral Output Function is Assigned to RP2 Output Pin (see Table 10-2 for peripheral function numbers)

REGISTER 10-12: RPOR2: PERIPHERAL PIN SELECT OUTPUT REGISTER 2

U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	
_	_				RP5R<4:0>			
bit 15							bit 8	
U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	
_	—	—			RP4R<4:0>			
bit 7							bit 0	
Legend:								
R = Readab	le bit	W = Writable	bit	U = Unimplemented bit, read as '0'				
-n = Value a	t POR	'1' = Bit is set		'0' = Bit is cleared x = Bit is unknown			nown	
bit 15-13	Unimplomon	ted: Read as '	0'					
	-							
bit 12-8	RP5R<4:0>: function num		put Function i	s Assigned to R	P5 Output Pin	(see Table 10-2	for peripheral	
bit 7-5	Unimplemen	ted: Read as '	0'					
hit 1 0	DD4D 44105 1	Daripharal Out	out Eurotion i	Accianad to D			for poriphoral	

bit 4-0 **RP4R<4:0>:** Peripheral Output Function is Assigned to RP4 Output Pin (see Table 10-2 for peripheral function numbers)

REGISTER 10-13: RPOR3: PERIPHERAL PIN SELECT OUTPUT REGISTER 3

U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
_	_	_			RP7R<4:0>		
bit 15							bit 8
U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	_			RP6R<4:0>	•	
bit 7		·	•				bit C
Legend:							
R = Readable	e bit	W = Writable	bit	U = Unimpler	nented bit, rea	nd as '0'	
-n = Value at	POR	'1' = Bit is set	t	'0' = Bit is cle	ared	x = Bit is unkr	nown
bit 15-13	Unimplemen	ted: Read as '	0'				
bit 12-8	RP7R<4:0>: function num	•	put Function i	s Assigned to R	P7 Output Pin	(see Table 10-2	for peripheral
bit 7-5	Unimplemen	ted: Read as '	0'				

bit 4-0 **RP6R<4:0>:** Peripheral Output Function is Assigned to RP6 Output Pin (see Table 10-2 for peripheral function numbers)

REGISTER 10-14: RPOR4: PERIPHERAL PIN SELECT OUTPUT REGISTER 4

U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—			RP9R<4:0>		
bit 15							bit 8
U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—			RP8R<4:0>		
bit 7							bit 0
Legend:							
R = Readable bit W = Writable bit				U = Unimplemented bit, read as '0'			
-n = Value at POR (1' = Bit is set				'0' = Bit is cle	ared	x = Bit is unkr	nown

bit 15-13 Unimplemented: Read as '0'

bit 12-8 **RP9R<4:0>:** Peripheral Output Function is Assigned to RP9 Output Pin (see Table 10-2 for peripheral function numbers)

bit 7-5 Unimplemented: Read as '0'

bit 4-0 **RP8R<4:0>:** Peripheral Output Function is Assigned to RP8 Output Pin (see Table 10-2 for peripheral function numbers)

REGISTER 10-15: RPOR5: PERIPHERAL PIN SELECT OUTPUT REGISTER 5

U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
_	—	—			RP11R<4:0:	>	
bit 15							bit 8
U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
_	_				RP10R<4:0	>	
bit 7			L				bit 0
Legend:							
R = Readable	e bit	W = Writable	bit	U = Unimpler	mented bit, rea	ıd as '0'	
-n = Value at POR '1' = Bit is set			'0' = Bit is cleared x = Bit is unknown				
bit 15-13	Unimplemer	ted: Read as '	כי				

- bit 12-8 **RP11R<4:0>:** Peripheral Output Function is Assigned to RP11 Output Pin (see Table 10-2 for peripheral function numbers)
- bit 7-5 **Unimplemented:** Read as '0'
- bit 4-0 **RP10R<4:0>:** Peripheral Output Function is Assigned to RP10 Output Pin (see Table 10-2 for peripheral function numbers)

REGISTER 10-16: RPOR6: PERIPHERAL PIN SELECT OUTPUT REGISTER 6

U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
_	—	—			RP13R<4:0>	>	
bit 15							bit 8
U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—			RP12R<4:0>	>	
bit 7							bit 0
Legend:							
R = Readabl	le bit	W = Writable	bit	U = Unimpler	nented bit, rea	d as '0'	
-n = Value at	t POR	'1' = Bit is set		'0' = Bit is cle	ared	x = Bit is unkr	nown
<u> </u>							
bit 15-13	Unimplemen	ted: Read as '	כי				
bit 12-8		: Peripheral Ounction numbers)	•	n is Assigned to	RP13 Output	Pin (see Table 1	10-2 for
hit 7 5	Unimplomor	tod. Dood on '	<u>.</u> ,				

- bit 7-5 Unimplemented: Read as '0'
- bit 4-0 **RP12R<4:0>:** Peripheral Output Function is Assigned to RP12 Output Pin (see Table 10-2 for peripheral function numbers)

REGISTER 10-17: RPOR7: PERIPHERAL PIN SELECT OUTPUT REGISTER 7

U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
_		_			RP15R<4:0:	>	
bit 15							bit 8
U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—					RP14R<4:0:	>	
bit 7							bit 0
Legend:							
R = Readable	e bit	W = Writable I	bit	U = Unimplem	nented bit, rea	id as '0'	
-n = Value at	POR	'1' = Bit is set		'0' = Bit is clea	ared	x = Bit is unkr	nown
bit 15-13	Unimplemen	ted: Read as '(כי				
bit 12-8		Peripheral Ou ction numbers)		is Assigned to	RP15 Output	Pin (see Table 1	0-2 for
bit 7-5	Unimplemen	ted: Read as '	o'				
bit 4-0	RP14R<4:0>:	Peripheral Ou	tput Function	is Assigned to	RP14 Output	Pin (see Table 1	0-2 for

REGISTER 10-18: RPOR8: PERIPHERAL PIN SELECT OUTPUT REGISTER 8

peripheral function numbers)

U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—			RP17R<4:0>		
bit 15							bit 8
U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
_	—	—			RP16R<4:0>		
bit 7							bit 0
Legend:							
R = Readable	bit	W = Writable	ble bit U = Unimplemented bit, read as '0'				

'0' = Bit is cleared

bit 15-13 Unimplemented: Read as '0'

'1' = Bit is set

-n = Value at POR

bit 12-8 **RP17R<4:0>:** Peripheral Output Function is Assigned to RP15 Output Pin (see Table 10-2 for peripheral function numbers)

bit 7-5 Unimplemented: Read as '0'

bit 4-0 **RP16R<4:0>:** Peripheral Output Function is Assigned to RP14 Output Pin (see Table 10-2 for peripheral function numbers)

x = Bit is unknown

REGISTER 10-19: RPOR9: PERIPHERAL PIN SELECT OUTPUT REGISTER 9

					KP18K<4:0>	•	
0-0		<u> </u>			RP18R<4:0>		10,00-0
U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
bit 15							bi
	—	—			RP19R<4:0>	•	
	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0

bit 15-13 Unimplemented: Read as '0'

bit 12-8 **RP19R<4:0>:** Peripheral Output Function is Assigned to RP19 Output Pin (see Table 10-2 for peripheral function numbers)

bit 7-5 Unimplemented: Read as '0'

bit 4-0 **RP18R<4:0>:** Peripheral Output Function is Assigned to RP18 Output Pin (see Table 10-2 for peripheral function numbers)

REGISTER 10-20: RPOR10: PERIPHERAL PIN SELECT OUTPUT REGISTER 10

U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
_	—	—			RP21R<4:0:	>	
bit 15							bit 8
U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	-			RP20R<4:0;	>	
bit 7							bit 0
Legend:							
R = Readab	le bit	W = Writable I	oit	U = Unimpler	nented bit, rea	d as '0'	
-n = Value a	t POR	'1' = Bit is set		'0' = Bit is cle	ared	x = Bit is unkr	nown
bit 15-13	Unimplemen	ted: Read as 'o)'				
bit 12-8		: Peripheral Oun	-	n is Assigned to	RP21 Output	Pin (see Table 1	0-2 for
hit 7-5	Unimplemen	tod. Pood as '(ı'				

bit 7-5 Unimplemented: Read as '0'

bit 4-0 **RP20R<4:0>:** Peripheral Output Function is Assigned to RP20 Output Pin (see Table 10-2 for peripheral function numbers)

REGISTER 10-21: RPOR11: PERIPHERAL PIN SELECT OUTPUT REGISTER 11

U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
_	_	_			RP23R<4:0	>	
bit 15							bit 8
U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—			RP22R<4:0	>	
bit 7							bit 0
Legend:							
R = Readab	le bit	W = Writable	bit	U = Unimplen	nented bit, rea	ad as '0'	
-n = Value a	t POR	'1' = Bit is set		'0' = Bit is clea	ared	x = Bit is unkr	nown
bit 15-13	Unimplemen	ted: Read as '	0'				
bit 12-8		: Peripheral Ou action numbers	•	n is Assigned to	RP23 Output	Pin (see Table 1	0-2 for
bit 7-5	Unimplemen	ted: Read as '	0'				

bit 4-0 **RP22R<4:0>:** Peripheral Output Function is Assigned to RP22 Output Pin (see Table 10-2 for peripheral function numbers)

REGISTER 10-22: RPOR12: PERIPHERAL PIN SELECT OUTPUT REGISTER 12

-n = Value at POR '1' = Bit is set			'0' = Bit is clea	ared	x = Bit is unkr	nown	
R = Readable		W = Writable		U = Unimplen			
Legend:							
							Dit O
bit 7							bit 0
_	_				RP24R<4:0	>	
U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
bit 15							bit 8
		_			KF20K<4.0	>	
					RP25R<4:0		
U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-

bit 12-8 **RP25R<4:0>:** Peripheral Output Function is Assigned to RP25 Output Pin (see Table 10-2 for peripheral function numbers)

bit 7-5 Unimplemented: Read as '0'

bit 4-0 **RP24R<4:0>:** Peripheral Output Function is Assigned to RP24 Output Pin (see Table 10-2 for peripheral function numbers)

NOTES:

11.0 TIMER1

- Note 1: This data sheet summarizes the features of the PIC24HJ32GP202/204 and PIC24HJ16GP304 family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to "Section 11. Timers" (DS70205) of the "dsPIC33F/PIC24H Family Reference Manual", which is available from the Microchip website (www.microchip.com).
 - 2: Some registers and associated bits described in this section may not be available on all devices. Refer to Section 4.0 "Memory Organization" in this data sheet for device-specific register and bit information.

The Timer1 module is a 16-bit timer, which can serve as the time counter for the real-time clock, or operate as a free-running interval timer/counter. Timer1 can operate in three modes:

- 16-bit Timer
- 16-bit Synchronous Counter
- 16-bit Asynchronous Counter

Timer1 also supports these features:

- Timer gate operation
- · Selectable prescaler settings
- Timer operation during CPU Idle and Sleep modes
- Interrupt on 16-bit Period register match or falling edge of external gate signal

Figure 11-1 shows a block diagram of the 16-bit timer module.

To configure Timer1 for operation:

- 1. Set the TON bit (= 1) in the T1CON register.
- 2. Select the timer prescaler ratio using the TCKPS<1:0> bits in the T1CON register.
- 3. Set the Clock and Gating modes using the TCS and TGATE bits in the T1CON register.
- 4. Set or clear the TSYNC bit in T1CON to select synchronous or asynchronous operation.
- 5. Load the timer period value into the PR1 register.
- 6. If interrupts are required, set the interrupt enable bit, T1IE. Use the priority bits, T1IP<2:0>, to set the interrupt priority.



REGISTER	11-1: T1CO	N: TIMER1 C	ONTROL R	EGISTER			
R/W-0	U-0	R/W-0	U-0	U-0	U-0	U-0	U-0
TON	—	TSIDL	—	—	—		—
bit 15							bit 8
U-0	R/W-0	R/W-0	R/W-0	U-0	R/W-0	R/W-0	U-0
_	TGATE	TCKPS		_	TSYNC	TCS	_
bit 7						II	bit (
Legend:							
R = Readable	e bit	W = Writable	bit	U = Unimplei	mented bit, read	as '0'	
-n = Value at	POR	'1' = Bit is set		'0' = Bit is cle		x = Bit is unkn	own
bit 15	TON: Timer1	On bit					
	1 = Starts 16- 0 = Stops 16-						
bit 14	-	ited: Read as '	∩'				
bit 13	-	in Idle Mode bit					
	•	ue module ope		device enters lo	lle mode		
		module operat					
bit 12-7	Unimplemen	ted: Read as '	0'				
bit 6		er1 Gated Time	Accumulatio	n Enable bit			
	When TCS = This bit is ign						
	When TCS =						
		ne accumulation	n enabled				
		ne accumulation					
bit 5-4		Timer1 Input (Clock Prescal	e Select bits			
	11 = 1:256 10 = 1:64						
	01 = 1:8						
	00 = 1:1						
bit 3	-	ted: Read as '					
bit 2		er1 External Clo	ock Input Syn	chronization So	elect bit		
	When TCS = 1 = Svnchron	⊥. iize external clo	ock input				
		nchronize exte		out			
	When TCS =						
bit 1	This bit is ign	orea. Clock Source S	Soloot hit				
		clock from pin T		risina edae)			
		•					
	0 = Internal c	IOCK (FCY)					

REGISTER 11-1: T1CON: TIMER1 CONTROL REGISTER

12.0 TIMER2/3 FEATURE

- Note 1: This data sheet summarizes the features of the PIC24HJ32GP202/204 and PIC24HJ16GP304 family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to "Section 11. Timers" (DS70205) of the "dsPIC33F/PIC24H Family Reference Manual", which is available from the Microchip website (www.microchip.com).
 - Some registers and associated bits described in this section may not be available on all devices. Refer to Section 4.0 "Memory Organization" in this data sheet for device-specific register and bit information.

The Timer2/3 feature has 32-bit timers that can also be configured as two independent 16-bit timers with selectable operating modes.

As a 32-bit timer, the Timer2/3 feature permits operation in three modes:

- Two Independent 16-bit timers (Timer2 and Timer3) with all 16-bit operating modes (except Asynchronous Counter mode)
- Single 32-bit timer (Timer2/3)
- Single 32-bit synchronous counter (Timer2/3)

The Timer2/3 feature also supports:

- Timer gate operation
- Selectable Prescaler Settings
- Timer operation during Idle and Sleep modes
- Interrupt on a 32-bit Period Register Match
- Time Base for Input Capture and Output Compare Modules (Timer2 and Timer3 only)
- ADC1 Event Trigger (Timer2/3 only)

Individually, all eight of the 16-bit timers can function as synchronous timers or counters. They also offer the features that are listed above, except for the event trigger. The operating modes and enabled features are determined by setting the appropriate bit(s) in the T2CON and T3CON registers. T2CON registers are shown in generic form in Register 12-1. T3CON registers are shown in Register 12-2.

For 32-bit timer/counter operation, Timer2 is the least significant word (lsw), and Timer3 is the most significant word (msw) of the 32-bit timers.

Note: For 32-bit operation, T3CON control bits are ignored. Only T2CON control bit is used for setup and control. Timer2 clock and gate inputs are used for the 32-bit timer modules, but an interrupt is generated with the Timer3 interrupt flags.

12.1 32-bit Operation

To configure the Timer2/3 feature for 32-bit operation:

- 1. Set the corresponding T32 control bit.
- 2. Select the prescaler ratio for Timer2 using the TCKPS<1:0> bits.
- 3. Set the Clock and Gating modes using the corresponding TCS and TGATE bits.
- 4. Load the timer period value. PR3 contains the most significant word of the value, while PR2 contains the least significant word.
- 5. Set the interrupt enable bit T3IE, if interrupts are required. Use the priority bits T3IP<2:0> to set the interrupt priority. While Timer2 controls the timer, the interrupt appears as a Timer3 interrupt.
- 6. Set the corresponding TON bit.

The timer value at any point is stored in the register pair TMR3:TMR2. TMR3 always contains the most significant word of the count, while TMR2 contains the least significant word.

To configure any of the timers for individual 16-bit operation:

- 1. Clear the T32 bit corresponding to that timer.
- 2. Select the timer prescaler ratio using the TCKPS<1:0> bits.
- 3. Set the Clock and Gating modes using the TCS and TGATE bits.
- 4. Load the timer period value into the PRx register.
- 5. If interrupts are required, set the interrupt enable bit, TxIE. Use the priority bits, TxIP<2:0>, to set the interrupt priority.
- 6. Set the TON bit.



FIGURE 12-1: TIMER2/3 (32-BIT) BLOCK DIAGRAM⁽¹⁾



REGISTER	12-1: T2COI	N CONTROL	REGISTER				
R/W-0	U-0	R/W-0	U-0	U-0	U-0	U-0	U-0
TON		TSIDL					
bit 15							bit 8
U-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	R/W-0	U-0
	TGATE	TCKPS		T32	_	TCS	_
bit 7	-			-			bit C
Legend: R = Readabl	o hit	W = Writable	hit.	II – Unimploi	monted hit read		
				-	mented bit, read		
-n = Value at	POR	'1' = Bit is set		'0' = Bit is cle	eared	x = Bit is unkno	own
bit 15	TON: Timer2	On bit					
	When T32 = 2	1:					
	1 = Starts 32-	bit Timer2/3					
	0 = Stops 32-						
	When T32 = $\frac{1}{1}$						
	1 = Starts 16- 0 = Stops 16-						
bit 14	-	ted: Read as '	0'				
bit 13	TSIDL: Stop i	in Idle Mode bit					
		ue module ope module operat			lle mode		
bit 12-7	Unimplemen	ted: Read as '	0'				
bit 6	TGATE: Time	er2 Gated Time	Accumulatio	n Enable bit			
	<u>When TCS =</u> This bit is ign						
	When TCS =						
		ne accumulation ne accumulation					
bit 5-4	TCKPS<1:0>	: Timer2 Input	Clock Presca	le Select bits			
	11 = 1:256						
	10 = 1:64						
	01 = 1:8 00 = 1:1						
bit 3		mer Mode Sele	ect bit				
		nd Timer3 form nd Timer3 act a	•				
bit 2	Unimplemen	ted: Read as '	0'				
bit 1		Clock Source S					
		clock from pin T		rising edge)			
	0 = Internal c						
bit 0	Unimplemen	ted: Read as '	0'				

REGISTER 12-1: T2CON CONTROL REGISTER

R/W-0	U-0	R/W-0	U-0	U-0	U-0	U-0	U-0			
TON ⁽²⁾		TSIDL ⁽¹⁾	_		_		_			
bit 15		10102					bit 8			
U-0	R/W-0	R/W-0	R/W-0	U-0	U-0	R/W-0	U-0			
	TGATE ⁽²⁾	TCKPS	<1:0> (2)	_		TCS ⁽²⁾				
bit 7							bit C			
Legend:										
R = Readable	e bit	W = Writable	oit	U = Unimpler	nented bit, rea	d as '0'				
-n = Value at	POR	'1' = Bit is set		'0' = Bit is cle	ared	x = Bit is unkno	own			
-										
bit 15	TON: Timer3	On bit ⁽²⁾								
	1 = Starts 16-									
bit 14	0 = Stops 16-	ted: Read as '	۰,							
bit 13	•	n Idle Mode bit								
bit 15	-			vice enters Idle	mode					
		timer operation								
bit 12-7	Unimplemen	ted: Read as ')'							
bit 6	TGATE: Time	r3 Gated Time	Accumulatio	n Enable bit ⁽²⁾						
	When TCS = This bit is igno									
	When TCS =									
	1 = Gated time accumulation enabled									
		e accumulatior		(0)						
bit 5-4			Clock Presca	le Select bits ⁽²⁾						
	11 = 1:256 pr 10 = 1:64 pre									
	01 = 1:8 pres									
	00 = 1:1 pres	cale value								
bit 3-2	-	ted: Read as '								
bit 1		Clock Source S								
		clock from T3Cl	<pin< td=""><td></td><td></td><td></td><td></td></pin<>							
bit 0	0 = Internal cl Unimplemen	· · · ·								
		tod. Dood oo ''	י ר							

REGISTER 12-2: T3CON CONTROL REGISTER

Note 1: When 32-bit timer operation is enabled (T32 = 1) in the Timer Control register (T2CON<3>), the TSIDL bit must be cleared to operate the 32-bit timer in Idle mode.

2: When the 32-bit timer operation is enabled (T32 = 1) in the Timer Control register (T2CON<3>), these bits have no effect.

NOTES:

13.0 INPUT CAPTURE

- Note 1: This data sheet summarizes the features of the PIC24HJ32GP202/204 and PIC24HJ16GP304 family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to "Section 12. Input Capture" (DS70198) of the "dsPIC33F/PIC24H Family Reference Manual", which is available from the Microchip website (www.microchip.com).
 - 2: Some registers and associated bits described in this section may not be available on all devices. Refer to Section 4.0 "Memory Organization" in this data sheet for device-specific register and bit information.

The input capture module is useful in applications requiring frequency (period) and pulse measurement. The PIC24HJ32GP202/204 and PIC24HJ16GP304 devices support up to eight input capture channels.

The input capture module captures the 16-bit value of the selected Time Base register when an event occurs at the ICx pin. The events that cause a capture event are listed below in three categories:

- Simple Capture Event modes:
 - Capture timer value on every falling edge of input at ICx pin
 - Capture timer value on every rising edge of input at ICx pin
- Capture timer value on every edge (rising and falling).
- Prescaler Capture Event modes:
 - Capture timer value on every 4th rising edge of input at ICx pin
 - Capture timer value on every 16th rising edge of input at ICx pin

Each input capture channel can select one of the two 16-bit timers (Timer2 or Timer3) for the time base. The selected timer can use either an internal or external clock.

Other operational features include:

- Device wake-up from capture pin during CPU Sleep and Idle modes
- Interrupt on input capture event
- Four-word FIFO buffer for capture values
 Interrupt optionally generated after 1, 2, 3 or 4 buffer locations are filled
- Use of input capture to provide additional sources of external interrupts





13.1 Input Capture Registers

REGISTER 13-1: ICxCON: INPUT CAPTURE x CONTROL REGISTER

U-0	U-0	R/W-0	U-0	U-0	U-0	U-0	U-0		
—		ICSIDL	—	—	—	_	—		
bit 15							bit 8		
-	-	5444.6	5.4.10	D A 110	-	D 444 a	D 444 a		
R/W-0	R/W-0	R/W-0	R-0, HC	R-0, HC	R/W-0	R/W-0	R/W-0		
	ICI<	:1:0>	ICOV	ICBNE		ICM<2:0>	h:+ (
bit 7							bit (
Legend:				HC =	HC = Cleared in Hardware				
R = Readable	bit	W = Writable	bit	U = Unimplem	nented bit, rea	d as '0'			
-n = Value at POR '1' = Bit is set				'0' = Bit is clea	ared	x = Bit is unkn	own		
bit 15-14	Unimplemen	ted: Read as '	0'						
bit 13	ICSIDL: Input Capture Module Stop in Idle Control bit								
	 1 = Input capture module will halt in CPU Idle mode 0 = Input capture module will continue to operate in CPU Idle mode 								
				operate in CPU	Idle mode				
bit 12-8	•	ted: Read as '							
bit 7	ICTMR: Input Capture Timer Select bits								
	1 = TMR2 contents are captured on capture event								
	 0 = TMR3 contents are captured on capture event ICI<1:0>: Select Number of Captures per Interrupt bits 								
bit 6-5			• •	•					
	11 = Interrupt on every fourth capture event								
	 10 = Interrupt on every third capture event 01 = Interrupt on every second capture event 								
		on every capt							
bit 4	ICOV: Input Capture Overflow Status Flag bit (read-only)								
	1 = Input capture overflow occurred								
	0 = No input of a line o	capture overflor	w occurred						
bit 3				s bit (read-only)					
	• •			ast one more ca	apture value o	an be read			
	0 = Input cap	ture buffer is er	npty						
bit 2-0		put Capture Mo							

- 111 = Input capture functions as interrupt pin only when device is in Sleep or Idle mode (Rising edge detect only, all other control bits are not applicable.)
 110 = Unused (module disabled)
 - 101 = Capture mode, every 16th rising edge
 - 100 = Capture mode, every 4th rising edge
 - 011 = Capture mode, every rising edge
 - 010 = Capture mode, every falling edge
 - 001 = Capture mode, every edge (rising and falling)
 - (ICI<1:0> bits do not control interrupt generation for this mode.)
 - 000 = Input capture module turned off

14.0 OUTPUT COMPARE

- Note 1: This data sheet summarizes the features of the PIC24HJ32GP202/204 and PIC24HJ16GP304 family of devices. However, it is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to "Section 13. Output Compare" (DS70209) of the "dsPIC33F/PIC24H Family Reference Manual", which is available from the Microchip website (www.microchip.com).
 - Some registers and associated bits described in this section may not be available on all devices. Refer to Section 4.0 "Memory Organization" in this data sheet for device-specific register and bit information.

The Output Compare module can select either Timer2 or Timer3 for its time base. The module compares the value of the timer with the value of one or two compare registers depending on the operating mode selected. The state of the output pin changes when the timer value matches the compare register value. The Output Compare module generates either a single output pulse or a sequence of output pulses, by changing the state of the output pin on the compare match events. The Output Compare module can also generate interrupts on compare match events.

The Output Compare module has multiple operating modes:

- Active-Low One-Shot mode
- Active-High One-Shot mode
- Toggle mode
- Delayed One-Shot mode
- Continuous Pulse mode
- PWM mode without fault protection
- PWM mode with fault protection

FIGURE 14-1: OUTPUT COMPARE MODULE BLOCK DIAGRAM



14.1 Output Compare Modes

Configure the Output Compare modes by setting the appropriate Output Compare Mode bits (OCM<2:0>) in the Output Compare Control register (OCxCON<2:0>). Table 14-1 lists the different bit settings for the Output Compare modes. Figure 14-2 illustrates the output compare operation for various modes. The user

TABLE 14-1: OUTPUT COMPARE MODES

application must disable the associated timer when writing to the output compare control registers to avoid malfunctions.

Note:	See Section 13. "Output Compare"					
	(DS70209) in the "dsPIC33F/PIC24H					
	Family Reference Manual" for OCxR and					
	OCxRS register restrictions.					

OCM<2:0>	Mode	OCx Pin Initial State	OCx Interrupt Generation
000	Module Disabled	Controlled by GPIO register	—
001	Active-Low One-Shot	0	OCx Rising edge
010	Active-High One-Shot	1	OCx Falling edge
011	Toggle Mode	Current output is maintained	OCx Rising and Falling edge
100	Delayed One-Shot	0	OCx Falling edge
101	Continuous Pulse mode	0	OCx Falling edge
110	PWM mode without fault protection	0, if OCxR is zero 1, if OCxR is non-zero	No interrupt
111	PWM mode with fault protection	0, if OCxR is zero 1, if OCxR is non-zero	OCFA Falling edge for OC1 to OC ²

FIGURE 14-2: OUTPUT COMPARE OPERATION



14.2 Output Compare Register

REGISTER 14-1: OCxCON: OUTPUT COMPARE x CONTROL REGISTER

U-0	U-0	R/W-0	U-0	U-0	U-0	U-0	U-0
—	—	OCSIDL	—	—	—	—	_
bit 15							bit 8
U-0	U-0	U-0	R-0 HC	R/W-0	R/W-0	R/W-0	R/W-0
	_	_	OCFLT	OCTSEL		OCM<2:0>	

bit 7

Legend:	HC = Cleared in Hardware	HS = Set in Hardware	
R = Readable bit	W = Writable bit	U = Unimplemented bit, rea	d as '0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-14	Unimplemented: Read as '0'
bit 13	OCSIDL: Stop Output Compare in Idle Mode Control bit
	 1 = Output Compare x will halt in CPU Idle mode 0 = Output Compare x will continue to operate in CPU Idle mode
h# 40 F	
bit 12-5	Unimplemented: Read as '0'
bit 4	OCFLT: PWM Fault Condition Status bit
	 1 = PWM Fault condition has occurred (cleared in hardware only) 0 = No PWM Fault condition has occurred (This bit is only used when OCM<2:0> = 111.)
bit 3	OCTSEL: Output Compare Timer Select bit
	 1 = Timer3 is the clock source for Compare x 0 = Timer2 is the clock source for Compare x
bit 2-0	OCM<2:0>: Output Compare Mode Select bits
	 111 = PWM mode on OCx, Fault pin enabled 110 = PWM mode on OCx, Fault pin disabled 101 = Initialize OCx pin low, generate continuous output pulses on OCx pin 100 = Initialize OCx pin low, generate single output pulse on OCx pin 011 = Compare event toggles OCx pin 010 = Initialize OCx pin high, compare event forces OCx pin low 001 = Initialize OCx pin low, compare event forces OCx pin high 000 = Output compare channel is disabled

bit 0

NOTES:

15.0 SERIAL PERIPHERAL INTERFACE (SPI)

- Note 1: This data sheet summarizes the features of the PIC24HJ32GP202/204 and PIC24HJ16GP304 family of devices. However, it is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to "Section 18. Serial Peripheral Interface (SPI)" (DS70206) of the "dsPIC33F/PIC24H Family Reference Manual", which is available from the Microchip website (www.microchip.com).
 - 2: Some registers and associated bits described in this section may not be available on all devices. Refer to Section 4.0 "Memory Organization" in this data sheet for device-specific register and bit information.

The Serial Peripheral Interface (SPI) module is a synchronous serial interface useful for communicating with other peripheral or microcontroller devices. These peripheral devices can be serial EEPROMs, shift registers, display drivers, Analog-to-Digital Converters (ADCs), and so on. The SPI module is compatible with Motorola[®] SPI and SIOP.

Each SPI module consists of a 16-bit shift register, SPIxSR (where x = 1 or 2), used for shifting data in and out, and a buffer register, SPIxBUF. A control register, SPIxCON, configures the module. Additionally, a status register, SPIxSTAT, indicates status conditions.

The serial interface consists of these four pins:

- SDIx (serial data input)
- SDOx (serial data output)
- SCKx (shift clock input or output)
- SSx (active-low slave select)

In Master mode operation, SCK is a clock output. In Slave mode, it is a clock input.



FIGURE 15-1: SPI MODULE BLOCK DIAGRAM

R/W-0	U-0	R/W-0	U-0	U-0	U-0	U-0	U-0				
SPIEN		SPISIDL	_	_	—	—	_				
bit 15						·	bit 8				
U-0	R/C-0	U-0	U-0	U-0	U-0	R-0	R-0				
	SPIROV				—	SPITBF	SPIRBF				
bit 7							bit (
Legend:		C = Clearable	bit								
R = Readat	ole hit	W = Writable I		LI = Unimpler	mented bit, rea	d as '0'					
-n = Value a		'1' = Bit is set		'0' = Bit is cle		x = Bit is unkr	NOWD				
bit 15	SPIEN: SPIX	Enable bit									
	1 = Enables r	module and con	figures SCK	x, SDOx, SDIx	and SSx as se	rial port pins					
	0 = Disables	module									
bit 14	Unimplemen	ted: Read as '0)'								
bit 13		SPISIDL: Stop in Idle Mode bit									
		ue module oper module operati			lle mode						
bit 12-7		ited: Read as '0									
bit 6											
bit 0		SPIROV: Receive Overflow Flag bit 1 = A new byte/word is completely received and discarded. The user software has not read the									
		previous data in the SPIxBUF register									
		0 = No overflow has occurred.									
bit 5-2	•	ted: Read as '0		1.14							
bit 1		x Transmit Buffe									
		1 = Transmit not yet started, SPIxTXB is full 0 = Transmit started, SPIxTXB is empty									
				writes SPIxBU	F location. load	dina SPIxTXB.					
		Automatically set in hardware when CPU writes SPIxBUF location, loading SPIxTXB. Automatically cleared in hardware when SPIx module transfers data from SPIxTXB to SPIxSR.									
bit 0	SPIRBF: SPI	x Receive Buffe	er Full Status	bit							
	1 = Receive of	complete, SPIxF	RXB is full								
	1 = Receive complete, SPIxRXB is full 0 = Receive is not complete, SPIxRXB is empty										
		0 = Receive is not complete, SPIxRXB is empty Automatically set in hardware when SPIx transfers data from SPIxSR to SPIxRXB.									
	Automatically	set in hardware	e when SPIx	transfers data		o SPIxRXB. reading SPIxRX					

REGISTER 15-1: SPIxSTAT: SPIx STATUS AND CONTROL REGISTER

U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0			
			DISSCK	DISSDO	MODE16	SMP	CKE ⁽¹⁾			
bit 15						•	bit			
R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0			
SSEN ⁽²) CKP	MSTEN		SPRE<2:0> ⁽³	i)	PPRE<	<1:0> ⁽³⁾			
bit 7							bit			
Legend:										
R = Reada	ble bit	W = Writable	bit	U = Unimplen	nented bit, rea	d as '0'				
-n = Value	at POR	'1' = Bit is se	t	'0' = Bit is cle	ared	x = Bit is unkr	nown			
bit 15-13	Unimplemen	nted: Read as	ʻ0'							
bit 12	-		bit (SPI Maste	r modes only)						
			abled, pin func	tions as I/O						
hit 11		SPI clock is ena								
bit 11		able SDOx pir	/ module; pin fi	unctions as I/O)					
		n is controlled b								
bit 10	MODE16: Wo	MODE16: Word/Byte Communication Select bit								
		1 = Communication is word-wide (16 bits) 0 = Communication is byte-wide (8 bits)								
h # 0		-								
bit 9	Master mode	ata Input Sam	ple Phase bit							
			nd of data outp	out time						
	-	a sampled at m	niddle of data o	output time						
	SMP must be	cleared when	SPIx is used i	n Slave mode						
bit 8		lock Edge Sele		n olave mode.						
		-		on from active of	clock state to le	dle clock state (see bit 6)			
						ve clock state (
bit 7			bit (Slave mod	de) ⁽²⁾						
		used for Slave		allad by mark	unation					
hit G	-	-	dule. Pin contr	olied by port fl	Inction					
bit 6		Polarity Select	bit high level; activ	ve state is a low	v level					
			ow level; active							
bit 5	MSTEN: Mas	ster Mode Enal	ole bit	-						
	1 = Master m									
	0 = Slave mo	ode								
	The CKE bit is not (FRMEN = 1).	t used in the Fr	amed SPI mod	des. Program ti	his bit to '0' for	the Framed SP	l modes			
2:	This bit must be cl	leared when Fl	RMEN = 1.							

REGISTER 15-2: SPIXCON1: SPIX CONTROL REGISTER 1

- 3: Do not set both Primary and Secondary prescalers to a value of 1:1.

REGISTER 15-2: SPIXCON1: SPIX CONTROL REGISTER 1 (CONTINUED)

bit 4-2	SPRE<2:0>: Secondary Prescale bits (Master mode) ⁽³⁾ 111 = Secondary prescale 1:1 110 = Secondary prescale 2:1
	•
	•
	•
	000 = Secondary prescale 8:1
bit 1-0	PPRE<1:0>: Primary Prescale bits (Master mode) ⁽³⁾
	11 = Primary prescale 1:1
	10 = Primary prescale 4:1
	01 = Primary prescale 16:1
	00 = Primary prescale 64:1

- **Note 1:** The CKE bit is not used in the Framed SPI modes. Program this bit to '0' for the Framed SPI modes (FRMEN = 1).
 - 2: This bit must be cleared when FRMEN = 1.
 - 3: Do not set both Primary and Secondary prescalers to a value of 1:1.

R/W-0	R/W-0	R/W-0	U-0	U-0	U-0	U-0	U-0
FRMEN	SPIFSD	FRMPOL	_	—	—	—	—
bit 15							bit 8
U-0	U-0	U-0	U-0	U-0	U-0	R/W-0	U-0
—	—	—	—	—	_	FRMDLY	—
bit 7							bit 0
Legend:							
R = Readable	bit	W = Writable	bit	U = Unimplen	nented bit, read	l as '0'	
-n = Value at POR '1' = Bit is set '0' =				'0' = Bit is cleared x = Bit is unknown			own
bit 15 bit 14 bit 13	1 = Framed S 0 = Framed S SPIFSD: Fran 1 = Frame syn 0 = Frame syn FRMPOL: Fra 1 = Frame syn	PIx support dis ne Sync Pulse nc pulse input (nc pulse output ame Sync Pulse nc pulse is activ	abled (SSx pi sabled Direction Cor (slave) (master) e Polarity bit ve-high		ie sync pulse ir	iput/output)	
bit 12-2 bit 1	Unimplemen	nc pulse is activ ted: Read as '(ime Sync Pulse nc pulse coincir)' e Edge Select				

REGISTER 15-3: SPIxCON2: SPIx CONTROL REGISTER 2

NOTES:

16.0 INTER-INTEGRATED CIRCUIT™ (I²C™)

- Note 1: This data sheet summarizes the features of the PIC24HJ32GP202/204 and PIC24HJ16GP304 family of devices. However, it is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to "Section 19. Inter-Integrated Circuit™ (I²CTM)" (DS70195) of the "dsPIC33Fj/PIC24H Family Reference Manual", which is available from the Microchip website (www.microchip.com).
 - Some registers and associated bits described in this section may not be available on all devices. Refer to Section 4.0 "Memory Organization" in this data sheet for device-specific register and bit information.

The Inter-Integrated Circuit (I^2C) module provides complete hardware support for both Slave and Multi-Master modes of the I^2C serial communication standard, with a 16-bit interface.

The I^2C module has a 2-pin interface:

- The SCLx pin is clock
- The SDAx pin is data.

The I²C module offers the following key features:

- I²C interface supporting both Master and Slave modes of operation
- I²C Slave mode supports 7-bit and 10-bit addressing
- I²C Master mode supports 7-bit and 10-bit addressing
- I²C port allows bidirectional transfers between master and slaves
- Serial clock synchronization for I²C port can be used as a handshake mechanism to suspend and resume serial transfer (SCLREL control)
- I²C supports multi-master operation, detects bus collision and arbitrates accordingly

16.1 Operating Modes

The hardware fully implements all the master and slave functions of the I^2C Standard and Fast mode specifications, as well as 7 and 10-bit addressing.

The I²C module can operate either as a slave or a master on an I²C bus.

The following types of I²C operation are supported:

- I²C slave operation with 7-bit addressing
- I²C slave operation with 10-bit addressing
- I²C master operation with 7-bit or 10-bit addressing

For details about the communication sequence in each of these modes, refer to the *"dsPIC33F/PIC24H Family Reference Manual"*.

16.2 I²C Registers

I2CxCON and I2CxSTAT are control and status registers, respectively. The I2CxCON register is readable and writable. The lower six bits of I2CxSTAT are read-only. The remaining bits of the I2CSTAT are read/write.

- I2CxRSR is the shift register used for shifting data
- I2CxRCV is the receive buffer and the register to which data bytes are written, or from which data bytes are read
- I2CxTRN is the transmit register to which bytes are written during a transmit operation
- The I2CxADD register holds the slave address
- A status bit, ADD10, indicates 10-bit Address mode
- I2CxBRG acts as the Baud Rate Generator (BRG) reload value

In receive operations, I2CxRSR and I2CxRCV together form a double-buffered receiver. When I2CxRSR receives a complete byte, it is transferred to I2CxRCV, and an interrupt pulse is generated.


R/W-0	U-0	R/W-0	R/W-1 HC	R/W-0	R/W-0	R/W-0	R/W-0			
I2CEN		I2CSIDL	SCLREL	IPMIEN	A10M	DISSLW	SMEN			
bit 15							bit 8			
R/W-0	R/W-0	R/W-0	R/W-0 HC	R/W-0 HC	R/W-0 HC	R/W-0 HC	R/W-0 HC			
GCEN	STREN	ACKDT	ACKEN	RCEN	PEN	RSEN	SEN			
bit 7		_	<u> </u>				bit C			
Legend:		U = Unimpler	nented bit, read	d as '0'						
R = Readable	e bit	W = Writable		HS = Set in h	ardware	HC = Cleared	in hardware			
-n = Value at	POR	'1' = Bit is set		'0' = Bit is cle	ared	x = Bit is unkn	iown			
							-			
bit 15	12CEN: 12Cx	Enable bit								
			e and configure	es the SDAx a	and SCLx pins a	as serial port pir	าร			
		the I2Cx modu								
bit 14	Unimplemer	nted: Read as '	0'							
bit 13	I2CSIDL: Sto	op in Idle Mode	bit							
		nue module ope module operat			n Idle mode					
bit 12	SCLREL: SCLx Release Control bit (when operating as I ² C slave)									
	1 = Release SCLx clock									
	0 = Hold SCLx clock low (clock stretch)									
	If STREN = 1: Bit is R/W (i.e., software can write '0' to initiate stretch and write '1' to release clock). Hardware clea at beginning of slave transmission. Hardware clear at end of slave reception.									
	If STREN = (puon.				
		., software can	only write '1' to	release cloc	k). Hardware cl	lear at beginning	g of slave			
bit 11	IPMIEN: Inte	lligent Peripher	al Managemen	t Interface (IP	MI) Enable bit					
	1 = IPMI mod 0 = IPMI mod	de is enabled; a de disabled	III addresses Ad	cknowledged						
bit 10	A10M: 10-bit Slave Address bit									
) is a 10-bit slav) is a 7-bit slave								
bit 9	DISSLW: Disable Slew Rate Control bit									
		e control disable								
bit 8	 0 = Slew rate control enabled SMEN: SMBus Input Levels bit 									
	1 = Enable I/	O pin threshold	s compliant wit	h SMBus spe	cification					
bit 7	GCEN: Gene	0 = Disable SMBus input thresholds GCEN: General Call Enable bit (when operating as I^2C slave)								
	(module	nterrupt when a is enabled for call address di	reception)	ddress is rece	eived in the I2C	xRSR				
	e conorui				120 1					
bit 6	STREN: SCI	x Clock Stretch	n Enable bit (wh	nen operating	as (+C slave)					
bit 6		_x Clock Stretch	-	nen operating	as I ² C slave)					
bit 6	Used in conju	-x Clock Stretch unction with SC oftware or rece	LREL bit.		as I ² C slave)					

REGISTER 16-1: I2CxCON: I2Cx CONTROL REGISTER

REGISTER 16-1: I2CxCON: I2Cx CONTROL REGISTER (CONTINUED)

bit 5	ACKDT: Acknowledge Data bit (when operating as I ² C master, applicable during master receive)
	Value that will be transmitted when the software initiates an Acknowledge sequence. 1 = Send NACK during Acknowledge 0 = Send ACK during Acknowledge
bit 4	ACKEN: Acknowledge Sequence Enable bit (when operating as I ² C master, applicable during master receive)
	 1 = Initiate Acknowledge sequence on SDAx and SCLx pins and transmit ACKDT data bit. Hardware clear at end of master Acknowledge sequence 0 = Acknowledge sequence not in progress
bit 3	RCEN: Receive Enable bit (when operating as I ² C master)
	1 = Enables Receive mode for I^2C . Hardware clear at end of eighth bit of master receive data byte 0 = Receive sequence not in progress
bit 2	PEN: Stop Condition Enable bit (when operating as I ² C master)
	 1 = Initiate Stop condition on SDAx and SCLx pins. Hardware clear at end of master Stop sequence 0 = Stop condition not in progress
bit 1	RSEN: Repeated Start Condition Enable bit (when operating as I ² C master)
	 1 = Initiate Repeated Start condition on SDAx and SCLx pins. Hardware clear at end of master Repeated Start sequence
	0 = Repeated Start condition not in progress
bit 0	SEN: Start Condition Enable bit (when operating as I ² C master)
	 1 = Initiate Start condition on SDAx and SCLx pins. Hardware clear at end of master Start sequence 0 = Start condition not in progress

R-0 HSC	R-0 HSC	U-0	U-0	U-0	R/C-0 HS	R-0 HSC	R-0 HSC			
ACKSTAT	TRSTAT	—	—		BCL	GCSTAT	ADD10			
bit 15							bit 8			
L										
R/C-0 HS	R/C-0 HS	R-0 HSC	R/C-0 HSC	R/C-0 HSC	R-0 HSC	R-0 HSC	R-0 HSC			
IWCOL	I2COV	D_A	Р	S	R_W	RBF	TBF			
bit 7							bit 0			
Legend:		U = Unimplei	mented bit, rea	ad as '0'						
R = Readable	bit	W = Writable	bit	HS = Set in h	ardware	HSC = Hardw	are set/cleared			
-n = Value at I	POR	'1' = Bit is se	t	'0' = Bit is cle	ared	x = Bit is unkr	nown			
bit 15		cknowledge St				、				
		ceived from sla		e to master trar	nsmit operation)				
		eived from slav								
	Hardware set	or clear at en	d of slave Ack	nowledge.						
bit 14	TRSTAT: Tra	nsmit Status bi	t (when opera	ting as I ² C ma	ster, applicable	to master trans	smit operation)			
		= Master transmit is in progress (8 bits + ACK)								
	 0 = Master transmit is not in progress Hardware set at beginning of master transmission. Hardware clear at end of slave Acknowledge. 									
bit 13-11		ited: Read as					nowledge.			
bit 10	-	Bus Collision								
Dit 10	1 = A bus collision has been detected during a master operation									
	0 = No collision									
		at detection o								
bit 9		neral Call State								
		call address wa call address wa		4						
					ss. Hardware d	lear at Stop det	tection.			
bit 8	ADD10: 10-b	it Address Stat	tus bit							
	1 = 10-bit address was matched									
	 0 = 10-bit address was not matched Hardware set at match of 2nd byte of matched 10-bit address. Hardware clear at Stop detection. 									
bit 7		e Collision Det	-	ched 10-bit ad	dress. Hardwar	re clear at Stop	detection.			
Dit 7				ster failed heca	ause the l^2C mo	odule is busy				
	 1 = An attempt to write the I2CxTRN register failed because the I²C module is busy 0 = No collision 									
	Hardware set at occurrence of write to I2CxTRN while busy (cleared by software).									
bit 6		ive Overflow F	•							
	-		ile the I2CxR0	CV register is s	till holding the	previous byte				
	 0 = No overflow Hardware set at attempt to transfer I2CxRSR to I2CxRCV (cleared by software). 									
bit 5		ddress bit (whe			(,,,,,,,	,				
		that the last by								
				as device add						
1.11.4		ar at device ad	dress match.	Hardware set	by reception of	slave byte.				
bit 4	P: Stop bit	that a Stan hit	has been det	octod loot						
		that a Stop bit as not detecte								
				ed Start or Sto	p detected.					

REGISTER 16-2: I2CxSTAT: I2Cx STATUS REGISTER

REGISTER 16-2: I2CxSTAT: I2Cx STATUS REGISTER (CONTINUED)

bit 3	S: Start bit
	1 = Indicates that a Start (or Repeated Start) bit has been detected last 0 = Start bit was not detected last
	Hardware set or clear when Start, Repeated Start or Stop detected.
bit 2	R_W: Read/Write Information bit (when operating as I ² C slave)
	 1 = Read – indicates data transfer is output from slave 0 = Write – indicates data transfer is input to slave Hardware set or clear after reception of I²C device address byte.
bit 1	RBF: Receive Buffer Full Status bit
	 1 = Receive complete, I2CxRCV is full 0 = Receive not complete, I2CxRCV is empty Hardware set when I2CxRCV is written with received byte. Hardware clear when software reads I2CxRCV.
bit 0	TBF: Transmit Buffer Full Status bit
	 1 = Transmit in progress, I2CxTRN is full 0 = Transmit complete, I2CxTRN is empty Hardware set when software writes I2CxTRN. Hardware clear at completion of data transmission.

REGISTER 16-3: I2CxMSK: I2Cx SLAVE MODE ADDRESS MASK REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0
_	_	—	—	—		AMSK9	AMSK8
bit 15	-						bit 8
R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
AMSK7	AMSK6	AMSK5	AMSK4	AMSK3	AMSK2	AMSK1	AMSK0
bit 7		•		·			bit 0
Legend:							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit,	read as '0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-10 Unimplemented: Read as '0'

bit 9-0

AMSKx: Mask for Address bit x Select bit

1 = Enable masking for bit x of incoming message address; bit match not required in this position

0 = Disable masking for bit x; bit match required in this position

NOTES:

17.0 UNIVERSAL ASYNCHRONOUS RECEIVER TRANSMITTER (UART)

- Note 1: This data sheet summarizes the features of the PIC24HJ32GP202/204 and PIC24HJ16GP304 family of devices. However, it is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to "Section 17. UART" (DS70188) of the "dsPIC33F/PIC24H Family Reference Manual", which is available from the Microchip website (www.microchip.com).
 - Some registers and associated bits described in this section may not be available on all devices. Refer to Section 4.0 "Memory Organization" in this data sheet for device-specific register and bit information.

The Universal Asynchronous Receiver Transmitter (UART) module is one of the serial I/O modules available in the PIC24HJ32GP202/204 and PIC24HJ16GP304 device family. The UART is a asynchronous system that full-duplex can communicate with peripheral devices, such as personal computers, LIN, RS-232 and RS-485 interfaces. The module also supports a hardware flow control option with the UxCTS and UxRTS pins and also includes an IrDA[®] encoder and decoder.

The primary features of the UART module are:

- Full-Duplex 8-bit or 9-bit Data Transmission through the UxTX and UxRX pins
- Even, odd or no parity options (for 8-bit data)
- One or two stop bits
- Hardware Flow Control Option with UxCTS and UxRTS pins
- Fully Integrated Baud Rate Generator with 16-bit prescaler
- Baud rates ranging from 10 Mbps to 38 bps at 40 MIPS
- 4-deep first-in-first-out (FIFO) Transmit Data Buffer
- 4-deep FIFO Receive Data Buffer
- Parity, framing and buffer overrun error detection
- Support for 9-bit mode with Address Detect (9th bit = 1)
- Transmit and Receive interrupts
- · A separate interrupt for all UART error conditions
- Loopback mode for diagnostic support
- Support for Sync and Break characters
- · Support for automatic baud rate detection
- IrDA[®] encoder and decoder logic
- 16x baud clock output for IrDA[®] support

A simplified block diagram of the UART module is shown in Figure 17-1. The UART module consists of the following key hardware elements:

- Baud Rate Generator
- Asynchronous Transmitter
- Asynchronous Receiver

FIGURE 17-1: UART SIMPLIFIED BLOCK DIAGRAM



R/W-0	U-0	R/W-0	R/W-0	R/W-0	U-0	R/W-0	R/W-0			
UARTEN ⁽¹⁾	_	USIDL	IREN ⁽²⁾	RTSMD	—	UEN	<1:0>			
bit 15							bit 8			
R/W-0 HC	R/W-0		R/W-0	R/W-0	R/W-0	R/W-0	R/W-0			
		R/W-0, HC					STSEL			
WAKE bit 7	LPBACK	ABAUD	URXINV	BRGH	PDSEI	_<1.0>	bit			
							DIL			
Legend:		HC = Hardwa	re Clearable							
R = Readable	bit	W = Writable	bit	U = Unimpler	mented bit, read	l as '0'				
-n = Value at F	POR	'1' = Bit is set		'0' = Bit is cle	ared	x = Bit is unkr	iown			
bit 15	UARTEN: UA	RTx Enable bi	t(1)							
	1 = UARTx is	s enabled; all U	IARTx pins ar	e controlled by	UARTx as defi	ned by UEN<1:	0>			
	0 = UARTx is	disabled; all UA	ARTx pins are	controlled by pc	ort latches; UAR	Tx power consur	nption minima			
bit 14	Unimplemen	ted: Read as '	0'							
bit 13	USIDL: Stop	in Idle Mode bi	t							
	 1 = Discontinue module operation when device enters Idle mode 0 = Continue module operation in Idle mode 									
		-								
bit 12	IREN: IrDA [®] Encoder and Decoder Enable bit ⁽²⁾ 1 = IrDA [®] encoder and decoder enabled									
	$1 = IrDA^{\text{B}}$ encoder and decoder enabled $0 = IrDA^{\text{B}}$ encoder and decoder disabled									
bit 11	RTSMD: Mode Selection for UxRTS Pin bit									
		oin in Simplex n A Flow Con								
bit 10	•	ted: Read as '								
bit 9-8	•	IARTx Enable b								
	11 = UxTX,	UxRX and BCL	K pins are en	abled and use	d; UxCTS pin c	ontrolled by por	t latches			
	10 = UxTX, UxRX, UxCTS and UxRTS pins are enabled and used									
	01 = UxTX, UxRX and UxRTS pins are enabled and used; UxCTS pin controlled by port latches 00 = UxTX and UxRX pins are enabled and used; UxCTS and UxRTS/BCLK pins controlled by									
	port lat		are enabled a	and used; UXC	15 and UXR15/	BULK pins con	trolled by			
bit 7	•	-up on Start bit	t Detect Durin	g Sleep Mode	Enable bit					
	1 = UARTx w	vill continue to	sample the Ux	kRX pin; interru	pt generated o	n falling edge; k	oit cleared			
	in hardware on following rising edge									
	0 = No wake	-								
bit 6	LPBACK: UARTx Loopback Mode Select bit									
	 1 = Enable Loopback mode 0 = Loopback mode is disabled 									
bit 5		o-Baud Enable								
	1 = Enable b	aud rate meas	urement on th	ne next charact	er – requires re	eception of a Sy	/nc field (55h			
		her data; clear			tion					
	A – Boud rote	a magguraman	t disabled or o	completed						
				ompiotou						
bit 4		ceive Polarity Ir		Joinpieted						

REGISTER 17-1: UXMODE: UARTX MODE REGISTER

- **Note 1:** Refer to **Section 17. "UART**" (DS70188) in the *"dsPIC33F/PIC24H Family Reference Manual"* for information on enabling the UART module for receive or transmit operation.
 - 2: This feature is only available for the 16x BRG mode (BRGH = 0).

REGISTER 17-1: UXMODE: UARTX MODE REGISTER (CONTINUED)

- bit 3 BRGH: High Baud Rate Enable bit
 - 1 = BRG generates 4 clocks per bit period (4x baud clock, High-Speed mode)
 - 0 = BRG generates 16 clocks per bit period (16x baud clock, Standard mode)

bit 2-1 **PDSEL<1:0>:** Parity and Data Selection bits

- 11 = 9-bit data, no parity
- 10 = 8-bit data, odd parity
 - 01 = 8-bit data, even parity
- 00 = 8-bit data, no parity
- bit 0 STSEL: Stop Bit Selection bit
 - 1 = Two Stop bits
 - 0 = One Stop bit
- **Note 1:** Refer to **Section 17. "UART"** (DS70188) in the *"dsPIC33F/PIC24H Family Reference Manual"* for information on enabling the UART module for receive or transmit operation.
 - **2:** This feature is only available for the 16x BRG mode (BRGH = 0).

R/W-0	R/W-0	R/W-0	U-0	R/W-0 HC	R/W-0	R-0	R-1			
UTXISEL1	UTXINV	UTXISEL0	—	UTXBRK	UTXEN ⁽¹⁾	UTXBF	TRMT			
bit 15		1					bit 8			
R/W-0	R/W-0	R/W-0	R-1	R-0	R-0	R/C-0	R-0			
URXISE	L<1:0>	ADDEN	RIDLE	PERR	FERR	OERR	URXDA			
bit 7							bit (
Legend:		HC = Hardwar	e cleared		C = Clea	r only hit				
R = Readable	bit	W = Writable t		U = Unimpler	nented bit, read					
-n = Value at P		(1) = Bit is set		'0' = Bit is cle		x = Bit is unkr				
					areu		IOWIT			
bit 15,13	UTXISEL<1:	0>: Transmissio	n Interrupt M	ode Selection I	bits					
, -		ed; do not use								
		t when a charac	ter is transfe	rred to the Trar	nsmit Shift Regi	ster, and as a r	esult, the			
		t buffer become								
		t when the last o		hifted out of the	e Transmit Shift	Register; all tra	ansmit			
	operations are completed 00 = Interrupt when a character is transferred to the Transmit Shift Register (this implies there is									
		one character o			lonne onne reogn					
bit 14	UTXINV: Transmit Polarity Inversion bit									
	If $IREN = 0$:									
	1 = UxTX Idle state is '0'									
	0 = UxTX Idle state is '1'									
	$\frac{\text{If IREN} = 1:}{1 = \text{IrDA}^{\text{®}} \text{ encoded UxTX Idle state is '1'}}$									
	$1 = IrDA^{\mathbb{R}} er$	ncoded UxTX Id	e state is '1'							
		coded UxTX Id								
bit 12	-	nted: Read as '0								
bit 11	UTXBRK: Transmit Break bit									
	1 = Send Sync Break on next transmission – Start bit, followed by twelve '0' bits, followed by Stop bi cleared by hardware upon completion									
	0 = Sync Break transmission disabled or completed									
bit 10		nsmit Enable bit								
	1 = Transmit enabled, UxTX pin controlled by UARTx									
	0 = Transmit disabled, any pending transmission is aborted and buffer is reset. UxTX pin controlled									
	by port									
bit 9		smit Buffer Full	Status bit (re	ad-only)						
	1 = Transmit buffer is full									
L:0		0 = Transmit buffer is not full, at least one more character can be written TRMT: Transmit Shift Register Empty bit (read-only)								
					ompty (the lest	transmission h	ac completed			
bit 8	 1 = Transmit Shift Register is empty and transmit buffer is empty (the last transmission has completed 0 = Transmit Shift Register is not empty, a transmission is in progress or queued 									
DIT 8	0 = Transmit									
bit 7-6			s not empty,	a transmission						
	URXISEL<1:	Shift Register is	s not empty, errupt Mode	a transmission Selection bits	is in progress o	r queued				
	URXISEL<1: 11 = Interrup 10 = Interrup	Shift Register is 0>: Receive Inte	s not empty, errupt Mode SR transfer m SR transfer m	a transmission Selection bits aking the recei aking the recei	is in progress o ve buffer full (i.e ve buffer 3/4 ful	r queued e., has 4 data c I (i.e., has 3 da	haracters) ta characters			

REGISTER 17-2: UxSTA: UARTx STATUS AND CONTROL REGISTER

Note 1: Refer to **Section 17. "UART**" (DS70188) in the *"dsPIC33F/PIC24H Family Reference Manual"* for information on enabling the UART module for transmit operation.

REGISTER 17-2: UxSTA: UARTx STATUS AND CONTROL REGISTER (CONTINUED)

bit 5	ADDEN: Address Character Detect bit (bit 8 of received data = 1)
	 1 = Address Detect mode enabled. If 9-bit mode is not selected, this does not take effect 0 = Address Detect mode disabled
bit 4	RIDLE: Receiver Idle bit (read-only)
	1 = Receiver is Idle0 = Receiver is active
bit 3	PERR: Parity Error Status bit (read-only)
	 1 = Parity error has been detected for the current character (character at the top of the receive FIFO) 0 = Parity error has not been detected
bit 2	FERR: Framing Error Status bit (read-only)
	1 = Framing error has been detected for the current character (character at the top of the receive FIFO)
	0 = Framing error has not been detected
bit 1	OERR: Receive Buffer Overrun Error Status bit (read/clear only)
	 1 = Receive buffer has overflowed 0 = Receive buffer has not overflowed. Clearing a previously set OERR bit (1 →0 transition) will reset the receiver buffer and the UxRSR to the empty state
bit 0	URXDA: Receive Buffer Data Available bit (read-only)
	 1 = Receive buffer has data, at least one more character can be read 0 = Receive buffer is empty
Note 1:	Refer to Section 17. "UART" (DS70188) in the "dsPIC33F/PIC24H Family Reference Manual" for

information on enabling the UART module for transmit operation.

NOTES:

18.0 10-BIT/12-BIT ANALOG-TO-DIGITAL CONVERTER (ADC)

- Note 1: This data sheet summarizes the features of the PIC24HJ32GP202/204 and PIC24HJ16GP304 family of devices. However, it is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to "Section 16. Analog-to-Digital Converter (ADC)" (DS70183) of the "dsPIC33F/PIC24H Family Reference Manual", which is available from the Microchip website (www.microchip.com).
 - Some registers and associated bits described in this section may not be available on all devices. Refer to Section 4.0 "Memory Organization" in this data sheet for device-specific register and bit information.

The PIC24HJ32GP202/204 and PIC24HJ16GP304 devices have up to 13 Analog-to-Digital Conversion (ADC) module input channels.

The AD12B bit (AD1CON1<10>) allows each of the ADC modules to be configured as either a 10-bit, 4-sample-and-hold ADC (default configuration), or a 12-bit, 1- sample and hold ADC.

Note: The ADC module must be disabled before the AD12B bit can be modified.

18.1 Key Features

The 10-bit ADC configuration has the following key features:

- Successive Approximation (SAR) conversion
- Conversion speeds of up to 1.1 Msps
- Up to 13 analog input pins
- External voltage reference input pins
- Simultaneous sampling of up to four analog input pins
- Automatic Channel Scan mode
- Selectable conversion trigger source
- Selectable Buffer Fill modes
- Operation during CPU Sleep and Idle modes
- 16-word conversion result buffer

The 12-bit ADC configuration supports all the above features, except:

- In the 12-bit configuration, conversion speeds of up to 500 ksps are supported
- There is only 1 sample-and-hold amplifier in the 12-bit configuration, so simultaneous sampling of multiple channels is not supported

Depending on the particular device pinout, the ADC can have up to 13 analog input pins, designated AN0 through AN12. In addition, there are two analog input pins for external voltage reference connections. These voltage reference inputs can be shared with other analog input pins.

The actual number of analog input pins and external voltage reference input configuration will depend on the specific device. Refer to the device data sheet for further details.

A block diagram of ADC for PIC24HJ16GP304 and PIC24HJ32GP204 devices is shown in Figure 18-1. A block diagram of the ADC for the PIC24HJ32GP202 device is shown in Figure 18-2.

18.2 ADC Initialization

To configure the ADC module:

- 1. Select port pins as analog inputs (AD1PCFGH<15:0> or AD1PCFGL<15:0>).
- Select voltage reference source to match expected range on analog inputs (AD1CON2<15:13>).
- Select the analog conversion clock to match desired data rate with processor clock (AD1CON3<7:0>).
- 4. Determine how many sample-and-hold channels will be used (AD1CON2<9:8> and AD1PCFGH<15:0> or AD1PCFGL<15:0>).
- 5. Select the appropriate sample/conversion sequence (AD1CON1<7:5> and AD1CON3<12:8>).
- 6. Select the way conversion results are presented in the buffer (AD1CON1<9:8>).
- 7. Turn on the ADC module (AD1CON1<15>).
- 8. Configure ADC interrupt (if required):
 - a) Clear the AD1IF bit.
 - b) Select ADC interrupt priority.





FIGURE 18-3: ADC CONVERSION CLOCK PERIOD BLOCK DIAGRAM



REGISTER	18-1: AD1C	ON1: ADC1 (CONTROL R	EGISTER 1						
R/W-0	U-0	R/W-0	U-0	U-0	R/W-0	R/W-0	R/W-0			
ADON		ADSIDL		—	AD12B	FORM	1<1:0>			
bit 15							bit 8			
R/W-0	R/W-0	R/W-0	U-0	R/W-0	R/W-0	R/W-0 HC,HS	R/C-0 HC, HS			
	SSRC<2:0>			SIMSAM	ASAM	SAMP	DONE			
bit 7			·				bit 0			
Legend:		HC = Cleared	by hardware	HS = Set by h	ardware	C = Clear only	y bit			
R = Readable	e bit	W = Writable	bit	U = Unimplen	nented bit, rea	ıd as '0'				
-n = Value at	POR	'1' = Bit is set		'0' = Bit is clea		x = Bit is unki	nown			
bit 15		Operating Moc dule is operatir								
bit 14	Unimplemer	ted: Read as '	0'							
bit 13	ADSIDL: Sto	p in Idle Mode	bit							
		nue module op e module opera		device enters Id	le mode					
bit 12-11		ited: Read as '		ide						
bit 10	-			.;4						
bit to	1 = 12-bit, 1	it or 12-bit Ope -channel ADC -channel ADC o	operation	nt.						
bit 9-8	FORM<1:0>: Data Output Format bits									
	00 = Integer For 12-bit op 11 = Reserve 10 = Reserve 01 = Signed 00 = Integer	ed ed (DOUT = 0000 eration: ed ed Integer (DOUT = (DOUT = 0000	00dd dddd = ssss sddd dddd dddd	dddd dddd, w dddd)						
bit 7-5	SSRC<2:0>:	Sample Clock	Source Select	t bits						
	110 = Resen 101 = Resen 100 = Resen 011 = Resen 010 = GP tim 001 = Active	ved ved ved ved her 3 compare e transition on IN	ends sampling IT0 pin ends s	and starts conversion and starts conversion sampling and starts conversion	version arts conversion					
bit 4		ted: Read as '								
bit 3	SIMSAM: Sir When AD12I 1 = Samples Samples	multaneous Sar B = 1, SIMSAN s CH0, CH1, CH	mple Select bi I is: U-0, Unin I2, CH3 simul simultaneous	t (applicable onl nplemented, R taneously (wher ly (when CHPS- y in sequence	ead as '0' CHPS<1:0>		Lx)			

REGISTER 18-1: AD1CON1: ADC1 CONTROL REGISTER 1

REGISTER 18-1: AD1CON1: ADC1 CONTROL REGISTER 1 (CONTINUED)

bit 2	ASAM: ADC Sample Auto-Start bit
	 1 = Sampling begins immediately after last conversion. SAMP bit is auto-set 0 = Sampling begins when SAMP bit is set
bit 1	SAMP: ADC Sample Enable bit
	 1 = ADC sample-and-hold amplifiers are sampling 0 = ADC sample-and-hold amplifiers are holding If ASAM = 0, software can write '1' to begin sampling. Automatically set by hardware if ASAM = 1. If SSRC = 000, software can write '0' to end sampling and start conversion. If SSRC ≠ 000, automatically cleared by hardware to end sampling and start conversion.
bit 0	DONE: ADC Conversion Status bit
	 1 = ADC conversion cycle is completed 0 = ADC conversion not started or in progress

Automatically set by hardware when ADC conversion is complete. Software can write '0' to clear DONE status (software not allowed to write '1'). Clearing this bit will not affect any operation in progress. Automatically cleared by hardware at start of a new conversion.

REGISTER 18-2: AD1CON2: ADC1 CONTROL REGISTER 2

R/W-0	R/W-0	R/W-0	U-0	U-0	R/W-0	R/W-0	R/W-0
VCFG<2:0>				—	CSCNA	CHPS	<1:0>
bit 15			·	•			bit
R-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
BUFS		SMPI<3:0>				BUFM	ALTS
oit 7						•	bit

Legena:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, rea	d as '0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-13

bit bit

bit

bit

bit

13 VCFG<2:0>: Converter Voltage Reference Configuration bits

		ADREF+	ADREF-
	000	Avdd	Avss
	001	External VREF+	Avss
	010	Avdd	External VREF-
	011	External VREF+	External VREF-
	1xx	Avdd	Avss
: 12-11 : 10	CSCN 1 = Sc	lemented: Read a A: Scan Input Select can inputs	
9-8		o not scan inputs < 1:0>: Select Chan	nels Utilized bits
	1x = C 01 = C	AD12B = 1, CHPS converts CH0, CH1, converts CH0 and C converts CH0	CH2 and CH3
: 7	1 = A[Buffer Fill Status b DC is currently filling DC is currently filling	g second half of bu
t 6	Unimp	lemented: Read as	s '0'
t 5-2	SMPI<	3:0>: Sample/Conv	vert Sequences Pe

bit 5-2	SMPI<3:0>: Sample/Convert Sequences Per Interrupt Selection bits
	1111 = Interrupts at the completion of conversion for each 16th sample/convert sequence 1110 = Interrupts at the completion of conversion for each 15th sample/convert sequence
	•
	•
	•
	0001 = Interrupts at the completion of conversion for each 2nd sample/convert sequence 0000 = Interrupts at the completion of conversion for each sample/convert sequence
bit 1	BUFM: Buffer Fill Mode Select bit
	 1 = Starts filling first half of buffer on first interrupt and the second half of buffer on next interrupt 0 = Always starts filling buffer from the beginning
bit 0	ALTS: Alternate Input Sample Mode Select bit
	 1 = Uses channel input selects for Sample A on first sample and Sample B on next sample 0 = Always uses channel input selects for Sample A

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R/W-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
ADRC	—	_			SAMC<4:0>(1)	
bit 15							bit 8
U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
h:+ 7			ADCS	<7:0> ⁽²⁾			h:+ (
bit 7							bit (
Legend:							
R = Readabl	e bit	W = Writable I	bit	U = Unimplei	mented bit, rea	ad as '0'	
-n = Value at	POR	'1' = Bit is set		'0' = Bit is cle	ared	x = Bit is unk	nown
bit 15		Conversion Clo	ock Source bit				
		rnal RC clock rived from syste	m clock				
bit 14-13		nted: Read as '0					
bit 12-8	=	: Auto Sample T					
	11111 = 31	•					
	•						
	•						
	•						
	00001 = 1 TA 00000 = 0 TA						
bit 7-0	ADCS<7:0>:	ADC Conversio	on Clock Sele	ct bits ⁽²⁾			
	11111111 =	Reserved					
	•						
	•						
	•						
	•						
	01000000 =	Reserved TCY · (ADCS<7	7:0> + 1) - 64				
	•		r.02 + 1) = 04				
	•						
	•						
		TCY · (ADCS<7					
		TCY · (ADCS<7 TCY · (ADCS<7					
	0000000		7.7 4. 4	$\Gamma_{OV} - T_{AD}$			

- - 2: This bit is not used if AD1CON3<15> (ADRC) = 1.

REGISTER 18-4: AD1CHS123: ADC1 INPUT CHANNEL 1, 2, 3 SELECT REGISTER

U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0
—	—	—	—	—	CH123N	IB<1:0>	CH123SB
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0
—	_		—	—	CH123N	IA<1:0>	CH123SA
bit 7							bit 0

Legend:

bit 8

Legena.							
R = Readable bit W = Writable bit		U = Unimplemented bit	U = Unimplemented bit, read as '0'				
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown				

bit 15-11 Unimplemented: Read as '0'

bit 10-9 CH123NB<1:0>: Channel 1, 2, 3 Negative Input Select for Sample B bits PIC24HJ32GP202 devices only:

If AD12B = 1: 11 = Reserved 10 = Reserved 01 = Reserved 00 = Reserved

If AD12B = 0:

11 = CH1 negative input is AN9, CH2 negative input is AN10, CH3 negative input is AN11

10 = Reserved

01 = CH1, CH2, CH3 negative input is VREF-

00 = CH1, CH2, CH3 negative input is VREF-

PIC24HJ32GP204 and PIC24HJ16GP304 devices only:

- If AD12B = 1: 11 = Reserved 10 = Reserved 01 = Reserved 00 = Reserved

If AD12B = 0: 11 = CH1 negative input is AN9, CH2 negative input is AN10, CH3 negative input is AN11 10 = CH1 negative input is AN6, CH2 negative input is AN7, CH3 negative input is AN8 01 = CH1, CH2, CH3 negative input is VREF-00 = CH1, CH2, CH3 negative input is VREF- **CH123SB:** Channel 1, 2, 3 Positive Input Select for Sample B bit If AD12B = 1: 1 = Reserved

0 = Reserved

<u>If AD12B = 0:</u>

1 = CH1 positive input is AN3, CH2 positive input is AN4, CH3 positive input is AN5 0 = CH1 positive input is AN0, CH2 positive input is AN1, CH3 positive input is AN2

bit 7-3 Unimplemented: Read as '0'

REGISTER 18-4: AD1CHS123: ADC1 INPUT CHANNEL 1, 2, 3 SELECT REGISTER (CONTINUED)

bit 2-1 CH123NA<1:0>: Channel 1, 2, 3 Negative Input Select for Sample A bits

PIC24HJ32GP202 devices only:

If AD12B = 1:

- 11 = Reserved
- 10 = Reserved
- 01 = Reserved
- 00 = Reserved

If AD12B = 0:

11 = CH1 negative input is AN9, CH2 negative input is AN10, CH3 negative input is AN11

- 10 = Reserved
- 01 = CH1, CH2, CH3 negative input is VREF-
- 00 = CH1, CH2, CH3 negative input is VREF-

PIC24HJ32GP204 and PIC24HJ16GP304 devices only:

If AD12B = 1:

- 11 = Reserved
- 10 = Reserved
- 01 = Reserved
- 00 = Reserved

If AD12B = 0:

11 = CH1 negative input is AN9, CH2 negative input is AN10, CH3 negative input is AN11 10 = CH1 negative input is AN6, CH2 negative input is AN7, CH3 negative input is AN8

- 01 = CH1, CH2, CH3 negative input is VREF-
- 00 = CH1, CH2, CH3 negative input is VREF-

CH123SA: Channel 1, 2, 3 Positive Input Select for Sample A bit

If AD12B = 1:

bit 0

1 = Reserved

0 = Reserved

If AD12B = 0:

- 1 = CH1 positive input is AN3, CH2 positive input is AN4, CH3 positive input is AN5
- 0 = CH1 positive input is AN0, CH2 positive input is AN1, CH3 positive input is AN2

REGISTER 1	8-5: AD1C	H50: ADC1 II	NPUT CHAN	NEL 0 SELE		τ.	
R/W-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
CH0NB	—	—			CH0SB<4:0>		
bit 15							bit 8
R/W-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
CHONA	_	_			CH0SA<4:0>		
bit 7							bit 0
Legend:							
R = Readable	bit	W = Writable	bit	U = Unimple	mented bit, read	l as '0'	
-n = Value at I	POR	'1' = Bit is set		'0' = Bit is cl		x = Bit is unkr	nown
bit 15	1 = Channel	annel 0 Negative 0 negative inpu 0 negative inpu	t is AN1	for Sample B I	oit		
bit 14-13	Unimplemer	nted: Read as '	0'				
bit 12-8	PIC24HJ32G 01100 = Cha 00010 = Cha 00001 = Cha 00000 = Cha PIC24HJ32G	served	24HJ16GP304 input is AN12 input is AN2 input is AN1 input is AN0 only:	l devices only			
	00001 = Ch a	annel 0 positive annel 0 positive					
bit 7	CH0NA: Cha 1 = Channel	annel 0 positive annel 0 Negative 0 negative inpu 0 negative inpu	e Input Select it is AN1	for Sample A I	bit		

REGISTER 18-5: AD1CHS0: ADC1 INPUT CHANNEL 0 SELECT REGISTER

REGISTER 18-5: AD1CHS0: ADC1 INPUT CHANNEL 0 SELECT REGISTER (CONTINUED)

bit 4-0	CH0SA<4:0>: Channel 0 Positive Input Select for Sample A bits
	PIC24HJ32GP204 and PIC24HJ16GP304 devices only:
	01100 = Channel 0 positive input is AN12
	•
	•
	•
	00010 = Channel 0 positive input is AN2
	00001 = Channel 0 positive input is AN1
	00000 = Channel 0 positive input is AN0
	PIC24HJ32GP202 devices only:
	01100 = Channel 0 positive input is AN12
	•
	•
	•
	01000 = Reserved
	00111 = Reserved
	00110 = Reserved
	•
	•
	•
	00010 = Channel 0 positive input is AN2
	00001 = Channel 0 positive input is AN1
	00000 = Channel 0 positive input is AN0
	······································

							Dit (
bit 7	•		•	•		•	bit (
CSS7	CSS6	CSS5	CSS4	CSS3	CSS2	CSS1	CSS0
R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
bit 15							bit 8
—	—	—	CSS12	CSS11	CSS10	CSS9	CSS8
U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0

REGISTER 18-6: AD1CSSL: ADC1 INPUT SCAN SELECT REGISTER LOW⁽¹⁾

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit	, read as '0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-13 Unimplemented: Read as '0'

bit 12-0 CSS<12:0>: ADC Input Scan Selection bits

1 = Select ANx for input scan

0 = Skip ANx for input scan

Note 1: On devices without 13 analog inputs, all AD1CSSL bits can be selected by the user application. However, inputs selected for scan without a corresponding input on device converts VREFL.

2: CSSx = ANx, where x = 0 through 12.

REGISTER 18-7: AD1PCFGL: ADC1 PORT CONFIGURATION REGISTER LOW^(1,2,3)

U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	_	_	PCFG12	PCFG11	PCFG10	PCFG9	PCFG8
bit 15							bit 8
R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PCFG7	PCFG6	PCFG5	PCFG4	PCFG3	PCFG2	PCFG1	PCFG0
bit 7							bit C

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit	, read as '0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-13 Unimplemented: Read as '0'

bit 12-0 PCFG<12:0>: ADC Port Configuration Control bits

1 = Port pin in Digital mode, port read input enabled, ADC input multiplexer connected to AVss

0 = Port pin in Analog mode, port read input disabled, ADC samples pin voltage

Note 1: On devices without 13 analog inputs, all PCFG bits are R/W by user software. However, the PCFG bits are ignored on ports without a corresponding input on device.

- **2:** PCFGx = ANx, where x = 0 through 12.
- 3: The PCFGx bits have no effect if the ADC module is disabled by setting ADxMD bit in the PMDx register. In this case, all port pins multiplexed with ANx will be in Digital mode.

NOTES:

19.0 SPECIAL FEATURES

Note: This data sheet summarizes the features of the PIC24HJ32GP202/204 and PIC24HJ16GP304 devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the "dsPIC33F/PIC24H Family Reference Manual". Please see the Microchip web site (www.microchip.com) for the latest dsPIC33F/PIC24H Family Reference Manual sections.

PIC24HJ32GP202/204 and PIC24HJ16GP304 devices include several features that are intended to maximize application flexibility and reliability, and minimize cost through elimination of external components. These are:

- Flexible configuration
- Watchdog Timer (WDT)
- Code Protection and CodeGuard[™] Security
- JTAG Boundary Scan Interface
- In-Circuit Serial Programming[™] (ICSP[™])
- In-Circuit Emulation

19.1 Configuration Bits

PIC24HJ32GP202/204 and PIC24HJ16GP304 devices provide nonvolatile memory implementation for device configuration bits. Refer to **Section 25. "Device Configuration"** (DS70194) of the *"dsPIC33F/PIC24H Family Reference Manual"*, for more information on this implementation.

The Configuration bits can be programmed (read as '0'), or left unprogrammed (read as '1'), to select various device configurations. These bits are mapped starting at program memory location 0xF80000.

The Device Configuration register map is shown in Table 19-1.

The individual Configuration bit descriptions for the Configuration registers are shown in Table 19-2.

Note that address 0xF80000 is beyond the user program memory space. It belongs to the configuration memory space (0x800000-0xFFFFF), which can only be accessed using table reads and table writes.

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
0xF80000	FBS	— —			—	BSS<2:0> BWF		BWRP	
0xF80002	Reserved	_	—	_	—		_		—
0xF80004	FGS	_	—	_	—	_	GSS<1	:0>	GWRP
0xF80006	FOSCSEL	IESO	—	_	_	-	FNOSC<2:0>		•
0xF80008	FOSC	FCKSM	<1:0>	IOL1WAY	—	—	OSCIOFNC POSCMD<1:0		1D<1:0>
0xF8000A	FWDT	FWDTEN	WINDIS	_	WDTPRE		WDTPOST<3:0>		
0xF8000C	FPOR	Reserved ⁽¹⁾		ALTI2C		FPV	VRT<2:0>	>	
0xF8000E	FICD	Reserved ⁽²⁾ JTAGEN		—	_	—	ICS<	<1:0>	
0xF80010	FUID0	User Unit ID Byte 0							
0xF80012	FUID1	User Unit ID Byte 1							
0xF80014	FUID2	User Unit ID Byte 2							
0xF80016	FUID3	User Unit ID Byte 3							

TABLE 19-1: DEVICE CONFIGURATION REGISTER MAP

Legend: — = unimplemented bit, read as '0'.

Note 1: These bits are reserved and always read as '1'.

2: These bits are reserved for use by development tools and must be programmed as '1'.

RTSP **Bit Field** Register Description Effect BWRP FBS Boot Segment Program Flash Write Protection Immediate 1 = Boot segment may be written 0 = Boot segment is write-protected FBS PIC24HJ32GP202 and PIC24HJ32GP204 Devices Only BSS<2:0> Immediate Boot Segment Program Flash Code Protection Size x11 = No Boot program Flash segment Boot space is 768 Instruction Words (except interrupt vectors) 110 = Standard security; boot program Flash segment ends at 0x0007FE 010 = High security; boot program Flash segment ends at 0x0007FE Boot space is 3840 Instruction Words (except interrupt vectors) 101 = Standard security; boot program Flash segment, ends at 0x001FFE 001 = High security; boot program Flash segment ends at 0x001FFE Boot space is 7936 Instruction Words (except interrupt vectors) 100 = Standard security: boot program Flash segment ends at 0x003FFE 000 = High security; boot program Flash segment ends at 0x003FFE BSS<2:0> FBS Immediate PIC24HJ16GP304 Devices Only Boot Segment Program Flash Code Protection Size X11 = No Boot program Flash segment Boot space is 768 Instruction Words (except interrupt vectors) 110 = Standard security; boot program Flash segment ends at 0x0007FE 010 = High security; boot program Flash segment ends at 0x0007FE Boot space is 3840 Instruction Words (except interrupt vectors) 101 = Standard security; boot program Flash segment, ends at 0x001FFE 001 = High security; boot program Flash segment ends at 0x001FFE Boot space is 5376 Instruction Words (except interrupt vectors) 100 = Standard security; boot program Flash segment ends at 0x002BFE 000 = High security; boot program Flash segment ends at 0x002BFE General Segment Code-Protect bit GSS<1:0> FGS Immediate 11 = User program memory is not code-protected 10 = Standard security 0x = High security GWRP FGS Immediate General Segment Write-Protect bit 1 = User program memory is not write-protected 0 = User program memory is write-protected **IESO** FOSCSEL Immediate Two-speed Oscillator Start-up Enable bit 1 = Start-up device with FRC, then automatically switch to the user-selected oscillator source when ready 0 = Start-up device with user-selected oscillator source FOSCSEL FNOSC<2:0> Initial Oscillator Source Selection bits If clock 111 = Internal Fast RC (FRC) oscillator with postscaler switch is enabled, 110 = Internal Fast RC (FRC) oscillator with divide-by-16 101 = LPRC oscillator RTSP 100 = Secondary (LP) oscillator effect is 011 = Primary (XT, HS, EC) oscillator with PLL on any 010 = Primary (XT, HS, EC) oscillator device Reset; 001 = Internal Fast RC (FRC) oscillator with PLL 000 = FRC oscillator otherwise, Immediate

TABLE 19-2: PIC24HJ32GP202/204 AND PIC24HJ16GP304 CONFIGURATION BITS DESCRIPTION

TABLE 19-2:PIC24HJ32GP202/204 AND PIC24HJ16GP304 CONFIGURATION BITS DESCRIPTION
(CONTINUED)

(CONTINUED)			
Bit Field	Register	RTSP Effect	Description
FCKSM<1:0>	FOSC	Immediate	Clock Switching Mode bits 1x = Clock switching is disabled, Fail-Safe Clock Monitor is disabled 01 = Clock switching is enabled, Fail-Safe Clock Monitor is disabled 00 = Clock switching is enabled, Fail-Safe Clock Monitor is enabled
IOL1WAY	FOSC	Immediate	Peripheral Pin Select Configuration 1 = Allow only one re-configuration 0 = Allow multiple re-configurations
OSCIOFNC	FOSC	Immediate	OSC2 Pin Function bit (except in XT and HS modes) 1 = OSC2 is clock output 0 = OSC2 is general purpose digital I/O pin
POSCMD<1:0>	FOSC	Immediate	Primary Oscillator Mode Select bits 11 = Primary oscillator disabled 10 = HS Crystal Oscillator mode 01 = XT Crystal Oscillator mode 00 = EC (External Clock) mode
FWDTEN	FWDT	Immediate	 Watchdog Timer Enable bit 1 = Watchdog Timer always enabled (LPRC oscillator cannot be disabled. Clearing the SWDTEN bit in the RCON register will have no effect.) 0 = Watchdog Timer enabled/disabled by user software (LPRC can be disabled by clearing the SWDTEN bit in the RCON register)
WINDIS	FWDT	Immediate	Watchdog Timer Window Enable bit 1 = Watchdog Timer in Non-Window mode 0 = Watchdog Timer in Window mode
WDTPRE	FWDT	Immediate	Watchdog Timer Prescaler bit 1 = 1:128 0 = 1:32
WDTPOST<3:0>	FWDT	Immediate	Watchdog Timer Postscaler bits 1111 = 1:32,768 1110 = 1:16,384 0001 = 1:2 0000 = 1:1
ALTI2C	FPOR	Immediate	Alternate I ² C pins $1 = I^2$ C mapped to SDA1/SCL1 pins $0 = I^2$ C mapped to ASDA1/ASCL1 pins
FPWRT<2:0>	FPOR	Immediate	Power-on Reset Timer Value Select bits 111 = PWRT = 128 ms 110 = PWRT = 64 ms 101 = PWRT = 32 ms 100 = PWRT = 16 ms 011 = PWRT = 8 ms 010 = PWRT = 4 ms 001 = PWRT = 2 ms 000 = PWRT = Disabled
JTAGEN	FICD	Immediate	JTAG Enable bit 1 = JTAG enabled 0 = JTAG disabled

TABLE 19-2: PIC24HJ32GP202/204 AND PIC24HJ16GP304 CONFIGURATION BITS DESCRIPTION (CONTINUED)

Bit Field	Register	RTSP Effect	Description
ICS<1:0>	FICD	Immediate	ICD Communication Channel Select bits
			11 = Communicate on PGEC1 and PGED1
			10 = Communicate on PGEC2 and PGED2
			01 = Communicate on PGEC3 and PGED3
			00 = Reserved, do not use

19.2 On-Chip Voltage Regulator

PIC24HJ32GP202/204 All of the and PIC24HJ16GP304 devices power their core digital logic at a nominal 2.5V. This can create a conflict for designs that are required to operate at a higher typical voltage, such as 3.3V. To simplify system design, all devices in the PIC24HJ32GP202/204 and PIC24HJ16GP304 family incorporate an on-chip regulator that allows the device to run its core logic from VDD.

The regulator provides power to the core from the other VDD pins. When the regulator is enabled, a low-ESR (less than 5 ohms) capacitor (such as tantalum or ceramic) must be connected to the VCAP pin (Figure 19-1). This helps to maintain the stability of the regulator. The recommended value for the filter capacitor is provided in Table 22-13 located in Section 22.1 "DC Characteristics".

Note:	It is important for the low-ESR capacitor to
	be placed as close as possible to the VCAP
	pin.

On a POR, it takes approximately 20 μ s for the on-chip voltage regulator to generate an output voltage. During this time, designated as TSTARTUP, code execution is disabled. TSTARTUP is applied every time the device resumes operation after any power-down.

FIGURE 19-1: CONNECTIONS FOR THE ON-CHIP VOLTAGE REGULATOR⁽¹⁾



19.3 Brown-Out Reset (BOR)

The Brown-out Reset (BOR) module is based on an internal voltage reference circuit that monitors the regulated voltage VCAP. The main purpose of the BOR module is to generate a device Reset when a brown-out condition occurs. Brown-out conditions are generally caused by glitches on the AC mains (for example, missing portions of the AC cycle waveform due to bad power transmission lines, or voltage sags due to excessive current draw when a large inductive load is turned on).

A BOR generates a Reset pulse, which resets the device. The BOR selects the clock source, based on the device Configuration bit values (FNOSC<2:0> and POSCMD<1:0>).

If an oscillator mode is selected, the BOR activates the Oscillator Start-up Timer (OST). The system clock is held until OST expires. If the PLL is used, the clock is held until the LOCK bit (OSCCON<5>) is '1'.

Concurrently, the PWRT time-out (TPWRT) will be applied before the internal Reset is released. If TPWRT = 0 and a crystal oscillator is being used, a nominal delay of TFSCM = 100 is applied. The total delay in this case is TFSCM.

The BOR Status bit (RCON<1>) is set to indicate that a BOR has occurred. The BOR circuit continues to operate while in Sleep or Idle mode and resets the device in case VDD falls below the BOR threshold voltage.

19.4 Watchdog Timer (WDT)

For PIC24HJ32GP202/204 and PIC24HJ16GP304 devices, the WDT is driven by the LPRC oscillator. When the WDT is enabled, the clock source is also enabled.

19.4.1 PRESCALER/POSTSCALER

The nominal WDT clock source from LPRC is 32 kHz. This feeds a prescaler than can be configured for either 5-bit (divide-by-32) or 7-bit (divide-by-128) operation. The prescaler is set by the WDTPRE Configuration bit. With a 32 kHz input, the prescaler yields a nominal WDT time-out period (TWDT) of 1 ms in 5-bit mode, or 4 ms in 7-bit mode.

A variable postscaler divides down the WDT prescaler output and allows for a wide range of time-out periods. The postscaler is controlled by the WDTPOST<3:0> Configuration bits (FWDT<3:0>), which allows the selection of 16 settings, from 1:1 to 1:32,768. Using the prescaler and postscaler, time-out periods ranging from 1 ms to 131 seconds can be achieved.

The WDT, prescaler and postscaler are reset:

- · On any device Reset
- On the completion of a clock switch, whether invoked by software (i.e., setting the OSWEN bit after changing the NOSC bits) or by hardware (i.e., Fail-Safe Clock Monitor)
- When a PWRSAV instruction is executed (Sleep or Idle mode is entered)
- When the device exits Sleep or Idle mode to resume normal operation
- By a CLRWDT instruction during normal execution
- Note: The CLRWDT and PWRSAV instructions clear the prescaler and postscaler counts when executed.

All Device Resets Transition to New Clock Source Exit Sleep or Idle Mode PWRSAV Instruction CLRWDT Instruction Watchdog Timer Sleep/Idle WDTPOST<3:0> WDTPRE SWDTEN WDT Wake-up FWDTEN RS Prescaler Postscaler WDT LPRC Clock (divide by N1) (divide by N2) Reset 0 WDT Window Select WINDIS CLRWDT Instruction

FIGURE 19-2: WDT BLOCK DIAGRAM

19.4.2 SLEEP AND IDLE MODES

If the WDT is enabled, it will continue to run during Sleep or Idle modes. When the WDT time-out occurs, the device will wake the device and code execution will continue from where the PWRSAV instruction was executed. The corresponding SLEEP or IDLE bits (RCON<3,2>) will need to be cleared in software after the device wakes up.

19.4.3 ENABLING WDT

The WDT is enabled or disabled by the FWDTEN Configuration bit in the FWDT Configuration register. When the FWDTEN Configuration bit is set, the WDT is always enabled.

The WDT flag bit, WDTO (RCON<4>), is not automatically cleared following a WDT time-out. To detect subsequent WDT events, the flag must be cleared in software.

The WDT can be optionally controlled in software when the FWDTEN Configuration bit has been programmed to '0'. The WDT is enabled in software by setting the SWDTEN control bit (RCON<5>). The SWDTEN control bit is cleared on any device Reset. The software WDT option allows the user application to enable the WDT for critical code segments and disable the WDT during non-critical segments for maximum power savings.

Note: If the WINDIS bit (FWDT<6>) is cleared, the CLRWDT instruction should be executed by the application software only during the last 1/4 of the WDT period. This CLRWDT window can be determined by using a timer. If a CLRWDT instruction is executed before this window, a WDT Reset occurs.

19.5 JTAG Interface

PIC24HJ32GP202/204 and PIC24HJ16GP304 devices implement a JTAG interface, which supports boundary scan device testing, as well as in-circuit programming. Detailed information on this interface will be provided in future revisions of the document.

19.6 Code Protection and CodeGuard™ Security

The PIC24HJ32GP202/204 and PIC24HJ16GP304 product family offers the intermediate implementation of CodeGuard Security. CodeGuard Security allows multiple parties to securely share resources (memory,

TABLE 19-3:CODE FLASH SECURITYSEGMENT SIZES FOR32 KBYTE DEVICES

CONFIG BITS		
	VS = 256 IW	0x000000 0x0001FE
BSS<2:0>=x11 0K	GS = 11008 IW	0x000200 0x0007FE 0x000800 0x001FFE 0x002000 0x003FFE 0x004000 0x0057FE
	VS = 256 IW	0x000000 0x0001FE
BSS<2:0>=x10	BS = 768 IW	0x000200 0x0007FE
256		0x000800 0x001FFE 0x002000 0x003FFE 0x004000
	GS = 10240 IW	0x0057FE
	VS = 256 IW	0x000000 0x0001FE
BSS<2:0>=x01	BS = 3840 IW	0x000200 0x0007FE 0x000800 0x001FFE
768	GS = 7168 IW	0x002000 0x003FFE 0x004000 0x0057FE
	1/0 050 l\//	OX000000
	VS = 256 IW	0x0001FE 0x000200
BSS<2:0>=x00	BS = 7936 IW	0x0007FE 0x000800 0x001FFE
1792		0x002000 0x003FFE 0x004000
	GS = 3072 IW	0x004000 0x0057FE

interrupts and peripherals) on a single chip. This feature helps to protect individual Intellectual Property in collaborative system designs.

When coupled with software encryption libraries, CodeGuard Security can be used to securely update Flash even when multiple IPs reside on the single chip.

The code protection features are controlled by the Configuration registers: FBS and FGS. The Secure segment and RAM is not implemented.

Note:	Refer to Section 23. "CodeGuard™
	Security" (DS70199) in the
	"dsPIC33F/PIC24H Family Reference
	Manual" for further information on
	usage, configuration and operation of
	CodeGuard Security.

TABLE 19-4: CODE FLASH SECURITY SEGMENT SIZES FOR 16 KBYTE DEVICES

		L3
CONFIG BITS		
BSS<2:0>=x11	VS = 256 IW	0x000000 0x0001FE 0x000200 0x0007FE 0x000800 0x001FFE
ок	GS = 5376 IW	0x002000
	VS = 256 IW	0x000000 0x0001FE
BSS<2:0>=x10	BS = 768 IW	0x000200 0x0007FE 0x000800
256		0x001FFE 0x002000
	GS = 4608 IW	002BFEh
	VS = 256 IW	0x000000 0x0001FE
BSS<2:0>=x01	BS = 3840 IW	0x000200 0x0007FE 0x000800 0x001FFE
768		0x002000
	GS = 1536 IW	0x002BFE
	VS = 256 IW	0x000000 0x0001FE
BSS<2:0>=x00 1792	BS = 5376 IW	0x000200 0x0007FE 0x000800 0x001FFE 0x002000
		0x002BFE

19.7 In-Circuit Serial Programming

PIC24HJ32GP202/204 and PIC24HJ16GP304 family microcontrollers can be serially programmed while in the end application circuit. This is done with two lines for clock and data, and three other lines for power, ground and the programming sequence. Serial programming allows customers to manufacture boards with unprogrammed devices and then program the microcontroller just before shipping the product. Serial programming also allows the most recent firmware or a custom firmware to be programmed. Refer to the "*dsPIC30F/33F* Flash Programming Specification" (DS70152) document for details about In-Circuit Serial Programming[™] (ICSP)[™].

Any of the following three pairs of programming clock/data pins can be used:

- PGEC1 and PGED1
- PGEC2 and PGED2
- PGEC3 and PGED3

19.8 In-Circuit Debugger

When MPLAB[®] ICD 2 is selected as a debugger, the in-circuit debugging functionality is enabled. This function allows simple debugging functions when used with MPLAB IDE. Debugging functionality is controlled through the Emulation/Debug Clock (PGECx) and Emulation/Debug Data (PGEDx) pin functions.

Any of the following three pairs of debugging clock/data pins can be used:

- PGEC1 and PGED1
- PGEC2 and PGED2
- PGEC3 and PGED3

To make use of the in-circuit debugger function of the device, the design must implement ICSP connections to MCLR, VDD, Vss and PGECx/PGEDx pin pair. In addition, when the feature is enabled, some of the resources are not available for general use. These resources include the first 80 bytes of data RAM and two I/O pins.

20.0 INSTRUCTION SET SUMMARY

Note: This data sheet summarizes the features of this group of PIC24HJ32GP202/204 and PIC24HJ16GP304 devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the "dsPIC33F/PIC24H Family Reference Manual". Please see the Microchip web site (www.microchip.com) for the latest dsPIC33F/PIC24H Family Reference Manual sections.

The PIC24H instruction set is identical to that of the PIC24F, and is a subset of the dsPIC30F/33F instruction set.

Most instructions are a single program memory word (24 bits). Only three instructions require two program memory locations.

Each single-word instruction is a 24-bit word, divided into an 8-bit opcode, which specifies the instruction type and one or more operands, which further specify the operation of the instruction.

The instruction set is highly orthogonal and is grouped into five basic categories:

- Word or byte-oriented operations
- Bit-oriented operations
- · Literal operations
- · Control operations

Table 20-1shows the general symbols used indescribing the instructions.

The PIC24H instruction set summary in Table 20-2 lists all the instructions, along with the status flags affected by each instruction.

Most word or byte-oriented W register instructions (including barrel shift instructions) have three operands:

- The first source operand which is typically a register 'Wb' without any address modifier
- The second source operand which is typically a register 'Ws' with or without an address modifier
- The destination of the result which is typically a register 'Wd' with or without an address modifier

However, word or byte-oriented file register instructions have two operands:

- The file register specified by the value 'f'
- The destination, which could either be the file register 'f' or the W0 register, which is denoted as 'WREG'

Most bit-oriented instructions (including simple rotate/shift instructions) have two operands:

- The W register (with or without an address modifier) or file register (specified by the value of 'Ws' or 'f')
- The bit in the W register or file register (specified by a literal value or indirectly by the contents of register 'Wb')

The literal instructions that involve data movement may use some of the following operands:

- A literal value to be loaded into a W register or file register (specified by the value of 'k')
- The W register or file register where the literal value is to be loaded (specified by 'Wb' or 'f')

However, literal instructions that involve arithmetic or logical operations use some of the following operands:

- The first source operand which is a register 'Wb' without any address modifier
- The second source operand which is a literal value
- The destination of the result (only if not the same as the first source operand) which is typically a register 'Wd' with or without an address modifier

The control instructions may use some of the following operands:

- A program memory address
- The mode of the table read and table write instructions

All instructions are single word. Certain double-word instructions are designed to provide all of the required information in these 48 bits. In the second word, the 8 MSbs are '0's. If this second word is executed as an instruction (by itself), it will execute as a NOP.

Most single-word instructions are executed in a single instruction cycle, unless a conditional test is true, or the program counter is changed as a result of the instruction. In these cases, the execution takes two instruction cycles with the additional instruction cycle(s) executed as a NOP. Notable exceptions are the BRA (unconditional/computed branch), indirect CALL/GOTO, all table reads and writes and RETURN/RETFIE instructions, which are single-word instructions but take two or three cycles. Certain instructions that involve skipping over the subsequent instruction require either two or three cycles if the skip is performed, depending on whether the instruction being skipped is a single-word or double word instruction. Moreover, double word moves require two cycles. The double word instructions execute in two instruction cycles.

Note: For more details on the instruction set, refer to the *"16-bit MCU and DSC Programmer's Reference Manual"* (DS70157).

TABLE 20-1: SYMBOLS USED IN OPCODE DESCRIPTIONS

Field	Description						
#text	Means literal defined by "text"						
(text)	Means "content of text"						
[text]	Means "the location addressed by text"						
{ }	Optional field or operation						
<n:m></n:m>	Register bit field						
.b	Byte mode selection						
.d	Double Word mode selection						
.S	Shadow register select						
.w	Word mode selection (default)						
bit4	4-bit bit selection field (used in word addressed instructions) $\in \{015\}$						
C, DC, N, OV, Z	MCU Status bits: Carry, Digit Carry, Negative, Overflow, Sticky Zero						
Expr	Absolute address, label or expression (resolved by the linker)						
f	File register address ∈ {0x00000x1FFF}						
lit1	1-bit unsigned literal ∈ {0,1}						
lit4	4-bit unsigned literal ∈ {015}						
lit5	5-bit unsigned literal ∈ {031}						
lit8	8-bit unsigned literal ∈ {0255}						
lit10	10-bit unsigned literal ∈ {0255} for Byte mode, {0:1023} for Word mode						
lit14	14-bit unsigned literal ∈ {016384}						
lit16	16-bit unsigned literal ∈ {065535}						
lit23	23-bit unsigned literal ∈ {08388608}; LSB must be '0'						
None	Field does not require an entry, may be blank						
PC	Program Counter						
Slit10	10-bit signed literal ∈ {-512511}						
Slit16	16-bit signed literal ∈ {-3276832767}						
Slit6	6-bit signed literal ∈ {-1616}						
Wb	Base W register ∈ {W0W15}						
Wd	Destination W register ∈ { Wd, [Wd], [Wd++], [Wd], [++Wd], [Wd] }						
Wdo	Destination W register ∈ { Wnd, [Wnd], [Wnd++], [Wnd], [++Wnd], [Wnd], [Wnd+Wb] }						
Wm,Wn	Dividend, Divisor working register pair (direct addressing)						
Wm*Wm	Multiplicand and Multiplier working register pair for Square instructions ∈ {W4 * W4,W5 * W5,W6 * W6,W7 * W7}						
Wn	One of 16 working registers ∈ {W0W15}						
Wnd	One of 16 destination working registers ∈ {W0W15}						
Wns	One of 16 source working registers ∈ {W0W15}						
WREG	W0 (working register used in file register instructions)						
Ws	Source W register ∈ { Ws, [Ws], [Ws++], [Ws], [++Ws], [Ws] }						
Wso	Source W register ∈ { Wns, [Wns], [Wns++], [Wns], [++Wns], [Wns], [Wns+Wb] }						
Base Instr #	Assembly Mnemonic			Description	# of Words	# of Cycles	Status Flags Affected
--------------------	----------------------	-------	--------------	--	---------------	----------------	--------------------------
1	ADD	ADD	f	f = f + WREG	1	1	C,DC,N,OV,Z
		ADD	f,WREG	WREG = f + WREG	1	1	C,DC,N,OV,Z
		ADD	#lit10,Wn	Wd = lit10 + Wd	1	1	C,DC,N,OV,Z
		ADD	Wb,Ws,Wd	Wd = Wb + Ws	1	1	C,DC,N,OV,Z
		ADD	Wb,#lit5,Wd	Wd = Wb + lit5	1	1	C,DC,N,OV,Z
2	ADDC	ADDC	f	f = f + WREG + (C)	1	1	C,DC,N,OV,Z
		ADDC	f,WREG	WREG = f + WREG + (C)	1	1	C,DC,N,OV,Z
		ADDC	#lit10,Wn	Wd = Iit10 + Wd + (C)	1	1	C,DC,N,OV,Z
		ADDC	Wb,Ws,Wd	Wd = Wb + Ws + (C)	1	1	C,DC,N,OV,Z
		ADDC	Wb,#lit5,Wd	Wd = Wb + lit5 + (C)	1	1	C,DC,N,OV,Z
3	AND	AND	f	f = f .AND. WREG	1	1	N,Z
		AND	f,WREG	WREG = f .AND. WREG	1	1	N,Z
		AND	#lit10,Wn	Wd = lit10 .AND. Wd	1	1	N,Z
		AND	Wb,Ws,Wd	Wd = Wb .AND. Ws	1	1	N,Z
		AND	Wb,#lit5,Wd	Wd = Wb .AND. lit5	1	1	N,Z
4	ASR	ASR	f	f = Arithmetic Right Shift f	1	1	C,N,OV,Z
		ASR	f,WREG	WREG = Arithmetic Right Shift f	1	1	C,N,OV,Z
		ASR	Ws,Wd	Wd = Arithmetic Right Shift Ws	1	1	C,N,OV,Z
		ASR	Wb,Wns,Wnd	Wnd = Arithmetic Right Shift Wb by Wns	1	1	N,Z
		ASR	Wb,#lit5,Wnd	Wnd = Arithmetic Right Shift Wb by lit5	1	1	N,Z
5	BCLR	BCLR	f,#bit4	Bit Clear f	1	1	None
		BCLR	Ws,#bit4	Bit Clear Ws	1	1	None
6	BRA	BRA	C,Expr	Branch if Carry	1	1 (2)	None
		BRA	GE, Expr	Branch if greater than or equal	1	1 (2)	None
		BRA	GEU,Expr	Branch if unsigned greater than or equal	1	1 (2)	None
		BRA	GT,Expr	Branch if greater than	1	1 (2)	None
		BRA	GTU,Expr	Branch if unsigned greater than	1	1 (2)	None
		BRA	LE,Expr	Branch if less than or equal	1	1 (2)	None
		BRA	LEU,Expr	Branch if unsigned less than or equal	1	1 (2)	None
		BRA	LT,Expr	Branch if less than	1	1 (2)	None
		BRA	LTU,Expr	Branch if unsigned less than	1	1 (2)	None
		BRA	N,Expr	Branch if Negative	1	1 (2)	None
		BRA	NC,Expr	Branch if Not Carry	1	1 (2)	None
		BRA	NN,Expr	Branch if Not Negative	1	1 (2)	None
		BRA	NZ,Expr	Branch if Not Zero	1	1 (2)	None
		BRA	Expr	Branch Unconditionally	1	2	None
		BRA	Z,Expr	Branch if Zero	1	1 (2)	None
		BRA	Wn	Computed Branch	1	2	None
7	BSET	BSET	f,#bit4	Bit Set f	1	1	None
		BSET	Ws,#bit4	Bit Set Ws	1	1	None
8	BSW	BSW.C	Ws,Wb	Write C bit to Ws <wb></wb>	1	1	None
		BSW.Z	Ws,Wb	Write Z bit to Ws <wb></wb>	1	1	None
9	BTG	BTG	f,#bit4	Bit Toggle f	1	1	None
		BTG	Ws,#bit4	Bit Toggle Ws	1	1	None
10	BTSC	BTSC	f,#bit4	Bit Test f, Skip if Clear	1	1 (2 or 3)	None
		BTSC	Ws,#bit4	Bit Test Ws, Skip if Clear	1	1 (2 or 3)	None
11	BTSS	BTSS	f,#bit4	Bit Test f, Skip if Set	1	1 (2 or 3)	None
		BTSS	Ws,#bit4	Bit Test Ws, Skip if Set	1	1 (2 or 3)	None

TABLE 20-2: INSTRUCTION SET OVERVIEW

Base Assembly # of # of Status Flags Instr Assembly Syntax Description Mnemonic Words Cycles Affected # BTST 12 BTST f,#bit4 Bit Test f 1 1 7 Bit Test Ws to C 1 1 С BTST.C Ws,#bit4 Ζ BTST.Z Ws,#bit4 Bit Test Ws to Z 1 1 BTST.C Bit Test Ws<Wb> to C 1 1 С Ws,Wb Bit Test Ws<Wb> to Z 1 1 Ζ BTST.Z Ws,Wb 13 BTSTS z BTSTS f,#bit4 Bit Test then Set f 1 1 Bit Test Ws to C, then Set 1 1 С BTSTS.C Ws,#bit4 1 z Bit Test Ws to Z, then Set 1 BTSTS.Z Ws,#bit4 14 CALL 2 2 None CALL lit23 Call subroutine 2 CALL Wn Call indirect subroutine 1 None 15 CLR CLR f f = 0x00001 1 None CLR WREG = 0x00001 1 WREG None Ws = 0x00001 1 None CLR Ws CLRWDT 16 CLRWDT Clear Watchdog Timer 1 1 WDTO,Sleep 17 COM COM $f = \overline{f}$ 1 1 N,Z f WREG = \overline{f} 1 1 COM f,WREG N,Z 1 1 COM Wd = WsN,Z Ws,Wd 18 CP Compare f with WREG 1 1 C,DC,N,OV,Z CP f CP Compare Wb with lit5 1 1 C,DC,N,OV,Z Wb,#lit5 CP Wb,Ws Compare Wb with Ws (Wb - Ws) 1 1 C,DC,N,OV,Z CP0 19 1 C,DC,N,OV,Z CP0 f Compare f with 0x0000 1 CP0 Compare Ws with 0x0000 1 1 C,DC,N,OV,Z Ws 20 CPB CPB Compare f with WREG, with Borrow 1 1 C,DC,N,OV,Z f СРВ Wb,#lit5 Compare Wb with lit5, with Borrow 1 1 C,DC,N,OV,Z Compare Wb with Ws, with Borrow 1 1 C,DC,N,OV,Z CPB Wb,Ws (Wb - Ws - C) 21 CPSEQ CPSEO Wb, Wn Compare Wb with Wn, skip if = 1 1 None (2 or 3) CPSGT 22 CPSGT Compare Wb with Wn, skip if > 1 None Wb, Wn 1 (2 or 3) 23 CPSLT Compare Wb with Wn, skip if < 1 CPSLT Wb, Wn None 1 (2 or 3) 24 CPSNE CPSNE Compare Wb with Wn, skip if 1/4 1 None Wb, Wn 1 (2 or 3) 25 DAW DAW Wn = decimal adjust Wn 1 С Wn 1 26 DEC f = f - 11 C,DC,N,OV,Z 1 DEC f WREG = f - 11 1 C,DC,N,OV,Z DEC f,WREG DEC Ws,Wd Wd = Ws - 1 1 1 C,DC,N,OV,Z 27 DEC2 DEC2 f f = f - 2 1 1 C,DC,N,OV,Z WREG = f - 21 DEC2 f,WREG 1 C,DC,N,OV,Z DEC2 Ws,Wd Wd = Ws - 2 1 1 C,DC,N,OV,Z DISI 1 Disable Interrupts for k instruction cycles 1 28 DISI #lit14 None 29 עוח Signed 16/16-bit Integer Divide 1 18 N,Z,C,OV DIV.S Wm,Wn DIV.SD Signed 32/16-bit Integer Divide 1 18 N,Z,C,OV Wm,Wn 1 18 N,Z,C,OV DIV.U Wm,Wn Unsigned 16/16-bit Integer Divide DIV.UD Unsigned 32/16-bit Integer Divide 1 18 N,Z,C,OV Wm,Wn 30 EXCH EXCH Wns,Wnd Swap Wns with Wnd 1 1 None 31 FBCL FBCL Find Bit Change from Left (MSb) Side 1 1 С Ws . Wnd 32 FF1L FF1L Find First One from Left (MSb) Side 1 1 С Ws.Wnd FF1R Find First One from Right (LSb) Side С 33 1 1 FF1R Ws,Wnd 34 GOTO 2 2 GOTO Expr Go to address None GOTO Go to indirect 1 2 Wn None

TABLE 20-2: INSTRUCTION SET OVERVIEW (CONTINUED)

Base Instr #	Assembly Mnemonic		Assembly Syntax	Description	# of Words	# of Cycles	Status Flags Affected
35	INC	INC	f	f = f + 1	1	1	C,DC,N,OV,Z
		INC	f,WREG	WREG = f + 1	1	1	C,DC,N,OV,Z
		INC	Ws,Wd	Wd = Ws + 1	1	1	C,DC,N,OV,Z
36	INC2	INC2	f	f = f + 2	1	1	C,DC,N,OV,Z
		INC2	f,WREG	WREG = f + 2	1	1	C,DC,N,OV,Z
		INC2	Ws,Wd	Wd = Ws + 2	1	1	C,DC,N,OV,Z
37	IOR	IOR	f	f = f .IOR. WREG	1	1	N,Z
		IOR	f,WREG	WREG = f .IOR. WREG	1	1	N,Z
		IOR	#lit10,Wn	Wd = lit10 .IOR. Wd	1	1	N,Z
		IOR	Wb,Ws,Wd	Wd = Wb .IOR. Ws	1	1	N,Z
		IOR	Wb,#lit5,Wd	Wd = Wb .IOR. lit5	1	1	N,Z
38	LNK	LNK	#lit14	Link Frame Pointer	1	1	None
39	LSR	LSR	f	f = Logical Right Shift f	1	1	C,N,OV,Z
		LSR	f,WREG	WREG = Logical Right Shift f	1	1	C,N,OV,Z
		LSR	Ws,Wd	Wd = Logical Right Shift Ws	1	1	C,N,OV,Z
		LSR	Wb,Wns,Wnd	Wnd = Logical Right Shift Wb by Wns	1	1	N,Z
		LSR	Wb,#lit5,Wnd	Wnd = Logical Right Shift Wb by lit5	1	1	N,Z
40 N	MOV	MOV	f,Wn	Move f to Wn	1	1	None
		MOV	f	Move f to f	1	1	N,Z
		MOV	f,WREG	Move f to WREG	1	1	None
		MOV	#lit16,Wn	Move 16-bit literal to Wn	1	1	None
		MOV.b	#lit8,Wn	Move 8-bit literal to Wn	1	1	None
		MOV	Wn,f	Move Wn to f	1	1	None
		MOV	Wso,Wdo	Move Ws to Wd	1	1	None
		MOV	WREG, f	Move WREG to f	1	1	None
		MOV.D	Wns,Wd	Move Double from W(ns):W(ns + 1) to Wd	1	2	None
		MOV.D	Ws,Wnd	Move Double from Ws to W(nd + 1):W(nd)	1	2	None
41	MUL	MUL.SS	Wb,Ws,Wnd	{Wnd + 1, Wnd} = signed(Wb) * signed(Ws)	1	1	None
		MUL.SU	Wb,Ws,Wnd	{Wnd + 1, Wnd} = signed(Wb) * unsigned(Ws)	1	1	None
		MUL.US	Wb,Ws,Wnd	{Wnd + 1, Wnd} = unsigned(Wb) * signed(Ws)	1	1	None
		MUL.UU	Wb,Ws,Wnd	{Wnd + 1, Wnd} = unsigned(Wb) * unsigned(Ws)	1	1	None
		MUL.SU	Wb,#lit5,Wnd	{Wnd + 1, Wnd} = signed(Wb) * unsigned(lit5)	1	1	None
		MUL.UU	Wb,#lit5,Wnd	{Wnd + 1, Wnd} = unsigned(Wb) * unsigned(lit5)	1	1	None
		MUL	f	W3:W2 = f * WREG	1	1	None
42	NEG	NEG	f	$f = \overline{f} + 1$	1	1	C,DC,N,OV,Z
		NEG	f,WREG	WREG = \overline{f} + 1	1	1	C,DC,N,OV,Z
		NEG	Ws,Wd	$Wd = \overline{Ws} + 1$	1	1	C,DC,N,OV,Z
43	NOP	NOP		No Operation	1	1	None
		NOPR		No Operation	1	1	None
44	POP	POP	f	Pop f from Top-of-Stack (TOS)	1	1	None
		POP	Wdo	Pop from Top-of-Stack (TOS) to Wdo	1	1	None
		POP.D	Wnd	Pop from Top-of-Stack (TOS) to W(nd):W(nd + 1)	1	2	None
		POP.S		Pop Shadow Registers	1	1	All
45	PUSH	PUSH	f	Push f to Top-of-Stack (TOS)	1	1	None
		PUSH	Wso	Push Wso to Top-of-Stack (TOS)	1	1	None
		PUSH.D	Wns	Push W(ns):W(ns + 1) to Top-of-Stack (TOS)	1	2	None
		PUSH.S		Push Shadow Registers	1	1	None
46	PWRSAV	PWRSAV	#lit1	Go into Sleep or Idle mode	1	1	WDTO,Sleep

TABLE 20-2: INSTRUCTION SET OVERVIEW (CONTINUED)

TABL	E 20-2:	INSTRU	NSTRUCTION SET OVERVIEW (CONTINUED)									
Base Instr #	Assembly Mnemonic			Description	# of Words	# of Cycles	Status Flags Affected					
47	RCALL	RCALL	Expr	Relative Call	1	2	None					
		RCALL	Wn	Computed Call	1	2	None					
48	REPEAT	REPEAT	#lit14	Repeat Next Instruction lit14 + 1 times	1	1	None					
		REPEAT	Wn	Repeat Next Instruction (Wn) + 1 times	1	1	None					
49	RESET	RESET		Software device Reset	1	1	None					
50	RETFIE	RETFIE		Return from interrupt	1	3 (2)	None					
51	RETLW	RETLW	#lit10,Wn	Return with literal in Wn	1	3 (2)	None					
52	RETURN	RETURN		Return from Subroutine	1	3 (2)	None					
53	RLC	RLC	f	f = Rotate Left through Carry f	1	1	C,N,Z					
		RLC	f,WREG	WREG = Rotate Left through Carry f	1	1	C,N,Z					
		RLC	Ws,Wd	Wd = Rotate Left through Carry Ws	1	1	C,N,Z					
54	RLNC	RLNC	f	f = Rotate Left (No Carry) f	1	1	N,Z					
		RLNC	f,WREG	WREG = Rotate Left (No Carry) f	1	1	N,Z					
		RLNC	Ws,Wd	Wd = Rotate Left (No Carry) Ws	1	1	N,Z					
55	RRC	RRC	f	f = Rotate Right through Carry f	1	1	C,N,Z					
		RRC	f,WREG	WREG = Rotate Right through Carry f	1	1	C,N,Z					
		RRC	Ws,Wd	Wd = Rotate Right through Carry Ws	1	1	C,N,Z					
56	RRNC	RRNC	f	f = Rotate Right (No Carry) f	1	1	N,Z					
		RRNC	f,WREG	WREG = Rotate Right (No Carry) f	1	1	N,Z					
		RRNC	Ws,Wd	Wd = Rotate Right (No Carry) Ws	1	1	N,Z					
57	SE	SE	Ws,Wnd	Wnd = sign-extended Ws	1	1	C,N,Z					
58	SETM	SETM	f	f = 0xFFFF	1	1	None					
		SETM	WREG	WREG = 0xFFFF	1	1	None					
		SETM	Ws	Ws = 0xFFFF	1	1	None					
59	SL	SL	f	f = Left Shift f	1	1	C,N,OV,Z					
		SL	f,WREG	WREG = Left Shift f	1	1	C,N,OV,Z					
		SL	Ws,Wd	Wd = Left Shift Ws	1	1	C,N,OV,Z					
		SL	Wb,Wns,Wnd	Wnd = Left Shift Wb by Wns	1	1	N,Z					
		SL	Wb,#lit5,Wnd	Wnd = Left Shift Wb by lit5	1	1	N,Z					
60	SUB	SUB	f	f = f - WREG	1	1	C,DC,N,OV,Z					
		SUB	f,WREG	WREG = f - WREG	1	1	C,DC,N,OV,Z					
		SUB	#lit10,Wn	Wn = Wn - lit10	1	1	C,DC,N,OV,Z					
		SUB	Wb,Ws,Wd	Wd = Wb - Ws	1	1	C,DC,N,OV,Z					
		SUB	Wb,#lit5,Wd	Wd = Wb - lit5	1	1	C,DC,N,OV,Z					
61	SUBB	SUBB	f	$f = f - WREG - (\overline{C})$	1	1	C,DC,N,OV,Z					
		SUBB	f,WREG	$WREG = f - WREG - (\overline{C})$	1	1	C,DC,N,OV,Z					
				$Wn = Wn - lit10 - (\overline{C})$	1	1						
		SUBB	#lit10,Wn				C,DC,N,OV,Z					
		SUBB	Wb,Ws,Wd	Wd = Wb - Ws - (C)	1	1	C,DC,N,OV,Z					
		SUBB	Wb,#lit5,Wd	Wd = Wb - lit5 - (C)	1	1	C,DC,N,OV,Z					
62	SUBR	SUBR	f	f = WREG - f	1	1	C,DC,N,OV,Z					
		SUBR	f,WREG	WREG = WREG - f	1	1	C,DC,N,OV,Z					
		SUBR	Wb,Ws,Wd	Wd = Ws - Wb	1	1	C,DC,N,OV,Z					
		SUBR	Wb,#lit5,Wd	Wd = lit5 - Wb	1	1	C,DC,N,OV,Z					
63	SUBBR	SUBBR	f	$f = WREG - f - (\overline{C})$	1	1	C,DC,N,OV,Z					
		SUBBR	f,WREG	WREG = WREG - f - (\overline{C})	1	1	C,DC,N,OV,Z					
		SUBBR	Wb,Ws,Wd	$Wd = Ws - Wb - (\overline{C})$	1	1	C,DC,N,OV,Z					
		SUBBR	Wb,#lit5,Wd	$Wd = lit5 - Wb - (\overline{C})$	1	1	C,DC,N,OV,Z					
64	SWAP	SWAP.b	Wn	Wn = nibble swap Wn	1	1	None					
		SWAP	Wn	Wn = byte swap Wn	1	1	None					
65	TBLRDH	TBLRDH	Ws,Wd	Read Prog<23:16> to Wd<7:0>	1	2	None					

TADIE 20 2. INSTRUCTION SET OVERVIEW (CONTINUED)

TABLE 20-2:	INSTRUCTION SET OVERVIEW	(CONTINUED)	١
			,

Base Instr #	Assembly Mnemonic		Assembly Syntax	Description	# of Words	# of Cycles	Status Flags Affected
66	TBLRDL	TBLRDL	Ws,Wd	Read Prog<15:0> to Wd	1	2	None
67	TBLWTH	TBLWTH	Ws,Wd	Write Ws<7:0> to Prog<23:16>	1	2	None
68	TBLWTL	TBLWTL	Ws,Wd	Write Ws to Prog<15:0>	1	2	None
69	ULNK	ULNK		Unlink Frame Pointer	1	1	None
70	XOR	XOR	f	f = f .XOR. WREG	1	1	N,Z
		XOR	f,WREG	WREG = f .XOR. WREG	1	1	N,Z
		XOR	#lit10,Wn	Wd = lit10 .XOR. Wd	1	1	N,Z
		XOR	Wb,Ws,Wd	Wd = Wb .XOR. Ws	1	1	N,Z
		XOR	Wb,#lit5,Wd	Wd = Wb .XOR. lit5	1	1	N,Z
71	ZE	ZE	Ws,Wnd	Wnd = Zero-extend Ws	1	1	C,Z,N

NOTES:

21.0 DEVELOPMENT SUPPORT

The PIC[®] microcontrollers and dsPIC[®] digital signal controllers are supported with a full range of software and hardware development tools:

- Integrated Development Environment
 - MPLAB[®] IDE Software
- Compilers/Assemblers/Linkers
 - MPLAB C Compiler for Various Device Families
 - HI-TECH C for Various Device Families
 - MPASM[™] Assembler
 - MPLINK[™] Object Linker/ MPLIB[™] Object Librarian
 - MPLAB Assembler/Linker/Librarian for Various Device Families
- Simulators
 - MPLAB SIM Software Simulator
- Emulators
 - MPLAB REAL ICE™ In-Circuit Emulator
- In-Circuit Debuggers
 - MPLAB ICD 3
 - PICkit[™] 3 Debug Express
- Device Programmers
 - PICkit[™] 2 Programmer
 - MPLAB PM3 Device Programmer
- Low-Cost Demonstration/Development Boards, Evaluation Kits, and Starter Kits

21.1 MPLAB Integrated Development Environment Software

The MPLAB IDE software brings an ease of software development previously unseen in the 8/16/32-bit microcontroller market. The MPLAB IDE is a Windows[®] operating system-based application that contains:

- A single graphical interface to all debugging tools
 - Simulator
 - Programmer (sold separately)
 - In-Circuit Emulator (sold separately)
 - In-Circuit Debugger (sold separately)
- · A full-featured editor with color-coded context
- A multiple project manager
- Customizable data windows with direct edit of contents
- High-level source code debugging
- Mouse over variable inspection
- Drag and drop variables from source to watch windows
- Extensive on-line help
- Integration of select third party tools, such as IAR C Compilers

The MPLAB IDE allows you to:

- · Edit your source files (either C or assembly)
- One-touch compile or assemble, and download to emulator and simulator tools (automatically updates all project information)
- Debug using:
 - Source files (C or assembly)
 - Mixed C and assembly
 - Machine code

MPLAB IDE supports multiple debugging tools in a single development paradigm, from the cost-effective simulators, through low-cost in-circuit debuggers, to full-featured emulators. This eliminates the learning curve when upgrading to tools with increased flexibility and power.

21.2 MPLAB C Compilers for Various Device Families

The MPLAB C Compiler code development systems are complete ANSI C compilers for Microchip's PIC18, PIC24 and PIC32 families of microcontrollers and the dsPIC30 and dsPIC33 families of digital signal controllers. These compilers provide powerful integration capabilities, superior code optimization and ease of use.

For easy source level debugging, the compilers provide symbol information that is optimized to the MPLAB IDE debugger.

21.3 HI-TECH C for Various Device Families

The HI-TECH C Compiler code development systems are complete ANSI C compilers for Microchip's PIC family of microcontrollers and the dsPIC family of digital signal controllers. These compilers provide powerful integration capabilities, omniscient code generation and ease of use.

For easy source level debugging, the compilers provide symbol information that is optimized to the MPLAB IDE debugger.

The compilers include a macro assembler, linker, preprocessor, and one-step driver, and can run on multiple platforms.

21.4 MPASM Assembler

The MPASM Assembler is a full-featured, universal macro assembler for PIC10/12/16/18 MCUs.

The MPASM Assembler generates relocatable object files for the MPLINK Object Linker, Intel[®] standard HEX files, MAP files to detail memory usage and symbol reference, absolute LST files that contain source lines and generated machine code and COFF files for debugging.

The MPASM Assembler features include:

- Integration into MPLAB IDE projects
- User-defined macros to streamline
 assembly code
- Conditional assembly for multi-purpose source files
- Directives that allow complete control over the assembly process

21.5 MPLINK Object Linker/ MPLIB Object Librarian

The MPLINK Object Linker combines relocatable objects created by the MPASM Assembler and the MPLAB C18 C Compiler. It can link relocatable objects from precompiled libraries, using directives from a linker script.

The MPLIB Object Librarian manages the creation and modification of library files of precompiled code. When a routine from a library is called from a source file, only the modules that contain that routine will be linked in with the application. This allows large libraries to be used efficiently in many different applications.

The object linker/library features include:

- Efficient linking of single libraries instead of many smaller files
- Enhanced code maintainability by grouping related modules together
- Flexible creation of libraries with easy module listing, replacement, deletion and extraction

21.6 MPLAB Assembler, Linker and Librarian for Various Device Families

MPLAB Assembler produces relocatable machine code from symbolic assembly language for PIC24, PIC32 and dsPIC devices. MPLAB C Compiler uses the assembler to produce its object file. The assembler generates relocatable object files that can then be archived or linked with other relocatable object files and archives to create an executable file. Notable features of the assembler include:

- · Support for the entire device instruction set
- · Support for fixed-point and floating-point data
- · Command line interface
- Rich directive set
- Flexible macro language
- MPLAB IDE compatibility

21.7 MPLAB SIM Software Simulator

The MPLAB SIM Software Simulator allows code development in a PC-hosted environment by simulating the PIC MCUs and dsPIC[®] DSCs on an instruction level. On any given instruction, the data areas can be examined or modified and stimuli can be applied from a comprehensive stimulus controller. Registers can be logged to files for further run-time analysis. The trace buffer and logic analyzer display extend the power of the simulator to record and track program execution, actions on I/O, most peripherals and internal registers.

The MPLAB SIM Software Simulator fully supports symbolic debugging using the MPLAB C Compilers, and the MPASM and MPLAB Assemblers. The software simulator offers the flexibility to develop and debug code outside of the hardware laboratory environment, making it an excellent, economical software development tool.

21.8 MPLAB REAL ICE In-Circuit Emulator System

MPLAB REAL ICE In-Circuit Emulator System is Microchip's next generation high-speed emulator for Microchip Flash DSC and MCU devices. It debugs and programs PIC[®] Flash MCUs and dsPIC[®] Flash DSCs with the easy-to-use, powerful graphical user interface of the MPLAB Integrated Development Environment (IDE), included with each kit.

The emulator is connected to the design engineer's PC using a high-speed USB 2.0 interface and is connected to the target with either a connector compatible with incircuit debugger systems (RJ11) or with the new high-speed, noise tolerant, Low-Voltage Differential Signal (LVDS) interconnection (CAT5).

The emulator is field upgradable through future firmware downloads in MPLAB IDE. In upcoming releases of MPLAB IDE, new devices will be supported, and new features will be added. MPLAB REAL ICE offers significant advantages over competitive emulators including low-cost, full-speed emulation, run-time variable watches, trace analysis, complex breakpoints, a ruggedized probe interface and long (up to three meters) interconnection cables.

21.9 MPLAB ICD 3 In-Circuit Debugger System

MPLAB ICD 3 In-Circuit Debugger System is Microchip's most cost effective high-speed hardware debugger/programmer for Microchip Flash Digital Signal Controller (DSC) and microcontroller (MCU) devices. It debugs and programs PIC[®] Flash microcontrollers and dsPIC[®] DSCs with the powerful, yet easyto-use graphical user interface of MPLAB Integrated Development Environment (IDE).

The MPLAB ICD 3 In-Circuit Debugger probe is connected to the design engineer's PC using a high-speed USB 2.0 interface and is connected to the target with a connector compatible with the MPLAB ICD 2 or MPLAB REAL ICE systems (RJ-11). MPLAB ICD 3 supports all MPLAB ICD 2 headers.

21.10 PICkit 3 In-Circuit Debugger/ Programmer and PICkit 3 Debug Express

The MPLAB PICkit 3 allows debugging and programming of PIC[®] and dsPIC[®] Flash microcontrollers at a most affordable price point using the powerful graphical user interface of the MPLAB Integrated Development Environment (IDE). The MPLAB PICkit 3 is connected to the design engineer's PC using a full speed USB interface and can be connected to the target via an Microchip debug (RJ-11) connector (compatible with MPLAB ICD 3 and MPLAB REAL ICE). The connector uses two device I/O pins and the reset line to implement in-circuit debugging and In-Circuit Serial Programming[™].

The PICkit 3 Debug Express include the PICkit 3, demo board and microcontroller, hookup cables and CDROM with user's guide, lessons, tutorial, compiler and MPLAB IDE software.

21.11 PICkit 2 Development Programmer/Debugger and PICkit 2 Debug Express

The PICkit[™] 2 Development Programmer/Debugger is a low-cost development tool with an easy to use interface for programming and debugging Microchip's Flash families of microcontrollers. The full featured Windows[®] programming interface supports baseline (PIC10F, PIC12F5xx, PIC16F5xx), midrange (PIC12F6xx, PIC16F), PIC18F, PIC24, dsPIC30, dsPIC33, and PIC32 families of 8-bit, 16-bit, and 32-bit microcontrollers, and many Microchip Serial EEPROM products. With Microchip's powerful MPLAB Integrated Development Environment (IDE) the PICkit[™] 2 in-circuit debugging on most PIC® enables microcontrollers. In-Circuit-Debugging runs, halts and single steps the program while the PIC microcontroller is embedded in the application. When halted at a breakpoint, the file registers can be examined and modified.

The PICkit 2 Debug Express include the PICkit 2, demo board and microcontroller, hookup cables and CDROM with user's guide, lessons, tutorial, compiler and MPLAB IDE software.

21.12 MPLAB PM3 Device Programmer

The MPLAB PM3 Device Programmer is a universal, CE compliant device programmer with programmable voltage verification at VDDMIN and VDDMAX for maximum reliability. It features a large LCD display (128 x 64) for menus and error messages and a modular, detachable socket assembly to support various package types. The ICSP™ cable assembly is included as a standard item. In Stand-Alone mode, the MPLAB PM3 Device Programmer can read, verify and program PIC devices without a PC connection. It can also set code protection in this mode. The MPLAB PM3 connects to the host PC via an RS-232 or USB cable. The MPLAB PM3 has high-speed communications and optimized algorithms for quick programming of large memory devices and incorporates an MMC card for file storage and data applications.

21.13 Demonstration/Development Boards, Evaluation Kits, and Starter Kits

A wide variety of demonstration, development and evaluation boards for various PIC MCUs and dsPIC DSCs allows quick application development on fully functional systems. Most boards include prototyping areas for adding custom circuitry and provide application firmware and source code for examination and modification.

The boards support a variety of features, including LEDs, temperature sensors, switches, speakers, RS-232 interfaces, LCD displays, potentiometers and additional EEPROM memory.

The demonstration and development boards can be used in teaching environments, for prototyping custom circuits and for learning about various microcontroller applications.

In addition to the PICDEM[™] and dsPICDEM[™] demonstration/development board series of circuits, Microchip has a line of evaluation kits and demonstration software for analog filter design, KEELOQ[®] security ICs, CAN, IrDA[®], PowerSmart battery management, SEEVAL[®] evaluation system, Sigma-Delta ADC, flow rate sensing, plus many more.

Also available are starter kits that contain everything needed to experience the specified device. This usually includes a single application and debug capability, all on one board.

Check the Microchip web page (www.microchip.com) for the complete list of demonstration, development and evaluation kits.

22.0 ELECTRICAL CHARACTERISTICS

This section provides an overview of PIC24HJ32GP202/204 and PIC24HJ16GP304 electrical characteristics. Additional information will be provided in future revisions of this document as it becomes available.

Absolute maximum ratings for the PIC24HJ32GP202/204 and PIC24HJ16GP304 family are listed below. Exposure to these maximum rating conditions for extended periods can affect device reliability. Functional operation of the device at these or any other conditions above the parameters indicated in the operation listings of this specification is not implied.

Absolute Maximum Ratings⁽¹⁾

Ambient temperature under bias	40°C to +125°C
Storage temperature	65°C to +160°C
Voltage on VDD with respect to Vss	-0.3V to +4.0V
Voltage on any pin that is not 5V tolerant with respect to Vss ⁽⁴⁾	0.3V to (VDD + 0.3V)
Voltage on any 5V tolerant pin with respect to Vss when VDD < 3.0V ⁽⁴⁾	0.3V to 3.6V
Voltage on any 5V tolerant pin with respect to Vss when $VDD \ge 3.0V^{(4)}$	0.3V to +5.6V
Maximum current out of Vss pin	
Maximum current into Vod pin ⁽²⁾	
Maximum output current sunk by any I/O pin ⁽³⁾	4 mA
Maximum output current sourced by any I/O pin ⁽³⁾	4 mA
Maximum current sunk by all ports	
Maximum current sourced by all ports ⁽²⁾	200 mA

- **Note 1:** Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only, and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.
 - 2: Maximum allowable current is a function of device maximum power dissipation (see Table 22-2).
 - 3: Exceptions are CLKOUT, which is able to sink/source 25 mA, and the VREF+, VREF-, SCLx, SDAx, PGECx and PGEDx pins, which are able to sink/source 12 mA.
 - 4: Refer to the "Pin Diagrams" section for 5V tolerant pins.

22.1 DC Characteristics

	Voo Benge	Tomp Dongo	Max MIPS
Characteristic	VDD Range (in Volts)	Temp Range (in °C)	PIC24HJ32GP202/204 and PIC24HJ16GP304
	3.0-3.6V	-40°C to +85°C	40
	3.0-3.6V	-40°C to +125°C	40

TABLE 22-1: OPERATING MIPS VS. VOLTAGE

TABLE 22-2: THERMAL OPERATING CONDITIONS

Rating	Symbol	Min	Тур	Max	Unit
Industrial Temperature Devices					
Operating Junction Temperature Range	TJ	-40		+125	°C
Operating Ambient Temperature Range	TA	-40		+85	°C
Extended Temperature Devices					
Operating Junction Temperature Range	TJ	-40		+155	°C
Operating Ambient Temperature Range	TA	-40		+125	°C
Power Dissipation: Internal chip power dissipation: $PINT = VDD x (IDD - \Sigma IOH)$	PD		PINT + PI/0	D	W
I/O Pin Power Dissipation: I/O = Σ ({VDD - VOH} x IOH) + Σ (VOL x IOL)					
Maximum Allowed Power Dissipation	PDMAX	(Tj - Ta)/θj	A	W

TABLE 22-3: THERMAL PACKAGING CHARACTERISTICS

Characteristic	Symbol	Тур	Max	Unit	Notes
Package Thermal Resistance, 44-pin QFN	θја	32	—	°C/W	1
Package Thermal Resistance, 44-pin TFQP	θја	45	—	°C/W	1
Package Thermal Resistance, 28-pin SPDIP	θја	45	—	°C/W	1
Package Thermal Resistance, 28-pin SOIC	θја	50	—	°C/W	1
Package Thermal Resistance, 28-pin SSOP	θја	71	—	°C/W	1
Package Thermal Resistance, 28-pin QFN-S	θja	35	_	°C/W	1

Note 1: Junction to ambient thermal resistance, Theta-JA (θ JA) numbers are achieved by package simulations.

TABLE 22-4: DC TEMPERATURE AND VOLTAGE SPECIFICATIONS

DC CHA	ARACTER	Standard Operating Conditions: 3.0V to 3.6V(unless otherwise stated)Operating temperature $-40^{\circ}C \leq TA \leq +85^{\circ}C$ for Industrial $-40^{\circ}C \leq TA \leq +125^{\circ}C$ for Extended					
Param No.	Symbol	Characteristic	Min	Тур ⁽¹⁾	Max	Units	Conditions
Operati	ng Voltag	9					
DC10	Supply V	oltage					
	Vdd	—	3.0	_	3.6	V	Industrial and Extended
DC12	Vdr	RAM Data Retention Voltage ⁽²⁾	1.8	—	—	V	—
DC16	VPOR	VDD Start Voltage to ensure internal Power-on Reset signal	_	_	Vss	V	_
DC17 SVDD VDD Rise Rate to ensure internal Power-on Reset signal			0.03	_	—	V/ms	0-3.0V in 0.1s

Note 1: Data in "Typ" column is at 3.3V, 25°C unless otherwise stated.

2: This is the limit to which VDD can be lowered without losing RAM data.

TABLE 22-5: DC CHARACTERISTICS: OPERATING CURRENT (IDD)

DC CHARACT	ERISTICS		Standard Operating Conditions: 3.0V to 3.6V(unless otherwise stated)Operating temperature $-40^{\circ}C \leq TA \leq +85^{\circ}C$ for Industrial $-40^{\circ}C \leq TA \leq +125^{\circ}C$ for Extended				
Parameter No.	Typical ⁽¹⁾	Max	Units		Conditions		
Operating Cur	rent (IDD) ⁽²⁾						
DC20d	20	30	mA	-40°C			
DC20a	19	22	mA	+25°C	- 3.3V	10 MIPS ⁽³⁾	
DC20b	19	25	mA	+85°C	3.3V	10 MIPS(*/	
DC20c	19	30	mA	+125°C			
DC21d	28	40	mA	-40°C			
DC21a	27	30	mA	+25°C	3.3V	16 MIPS ⁽³⁾	
DC21b	27	32	mA	+85°C		10 MIPS(*)	
DC21c	27	36	mA	+125°C			
DC22d	33	50	mA	-40°C			
DC22a	33	40	mA	+25°C	3.3∨	20 MIPS ⁽³⁾	
DC22b	33	40	mA	+85°C	3.3V	20 MIP 307	
DC22c	33	50	mA	+125°C			
DC23d	44	60	mA	-40°C			
DC23a	43	50	mA	+25°C	- 3.3∨	30 MIPS ⁽³⁾	
DC23b	42	55	mA	+85°C	3.3V	30 MIPS(*)	
DC23c	41	65	mA	+125°C]		
DC24d	55	75	mA	-40°C			
DC24a	54	65	mA	+25°C	2.21/		
DC24b	52	70	mA	+85°C	- 3.3V	40 MIPS	
DC24c	51	80	mA	+125°C			

Note 1: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors, such as I/O pin loading and switching rate, oscillator type, internal code execution pattern and temperature, also have an impact on the current consumption. The test conditions for all IDD measurements are as follows: OSC1 driven with external square wave from rail to rail. All I/O pins are configured as inputs and pulled to Vss. MCLR = VDD, WDT and FSCM are disabled. CPU, SRAM, program memory and data memory are operational. No peripheral modules are operating; however, every peripheral is being clocked (PMD bits are all zeroed).

3: These parameters are characterized, but are not tested in manufacturing.

DC CHARACT	ERISTICS		(unless oth	perating Conditions erwise stated) emperature -40°C = -40°C =				
Parameter No.	Typical ⁽¹⁾	Max	Units	s Conditions				
Idle Current (li	DLE): Core OF	F Clock ON	Base Curren	t ⁽²⁾				
DC40d	7	20	mA	-40°C				
DC40a	6	7	mA	+25°C		10 MIPS ⁽³⁾		
DC40b	6	10	mA	+85°C	3.3V	10 MIPS**		
DC40c	6	20	mA	+125°C				
DC41d	10	20	mA	-40°C				
DC41a	8	9	mA	+25°C	2.2\/	16 MIPS ⁽³⁾		
DC41b	8	10	mA	+85°C	3.3V			
DC41c	8	20	mA	+125°C				
DC42d	11	20	mA	-40°C				
DC42a	10	10	mA	+25°C	3.3∨	20 MIPS ⁽³⁾		
DC42b	10	12	mA	+85°C	3.3V	20 MIP3**		
DC42c	10	20	mA	+125°C				
DC43d	14	25	mA	-40°C				
DC43a	13	14	mA	+25°C	3.3V	30 MIPS ⁽³⁾		
DC43b	13	15	mA	+85°C	3.3V	30 WIF 3(*)		
DC43c	13	25	mA	+125°C				
DC44d	14	25	mA	-40°C				
DC44a	17	20	mA	+25°C	3.3∨	40 MIPS		
DC44b	17	20	mA	+85°C		40 101175		
DC44c	18	30	mA	+125°C				

TABLE 22-6: DC CHARACTERISTICS: IDLE CURRENT (IIDLE)

Note 1: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated.

2: Base IIDLE current is measured with core off, clock on and all modules turned off. Peripheral Module Disable SFR registers are zeroed. All I/O pins are configured as inputs and pulled to Vss.

3: These parameters are characterized, but are not tested in manufacturing.

DC CHARAG	CTERISTICS		Standard Operating Conditions: 3.0V to 3.6V(unless otherwise stated)Operating temperature $-40^{\circ}C \leq TA \leq +85^{\circ}C$ for Industrial $-40^{\circ}C \leq TA \leq +125^{\circ}C$ for Extended							
Parameter No.	Typical ⁽¹⁾	Max	Units	Units Conditions						
Power-Dow	n Current (IPD) ⁽²⁾								
DC60d	55	500	μA	-40°C						
DC60a	63	300	μA	+25°C	2.21/	Base Power-Down Current ^(3,4)				
DC60b	85	350	μA	+85°C	3.3V					
DC60c	146	600	μA	+125°C						
DC61d	8	15	μΑ	-40°C						
DC61a	2	3	μA	+25°C	2.21/	Watchdog Timer Current: ∆IwDT ^(3,5)				
DC61b	2	2	μA	+85°C	3.3V	Watchdog Timer Current: AlwD1(5)				
DC61c	3	5	μA	+125°C						

TABLE 22-7: DC CHARACTERISTICS: POWER-DOWN CURRENT (IPD)

Note 1: Data in the Typical column is at 3.3V, 25°C unless otherwise stated.

2: Base IPD is measured with all peripherals and clocks shut down. All I/Os are configured as inputs and pulled to Vss. WDT, etc., are all switched off, and VREGS (RCON<8>)=1.

3: The Δ current is the additional current consumed when the module is enabled. This current should be added to the base IPD current.

4: These currents are measured on the device containing the most memory in this family.

5: These parameters are characterized, but are not tested in manufacturing.

TABLE 22-8: DC CHARACTERISTICS: DOZE CURRENT (IDOZE)

DC CHARACTERI	STICS	Standard Operating Conditions: 3.0V to 3.6V(unless otherwise stated)Operating temperature $-40^{\circ}C \leq TA \leq +85^{\circ}C$ for Industrial $-40^{\circ}C \leq TA \leq +125^{\circ}C$ for Extended						
Parameter No.	Typical ^(1,2)	Max	Doze Ratio	Units	Conditions			
DC73a	41	51	1:2	mA				
DC73f	20	28	1:64	mA	-40°C	3.3V	40 MIPS	
DC73g	19	24	1:128	mA				
DC70a	40	46	1:2	mA				
DC70f	18	20	1:64	mA	+25°C	3.3V	40 MIPS	
DC70g	18	20	1:128	mA				
DC71a	40	46	1:2	mA				
DC71f	18	25	1:64	mA	+85°C	3.3V	40 MIPS	
DC71g	18	20	1:128	mA				
DC72a	39	55	1:2	mA				
DC72f	18	30	1:64	mA	+125°C	3.3V	40 MIPS	
DC72g	18	25	1:128	mA				

Note 1: Data in the Typical column is at 3.3V, 25°C unless otherwise stated.

2: Parameters with Doze ratios of 1:2 and 1:64 are characterized, but are not tested in manufacturing.

TABLE 22-9: DC CHARACTERISTICS: I/O PIN INPUT SPECIFICAT
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DC CHARACTERISTICS		Standard Operating Conditions: 3.0V to 3.6V(unless otherwise stated)Operating temperature $-40^{\circ}C \leq TA \leq +85^{\circ}C$ for Industrial $-40^{\circ}C \leq TA \leq +125^{\circ}C$ for Extended					
Param No.	Symbol	Characteristic	Min	Typ ⁽¹⁾	Max	Units	Conditions
	VIL	Input Low Voltage					
DI10		I/O pins	Vss	—	0.2 Vdd	V	
DI15		MCLR	Vss	—	0.2 Vdd	V	
DI16		I/O Pins with OSC1 or SOSCI	Vss	—	0.2 Vdd	V	
DI18		SDAx, SCLx	Vss	—	0.3 Vdd	V	SMbus disabled
DI19		SDAx, SCLx	Vss	—	0.8	V	SMbus enabled
	Vih	Input High Voltage					
DI20		I/O Pins Not 5V Tolerant ⁽⁴⁾ I/O Pins 5V Tolerant ⁽⁴⁾	0.7 Vdd 0.7 Vdd	_	Vdd 5.5	V V	—
DI28		SDAx, SCLx	0.7 Vdd	—	5.5	V	SMbus disabled
DI29		SDAx, SCLx	2.1	—	5.5	V	SMbus enabled
	ICNPU	CNx Pull-up Current					
DI30			50	250	400	μA	VDD = 3.3V, VPIN = VSS

Note 1: Data in "Typ" column is at 3.3V, 25°C unless otherwise stated.

2: The leakage current on the MCLR pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

- **3:** Negative current is defined as current sourced by the pin.
- 4: See the "Pin Diagrams" section for a list of digital-only and analog pins.
- **5:** VIL source < (Vss 0.3). Characterized but not tested.
- **6:** Non-5V tolerant pins VIH source > (VDD + 0.3), 5V tolerant pins VIH source > 5V or devices with USB, "D+" and "D-" VIH source > (VUSB + 0.3). Characterized but not tested.
- 7: Digital 5V tolerant pins cannot tolerate any "positive" input injection current from input sources > 5V.
- 8: Injection currents > | 0 | can affect the ADC results by approximately 4-6 counts.
- **9:** Any number and/or combination of I/O pins not excluded under IICL or IICH conditions are permitted provided the mathematical "absolute instantaneous" sum of the input injection currents from all pins do not exceed the specified limit. Characterized but not tested.

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+125°C for Extended					
Param No.	Symbol	Characteristic	Min	Typ ⁽¹⁾	Max	Units	Conditions	
DI50	lil	Input Leakage Current ^(2,3) I/O Pins 5V Tolerant ⁽⁴⁾	_		±2	μΑ	Vss ⊴VPIN ⊴VDD, Pin at high-impedance	
DI51		I/O Pins Not 5V Tolerant ⁽⁴⁾	—	_	±1	μA	Vss ≤VPıN ≤VDD, Pin at high-impedance, -40°C ≤TA ≤+85°C	
DI51a		I/O Pins Not 5V Tolerant ⁽⁴⁾	_	_	±2	μA	Shared with external refer- ence pins, -40°C ≤TA ≤+85°C	
DI51b		I/O Pins Not 5V Tolerant ⁽⁴⁾	_	_	±3.5	μA	Vss ≤VPIN ≤VDD, Pin at high-impedance, -40°C ≤TA ≤+125°C	
DI51c		I/O Pins Not 5V Tolerant ⁽⁴⁾	_	_	±8	μA	Analog pins shared with external reference pins, -40°C ≤TA ≤+125°C	
DI55		MCLR	_	—	±2	μA	Vss ≤Vpin ≤Vdd	
DI56		OSC1	—	—	±2	μA	Vss ⊴VPIN ⊴VDD, XT and HS modes	

TABLE 22-9: DC CHARACTERISTICS: I/O PIN INPUT SPECIFICATIONS (CONTINUED)

Note 1: Data in "Typ" column is at 3.3V, 25°C unless otherwise stated.

2: The leakage current on the MCLR pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

- **3:** Negative current is defined as current sourced by the pin.
- 4: See the "Pin Diagrams" section for a list of digital-only and analog pins.
- 5: VIL source < (VSS 0.3). Characterized but not tested.
- **6:** Non-5V tolerant pins VIH source > (VDD + 0.3), 5V tolerant pins VIH source > 5V or devices with USB, "D+" and "D-" VIH source > (VUSB + 0.3). Characterized but not tested.
- 7: Digital 5V tolerant pins cannot tolerate any "positive" input injection current from input sources > 5V.
- 8: Injection currents > | 0 | can affect the ADC results by approximately 4-6 counts.
- **9:** Any number and/or combination of I/O pins not excluded under IICL or IICH conditions are permitted provided the mathematical "absolute instantaneous" sum of the input injection currents from all pins do not exceed the specified limit. Characterized but not tested.

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V(unless otherwise stated)Operating temperature $-40^{\circ}C \leq TA \leq +85^{\circ}C$ for Industrial $-40^{\circ}C \leq TA \leq +125^{\circ}C$ for Extended					
Param No.	Symbol	Characteristic	Min	Typ ⁽¹⁾	Max	Units	Conditions	
DI60a	licl	Input Low Injection Current	0		₋₅ (5,8)	mA	All pins exce <u>pt VDD,</u> Vss, AVDD, AVss, MCLR, VCAP, SOSCI, SOSCO, and RB14	
DI60b	Іісн	Input High Injection Current	0	_	+5 ^(6,7,8)	mA	All pins except VDD, VSS, AVDD, AVSS, MCLR, VCAP, SOSCI, SOSCO, RB14, and digital 5V-tolerant designated pins	
DI60c	∑іст	Total Input Injection Current (sum of all I/O and control pins)	-20 ⁽⁹⁾		+20 ⁽⁹⁾	mA	Absolute instantaneous sum of all \pm input injection currents from all I/O pins (IICL + IICH) $\leq \mathbb{I}$ ICT	

TABLE 22-9: DC CHARACTERISTICS: I/O PIN INPUT SPECIFICATIONS (CONTINUED)

Note 1: Data in "Typ" column is at 3.3V, 25°C unless otherwise stated.

2: The leakage current on the MCLR pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

- **3:** Negative current is defined as current sourced by the pin.
- 4: See the "Pin Diagrams" section for a list of digital-only and analog pins.
- **5:** VIL source < (VSS 0.3). Characterized but not tested.
- **6:** Non-5V tolerant pins VIH source > (VDD + 0.3), 5V tolerant pins VIH source > 5V or devices with USB, "D+" and "D-" VIH source > (VUSB + 0.3). Characterized but not tested.
- 7: Digital 5V tolerant pins cannot tolerate any "positive" input injection current from input sources > 5V.
- 8: Injection currents > | 0 | can affect the ADC results by approximately 4-6 counts.
- **9:** Any number and/or combination of I/O pins not excluded under IICL or IICH conditions are permitted provided the mathematical "absolute instantaneous" sum of the input injection currents from all pins do not exceed the specified limit. Characterized but not tested.

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V(unless otherwise stated)Operating temperature $-40^{\circ}C \leq TA \leq +85^{\circ}C$ for Industrial $-40^{\circ}C \leq TA \leq +125^{\circ}C$ for Extended					
Param No.	Symbol	Characteristic	Min Typ Max Units Conditions					
	Vol	Output Low Voltage						
DO10		I/O ports	_	_	0.4	V	IOL = 2mA, VDD = 3.3V	
DO16		OSC2/CLKO	—	—	0.4	V	IOL = 2mA, VDD = 3.3V	
	Voh	Output High Voltage						
DO20		I/O ports	2.40	—	—	V	IOH = -2.3 mA, VDD = 3.3V	
DO26		OSC2/CLKO	2.41		—	V	IOH = -1.3 mA, VDD = 3.3V	

TABLE 22-10: DC CHARACTERISTICS: I/O PIN OUTPUT SPECIFICATIONS

TABLE 22-11: ELECTRICAL CHARACTERISTICS: BOR

DC CHAR	DC CHARACTERISTICS		Standard Operating Conditions: 3.0V to 3.6V(unless otherwise stated)Operating temperature $-40^{\circ}C \leq TA \leq +85^{\circ}C$ for Industrial $-40^{\circ}C \leq TA \leq +125^{\circ}C$ for Extended						
Param No.	Symbol	Characteristic ⁽¹⁾		Min	Тур	Max	Units	Conditions	
BO10	VBOR	BOR Event on VDD transition high-to-low		2.40	—	2.55	V	Vdd	

Note 1: Parameters are for design guidance only and are not tested in manufacturing.

DC CHA	RACTER	ISTICS	(unless		ise state	nditions: 3.0V to 3.6V ed) -40°C ≤TA ≤+85°C for Industrial			
		Operation	ng temp	erature	-40°C ≤TA ≤+05°C for Extended				
Param No.	Symbol	Characteristic ⁽³⁾	Min	Typ ⁽¹⁾	Max	Units	Conditions		
		Program Flash Memory							
D130	Eр	Cell Endurance	10,000	—	—	E/W	-40° C to +125° C		
D131	Vpr	VDD for Read	VMIN	—	3.6	V	VMIN = Minimum operating voltage		
D132B	VPEW	VDD for Self-Timed Write	VMIN	—	3.6	V	VMIN = Minimum operating voltage		
D134	TRETD	Characteristic Retention	20	—	—	Year	Provided no other specifications are violated, -40°C to +125°C		
D135	IDDP	Supply Current during Programming	-	10	—	mA			
D136a	Trw	Row Write Time	1.32	—	1.74	ms	TRW = 11064 FRC cycles, TA = +85°C, See Note 2		
D136b	Trw	Row Write Time	1.28	—	1.79	ms	TRW = 11064 FRC cycles, TA = +125°C, See Note 2		
D137a	Тре	Page Erase Time	20.1	—	26.5	ms	TPE = 168517 FRC cycles, TA = +85°C, See Note 2		
D137b	Тре	Page Erase Time	19.5	—	27.3	ms	TPE = 168517 FRC cycles, TA = +125°C, See Note 2		
D138a	Tww	Word Write Cycle Time	42.3	—	55.9	μs	Tww = 355 FRC cycles, Ta = +85°C, See Note 2		
D138b	Tww	Word Write Cycle Time	41.1	—	57.6	μs	Tww = 355 FRC cycles, TA = +125°C, See Note 2		

TABLE 22-12: DC CHARACTERISTICS: PROGRAM MEMORY

Note 1: Data in "Typ" column is at 3.3V, 25°C unless otherwise stated.

2: Other conditions: FRC = 7.37 MHz, TUN<5:0> = b'011111 (for Min), TUN<5:0> = b'100000 (for Max). This parameter depends on the FRC accuracy (see Table 22-18) and the value of the FRC Oscillator Tuning register (see Register 8-4). For complete details on calculating the Minimum and Maximum time see Section 5.3 "Programming Operations".

3: These parameters are assured by design, but are not characterized or tested in manufacturing.

TABLE 22-13: INTERNAL VOLTAGE REGULATOR SPECIFICATIONS

(unless c	Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)Operating temperature $-40^{\circ}C \le TA \le +85^{\circ}C$ for Industrial $-40^{\circ}C \le TA \le +125^{\circ}C$ for Extended								
Param No.	Symbol	Characteristics	Min	Тур	Max	Units	Comments		
_	Cefc	External Filter Capacitor Value ⁽¹⁾	4.7	10	_	μF	Capacitor must be low series resistance (< 5 ohms)		

Note 1: Typical VCAP voltage = 2.5V when VDD \geq VDDMIN.

22.2 AC Characteristics and Timing Parameters

The information contained in this section defines PIC24HJ32GP202/204 and PIC24HJ16GP304 AC characteristics and timing parameters.

TABLE 22-14: TEMPERATURE AND VOLTAGE SPECIFICATIONS - AC

	Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)
AC CHARACTERISTICS	Operating temperature -40°C ≤TA ≤+85°C for Industrial
	-40°C ≤TA ≤+125°C for Extended
	Operating voltage VDD range as described in Table 22-1.

FIGURE 22-1: LOAD CONDITIONS FOR DEVICE TIMING SPECIFICATIONS



TABLE 22-15: CAPACITIVE LOADING REQUIREMENTS ON OUTPUT PINS

Param No.	Symbol	Characteristic	Min	Тур	Max	Units	Conditions
DO50	Cosc2	OSC2/SOSC2 pin	_		15	pF	In XT and HS modes when external clock is used to drive OSC1
DO56	Cio	All I/O pins and OSC2	—	—	50	pF	EC mode
DO58	Св	SCLx, SDAx	—	—	400	pF	In I ² C™ mode

FIGURE 22-2: EXTERNAL CLOCK TIMING



TABLE 22-16: EXTERNAL CLOCK TIMING REQUIREMENTS

AC CHA	RACTEF	RISTICS	Standard Operating Conditions: 3.0V to 3.6V(unless otherwise stated)Operating temperature $-40^{\circ}C \leq TA \leq +85^{\circ}C$ for Industrial $-40^{\circ}C \leq TA \leq +125^{\circ}C$ for Extended						
Param No.	Symb	Characteristic	Min	Typ ⁽¹⁾	Мах	Units	Conditions		
OS10	Fin	External CLKI Frequency (External clocks allowed only in EC and ECPLL modes) ⁽⁴⁾	DC	_	40	MHz	EC		
		Oscillator Crystal Frequency ⁽⁵⁾	3.5 10		10 40 33	MHz MHz kHz	XT HS SOSC		
OS20	Tosc	Tosc = 1/Fosc ⁽⁴⁾	12.5		DC	ns	_		
OS25	Тсү	Instruction Cycle Time ^(2,4)	25	—	DC	ns			
OS30	TosL, TosH	External Clock in (OSC1) ⁽⁵⁾ High or Low Time	0.375 x Tosc	—	0.625 x Tosc	ns	EC		
OS31	TosR, TosF	External Clock in (OSC1) ⁽⁵⁾ Rise or Fall Time	—	—	20	ns	EC		
OS40	TckR	CLKO Rise Time ^(3,5)		5.2		ns	—		
OS41	TckF	CLKO Fall Time ^(3,5)	—	5.2	—	ns	—		
OS42	Gм	External Oscillator Transconductance ⁽⁶⁾	14	16	18	mA/V	VDD = 3.3V TA = +25°C		

Note 1: Data in "Typ" column is at 3.3V, 25°C unless otherwise stated.

- 2: Instruction cycle period (TCY) equals two times the input oscillator time-base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits can result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "min." values with an external clock applied to the OSC1/CLKI pin. When an external clock input is used, the "max." cycle time limit is "DC" (no clock) for all devices.
- 3: Measurements are taken in EC mode. The CLKO signal is measured on the OSC2 pin.
- 4: These parameters are characterized by similarity, but are tested in manufacturing at FIN = 40 MHz only.
- 5: These parameters are characterized by similarity, but are not tested in manufacturing.
- 6: Data for this parameter is preliminary. This parameter is characterized, but is not tested in manufacturing.

TABLE 22-17: PLL CLOCK TIMING SPECIFICATIONS (VDD = 3.0V TO 3.6V)

АС СНА	RACTERI	STICS	Standard Operating Conditions: 3.0V to 3.6V (unless otherwise statedOperating temperature $-40^{\circ}C \leq T_A \leq +85^{\circ}C$ for Industrial $-40^{\circ}C \leq T_A \leq +125^{\circ}C$ for Extended							
Param No.	Symbol	Characteris	tic	Min	Typ ⁽¹⁾	Max	Units	Conditions		
OS50	Fplli	PLL Voltage Controlled Oscillator (VCO) Input Frequency Range ⁽²⁾		0.8		8	MHz	ECPLL, XTPLL modes		
OS51	Fsys	On-Chip VCO System Frequency ⁽³⁾		100		200	MHz	_		
OS52	TLOCK	PLL Start-up Time (Lo	ock Time) ⁽³⁾	0.9	1.5	3.1	ms	—		
OS53	DCLK	CLKO Stability (Jitter)	-3	0.5	3	%	Measured over 100 ms period			

Note 1: Data in "Typ" column is at 3.3V, 25°C unless otherwise stated.

2: These parameters are characterized by similarity, but are tested in manufacturing at 7.7 MHz input only.

3: These parameters are characterized by similarity, but are not tested in manufacturing. This specification is based on clock cycle by clock cycle measurements. To calculate the effective jitter for individual time bases or communication clocks use this formula:

$$Peripheral Clock Jitter = \frac{DCLK}{\sqrt{\frac{FOSC}{Peripheral Bit Rate Clock}}}$$

For example: Fosc = 32 MHz, DCLK = 3%, SPI bit rate clock, (i.e., SCK) is 2 MHz.

$$SPI SCK Jitter = \left[\frac{D_{CLK}}{\sqrt{\left(\frac{32 MHz}{2 MHz}\right)}}\right] = \left[\frac{3\%}{\sqrt{16}}\right] = \left[\frac{3\%}{4}\right] = 0.75\%$$

TABLE 22-18: AC CHARACTERISTICS: INTERNAL RC ACCURACY

АС СНА	RACTERISTICS		Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)Operating temperature $-40^{\circ}C \leq TA \leq +85^{\circ}C$ for Industrial $-40^{\circ}C \leq TA \leq +125^{\circ}C$ for Extended							
Param No.	Characteristic	Min	Тур	Max	Units	tions				
	Internal FRC Accuracy @	FRC Fr	equency	= 7.37 N	lHz ⁽¹⁾					
F20a	FRC	-2 — +2 % -40°C ≤TA ≤+85°C VDD = 3.0								
F20b	RC -5 -5 % $-40^{\circ}C \leq TA \leq +125^{\circ}C$ VDD = $3.0-3.6V$									

Note 1: Frequency calibrated at 25°C and 3.3V. TUN bits can be used to compensate for temperature drift.

TABLE 22-19: INTERNAL RC ACCURACY

АС СН	ARACTERISTICS	Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)Operating temperature $-40^{\circ}C \le TA \le +85^{\circ}C$ for Industrial $-40^{\circ}C \le TA \le +125^{\circ}C$ for Extended							
Param No.	Characteristic	Min	Typ Max Units Conditions						
-	LPRC @ 32.768 kHz ^(1,2)								
F21a	a LPRC -15 ±6 +15 % -40°C ≤TA ≤+85°C VDD = 3.0-3.								
F21b	LPRC -40 -40°C ≤TA ≤+125°C VDD = 3.0-3.6V								

Note 1: Change of LPRC frequency as VDD changes.

2: LPRC accuracy impacts the Watchdog Timer Time-out Period (TwDT1). See Section 19.4 "Watchdog Timer (WDT)" for more information.

FIGURE 22-3: I/O TIMING CHARACTERISTICS



AC CHAR	AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V(unless otherwise stated)Operating temperature $-40^{\circ}C \leq TA \leq +85^{\circ}C$ for Industrial $-40^{\circ}C \leq TA \leq +125^{\circ}C$ for Extended					
Param No.	Symbol	Characteristic ⁽²⁾		Min	Typ ⁽¹⁾	Max	Units	Conditions	
DO31	TIOR	Port Output Rise Tim	е		10	25	ns	—	
DO32	TIOF	Port Output Fall Time		—	10	25	ns	—	
DI35	TINP	INTx Pin High or Low Time (input)		25	_		ns	_	
DI40	Trbp	CNx High or Low Tim	2		_	TCY			

TABLE 22-20: I/O TIMING REQUIREMENTS

Note 1: Data in "Typ" column is at 3.3V, 25°C unless otherwise stated.

2: These parameters are characterized, but are not tested in manufacturing.





TABLE 22-21: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER, POWER-UP TIMER TIMING REQUIREMENTS

AC CHA	RACTER	ISTICS	Standard Operating Conditions: 3.0V to 3.6V(unless otherwise stated)Operating temperature $-40^{\circ}C \leq TA \leq +85^{\circ}C$ for Industrial $-40^{\circ}C \leq TA \leq +125^{\circ}C$ for Extended							
Param No.	Symbol	Characteristic	Min	Тур ⁽²⁾	Max	Units	Conditions			
SY10	TMCL	MCLR Pulse-Width (low) ⁽¹⁾	2	_		μs	-40°C to +85°C			
SY11	TPWRT	Power-up Timer Period ⁽¹⁾		2 4 16 32 64 128	_	ms	-40°C to +85°C User programmable			
SY12	TPOR	Power-on Reset Delay ⁽³⁾	3	10	30	μs	-40°C to +85°C			
SY13	Tioz	I/O High-Impedance from MCLR Low or Watchdog Timer Reset ⁽¹⁾	0.68	0.72	1.2	μs	_			
SY20	Twdt1	Watchdog Timer Time-out Period ⁽¹⁾	—	—	—	ms	See Section 19.4 "Watchdog Timer (WDT)" and LPRC specification F21a (Table 22-19).			
SY30	Тозт	Oscillator Start-up Time	—	1024 Tosc	—	—	Tosc = OSC1 period			
SY35	TFSCM	Fail-Safe Clock Monitor Delay ⁽¹⁾	—	500	900	μs	-40°C to +85°C			

Note 1: These parameters are characterized but not tested in manufacturing.

2: Data in "Typ" column is at 3.3V, 25°C unless otherwise stated.

3: These parameters are characterized by similarity, but are not tested in manufacturing.

FIGURE 22-5: TIMER1, 2 AND 3 EXTERNAL CLOCK TIMING CHARACTERISTICS



AC CHA	RACTERIST	ICS		Standard Operating Conditions: 3.0V to 3.6V(unless otherwise stated)Operating temperature $-40^{\circ}C \leq TA \leq +85^{\circ}C$ for Industrial $-40^{\circ}C \leq TA \leq +125^{\circ}C$ for Extended							
Param No.	Symbol	Characte	ristic ⁽²⁾		Min	Тур	Max	Units	Conditions		
TA10	ТтхН	TxCK High Time	Synchron no presca		0.5 TCY + 20			ns	Must also meet parameter TA15		
			Synchron with prese		10	_	_	ns			
			Asynchro	nous	10	_	_	ns			
TA11	ΤτxL	TxCK Low Time	Synchron no presca		0.5 TCY + 20		—	ns	Must also meet parameter TA15		
			Synchron with prese		10		—	ns			
			Asynchro	nous	10			ns			
TA15	ΤτχΡ	TxCK Input Period	Synchron no presca		Tcy + 40		_	ns	—		
			Synchron with prese		Greater of: 20 ns or (Tcy + 40)/N	—	_	—	N = prescale value (1, 8, 64, 256)		
			Asynchro	nous	20	_		ns			
OS60	Ft1	SOSC1/T1CK Osci frequency Range (c by setting bit TCS (oscillator er	nabled	DC		50	kHz	_		
TA20	TCKEXTMRL	Delay from Externa Edge to Timer Incre		ock	0.5 Tcy		1.5 TCY		—		

TABLE 22-22: TIMER1 EXTERNAL CLOCK TIMING REQUIREMENTS⁽¹⁾

Note 1: Timer1 is a Type A.

2: These parameters are characterized by similarity, but are not tested in manufacturing.

AC CHARACTERISTICS				Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+125°C for Extended						
Param No.	Symbol	Charao	cteristic ⁽¹⁾)	Min	Тур	Max	Units	Conditions	
TB10	TtxH	TxCK High Time	Synchron mode	ious	Greater of: 20 or (Tcy + 20)/N		_	ns	Must also meet parameter TB15 N = prescale value (1, 8, 64, 256)	
TB11	TtxL	TxCK Low Time	Synchron mode	ious	Greater of: 20 or (Tcy + 20)/N	_		ns	Must also meet parameter TB15 N = prescale value (1, 8, 64, 256)	
TB15	TtxP	TxCK Input Period	Synchrone mode	ious	Greater of: 40 or (2 Tcy + 40)/N	—	_	ns	N = prescale value (1, 8, 64, 256)	
TB20	TCKEXTMRL	Delay from Clock Edge ment			0.75 Tcy + 40	_	1.75 Tcy + 40	ns		

Note 1: These parameters are characterized, but are not tested in manufacturing.

TABLE 22-24: TIMER3 EXTERNAL CLOCK TIMING REQUIREMENTS

AC CHARACTERISTICS				Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+125°C for Extended						
Param No.	ⁿ Symbol Characteristic ⁽¹⁾			Min	Тур	Мах	Units	Conditions		
TC10	TtxH	TxCK High Time	Synchronous	Tcy + 20	—	—	ns	Must also meet parameter TC15		
TC11	TtxL	TxCK Low Time	Synchronous	Tcy + 20	—	—	ns	Must also meet parameter TC15		
TC15	TtxP	TxCK Input Period	Synchronous with prescale		_	—	ns	N = prescale value (1, 8, 64, 256)		
TC20	TCKEXTMRL		xternal TxCK o Timer Incre-	0.75 Tcy + 40		1.75 Tcy + 40	ns			

Note 1: These parameters are characterized, but are not tested in manufacturing.

FIGURE 22-6: INPUT CAPTURE (CAPx) TIMING CHARACTERISTICS



TABLE 22-25: INPUT CAPTURE TIMING REQUIREMENTS

AC CHARACTERISTICS			(unless otherwise	Standard Operating Conditions: 3.0V to 3.6V(unless otherwise stated)Operating temperature $-40^{\circ}C \le TA \le +85^{\circ}C$ for Industrial $-40^{\circ}C \le TA \le +125^{\circ}C$ for Extended							
Param No.	Symbol	Characte	ristic ⁽¹⁾	Min	Мах	Units	Conditions				
IC10	TccL	ICx Input Low Time	No Prescaler	0.5 TCY + 20		ns	_				
			With Prescaler	10	_	ns					
IC11	TccH	ICx Input High Time	No Prescaler	0.5 Tcy + 20	_	ns	—				
			With Prescaler	10	_	ns					
IC15	TccP	ICx Input Period		(Tcy + 40)/N	—	ns	N = prescale value (1, 4, 16)				
Note 1:											

FIGURE 22-7: OUTPUT COMPARE MODULE (OCx) TIMING CHARACTERISTICS



TABLE 22-26: OUTPUT COMPARE MODULE TIMING REQUIREMENTS

AC CHA	AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V(unless otherwise stated)Operating temperature $-40^{\circ}C \leq TA \leq +85^{\circ}C$ for Industrial $-40^{\circ}C \leq TA \leq +125^{\circ}C$ for Extended					
Param No.	Symbol	Characteristic ⁽¹⁾	Min	Тур	Мах	Units	Conditions		
OC10	TccF	OCx Output Fall Time	—	—	—	ns	See parameter D032		
OC11	TccR	OCx Output Rise Time	— — — ns See parameter D031						

Note 1: These parameters are characterized but not tested in manufacturing.

FIGURE 22-8: OC/PWM MODULE TIMING CHARACTERISTICS



TABLE 22-27: SIMPLE OC/PWM MODE TIMING REQUIREMENTS

			Standard Operating Conditions: 3.0V to 3.6V(unless otherwise stated)Operating temperature $-40^{\circ}C \leq TA \leq +85^{\circ}C$ for Industrial $-40^{\circ}C \leq TA \leq +125^{\circ}C$ for Extended				
Param No.	Symbol	Characteristic ⁽¹⁾	Min	Тур	Max	Units	Conditions
OC15	Tfd	Fault Input to PWM I/O Change	—	_	Tcy + 20	ns	—
OC20	TFLT	Fault Input Pulse-Width	TCY + 20	_	—	ns	—

Note 1: These parameters are characterized but not tested in manufacturing.

TABLE 22-28: SPIx MAXIMUM DATA/CLOCK RATE SUMMARY

AC CHARAG	CTERISTICS		Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+125°C for Extended					
Maximum Data Rate	Transmit Only Trans		Slave Transmit/Receive (Full-Duplex)	CKE	СКР	SMP		
15 Mhz	Table 22-29	—		0,1	0,1	0,1		
9 Mhz	—	Table 22-30	—	1	0,1	1		
9 Mhz	—	Table 22-31		0	0,1	1		
15 Mhz	—	—	Table 22-32	1	0	0		
11 Mhz	—	—	Table 22-33	1	1	0		
15 Mhz	_	_	Table 22-34	0	1	0		
11 Mhz			Table 22-35	0	0	0		

FIGURE 22-9: SPIX MASTER MODE (HALF-DUPLEX, TRANSMIT ONLY CKE = 0) TIMING CHARACTERISTICS



FIGURE 22-10: SPIX MASTER MODE (HALF-DUPLEX, TRANSMIT ONLY CKE = 1) TIMING CHARACTERISTICS



AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+125°C for Extended					
Param No.	Symbol Characteristic ¹			Typ ⁽²⁾	Max	Units	Conditions	
SP10	TscP	Maximum SCK Frequency	—	—	15	MHz	See Note 3	
SP20	TscF	SCKx Output Fall Time	—	—		ns	See parameter DO32 and Note 4	
SP21	TscR	SCKx Output Rise Time	—	—		ns	See parameter DO31 and Note 4	
SP30	TdoF	SDOx Data Output Fall Time	—	—	_	ns	See parameter DO32 and Note 4	
SP31	TdoR	SDOx Data Output Rise Time	—	—		ns	See parameter DO31 and Note 4	
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	6	20	ns	_	
SP36	TdiV2scH, TdiV2scL	SDOx Data Output Setup to First SCKx Edge	30	—	_	ns	_	

TABLE 22-29: SPIX MASTER MODE (HALF-DUPLEX, TRANSMIT ONLY) TIMING REQUIREMENTS

Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in "Typ" column is at 3.3V, 25°C unless otherwise stated.

3: The minimum clock period for SCKx is 66.7 ns. Therefore, the clock generated in Master mode must not violate this specification.

4: Assumes 50 pF load on all SPIx pins.



FIGURE 22-11: SPIX MASTER MODE (FULL-DUPLEX, CKE = 1, CKP = X, SMP = 1) TIMING CHARACTERISTICS

TABLE 22-30:SPIX MASTER MODE (FULL-DUPLEX, CKE = 1, CKP = x, SMP = 1) TIMING
REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+125°C for Extended					
Param No.	Symbol	Characteristic ⁽¹⁾	Min Typ ⁽²⁾ Max Units Conditions					
SP10	TscP	Maximum SCK Frequency	—		9	MHz	See Note 3	
SP20	TscF	SCKx Output Fall Time	—	—	_	ns	See parameter DO32 and Note 4	
SP21	TscR	SCKx Output Rise Time	—	—	_	ns	See parameter DO31 and Note 4	
SP30	TdoF	SDOx Data Output Fall Time	—	—	_	ns	See parameter DO32 and Note 4	
SP31	TdoR	SDOx Data Output Rise Time	—	—	_	ns	See parameter DO31 and Note 4	
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	6	20	ns	—	
SP36	TdoV2sc, TdoV2scL	SDOx Data Output Setup to First SCKx Edge	30	—	—	ns	—	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	30	—	—	ns	_	
SP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	30			ns	_	

Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in "Typ" column is at 3.3V, 25°C unless otherwise stated.

- **3:** The minimum clock period for SCKx is 111 ns. The clock generated in Master mode must not violate this specification.
- 4: Assumes 50 pF load on all SPIx pins.

FIGURE 22-12: SPIX MASTER MODE (FULL-DUPLEX, CKE = 0, CKP = x, SMP = 1) TIMING CHARACTERISTICS



TABLE 22-31:SPIX MASTER MODE (FULL-DUPLEX, CKE = 0, CKP = x, SMP = 1) TIMING
REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+125°C for Extended					
Param No.	Symbol	Characteristic ⁽¹⁾	Min Typ ⁽²⁾ Max Units Conditions					
SP10	TscP	Maximum SCK Frequency	_	—	9	MHz	-40°C to +125°C and see Note 3	
SP20	TscF	SCKx Output Fall Time	_	—	_	ns	See parameter DO32 and Note 4	
SP21	TscR	SCKx Output Rise Time	_	—	_	ns	See parameter DO31 and Note 4	
SP30	TdoF	SDOx Data Output Fall Time	_	—	_	ns	See parameter DO32 and Note 4	
SP31	TdoR	SDOx Data Output Rise Time		—	_	ns	See parameter DO31 and Note 4	
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge		6	20	ns	_	
SP36	TdoV2scH, TdoV2scL	SDOx Data Output Setup to First SCKx Edge	30	—	—	ns	—	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	30	—		ns	_	
SP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	30	—		ns	_	

Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in "Typ" column is at 3.3V, 25°C unless otherwise stated.

3: The minimum clock period for SCKx is 111 ns. The clock generated in Master mode must not violate this specification.

4: Assumes 50 pF load on all SPIx pins.

FIGURE 22-13: SPIX SLAVE MODE (FULL-DUPLEX, CKE = 1, CKP = 0, SMP = 0) TIMING CHARACTERISTICS


TABLE 22-32:SPIX SLAVE MODE (FULL-DUPLEX, CKE = 1, CKP = 0, SMP = 0) TIMING
REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+125°C for Extended					
Param No.	Symbol	Characteristic ⁽¹⁾	Min	Тур ⁽²⁾	Max	Units	Conditions	
SP70	TscP	Maximum SCK Input Frequency	_	_	15	MHz	See Note 3	
SP72	TscF	SCKx Input Fall Time		_	_	ns	See parameter DO32 and Note 4	
SP73	TscR	SCKx Input Rise Time	—			ns	See parameter DO31 and Note 4	
SP30	TdoF	SDOx Data Output Fall Time	—		—	ns	See parameter DO32 and Note 4	
SP31	TdoR	SDOx Data Output Rise Time	—		—	ns	See parameter DO31 and Note 4	
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	6	20	ns	—	
SP36	TdoV2scH, TdoV2scL	SDOx Data Output Setup to First SCKx Edge	30	_	_	ns	—	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	30	_	—	ns	—	
SP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	30			ns	—	
SP50	TssL2scH, TssL2scL	$\overline{SSx} \downarrow$ to SCKx \uparrow or SCKx Input	120		—	ns	—	
SP51	TssH2doZ	SSx	10	—	50	ns	—	
SP52	TscH2ssH TscL2ssH	SSx after SCKx Edge	1.5 TCY + 40	—	_	ns	See Note 4	
SP60	TssL2doV	SDOx Data Output Valid after SSx Edge	—	_	50	ns	—	

Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in "Typ" column is at 3.3V, 25°C unless otherwise stated.

3: The minimum clock period for SCKx is 66.7 ns. Therefore, the SCK clock generated by the Master must not violate this specification.

4: Assumes 50 pF load on all SPIx pins.





TABLE 22-33:SPIX SLAVE MODE (FULL-DUPLEX, CKE = 1, CKP = 1, SMP = 0) TIMING
REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+125°C for Extended					
Param No.	Symbol	Characteristic ⁽¹⁾	Min	Тур ⁽²⁾	Max	Units	Conditions	
SP70	TscP	Maximum SCK Input Frequency	_	_	11	MHz	See Note 3	
SP72	TscF	SCKx Input Fall Time	—		_	ns	See parameter DO32 and Note 4	
SP73	TscR	SCKx Input Rise Time	—	_	_	ns	See parameter DO31 and Note 4	
SP30	TdoF	SDOx Data Output Fall Time	—	_	_	ns	See parameter DO32 and Note 4	
SP31	TdoR	SDOx Data Output Rise Time	—	_	_	ns	See parameter DO31 and Note 4	
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	6	20	ns	—	
SP36	TdoV2scH, TdoV2scL	SDOx Data Output Setup to First SCKx Edge	30	_	_	ns	—	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	30	_	_	ns	—	
SP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	30		_	ns	—	
SP50	TssL2scH, TssL2scL	$\overline{SSx} \downarrow to SCKx \uparrow or SCKx Input$	120	_	_	ns	—	
SP51	TssH2doZ	SSx ↑ to SDOx Output High-Impedance ⁽⁴⁾	10	_	50	ns	—	
SP52	TscH2ssH TscL2ssH	SSx after SCKx Edge	1.5 Tcy + 40	—	—	ns	See Note 4	
SP60	TssL2doV	SDOx Data Output Valid after SSx Edge	_	—	50	ns	_	

Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in "Typ" column is at 3.3V, 25°C unless otherwise stated.

3: The minimum clock period for SCKx is 91 ns. Therefore, the SCK clock generated by the Master must not violate this specification.

4: Assumes 50 pF load on all SPIx pins.





TABLE 22-34:SPIX SLAVE MODE (FULL-DUPLEX, CKE = 0, CKP = 1, SMP = 0) TIMING
REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+125°C for Extended					
Param No.	Symbol	Characteristic ⁽¹⁾	Min	Тур ⁽²⁾	Max	Units	Conditions	
SP70	TscP	Maximum SCK Input Frequency	_	_	15	MHz	See Note 3	
SP72	TscF	SCKx Input Fall Time	—			ns	See parameter DO32 and Note 4	
SP73	TscR	SCKx Input Rise Time	—	_	_	ns	See parameter DO31 and Note 4	
SP30	TdoF	SDOx Data Output Fall Time	_			ns	See parameter DO32 and Note 4	
SP31	TdoR	SDOx Data Output Rise Time	_	_		ns	See parameter DO31 and Note 4	
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	6	20	ns	—	
SP36	TdoV2scH, TdoV2scL	SDOx Data Output Setup to First SCKx Edge	30	_	_	ns	—	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	30			ns	—	
SP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	30	_	_	ns	—	
SP50	TssL2scH, TssL2scL	$\overline{SSx} \downarrow to SCKx \uparrow or SCKx Input$	120	—	_	ns	_	
SP51	TssH2doZ	SSx	10	—	50	ns	-	
SP52	TscH2ssH TscL2ssH	SSx after SCKx Edge	1.5 Tcy + 40	_	_	ns	See Note 4	

Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in "Typ" column is at 3.3V, 25°C unless otherwise stated.

3: The minimum clock period for SCKx is 66.7 ns. Therefore, the SCK clock generated by the Master must not violate this specification.

4: Assumes 50 pF load on all SPIx pins.





TABLE 22-35:SPIX SLAVE MODE (FULL-DUPLEX, CKE = 0, CKP = 0, SMP = 0) TIMING
REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+125°C for Extended					
Param No.	Symbol	Characteristic ⁽¹⁾	Min	Тур ⁽²⁾	Max	Units	Conditions	
SP70	TscP	Maximum SCK Input Frequency	—	_	11	MHz	See Note 3	
SP72	TscF	SCKx Input Fall Time	—	—		ns	See parameter DO32 and Note 4	
SP73	TscR	SCKx Input Rise Time	_	—		ns	See parameter DO31 and Note 4	
SP30	TdoF	SDOx Data Output Fall Time	—	_	_	ns	See parameter DO32 and Note 4	
SP31	TdoR	SDOx Data Output Rise Time	—	_	_	ns	See parameter DO31 and Note 4	
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	6	20	ns	—	
SP36	TdoV2scH, TdoV2scL	SDOx Data Output Setup to First SCKx Edge	30	_	_	ns	—	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	30	—		ns	—	
SP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	30	_		ns	—	
SP50	TssL2scH, TssL2scL	$\overline{SSx} \downarrow to SCKx \uparrow or SCKx Input$	120	-	—	ns	—	
SP51	TssH2doZ	SSx	10	—	50	ns	—	
SP52	TscH2ssH TscL2ssH	SSx after SCKx Edge	1.5 TCY + 40	—		ns	See Note 4	

Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in "Typ" column is at 3.3V, 25°C unless otherwise stated.

3: The minimum clock period for SCKx is 91 ns. Therefore, the SCK clock generated by the Master must not violate this specification.

4: Assumes 50 pF load on all SPIx pins.

FIGURE 22-17: I2Cx BUS START/STOP BITS TIMING CHARACTERISTICS (MASTER MODE)

FIGURE 22-18: I2Cx BUS DATA TIMING CHARACTERISTICS (MASTER MODE)



AC CHA	ARACTER	ISTICS		Standard Operatir (unless otherwise	stated)			
				Operating tempera			+85°C for Industrial 125°C for Extended	
Param No.	Symbol	Characte	eristic ⁽³⁾	Min ⁽¹⁾	Max	Units	Conditions	
IM10	TLO:SCL	Clock Low Time	100 kHz mode	Tcy/2 (BRG + 1)		μs	—	
			400 kHz mode	Tcy/2 (BRG + 1)	_	μs		
			1 MHz mode ⁽²⁾	Tcy/2 (BRG + 1)		μs	_	
IM11	THI:SCL	Clock High Time	100 kHz mode	Tcy/2 (BRG + 1)	—	μs	_	
			400 kHz mode	Tcy/2 (BRG + 1)	_	μs	_	
	1 MHz mode ⁽²⁾		Tcy/2 (BRG + 1)	_	μs	_		
IM20	TF:SCL	SDAx and SCLx	100 kHz mode	—	300	ns	CB is specified to be	
		Fall Time	400 kHz mode	20 + 0.1 Св	300	ns	from 10 to 400 pF	
			1 MHz mode ⁽²⁾	_	100	ns		
IM21	TR:SCL	SDAx and SCLx	100 kHz mode	—	1000	ns	CB is specified to be	
		Rise Time	400 kHz mode	20 + 0.1 Св	300	ns	from 10 to 400 pF	
			1 MHz mode ⁽²⁾	—	300	ns	-	
IM25	TSU:DAT	Data Input	100 kHz mode	250		ns	_	
		Setup Time	400 kHz mode	100		ns	-	
			1 MHz mode ⁽²⁾	40		ns	1	
IM26	THD:DAT	Data Input	100 kHz mode	0		μs	_	
		Hold Time	400 kHz mode	0	0.9	μs	-	
			1 MHz mode ⁽²⁾	0.2		μs	-	
IM30	TSU:STA	Start Condition	100 kHz mode	Tcy/2 (BRG + 1)		μs	Only relevant for	
		Setup Time	400 kHz mode	TCY/2 (BRG + 1)	_	μs	Repeated Start	
			1 MHz mode ⁽²⁾	Tcy/2 (BRG + 1) —		, μs	condition	
IM31	THD:STA	Start Condition	100 kHz mode	TCY/2 (BRG + 1)	_	, μs	After this period the	
		Hold Time	400 kHz mode	TCY/2 (BRG + 1)	_	μs	first clock pulse is	
			1 MHz mode ⁽²⁾	TCY/2 (BRG + 1)	_	, μs	generated	
IM33	TSU:STO	Stop Condition	100 kHz mode	TCY/2 (BRG + 1)		μs	_	
		Setup Time	400 kHz mode	TCY/2 (BRG + 1)	_	μs	-	
			1 MHz mode ⁽²⁾	TCY/2 (BRG + 1)	_	, μs	-	
IM34	THD:STO	Stop Condition	100 kHz mode	Tcy/2 (BRG + 1)		ns	_	
		Hold Time	400 kHz mode	Tcy/2 (BRG + 1)		ns	-	
			1 MHz mode ⁽²⁾	TCY/2 (BRG + 1)		ns	-	
IM40	TAA:SCL	Output Valid	100 kHz mode		3500	ns	_	
		From Clock	400 kHz mode	—	1000	ns	—	
			1 MHz mode ⁽²⁾	—	400	ns	—	
IM45	TBF:SDA	Bus Free Time	100 kHz mode	4.7	—	μs	Time the bus must be	
			400 kHz mode	1.3	—	, μs	free before a new	
			1 MHz mode ⁽²⁾	0.5		μs	transmission can start	
IM50	Св	Bus Capacitive L			400	pF		
IM51	TPGD	Pulse Gobbler de		65	390	ns	See Note 4	

TABLE 22-36: I2Cx BUS DATA TIMING REQUIREMENTS (MASTER MODE)

Note 1: BRG is the value of the I²C Baud Rate Generator. Refer to Section 19. "Inter-Integrated Circuit (I²C[™])" (DS70195) in the "dsPIC33F/PIC24H Family Reference Manual".

2: Maximum pin capacitance = 10 pF for all I2Cx pins (for 1 MHz mode only).

3: These parameters are characterized by similarity, but are not tested in manufacturing.

4: Typical value for this parameter is 130 ns.







AC CHA	RACTERI			(unless other	rwise sta	ated) -40°C	ns: 3.0V to 3.6V ≤TA ≤+85°C for Industrial ≤TA ≤+125°C for Extended
Param	Symbol	Characte	eristic ⁽²⁾	Min	Max	Units	Conditions
IS10	TLO:SCL	Clock Low Time	100 kHz mode	4.7	_	μs	Device must operate at a minimum of 1.5 MHz
			400 kHz mode	1.3	—	μs	Device must operate at a minimum of 10 MHz
			1 MHz mode ⁽¹⁾	0.5		μs	—
IS11	THI:SCL	Clock High Time	100 kHz mode	4.0	—	μs	Device must operate at a minimum of 1.5 MHz
			400 kHz mode	0.6		μs	Device must operate at a minimum of 10 MHz
			1 MHz mode ⁽¹⁾	0.5	—	μs	
IS20	TF:SCL	SDAx and SCLx	100 kHz mode		300	ns	CB is specified to be from
		Fall Time	400 kHz mode	20 + 0.1 Св	300	ns	10 to 400 pF
			1 MHz mode ⁽¹⁾	—	100	ns	
IS21	TR:SCL	SDAx and SCLx	100 kHz mode	—	1000	ns	CB is specified to be from
		Rise Time	400 kHz mode	20 + 0.1 Св	300	ns	10 to 400 pF
			1 MHz mode ⁽¹⁾	—	300	ns	
IS25	TSU:DAT	Data Input	100 kHz mode	250	_	ns	—
		Setup Time	400 kHz mode	100	_	ns	
			1 MHz mode ⁽¹⁾	100	—	ns	
IS26	THD:DAT	Data Input	100 kHz mode	0	0	μs	—
		Hold Time	400 kHz mode	0	0.9	μs	
			1 MHz mode ⁽¹⁾	0	0.3	μs	
IS30	TSU:STA	Start Condition	100 kHz mode	4.7	—	μs	Only relevant for Repeated
		Setup Time	400 kHz mode	0.6		μs	Start condition
			1 MHz mode ⁽¹⁾	0.25		μs	
IS31	THD:STA	Start Condition	100 kHz mode	4.0		μs	After this period, the first
		Hold Time	400 kHz mode	0.6	—	μs	clock pulse is generated
			1 MHz mode ⁽¹⁾	0.25	—	μs	
IS33	TSU:STO	Stop Condition	100 kHz mode	4.7	—	μs	—
		Setup Time	400 kHz mode	0.6	—	μs	
			1 MHz mode ⁽¹⁾	0.6	—	μs	
IS34	THD:ST	Stop Condition	100 kHz mode	4000	—	ns	—
	0	Hold Time	400 kHz mode	600	—	ns	
			1 MHz mode ⁽¹⁾	250		ns	
IS40	TAA:SCL	Output Valid	100 kHz mode	0	3500	ns	—
		From Clock	400 kHz mode	0	1000	ns	
			1 MHz mode ⁽¹⁾	0	350	ns	
IS45	TBF:SDA	Bus Free Time	100 kHz mode	4.7	—	μs	Time the bus must be free
			400 kHz mode	1.3		μs	before a new transmission can start
			1 MHz mode ⁽¹⁾	0.5		μs	
IS50	Св	Bus Capacitive Lo	ading	<u> </u>	400	pF	<u> </u>

TABLE 22-37: I2Cx BUS DATA TIMING REQUIREMENTS (SLAVE MODE)

Note 1: Maximum pin capacitance = 10 pF for all I2Cx pins (for 1 MHz mode only).

2: These parameters are characterized by similarity, but are not tested in manufacturing.

TABLE 22-38: ADC MODULE SPECIFICATIONS

AC CH	ARACTER	RISTICS	Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤+85°C for Industrial -40°C ≤TA ≤+125°C for Extended						
Param No.	Symbol	Characteristic	Min.	Тур	Max.	Units	Conditions		
			Device	Supply	/				
AD01	AVdd	Module VDD Supply ⁽²⁾	Greater of VDD – 0.3 or 3.0	—	Lesser of VDD + 0.3 or 3.6	V	—		
AD02	AVss	Module Vss Supply ⁽²⁾	Vss - 0.3		Vss + 0.3	V	—		
			Referen	ce Inpu	ts				
AD05	VREFH	Reference Voltage High	AVss + 2.5	_	AVdd	V	See Note 1		
AD05a			3.0		3.6	V	VREFH = AVDD VREFL = AVSS = 0, see Note 2		
AD06	VREFL	Reference Voltage Low	AVss	_	AVDD – 2.5	V	See Note 1		
AD06a			0		0	V	VREFH = AVDD VREFL = AVSS = 0, see Note 2		
AD07	Vref	Absolute Reference Voltage ⁽²⁾	2.5		3.6	V	Vref = Vrefh - Vrefl		
AD08	IREF	Current Drain	_	250 —	550 10	μΑ μΑ	ADC operating, See Note 1 ADC off, See Note 1		
AD08a	IAD	Operating Current	_	7.0 2.7	9.0 3.2	mA mA	10-bit ADC mode, See Note 2 12-bit ADC mode, See Note 2		
			Analo	g Input					
AD12	VINH	Input Voltage Range _{VINH} (2)	Vinl		Vrefh	V	This voltage reflects Sample and Hold Channels 0, 1, 2, and 3 (CH0-CH3), positive input		
AD13	VINL	Input Voltage Range _{VINL} (2)	VREFL	_	AVss + 1V	V	This voltage reflects Sample and Hold Channels 0, 1, 2, and 3 (CH0-CH3), negative input		
AD17	Rin	Recommended Imped- ance of Analog Voltage Source ⁽³⁾	-		200 200	Ω Ω	10-bit ADC 12-bit ADC		

Note 1: These parameters are not characterized or tested in manufacturing.

2: These parameters are characterized, but are not tested in manufacturing.

3: These parameters are assured by design, but are not characterized or tested in manufacturing.

АС СНА	RACTERIS	Standard Operating Conditions: 3.0V to 3.6V(unless otherwise stated)Operating temperature $-40^{\circ}C \leq TA \leq +85^{\circ}C$ for Industrial $-40^{\circ}C \leq TA \leq +125^{\circ}C$ for Extended										
Param No.	Symbol	Characteristic	Min.	Тур	Max.	Units	Conditions					
ADC Accuracy (12-bit Mode) – Measurements with external VREF+/VREF- ⁽³⁾												
AD20a	Nr	Resolution ⁽⁴⁾	12	2 data bit	s	bits	—					
AD21a	INL	Integral Nonlinearity	-2	_	+2	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3.6V					
AD22a	DNL	Differential Nonlinearity	> -1	—	< 1	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3.6V					
AD23a	Gerr	Gain Error	_	3.4	10	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3.6V					
AD24a	EOFF	Offset Error	—	0.9	5	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3.6V					
AD25a	—	Monotonicity	—	—			Guaranteed ⁽¹⁾					
	A	DC Accuracy (12-bit Mode)) – Measu	rements	s with in	ternal V	REF+/VREF- ⁽³⁾					
AD20a	Nr	Resolution ⁽⁴⁾	12	2 data bit	S	bits	—					
AD21a	INL	Integral Nonlinearity	-2		+2	LSb	VINL = AVSS = 0V, AVDD = 3.6V					
AD22a	DNL	Differential Nonlinearity	> -1	_	< 1	LSb	VINL = AVSS = 0V, AVDD = 3.6V					
AD23a	Gerr	Gain Error	—	10.5	20	LSb	VINL = AVSS = 0V, AVDD = 3.6V					
AD24a	EOFF	Offset Error	—	3.8	10	LSb	VINL = AVSS = 0V, AVDD = 3.6V					
AD25a	—	Monotonicity	—				Guaranteed ⁽¹⁾					
		Dynamic P	erforman	ice (12-k	it Mode) ⁽²⁾						
AD30a	THD	Total Harmonic Distortion	—	—	-75	dB	—					
AD31a	SINAD	Signal to Noise and Distortion	68.5	69.5	—	dB	—					
AD32a	SFDR	Spurious Free Dynamic Range	80	—	_	dB	_					
AD33a	Fnyq	Input Signal Bandwidth	_		250	kHz	—					
AD34a	ENOB	Effective Number of Bits	11.09	11.3	_	bits						

TABLE 22-39: ADC MODULE SPECIFICATIONS (12-BIT MODE)⁽⁴⁾

Note 1: The A/D conversion result never decreases with an increase in the input voltage, and has no missing codes.

2: These parameters are characterized by similarity, but are not tested in manufacturing.

3: These parameters are characterized, but are tested at 20 ksps only.

4: Injection currents > | 0 | can affect the ADC results by approximately 4-6 counts.

АС СНА	RACTERIS	Standard Operating Conditions: 3.0V to 3.6V(unless otherwise stated)Operating temperature $-40^{\circ}C \leq TA \leq +85^{\circ}C$ for Industrial $-40^{\circ}C \leq TA \leq +125^{\circ}C$ for Extended									
Param No.	Symbol	Characteristic	Min.	Тур	Max.	Units	Conditions				
ADC Accuracy (10-bit Mode) – Measurements with external VREF+/VREF- ⁽³⁾											
AD20b	Nr	Resolution ⁽⁴⁾	1	0 data bi	ts	bits	—				
AD21b	INL	Integral Nonlinearity	-1.5	—	+1.5	LSb	Vinl = AVSS = VREFL = 0V, AVDD = VREFH = 3.6V				
AD22b	DNL	Differential Nonlinearity	> -1	—	< 1	LSb	Vinl = AVSS = Vrefl = 0V, AVDD = Vrefh = 3.6V				
AD23b	Gerr	Gain Error	-	3	6	LSb	Vinl = AVSS = Vrefl = 0V, AVDD = Vrefh = 3.6V				
AD24b	EOFF	Offset Error	_	2	5	LSb	Vinl = AVss = Vrefl = 0V, AVdd = Vrefh = 3.6V				
AD25b	—	Monotonicity	_			_	Guaranteed ⁽¹⁾				
	A	DC Accuracy (10-bit Mode)) – Meası	irement	s with in	ternal V	ref+/Vref- ⁽³⁾				
AD20b	Nr	Resolution ⁽⁴⁾	10	0 data bi	ts	bits	—				
AD21b	INL	Integral Nonlinearity	-1		+1	LSb	VINL = AVSS = 0V, AVDD = 3.6V				
AD22b	DNL	Differential Nonlinearity	> -1		< 1	LSb	VINL = AVSS = 0V, AVDD = 3.6V				
AD23b	Gerr	Gain Error	_	7	15	LSb	VINL = AVSS = 0V, AVDD = 3.6V				
AD24b	EOFF	Offset Error		3	7	LSb	VINL = AVSS = 0V, AVDD = 3.6V				
AD25b	—	Monotonicity	—	—	—	—	Guaranteed ⁽¹⁾				
		Dynamic P	erformar	nce (10-l	oit Mode) ⁽²⁾					
AD30b	THD	Total Harmonic Distortion	_		-64	dB	—				
AD31b	SINAD	Signal to Noise and Distortion	57	58.5	_	dB	_				
AD32b	SFDR	Spurious Free Dynamic Range	72	—	_	dB					
AD33b	Fnyq	Input Signal Bandwidth	—	_	550	kHz	—				
AD34b	ENOB	Effective Number of Bits	9.16	9.4	_	bits					

TABLE 22-40: ADC MODULE SPECIFICATIONS (10-BIT MODE)⁽⁴⁾

Note 1: The A/D conversion result never decreases with an increase in the input voltage, and has no missing codes.

2: These parameters are characterized by similarity, but are not tested in manufacturing.

3: These parameters are characterized, but are tested at 20 ksps only.

4: Injection currents > | 0 | can affect the ADC results by approximately 4-6 counts.



FIGURE 22-21: ADC CONVERSION (12-BIT MODE) TIMING CHARACTERISTICS

TABLE 22-41: ADC CONVERSION (12-BIT MODE) TIMING REQUIREMENTS

AC CHA		STICS	$\begin{array}{l} \mbox{Standard Operating Conditions: 3.0V to 3.6V} \\ \mbox{(unless otherwise stated)} \\ \mbox{Operating temperature} & -40^{\circ}C \leq TA \leq +85^{\circ}C \mbox{ for Industrial} \\ & -40^{\circ}C \leq TA \leq +125^{\circ}C \mbox{ for Extended} \end{array}$								
Param No.	Symbol	Characteristic	Min. Typ Max. Units Conditions								
Clock Parameters											
AD50	Tad	ADC Clock Period ⁽²⁾	117.6		—	ns	—				
AD51	tRC	ADC Internal RC Oscillator Period ⁽²⁾	—	250	—	ns	—				
Conversion Rate											
AD55	t CONV	Conversion Time ⁽²⁾	—	14 Tad		ns	—				
AD56	FCNV	Throughput Rate ⁽²⁾	—	_	500	Ksps	—				
AD57	TSAMP	Sample Time ⁽²⁾	3.0 Tad		—	_	—				
		Timir	ng Parame	eters							
AD60	tPCS	Conversion Start from Sample Trigger ⁽²⁾	2.0 Tad	—	3.0 Tad	—	Auto Convert Trigger not selected				
AD61	tPSS	Sample Start from Setting Sample (SAMP) bit ⁽²⁾	2.0 Tad	—	3.0 Tad		-				
AD62	tCSS	Conversion Completion to Sample Start (ASAM = 1) ⁽²⁾	—	0.5 Tad	—	_	—				
AD63	tDPU	Time to Stabilize Analog Stage from ADC Off to ADC On ⁽²⁾	—	—	20	μs	—				

Because the sample caps will eventually lose charge, clock rates below 10 kHz can affect linearity Note 1: performance, especially at elevated temperatures.

2: These parameters are characterized but not tested in manufacturing.



FIGURE 22-23: ADC CONVERSION (10-BIT MODE) TIMING CHARACTERISTICS (CHPS<1:0> = 01, SIMSAM = 0, ASAM = 1, SSRC<2:0> = 111, SAMC<4:0> = 00001)



TABLE 22-42:	ADC CONVERSION (10-BIT MODE) TIMING REQUIREMENTS

AC CHA	ARACTER	RISTICS	Standard Operating Conditions: 3.0V to 3.6V(unless otherwise stated)Operating temperature $-40^{\circ}C \leq TA \leq +85^{\circ}C$ for Industrial $-40^{\circ}C \leq TA \leq +125^{\circ}C$ for Extended							
Param No.	Symbol	Characteristic	Min. Typ ⁽¹⁾ Max. Units Conditions							
Clock Parameters										
AD50	Tad	ADC Clock Period ⁽¹⁾	76		_	ns	—			
AD51	tRC	ADC Internal RC Oscillator Period ⁽¹⁾	—	250		ns	_			
Conversion Rate										
AD55	tCONV	Conversion Time ⁽¹⁾	_	12 TAD	—	_	—			
AD56	FCNV	Throughput Rate ⁽¹⁾	—	—	1.1	Msps	—			
AD57	TSAMP	Sample Time ⁽¹⁾	2.0 Tad	—			—			
		Timin	g Parame	eters						
AD60	tPCS	Conversion Start from Sample Trigger ⁽¹⁾	2.0 Tad	_	3.0 Tad		Auto-Convert Trigger not selected			
AD61	tPSS	Sample Start from Setting Sample (SAMP) bit ⁽¹⁾	2.0 Tad	_	3.0 Tad		—			
AD62	tCSS	Conversion Completion to Sample Start (ASAM = 1) ⁽¹⁾	—	0.5 Tad	—	_	—			
AD63	tdpu	Time to Stabilize Analog Stage from ADC Off to ADC On ⁽¹⁾	—	—	20	μs	—			

Note 1: These parameters are characterized but not tested in manufacturing.

2: Because the sample caps will eventually lose charge, clock rates below 10 kHz can affect linearity performance, especially at elevated temperatures.

NOTES:

23.0 HIGH TEMPERATURE ELECTRICAL CHARACTERISTICS

This section provides an overview of PIC24HJ32GP202/204 and PIC24HJ16GP304 electrical characteristics for devices operating in an ambient temperature range of -40°C to +150°C.

Note: Programming of the Flash memory is not allowed above 125°C.

The specifications between -40°C to +150°C are identical to those shown in **Section 22.0 "Electrical Characteristics"** for operation between -40°C to +125°C, with the exception of the parameters listed in this section.

Parameters in this section begin with an H, which denotes High temperature. For example, parameter DC10 in **Section 22.0 "Electrical Characteristics"** is the Industrial and Extended temperature equivalent of HDC10.

Absolute maximum ratings for the PIC24HJ32GP202/204 and PIC24HJ16GP304 high temperature devices are listed below. Exposure to these maximum rating conditions for extended periods can affect device reliability. Functional operation of the device at these or any other conditions above the parameters indicated in the operation listings of this specification is not implied.

Absolute Maximum Ratings⁽¹⁾

Ambient temperature under bias ⁽⁴⁾	40°C to +150°C
Storage temperature	65°C to +160°C
Voltage on VDD with respect to Vss	-0.3V to +4.0V
Voltage on any pin that is not 5V tolerant with respect to Vss ⁽⁵⁾	0.3V to (VDD + 0.3V)
Voltage on any 5V tolerant pin with respect to Vss when $VDD < 3.0V^{(5)}$	-0.3V to 3.6V
Voltage on any 5V tolerant pin with respect to Vss when $VDD \ge 3.0V^{(5)}$	-0.3V to 5.6V
Maximum current out of Vss pin	60 mA
Maximum current into VDD pin ⁽²⁾	60 mA
Maximum junction temperature	+155°C
Maximum output current sunk by any I/O pin ⁽³⁾	1 mA
Maximum output current sourced by any I/O pin ⁽³⁾	1 mA
Maximum current sunk by all ports combined	
Maximum current sourced by all ports combined ⁽²⁾	10 mA

- **Note 1:** Stresses above those listed under "Absolute Maximum Ratings" can cause permanent damage to the device. This is a stress rating only, and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods can affect device reliability.
 - 2: Maximum allowable current is a function of device maximum power dissipation (see Table 23-2).
 - **3:** Unlike devices at 125°C and below, the specifications in this section also apply to the CLKOUT, VREF+, VREF-, SCLx, SDAx, PGCx and PGDx pins.
 - 4: AEC-Q100 reliability testing for devices intended to operate at 150°C is 1,000 hours. Any design in which the total operating time from 125°C to 150°C will be greater than 1,000 hours is not warranted without prior written approval from Microchip Technology Inc.
 - 5: Refer to the "Pin Diagrams" section for 5V tolerant pins.

23.1 High Temperature DC Characteristics

TABLE 23-1: OPERATING MIPS VS. VOLTAGE

	VDD Range	Temperature Range	Max MIPS
Characteristic	(in Volts)	(in °C)	PIC24HJ32GP202/204 and PIC24HJ16GP304
	3.0V to 3.6V	-40°C to +150°C	20

TABLE 23-2: THERMAL OPERATING CONDITIONS

Rating	Symbol	Min	Тур	Max	Unit
High Temperature Devices					
Operating Junction Temperature Range	TJ	-40	—	+155	°C
Operating Ambient Temperature Range	TA	-40	—	+150	°C
Power Dissipation: Internal chip power dissipation: $PINT = VDD x (IDD - \Sigma IOH)$ I/O Pin Power Dissipation: $I/O = \Sigma (\{VDD - VOH\} x IOH) + \Sigma (VOL x IOL)$	PD		Pint + Pi/c)	W
Maximum Allowed Power Dissipation	PDMAX	(TJ - TA)/θJ	A	W

TABLE 23-3: DC TEMPERATURE AND VOLTAGE SPECIFICATIONS

DC CHARACTERISTICS			(unless o	Operating therwise s temperate	stated)		to 3.6V 50°C for High Temperature
Parameter No.	Symbol	Characteristic	Min	Тур	Max	Units	Conditions
Operating V	Voltage						
HDC10	Supply Voltage						
	Vdd		3.0	3.3	3.6	V	-40°C to +150°C

TABLE 23-4: DC CHARACTERISTICS: POWER-DOWN CURRENT (IPD)

DC CHARACT	C CHARACTERISTICS Standard Operating Conditions: 3.0V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+*						
Parameter No.	Typical	Max	Units	Conditions			
Power-Down C	Current (IPD)						
HDC60e	250	2000	μA	+150°C	3.3V	Base Power-Down Current ^(1,3)	
HDC61c	3	5	μA	+150°C 3.3V Watchdog Timer Current: ΔΙω _{DT} ^(2,4)			

Note 1: Base IPD is measured with all peripherals and clocks shut down. All I/Os are configured as inputs and pulled to Vss. WDT, etc., are all switched off, and VREGS (RCON<8>) = 1.

2: The Δ current is the additional current consumed when the module is enabled. This current should be added to the base IPD current.

3: These currents are measured on the device containing the most memory in this family.

4: These parameters are characterized, but are not tested in manufacturing.

TABLE 23-5: DC CHARACTERISTICS: DOZE CURRENT (IDD)

DC CHARACTERISTICS (unless other			,		3.6V °C for High Temperature		
Parameter No.	Typical ⁽¹⁾	Max	Units	Conditions			
Operating C	urrent (IPD) ⁽¹⁾						
HDC20	19	35	mA	+150°C	3.3V	10 MIPS	
HDC21	27	45	mA	+150°C	3.3V	16 MIPS	
HDC22	33	55	mA	+150°C	3.3V	20 MIPS	

Note 1: These parameters are characterized, but are not tested in manufacturing.

TABLE 23-6: DC CHARACTERISTICS: DOZE CURRENT (IDOZE)

DC CHARA				erwise st	•		
Parameter No.	Typical ⁽¹⁾	Мах	Doze Ratio	Units	Conditions		
HDC72a	39	45	1:2	mA			
HDC72f	18	25	1:64	mA	+150°C	3.3V	20 MIPS
HDC72g	18	25	1:128	mA			

Note 1: Parameters with Doze ratios of 1:2 and 1:64 are characterized, but are not tested in manufacturing.

TABLE 23-7: DC CHARACTERISTICS: I/O PIN OUTPUT SPECIFICATIONS

DC CHARACTERISTICS		Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+150°C for High Temperat					
Param No.	Symbol	Characteristic	Min Typ Max Units			Conditions	
	Vol	Output Low Voltage					
HDO10		I/O ports	_	_	0.4	V	IOL = 1 mA, VDD = 3.3V
HDO16		OSC2/CLKO	_		0.4	V	IOL = 1 mA, VDD = 3.3 V
	Voh	Output High Voltage					
HDO20		I/O ports	2.40	—	_	V	Юн = -1 mA, VDD = 3.3V
HDO26		OSC2/CLKO	2.41	—	—	V	Юн = -1 mA, Vdd = 3.3V

TABLE 23-8: DC CHARACTERISTICS: PROGRAM MEMORY

DC CHARACTERISTICS			(unless	otherw	ise stated	d)	a 3.0V to 3.6V TA ≤+150°C for High Temperature
Param No.	Symbol	Characteristic ⁽¹⁾	Min	Min Typ Max Units			Conditions
		Program Flash Memory					
HD130	Eр	Cell Endurance	10,000	—	_	E/W	-40° C to +150° C ⁽²⁾
HD134	TRETD	Characteristic Retention	20	_		Year	1000 E/W cycles or less and no other specifications are violated

Note 1: These parameters are assured by design, but are not characterized or tested in manufacturing.

2: Programming of the Flash memory is not allowed above 125°C.

23.2 AC Characteristics and Timing Parameters

The information contained in this section defines PIC24HJ32GP202/204 and PIC24HJ16GP304 AC characteristics and timing parameters for high temperature devices. However, all AC timing specifications in this section are the same as those in Section 22.2 "AC Characteristics and Timing Parameters", with the exception of the parameters listed in this section.

Parameters in this section begin with an H, which denotes High temperature. For example, parameter OS53 in Section 22.2 "AC Characteristics and Timing Parameters" is the Industrial and Extended temperature equivalent of HOS53.

TABLE 23-9: TEMPERATURE AND VOLTAGE SPECIFICATIONS – AC

AC CHARACTERISTICS	Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+150°C for High Temperature Operating voltage VOP reages on described in Table 22.4
	Operating voltage VDD range as described in Table 23-1.

FIGURE 23-1: LOAD CONDITIONS FOR DEVICE TIMING SPECIFICATIONS



TABLE 23-10: PLL CLOCK TIMING SPECIFICATIONS

-	AC TERISTICS	Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+150°C for High Temperature					
Param No.	Symbol	Characteristic	Min	Тур	Max	Units	Conditions
HOS53	DCLK	CLKO Stability (Jitter) ⁽¹⁾	-5	0.5	5	%	Measured over 100 ms period

Note 1: These parameters are characterized by similarity, but are not tested in manufacturing. This specification is based on clock cycle by clock cycle measurements. To calculate the effective jitter for individual time bases or communication clocks use this formula:

$$Peripheral Clock Jitter = \frac{DCLK}{\sqrt{\frac{FOSC}{Peripheral Bit Rate Clock}}}$$

For example: Fosc = 32 MHz, DCLK = 5%, SPI bit rate clock, (i.e., SCK) is 2 MHz.

$$SPI SCK Jitter = \left\lfloor \frac{D_{CLK}}{\sqrt{\left(\frac{32 \ MHz}{2 \ MHz}\right)}} \right\rfloor = \left\lfloor \frac{5\%}{\sqrt{16}} \right\rfloor = \left\lfloor \frac{5\%}{4} \right\rfloor = 1.25\%$$

TABLE 23-11:	SPIx MASTER MODE (REQUIREMENTS
--------------	--------------------	--	--------------

	AC	Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+150°C for High Temperature						
CHARAC	TERISTICS	Operating temperature -40 C	SI4 2+130		ign remp	erature		
Param No.	Symbol	Characteristic ⁽¹⁾	Min	Тур	Max	Units	Conditions	
HSP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge		10	25	ns	_	
HSP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	28	_	_	ns		
HSP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	35		_	ns	_	

Note 1: These parameters are characterized but not tested in manufacturing.

TABLE 23-12: SPIX MODULE MASTER MODE (CKE = 1) TIMING REQUIREMENTS

AC CHARACTERISTICS		Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}C \leq TA \leq +150^{\circ}C$ for High Temperature						
Param No.	Symbol	Characteristic ⁽¹⁾	Min	Тур	Max	Units	Conditions	
HSP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	10	25	ns	_	
HSP36	TdoV2sc, TdoV2scL	SDOx Data Output Setup to First SCKx Edge	35	—	—	ns	_	
HSP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	28	—	—	ns	_	
HSP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	35	—	—	ns	_	

Note 1: These parameters are characterized but not tested in manufacturing.

TADLE	ABLE 23-13. SFIX MODULE SLAVE MODE (CRE = 0) I IMING REQUIREMENTS							
CHARA	AC CTERISTICS	Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)Operating temperature-40°C ≤TA ≤+150°C for High Temperature						
Param No.	Symbol	Characteristic ⁽¹⁾	Min	Тур	Max	Units	Conditions	
HSP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge			35	ns	_	
HSP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	25	_	—	ns	_	
HSP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	25		—	ns	_	
HSP51	TssH2doZ	SSx ↑ to SDOx Output High-Impedance	15		55	ns	See Note 2	

TABLE 23-13: SPIX MODULE SLAVE MODE (CKE = 0) TIMING REQUIREMENTS

Note 1: These parameters are characterized but not tested in manufacturing.

2: Assumes 50 pF load on all SPIx pins.

TABLE 23-14: SPIX MODULE SLAVE MODE (CKE = 1) TIMING REQUIREMENTS

-	AC TERISTICS	Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)Operating temperature-40°C ≤TA ≤+150°C for High Temperature						
Param No.	Symbol	Characteristic ⁽¹⁾	Min	Тур	Max	Units	Conditions	
HSP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	-	35	ns	—	
HSP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	25	_		ns	_	
HSP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	25	_		ns	_	
HSP51	TssH2doZ	SSx ↑ to SDOx Output High-Impedance	15	_	55	ns	See Note 2	
HSP60	TssL2doV	<u>SDO</u> x Data Output Valid after SSx Edge	—		55	ns	—	

Note 1: These parameters are characterized but not tested in manufacturing.

2: Assumes 50 pF load on all SPIx pins.

TABLE 23-15: INTERNAL RC ACCURACY

AC CH	ARACTERISTICS	Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)Operating temperature $-40^{\circ}C \leq TA \leq +150^{\circ}C$ for Extended							
Param No.	Characteristic	Min	Тур	Max	Units	Units Conditions			
	LPRC @ 32.768 kHz ^(1,2)								
HF21	LPRC	-70	_	+70	%	-40°C ≤TA ≤+150°C VDD = 3.0-3.6V			

Note 1: Change of LPRC frequency as VDD changes.

2: LPRC accuracy impacts the Watchdog Timer Time-out Period (TWDT1). See Section 19.4 "Watchdog Timer (WDT)" for more information.

TABLE 23	TABLE 23-16: ADC MODULE SPECIFICATIONS							
-	AC Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) CHARACTERISTICS Operating temperature -40°C ≤TA ≤+150°C for High Temperature							
Param No.	Symbol	Characteristic	Min	Typ Max Units		Units	Conditions	
			Referenc	e Input	s			
HAD08	$\begin{array}{c ccccccccccccccccccccccccccccccccccc$							

TABLE 22 4C. ADO MODULE OBECIELOATIONO

Note 1: These parameters are not characterized or tested in manufacturing.

2: These parameters are characterized, but are not tested in manufacturing.

TABLE 23-17: ADC MODULE SPECIFICATIONS (12-BIT MODE)⁽³⁾

-	AC TERISTICS	Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+150°C for High Temperature							
Param No.	Symbol	Characteristic	Min Typ Max U		Units	Conditions			
	ADC Accuracy (12-bit Mode) – Measurements with External VREF+/VREF- ⁽¹⁾								
HAD20a	Nr	Resolution ⁽³⁾	1	2 data bi	ts	bits	—		
HAD21a	INL	Integral Nonlinearity	-2	—	+2	LSb	Vinl = AVSS = VREFL = 0V, AVDD = VREFH = 3.6V		
HAD22a	DNL	Differential Nonlinearity	> -1	—	< 1	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3.6V		
HAD23a	Gerr	Gain Error	-2	—	10	LSb	Vinl = AVss = Vrefl = 0V, AVdd = Vrefh = 3.6V		
HAD24a	EOFF	Offset Error	-3	—	5	LSb	Vinl = AVSS = VREFL = 0V, AVDD = VREFH = 3.6V		
	AD	C Accuracy (12-bit Mode	e) – Meas	uremen	ts with In	ternal V	/REF+/VREF- ⁽¹⁾		
HAD20a	Nr	Resolution ⁽³⁾	1	2 data bi	ts	bits	—		
HAD21a	INL	Integral Nonlinearity	-2	—	+2	LSb	VINL = AVSS = 0V, AVDD = 3.6V		
HAD22a	DNL	Differential Nonlinearity	> -1	—	< 1	LSb	VINL = AVSS = 0V, AVDD = 3.6V		
HAD23a	Gerr	Gain Error	2	—	20	LSb	VINL = AVSS = 0V, AVDD = 3.6V		
HAD24a	EOFF	Offset Error	2	—	10	LSb	VINL = AVSS = 0V, AVDD = 3.6V		
		Dynamic I	Performa	nce (12	-bit Mode	e) ⁽²⁾			
HAD33a	Fnyq	Input Signal Bandwidth	_	—	200	kHz	_		

Note 1: These parameters are characterized, but are tested at 20 ksps only.

2: These parameters are characterized by similarity, but are not tested in manufacturing.

3: Injection currents > | 0 | can affect the ADC results by approximately 4-6 counts.

с	Standard Operating Cond						
ERISTICS	Operating temperature						
Symbol	Characteristic	Min Typ Max Uni			Units	Conditions	
ADC Accuracy (10-bit Mode) – Measurements with External VREF+/VREF- ⁽¹⁾							
Nr	Resolution ⁽³⁾	10	0 data bi	ts	bits		
INL	Integral Nonlinearity	-3	_	3	LSb	Vinl = AVss = Vrefl = 0V, AVdd = Vrefh = 3.6V	
DNL	Differential Nonlinearity	> -1	_	< 1	LSb	Vinl = AVss = Vrefl = 0V, AVdd = Vrefh = 3.6V	
Gerr	Gain Error	-5	-	6	LSb	Vinl = AVss = Vrefl = 0V, AVdd = Vrefh = 3.6V	
EOFF	Offset Error	-1	—	5	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3.6V	
AD	C Accuracy (10-bit Mode)	– Measu	rements	s with Int	ernal V	REF+/VREF- ⁽¹⁾	
Nr	Resolution ⁽³⁾	10	0 data bi	ts	bits		
INL	Integral Nonlinearity	-2		2	LSb	VINL = AVSS = 0V, AVDD = 3.6V	
DNL	Differential Nonlinearity	> -1		< 1	LSb	VINL = AVSS = 0V, AVDD = 3.6V	
Gerr	Gain Error	-5		15	LSb	VINL = AVSS = 0V, AVDD = 3.6V	
Eoff	Offset Error	-1.5	_	7	LSb	VINL = AVSS = 0V, AVDD = 3.6V	
	Dynamic Pe	erforman	ice (10-k	oit Mode)	(2)		
Fnyq	Input Signal Bandwidth	—	_	400	kHz	_	
	Symbol ADO Nr NL DNL GERR EOFF AD Nr NL DNL GERR EOFF	SymbolCharacteristicADC Accuracy (10-bit Mode)NrResolution(3)NLIntegral NonlinearityDNLDifferential NonlinearityGERRGain ErrorEOFFOffset ErrorADC Accuracy (10-bit Mode)NrResolution(3)NLIntegral NonlinearityONLDifferential NonlinearityGERRGain ErrorEOFFOffset ErrorDNLIntegral NonlinearitySERRGain ErrorEOFFOffset ErrorDNLDifferential NonlinearityGERRGain ErrorEOFFOffset ErrorEOFFOffset ErrorDynamic PerentENYQInput Signal Bandwidth	Symbol Characteristic Min ADC Accuracy (10-bit Mode) – Measu Nr Resolution ⁽³⁾ 10 NL Integral Nonlinearity -3 -3 DNL Differential Nonlinearity > -1 GERR Gain Error -5 EOFF Offset Error -1 ML Integral Nonlinearity > -2 DNL Differential Nonlinearity -2 ONL Differential Nonlinearity -2 OFF Offset Error -1 ADC Accuracy (10-bit Mode) – Measu Nr Resolution ⁽³⁾ 10 NL Integral Nonlinearity -2 ONL Differential Nonlinearity -2 ONL Differential Nonlinearity > -1 GERR Gain Error -5 EOFF Offset Error -1.5 Dynamic Performant -1.5 Dynamic Performant -1.5	SymbolCharacteristicMinTypADC Accuracy (10-bit Mode) – MeasurementsNrResolution ⁽³⁾ 10 data biNLIntegral Nonlinearity-3—DNLDifferential Nonlinearity> -1—GERRGain Error-5—EOFFOffset Error-1—ADC Accuracy (10-bit Mode) – MeasurementsNrResolution ⁽³⁾ 10 data biNLIntegral Nonlinearity-2—ADC Accuracy (10-bit Mode) – MeasurementsNrResolution ⁽³⁾ 10 data biNLIntegral Nonlinearity-2—DNLDifferential Nonlinearity> -1—GERRGain Error-5—EOFFOffset Error-1.5—DNLDifferential Nonlinearity> -1—GERRGain Error-5—EOFFOffset Error-1.5—EOFFOffset Error-1.5—TOTALDifferential Nonlinearity> -1Dynamic Performance (10-bit Mode)-—ENYQInput Signal Bandwidth——	SymbolCharacteristicMinTypMaxADC Accuracy (10-bit Mode) – Measurements with ExcNrResolution ⁽³⁾ 10 data bitsNLIntegral Nonlinearity-3—ONLDifferential Nonlinearity> -1—GERRGain Error-5—6EOFFOffset Error-1—5ADC Accuracy (10-bit Mode) – Measurements with Integral Nonlinearity> -1—4NrResolution ⁽³⁾ 10 data bits10 data bits10NLIntegral Nonlinearity-2—2ONLDifferential Nonlinearity> -1—<1	SymbolCharacteristicMinTypMaxUnitsADC Accuracy (10-bit Mode) – Measurements with External V NrResolution ⁽³⁾ 10 data bitsbitsNLIntegral Nonlinearity-3—3LSbDNLDifferential Nonlinearity>-1—<1	

TABLE 23-18: ADC MODULE SPECIFICATIONS (10-BIT MODE)⁽³⁾

Note 1: These parameters are characterized, but are tested at 20 ksps only.

2: These parameters are characterized by similarity, but are not tested in manufacturing.

3: Injection currents > | 0 | can affect the ADC results by approximately 4-6 counts.

TABLE 23-19:	ADC CONVERSION (12-BIT MODE) TIMING REQUIREMENTS	
--------------	--	--

CHARA	AC CTERISTICS						
Param No.	Symbol	Characteristic Min Typ Max Units Conditions					Conditions
		Clock	A Parame	ters			
HAD50	TAD	ADC Clock Period ⁽¹⁾	147	_	_	ns	—
	Conversion Rate						
HAD56	FCNV	Throughput Rate ⁽¹⁾	—	_	400	Ksps	—

Note 1: These parameters are characterized but not tested in manufacturing.

TABLE 23-20: ADC CONVERSION (10-BIT MODE) TIMING REQUIREMENTS

	AC TERISTICS	Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+150°C for High Temperature					
Param No.	Symbol	Characteristic Min Typ Max Units Condit				Conditions	
		Cloc	k Parame	ters			
HAD50	TAD	ADC Clock Period ⁽¹⁾	104	—	—	ns	—
	Conversion Rate						
HAD56	FCNV	Throughput Rate ⁽¹⁾			800	Ksps	—

Note 1: These parameters are characterized but not tested in manufacturing.

24.0 PACKAGING INFORMATION

24.1 Package Marking Information

28-Lead SPDIP



Example



28-Lead SOIC



Example



28-Lead SSOP



Example



Legend	: XXX Y YY WW NNN @3 *	Customer-specific information Year code (last digit of calendar year) Year code (last 2 digits of calendar year) Week code (week of January 1 is week '01') Alphanumeric traceability code Pb-free JEDEC designator for Matte Tin (Sn) This package is Pb-free. The Pb-free JEDEC designator ((e3)) can be found on the outer packaging for this package.
Note:		Aicrochip part number cannot be marked on one line, it is carried over to the next limiting the number of available characters for customer-specific information.

24.1 Package Marking Information (Continued)



24.2 Package Details

28-Lead Skinny Plastic Dual In-Line (SP) – 300 mil Body [SPDIP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	Units		INCHES		
Dimension Limits		MIN	NOM	MAX	
Number of Pins	Ν	28			
Pitch	е	.100 BSC			
Top to Seating Plane	A	-	-	.200	
Molded Package Thickness	A2	.120	.135	.150	
Base to Seating Plane	A1	.015	-	_	
Shoulder to Shoulder Width	E	.290	.310	.335	
Molded Package Width	E1	.240	.285	.295	
Overall Length	D	1.345	1.365	1.400	
Tip to Seating Plane	L	.110	.130	.150	
Lead Thickness	С	.008	.010	.015	
Upper Lead Width	b1	.040	.050	.070	
Lower Lead Width	b	.014	.018	.022	
Overall Row Spacing §	eВ	-	-	.430	

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.

2. § Significant Characteristic.

3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.

4. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-070B

28-Lead Plastic Small Outline (SO) – Wide, 7.50 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging









	Units	MILLMETERS		
	Dimension Limits		NOM	MAX
Number of Pins	N	28		
Pitch	e	1.27 BSC		
Overall Height	A	—	-	2.65
Molded Package Thickness	A2	2.05	-	—
Standoff §	A1	0.10	-	0.30
Overall Width	E	10.30 BSC		
Molded Package Width	E1	7.50 BSC		
Overall Length	D	17.90 BSC		
Chamfer (optional)	h	0.25	-	0.75
Foot Length	L	0.40	-	1.27
Footprint	L1	1.40 REF		
Foot Angle Top	φ	0°	-	8°
Lead Thickness	С	0.18	-	0.33
Lead Width	b	0.31	-	0.51
Mold Draft Angle Top	α	5°	-	15°
Mold Draft Angle Bottom	β	5°	-	15°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.

2. § Significant Characteristic.

3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.15 mm per side.

- 4. Dimensioning and tolerancing per ASME Y14.5M.
 - BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-052B

28-Lead Plastic Shrink Small Outline (SS) – 5.30 mm Body [SSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	Ν	28		
Pitch	е	0.65 BSC		
Overall Height	А	-	-	2.00
Molded Package Thickness	A2	1.65	1.75	1.85
Standoff	A1	0.05	_	-
Overall Width	Е	7.40	7.80	8.20
Molded Package Width	E1	5.00	5.30	5.60
Overall Length	D	9.90	10.20	10.50
Foot Length	L	0.55	0.75	0.95
Footprint	L1	1.25 REF		
Lead Thickness	с	0.09	-	0.25
Foot Angle	φ	0°	4°	8°
Lead Width	b	0.22	_	0.38

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.

2. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.20 mm per side.

3. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-073B

28-Lead Plastic Quad Flat, No Lead Package (MM) – 6x6x0.9 mm Body [QFN-S] with 0.40 mm Contact Length

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	Units		MILLIMETERS		
Dimensio	Dimension Limits		NOM	MAX	
Number of Pins	Ν	28			
Pitch	е	0.65 BSC			
Overall Height	А	0.80 0.90 1.00			
Standoff	A1	0.00	0.02	0.05	
Contact Thickness	A3	0.20 REF			
Overall Width	E	6.00 BSC			
Exposed Pad Width	E2	3.65	3.70	4.70	
Overall Length	D	6.00 BSC			
Exposed Pad Length	D2	3.65	3.70	4.70	
Contact Width	b	0.23	0.38	0.43	
Contact Length	L	0.30	0.40	0.50	
Contact-to-Exposed Pad	K	0.20	-	_	

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.

2. Package is saw singulated.

3. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-124B

28-Lead Plastic Quad Flat, No Lead Package (MM) – 6x6x0.9 mm Body [QFN-S] with 0.40 mm Contact Length

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.65 BSC		
Optional Center Pad Width	W2			4.70
Optional Center Pad Length	T2			4.70
Contact Pad Spacing	C1		6.00	
Contact Pad Spacing	C2		6.00	
Contact Pad Width (X28)	X1			0.40
Contact Pad Length (X28)	Y1			0.85
Distance Between Pads	G	0.25		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2124A

44-Lead Plastic Quad Flat, No Lead Package (ML) – 8x8 mm Body [QFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



TOP VIEW

BOTTOM VIEW





	Units		MILLIMETERS		
Dimensio	Dimension Limits		NOM	MAX	
Number of Pins	Ν	44			
Pitch	е	0.65 BSC			
Overall Height	Α	0.80 0.90 1.00			
Standoff	A1	0.00	0.02	0.05	
Contact Thickness	A3	0.20 REF			
Overall Width	E	8.00 BSC			
Exposed Pad Width	E2	6.30	6.45	6.80	
Overall Length	D	8.00 BSC			
Exposed Pad Length	D2	6.30	6.45	6.80	
Contact Width	b	0.25	0.30	0.38	
Contact Length	L	0.30	0.40	0.50	
Contact-to-Exposed Pad	К	0.20	-	-	

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.

2. Package is saw singulated.

3. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-103B
44-Lead Plastic Quad Flat, No Lead Package (ML) – 8x8 mm Body [QFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.65 BSC	•
Optional Center Pad Width	W2			6.80
Optional Center Pad Length	T2			6.80
Contact Pad Spacing	C1		8.00	
Contact Pad Spacing	C2		8.00	
Contact Pad Width (X44)	X1			0.35
Contact Pad Length (X44)	Y1			0.80
Distance Between Pads	G	0.25		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2103A

44-Lead Plastic Thin Quad Flatpack (PT) – 10x10x1 mm Body, 2.00 mm Footprint [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	Units		MILLIMETERS	3
	Dimension Limits	MIN	NOM	MAX
Number of Leads	N		44	
Lead Pitch	e		0.80 BSC	
Overall Height	A	-	-	1.20
Molded Package Thickness	A2	0.95	1.00	1.05
Standoff	A1	0.05	-	0.15
Foot Length	L	0.45	0.60	0.75
Footprint	L1		1.00 REF	-
Foot Angle	φ	0°	3.5°	7°
Overall Width	E		12.00 BSC	
Overall Length	D		12.00 BSC	
Molded Package Width	E1		10.00 BSC	
Molded Package Length	D1		10.00 BSC	
Lead Thickness	С	0.09	_	0.20
Lead Width	b	0.30	0.37	0.45
Mold Draft Angle Top	α	11°	12°	13°
Mold Draft Angle Bottom	β	11°	12°	13°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.

2. Chamfers at corners are optional; size may vary.

3. Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25 mm per side.

4. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-076B

44-Lead Plastic Thin Quad Flatpack (PT) – 10x10x1 mm Body, 2.00 mm [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

[1.1.24		ETERO	
	Units	MILLIM	ETERS	
Dimension	Limits	MIN	NOM	MAX
Contact Pitch	E		0.80 BSC	
Contact Pad Spacing	C1		11.40	
Contact Pad Spacing	C2		11.40	
Contact Pad Width (X44)	X1			0.55
Contact Pad Length (X44)	Y1			1.50
Distance Between Pads	G	0.25		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2076A

NOTES:

APPENDIX A: REVISION HISTORY

Revision A (July 2007)

Initial release of this document.

Revision B (June 2008)

This revision includes minor typographical and formatting changes throughout the data sheet text.

The major changes are referenced by their respective section in the following table.

TABLE 24-1:	MAJOR SECTION UPDATES

Section Name	Update Description
"High-Performance, 16-bit Microcontrollers"	Added Extended Interrupts column to Remappable Peripherals in the Controller Families table and Note 2 (see Table 1).
	Added Note 1 to all pin diagrams, which references RPn pin usage by remappable peripherals (see " Pin Diagrams ").
Section 1.0 "Device Overview"	Changed PORTA pin name from RA15 to RA10 (see Table 1-1).
Section 3.0 "Memory Organization"	Updated Reset values for the following SFRs: IPC1, IPC3-IPC5, IPC7, IPC16, and INTTREG (see Table 3-4).
	Added the System Control Register Map (see Table 3-20).
Section 5.0 "Resets"	Entire section was replaced to maintain consistency with other PIC24H data sheets.
Section 7.0 "Oscillator Configuration"	Removed the first sentence of the third clock source item (External Clock) in Section 7.1.1.2 "Primary" .
	Updated the default bit values for DOZE and FRCDIV in the Clock Divisor Register (see Register 7-2).
	Added the center frequency in the OSCTUN register for the FRC Tuning bits (TUN<5:0>) value 011111 and updated the center frequency for bits value 011110 (see Register 7-4).
Section 8.0 "Power-Saving	Added the following two registers:
Features"	PMD1: Peripheral Module Disable Control Register 1
	PMD2: Peripheral Module Disable Control Register 2
Section 9.0 "I/O Ports"	Added paragraph and Table 9-1 to Section 9.1.1 "Open-Drain Configuration ", which provides details on I/O pins and their functionality.
	Removed the following sections, which are now available in the related section of the dsPIC33F/PIC24H Family Reference Manual:
	9.4.2 "Available Peripherals"
	• 9.4.3.3 "Mapping"
	 9.4.5 "Considerations for Peripheral Pin Selection"
Section 13.0 "Output Compare"	Replaced sections 13.1, 13.2 and 13.3 and related figures and tables with entirely new content.
Section 14.0 "Serial Peripheral Interface (SPI)"	Removed the following sections, which are now available in the related section of the dsPIC33F/PIC24H Family Reference Manual:
	14.1 "Interrupts"
	14.2 "Receive Operations"
	14.3 "Transmit Operations"
	• 14.4 "SPI Setup" (retained Figure 14-1: SPI Module Block Diagram)

Section Name	Update Description
Section 15.0 "Inter-Integrated Circuit (I ² C™)"	Removed the following sections, which are now available in the related section of the dsPIC33F/PIC24H Family Reference Manual:
	 15.3 "I²C Interrupts"
	 15.4 "Baud Rate Generator" (retained Figure 15-1: I²C Block Diagram)
	• 15.5 "I ² C Module Addresses"
	 15.6 "Slave Address Masking"
	15.7 "IPMI Support"
	15.8 "General Call Address Support"
	15.9 "Automatic Clock Stretch"
	• 15.10 "Software Controlled Clock Stretching (STREN = 1)"
	15.11 "Slope Control"
	15.12 "Clock Arbitration"
	• 15.13 "Multi-Master Communication, Bus Collision, and Bus Arbitration"
	15.14 "Peripheral Pin Select Limitations"
Section 16.0 "Universal	Removed the following sections, which are now available in the related
Asynchronous Receiver Transmitter	section of the dsPIC33F/PIC24H Family Reference Manual:
(UART)"	16.1 "UART Baud Rate Generator"
	16.2 "Transmitting in 8-bit Data Mode"
	16.3 "Transmitting in 9-bit Data Mode"
	 16.4 "Break and Sync Transmit Sequence"
	16.5 "Receiving in 8-bit or 9-bit Data Mode"
	16.6 "Flow Control Using UxCTS and UxRTS Pins"
	16.7 "Infrared Support"
	Removed IrDA references and Note 1, and updated the bit and bit value descriptions for UTXINV (UxSTA<14>) in the UARTx Status and Control Register (see Register 16-2).
Section 17.0 "10-bit/12-bit Analog- to-Digital Converter (ADC)"	Removed Equation 17-1: ADC Conversion Clock Period and Figure 17-2: ADC Transfer Function (10-bit Example).
	Added ADC1 Module Block Diagram for PIC24HFJ16GP304 and PIC24HJ32GP204 Devices (Figure 17-1) and ADC1 Module Block Diagram FOR PIC24HJ32GP202 Devices (Figure 17-2).
	Added Note 2 to Figure 17-3: ADC Conversion Clock Period Block Diagram.
	Added device-specific information to Note 1 in the ADC1 Input Scan Select Register Low (see Register 17-6), and updated the default bit value for bits 12-10 (CSS12-CSS10) from U-0 to R/W-0.
	Added device-specific information to Note 1 in the ADC1 Port Configuration Register Low (see Register 17-7), and updated the default bit value for bits 12-10 (PCFG12-PCFG10) from U-0 to R/W-0.

TABLE 24-1: MAJOR SECTION UPDATES (CONTINUED)

TABLE 24-1: MAJOR SECTION UPDATES (CONTINUED)		
Section Name	Update Description	
Section 18.0 "Special Features"	Added FICD register information for address 0xF8000E in the Device Configuration Register Map (see Table 18-1).	
	Added FICD register content (BKBUG, COE, JTAGEN, and ICS<1:0> to the PIC24HJ32GP202/204 and PIC24HJ16GP304 Configuration Bits Description (see Table 18-2).	
	Added a note regarding the placement of low-ESR capacitors, after the second paragraph of Section 18.2 " On-Chip Voltage Regulator " and to Figure 18-1.	
	Removed the words "if enabled" from the second sentence in the fifth paragraph of Section 18.3 "BOR: Brown-Out Reset ".	
Section 21.0 "Electrical	Removed Typ value for parameter DC12 (see Table 21-4).	
Characteristics"	Updated MIPS conditions for parameters DC24c, DC44c, DC72a, DC72f and DC72g (see Table 21-5, Table 21-6 and Table 21-8).	
	Added Note 4 (reference to new table containing digital-only and analog pin information to I/O Pin Input Specifications (see Table 21-9).	
	Updated Min, Typ, and Max values and updated Min values for Program Memory parameters D136, D137 and D138 (see Table 21-12).	
	Updated Max value for Internal RC Accuracy parameter F21 for -40°C \leq TA \leq +125°C condition and added Note 2 (see Table 21-19).	
	Removed all values for Reset, Watchdog Timer, Oscillator Start-up Timer, and Power-up Timer parameter SY20 and updated conditions, which now refers to Section 18.4 " Watchdog Timer (WDT) " and LPRC parameter F21 (see Table 21-21).	
	Updated Min and Typ values for parameters AD60, AD61, AD62 and AD63 and removed Note 3 (see Table 21-37).	
	Updated Min and Typ values for parameters AD60, AD61, AD62 and AD63 and removed Note 3 (see Table 21-38).	

TABLE 24-1: MAJOR SECTION UPDATES (CONTINUED)

Revision C (December 2008)

This revision includes minor typographical and formatting changes throughout the data sheet text.

The major changes are referenced by their respective section in the following table.

TABLE 24-2: MAJOR SECTION UPDATES

Section Name	Update Description
"High-Performance, 16-bit Microcontrollers"	Updated all pin diagrams to denote the pin voltage tolerance (see " Pin Diagrams ").
Section 2.0 "Guidelines for Getting Started with 16-bit Microcontrollers"	Added new section to the data sheet that provides guidelines on getting started with 16-bit microcontrollers.
Section 10.0 "I/O Ports"	Updated 5V tolerant status for I/O pin RB4 from Yes to No (see Table 10-1).
Section 22.0 "Electrical Characteristics"	Removed the maximum value for parameter DC12 (RAM Data Retention Voltage) in Table 22-4.
	Updated typical values for Operating Current (IDD) and added Note 3 in Table 22-5.
	Updated typical and maximum values for Idle Current (IIDLE): Core OFF Clock ON Base Current and added Note 3 in Table 22-6.
	Updated typical and maximum values for Power Down Current (IPD) and added Note 5 in Table 22-7.
	Updated typical and maximum values for Doze Current (IDoze) and added Note 2 in Table 22-8.
	Added Note 3 to Table 22-12.
	Updated minimum value for Internal Voltage Regulator Specifications in Table 22-13.
	Added parameter OS42 (GM) and Notes 4, 5, and 6 to Table 22-16.
	Added Notes 2 and 3 to Table 22-17.
	Added Note 2 to Table 22-20.
	Added Note 2 to Table 22-21.
	Added Note 2 to Table 22-22.
	Added Note 1 to Table 22-23.
	Added Note 1 to Table 22-24.
	Added Note 3 to Table 22-32.
	Added Note 2 to Table 22-33.
	Updated typical value for parameter AD08 (ADC in operation) and added Notes 2 and 3 in Table 22-34.
	Updated minimum, typical, and maximum values for parameters AD23a, AD24a, AD30a, AD32a, AD32a, and AD34a, and added Notes 2 and 3 in Table 22-35.
	Updated minimum, typical, and maximum values for parameters AD23b, AD24b, AD30b, AD32b, AD32b, and AD34b, and added Notes 2 and 3 in Table 22-36.

Revision D (June 2009)

This revision includes minor typographical and formatting changes throughout the data sheet text.

Global changes include:

- Changed all instances of OSCI to OSC1 and OSCO to OSC2
- Changed all instances of PGCx/EMUCx and PGDx/EMUDx (where x = 1, 2, or 3) to PGECx and PGEDx

Changed all instances of VDDCORE and VDDCORE/VCAP to VCAP/VDDCORE

All other major changes are referenced by their respective section in the following table.

TABLE 24-3: MAJOR SECTION UPDATES	TABLE 24-3:	MAJOR SECTION UPDATES
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Section Name	Update Description
"High-Performance, 16-bit Microcontrollers"	Added Note 2 to the 28-Pin QFN-S and 44-Pin QFN pin diagrams, which references pin connections to Vss.
Section 8.0 "Oscillator Configuration"	Updated the Oscillator System Diagram (see Figure 8-1).
	Added Note 1 to the Oscillator Tuning (OSCTUN) register (see Register 8-4).
Section 10.0 "I/O Ports"	Removed Table 10-1 and added reference to pin diagrams for I/O pin availability and functionality.
Section 15.0 "Serial Peripheral Interface (SPI)"	Added Note 2 to the SPIx Control Register 1 (see Register 15-2).
Section 17.0 "Universal Asynchronous Receiver Transmitter (UART)"	Updated the UTXINV bit settings in the UxSTA register and added Note 1 (see Register 17-2).
Section 22.0 "Electrical Characteristics"	Updated the Min value for parameter DC12 (RAM Retention Voltage) and added Note 4 to the DC Temperature and Voltage Specifications (see Table 22-4).
	Updated the Min value for parameter DI35 (see Table 22-20).
	Updated AD08 and added reference to Note 2 for parameters AD05a, AD06a, and AD08a (see Table 22-34).

Revision E (November 2009)

The revision includes the following global update:

• Added Note 2 to the shaded table that appears at the beginning of each chapter. This new note provides information regarding the availability of registers and their associated bits

This revision also includes minor typographical and formatting changes throughout the data sheet text.

All other major changes are referenced by their respective section in the following table.

TABLE 24-4: MAJOR SECTION UPDATES

Section Name	Update Description
"High-Performance, 16-bit Microcontrollers"	Added information on high temperature operation (see "Operating Range:").
Section 10.0 "I/O Ports"	Changed the reference to digital-only pins to 5V tolerant pins in the second paragraph of Section 10.2 " Open-Drain Configuration ".
Section 17.0 "Universal Asynchronous Receiver Transmitter (UART)"	Updated the two baud rate range features to: 10 Mbps to 38 bps at 40 MIPS.
Section 18.0 "10-bit/12-bit Analog-to-Digital Converter (ADC)"	Updated the ADC1 block diagrams (see Figure 18-1 and Figure 18-2).
Section 19.0 "Special Features"	Updated the second paragraph and removed the fourth paragraph in Section 19.1 "Configuration Bits" . Updated the Device Configuration Register Map (see Table 19-1).
Section 22.0 "Electrical Characteristics"	Updated the Absolute Maximum Ratings for high temperature and added Note 4.
	Updated the SPIx Module Slave Mode (CKE = 1) Timing Characteristics (see Figure 22-12).
Section 23.0 "High Temperature Electrical Characteristics"	Added new chapter with high temperature specifications.
"Product Identification System"	Added the "H" definition for high temperature.

Revision F (November 2009)

This revision includes minor typographical and formatting changes throughout the data sheet text.

All other major changes are referenced by their respective section in the following table.

TABLE A-1: MAJOR SECTION UPDATES

Section Name	Update Description
"High-Performance, 16-bit Microcontrollers"	Updated MIPS rating from 16 to 20 for high temperature devices in "Operating Range:" and in TABLE 23-1: "Operating MIPS vs. Voltage".

Revision G (January 2011)

This revision includes typographical and formatting changes throughout the data sheet text. In addition, all instances of VDDCORE have been removed.

All other major changes are referenced by their respective section in the following table.

TABLE A-2: MAJOR SECTION UPDATES

Section Name	Update Description
High-Performance, 16-bit Microcontrollers	Added the SSOP package information (see " Packaging: ", Table 1, and " Pin Diagrams ").
Section 2.0 "Guidelines for Getting Started with 16-bit Microcontrollers"	The frequency limitation for device PLL start-up conditions was updated in Section 2.7 "Oscillator Value Conditions on Device Start-up".
	The second paragraph in Section 2.9 "Unused I/Os" was updated.
Section 4.0 "Memory Organization"	Updated the data memory reference in the third paragraph in Section 4.2 "Data Address Space".
	The All Resets values for the following SFRs in the Timer Register Map were changed (see Table 4-5):
	• TMR1
	• TMR2
	• TMR3
Section 8.0 "Oscillator Configuration"	Added Note 3 to the OSCCON: Oscillator Control Register (see Register 8-1).
	Added Note 2 to the CLKDIV: Clock Divisor Register (see Register 8-2).
	Added Note 1 to the PLLFBD: PLL Feedback Divisor Register (see Register 8-3).
	Added Note 2 to the OSCTUN: FRC Oscillator Tuning Register (see Register 8-4).
Section 18.0 "10-bit/12-bit Analog-to-Digital Converter (ADC)"	Updated the VREFL references in the ADC1 module block diagrams (see Figure 18-1 and Figure 18-2).
Section 19.0 "Special Features"	Added a new paragraph and removed the third paragraph in Section 19.1 "Configuration Bits".
	Added the column "RTSP Effects" to the Configuration Bits Descriptions (see Table 19-2).

Section Name	Update Description
Section 22.0 "Electrical Characteristics"	Added 28-pin SSOP Thermal Packaging Characteristics (see Table 22-3).
	Removed Note 4 from the DC Temperature and Voltage Specifications (see Table 22-4).
	Updated the maximum value for parameter DI19 and added parameters DI28, DI29, DI60a, DI60b, and DI60c to the I/O Pin Input Specifications (see Table 22-9).
	Updated Note 3 in the PLL Clock Timing Specifications (see Table 22-17).
	Removed Note 2 from the AC Characteristics: Internal RC Accuracy (see Table 22-18).
	Updated the characteristic description for parameter DI35 in the I/O Timing Requirements (see Table 22-20).
	Updated <i>all</i> SPI specifications (see Table 22-28 through Table 22-35 and Figure 22-10 through Figure 22-16).
	Added Note 4 to the 12-bit ADC Module Specifications (see Table 22-39).
	Added Note 4 to the 10-bit ADC Module Specifications (see Table 22-40).
Section 23.0 "High Temperature Electrical Characteristics"	Updated all ambient temperature end range values to +150°C throughout the chapter.
	Updated the storage temperature end range to +160°C.
	Updated the maximum junction temperature from +145°C to +155°C.
	Updated Note 1 in the PLL Clock Timing Specifications (see Table 23-10).
	Added Note 3 to the 12-bit Mode ADC Module Specifications (see Table 23-17).
	Added Note 3 to the 10-bit Mode ADC Module Specifications (see Table 23-18).
Section 24.0 "Packaging Information"	Added the 28-Lead SSOP package information (see Section 24.1 "Package Marking Information" and Section 24.2 "Package Details").
"Product Identification System"	Added the "SS" definition for the SSOP package.

TABLE A-2: MAJOR SECTION UPDATES (CONTINUED)

Revision H (July 2011)

This revision includes typographical and formatting changes throughout the data sheet text.

All other major changes are referenced by their respective section in the following table.

TABLE A-3: MAJOR SECTION UPDATES

Section Name	Update Description
Section 19.0 "Special Features"	Added Note 3 to the Connections for the On-chip Voltage Regulator diagram (see Figure 19-1).
Section 22.0 "Electrical Characteristics"	Removed Note 3 and parameter DC10 (VCORE) from the DC Temperature and Voltage Specifications (see Table 22-4).
	Updated the Characteristics definition and Conditions for parameter BO10 in the Electrical Characteristics: BOR (see Table 22-11).
	Added Note 1 to the Internal Voltage Regulator Specifications (see Table 22-13).

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Tape and Reel Flag Temperature Range Package	ily — ize (Kl (if app e	B) –		Examples: a) PIC24HJ32GP202-E/SP: General-purpose PIC24H, 32 KB program memory, 28-pin, Extended temp., SPDIP package.
Architecture:	24	=	16-bit Microcontroller	
Flash Memory Family:	HJ	=	Flash program memory, 3.3V	
Product Group:	GP2 GP3	= =	General purpose family General purpose family	
Pin Count:	02 03	= =	28-pin 44-pin	
Temperature Range:	I E H	= = =	-40° C to +85° C (Industrial) -40° C to +125° C (Extended) -40° C to +150° C (High)	
Package:	SP SO SS MM PT ML		Plastic Shrink Small Outline - 5.3 mm body (SSOP)	



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